# IGLOO Low Power Flash FPGAs
## with Flash*Freeze Technology

## Features and Benefits

### Low Power
- 1.2 V to 1.5 V Core Voltage Support for Low Power
- Supports Single-Voltage System Operation
- 5 µW Power Consumption in Flash*Freeze Mode
- Low Power Active FPGA Operation
- Flash*Freeze Technology Enables Ultra-Low Power Consumption while Maintaining FPGA Content
- Easy Entry to / Exit from Ultra-Low Power Flash*Freeze Mode

### High Capacity
- 15K to 1 Million System Gates
- Up to 144 Kbits of True Dual-Port SRAM
- Up to 300 User I/Os

### Reprogrammable Flash Technology
- 130-nm, 7-Layer Metal, Flash-Based CMOS Process
- Live-at-Power-Up (LAPU) Level 0 Support
- Single-Chip Solution
- Retains Programmed Design When Powered Off
- 250 MHz (1.5 V systems) and 160 MHz (1.2 V systems) System Performance

### In-System Programming (ISP) and Security
- ISP Using On-Chip 128-Bit Advanced Encryption Standard (AES) Decryption (except ARM®-enabled IGLOO® devices) via JTAG (IEEE 1532–compliant)†
- FlashLock® Designed to Secure FPGA Contents

### High-Performance Routing Hierarchy
- Segmented, Hierarchical Routing and Clock Structure

### Advanced I/O
- 700 Mbps DDR, LVDS-Capable I/Os (AGL250 and above)
- 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.3 V Mixed-Voltage Operation
- Bank-Selectable I/O Voltages—up to 4 Banks per Chip
- Single-Ended I/O Standards: LVTTL, LVCMOS 3.3 V / 2.5 V / 1.8 V / 1.5 V / 1.2 V, 3.3 V PCI / 3.3 V PCI-X†, and LVCMOS 2.5 V / 5.0 V Input†
- Differential I/O Standards: LVPECL, LVDS, B-LVDS, and M-LVDS (AGL250 and above)
- Wide Range Power Supply Voltage Support per JESD8-B, Allowing I/Os to Operate from 2.7 V to 3.6 V
- Wide Range Power Supply Voltage Support per JESD8-12, Allowing I/Os to Operate from 1.14 V to 1.575 V
- I/O Registers on Input, Output, and Enable Paths
- Hot-Swappable and Cold-Sparing I/Os‡
- Programmable Output Slew Rate† and Drive Strength
- Weak Pull-Up/-Down
- IEEE 1149.1 (JTAG) Boundary Scan Test
- Pin-Compatible Packages across the IGLOO Family

### Clock Conditioning Circuit (CCC) and PLL†
- Six CCC Blocks, One with an Integrated PLL
- Configurable Phase Shift, Multiply/Divide, Delay Capabilities, and External Feedback
- Wide Input Frequency Range (1.5 MHz up to 250 MHz)

### Embedded Memory
- 1 kbit of FlashROM User Nonvolatile Memory
- SRAMs and FIFOs with Variable-Aspect-Ratio 4,608-Bit† RAM Blocks (×1, ×2, ×4, ×9, and ×18 organizations)
- True Dual-Port SRAM (except ×18)†

### ARM Processor Support in IGLOO FPGAs
- M1 IGLOO Devices—Cortex™-M1 Soft Processor Available with or without Debug

| IGLOO Devices | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | AGL400 | AGL600 | AGL1000 |
|---|---|---|---|---|---|---|---|---|
| ARM-Enabled IGLOO Devices[1] | | | | | **M1AGL250** | | **M1AGL600** | **M1AGL1000** |
| System Gates | 15,000 | 30,000 | 60,000 | 125,000 | 250,000 | 400,000 | 600,000 | 1,000,000 |
| Typical Equivalent Macrocells | 128 | 256 | 512 | 1,024 | 2,048 | – | – | – |
| VersaTiles (D-flip-flops) | 384 | 768 | 1,536 | 3,072 | 6,144 | 9,216 | 13,824 | 24,576 |
| Flash*Freeze Mode (typical, µW) | 5 | 5 | 10 | 16 | 24 | 32 | 36 | 53 |
| RAM kbits (1,024 bits) | – | – | 18 | 36 | 36 | 54 | 108 | 144 |
| 4,608-Bit Blocks | – | – | 4 | 8 | 8 | 12 | 24 | 32 |
| FlashROM Kbits (1,024 bits) | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 |
| AES-Protected ISP [1] | – | – | Yes | Yes | Yes | Yes | Yes | Yes |
| Integrated PLL in CCCs [2] | – | – | 1 | 1 | 1 | 1 | 1 | 1 |
| VersaNet Globals [3] | 6 | 6 | 18 | 18 | 18 | 18 | 18 | 18 |
| I/O Banks | 2 | 2 | 2 | 2 | 4 | 4 | 4 | 4 |
| Maximum User I/Os | 49 | 81 | 96 | 133 | 143 | 194 | 235 | 300 |
| Package Pins | | | | | | | | |
| UC/CS | | UC81 | CS121[2] | CS121, CS196 | CS81, CS196[4] | CS196 | CS281 | CS281 |
| QFN | QN68 | CS81 QN48, QN68, QN132 | QN132 | QN132 | QN132 [4] | | | |
| VQFP | | VQ100 | VQ100 | VQ100 | VQ100 | | | |
| FBGA | | | FG144 | FG144 | FG144 | FG144, FG256, FG484 | FG144, FG256, FG484 | FG144, FG256, FG484 |

*Notes:*
1. *AES is not available for ARM-enabled IGLOO devices.*
2. *AGL060 in CS121 does not support the PLL.*
3. *Six chip (main) and twelve quadrant global networks are available for AGL060 and above.*
4. *The M1AGL250 device does not support this package.*
5. *The IGLOOe datasheet and IGLOOe FPGA Fabric User's Guide provide information on higher densities and additional features.*

*† AGL015 and AGL030 devices do not support this feature.*

*‡ Supported only by AGL015 and AGL030 devices.*


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# I/Os Per Package[1]

| IGLOO Devices | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | | AGL400 | | AGL600 | | AGL1000 | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| ARM-Enabled IGLOO Devices | | | | | M1AGL250 | | | | M1AGL600 | | M1AGL1000 | |
| | I/O Type[2] | | | | | | | | | | | |
| Package | Single-Ended I/O | Single-Ended I/O | Single-Ended I/O | Single-Ended I/O | Single-Ended I/O[3] | Differential I/O Pairs | Single-Ended I/O[3] | Differential I/O Pairs | Single-Ended I/O[3] | Differential I/O Pairs | Single-Ended I/O[3] | Differential I/O Pairs |
| QN48 | – | 34 | – | – | – | – | – | – | – | – | – | – |
| QN68 | 49 | 49 | – | – | – | – | – | – | – | – | – | – |
| UC81 | – | 66 | – | – | – | – | – | – | – | – | – | – |
| CS81 | – | 66 | – | – | 60 | 7 | – | – | – | – | – | – |
| CS121 | – | – | 96 | 96 | – | – | – | – | – | – | – | – |
| VQ100 | – | 77 | 71 | 71 | 68 | 13 | – | – | – | – | – | – |
| QN132 | – | 81 | 80 | 84 | 87[4] | 19[4] | – | – | – | – | – | – |
| CS196 | – | – | – | 133 | 143[4] | 35[4] | 143 | 35 | – | – | – | – |
| FG144 | – | – | 96 | 97 | 97 | 24 | 97 | 25 | 97 | 25 | 97 | 25 |
| FG256[5] | – | – | – | – | – | – | 178 | 38 | 177 | 43 | 177 | 44 |
| CS281 | – | – | – | – | – | – | – | – | 215 | 53 | 215 | 53 |
| FG484[5] | – | – | – | – | – | – | 194 | 38 | 235 | 60 | 300 | 74 |

*Notes:*

1. *When considering migrating your design to a lower- or higher-density device, refer to the IGLOO FPGA Fabric User's Guide to ensure compliance with design and board migration requirements.*
2. *When the Flash*Freeze pin is used to directly enable Flash*Freeze mode and not used as a regular I/O, the number of single-ended user I/Os available is reduced by one.*
3. *Each used differential I/O pair reduces the number of single-ended I/Os available by two.*
4. *The M1AGL250 device does not support QN132 or CS196 packages.*
5. *FG256 and FG484 are footprint-compatible packages.*

**Table 1 • IGLOO FPGAs Package Sizes Dimensions**

| Package | UC81 | CS81 | CS121 | QN48 | QN68 | QN132 | CS196 | CS281 | FG144 | VQ100 | FG256 | FG484 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Length × Width (mm\mm) | 4 × 4 | 5 × 5 | 6 × 6 | 6 × 6 | 8 × 8 | 8 × 8 | 8 × 8 | 10 × 10 | 13 × 13 | 14 × 14 | 17 × 17 | 23 × 23 |
| Nominal Area ($mm^2$) | 16 | 25 | 36 | 36 | 64 | 64 | 64 | 100 | 169 | 196 | 289 | 529 |
| Pitch (mm) | 0.4 | 0.5 | 0.5 | 0.4 | 0.4 | 0.5 | 0.5 | 0.5 | 1.0 | 0.5 | 1.0 | 1.0 |
| Height (mm) | 0.80 | 0.80 | 0.99 | 0.90 | 0.90 | 0.75 | 1.20 | 1.05 | 1.45 | 1.00 | 1.60 | 2.23 |

# IGLOO Ordering Information

AGL1000 V2 – FG G 144 Y I

Application (Temperature Range)
Blank = Commercial (0°C to +70°C Ambient Temperature)
I = Industrial (–40°C to +85°C Ambient Temperature)
PP = Pre-Production
ES = Engineering Sample (Room Temperature Only)

Security Feature
Y = Device Includes License to Implement IP Based on the Cryptography Research, Inc. (CRI) Patent Portfolio

LICENSED DPA COUNTERMEASURES

Package Lead Count

Lead-Free Packaging
Blank = Standard Packaging
G= RoHS-Compliant Packaging (some packages also halogen-free)

Package Type
UC = Micro Chip Scale Package (0.4 mm pitch)
CS = Chip Scale Package (0.4 mm and 0.5 mm pitches)
QN = Quad Flat Pack No Leads (0.4 mm and 0.5 mm pitch)
VQ = Very Thin Quad Flat Pack (0.5 mm pitch)
FG = Fine Pitch Ball Grid Array (1.0 mm pitch)

Supply Voltage
2 = 1.2 V to 1.5 V
5 = 1.5 V only

Part Number

**IGLOO Devices**

AGL015 = 15,000 System Gates
AGL030 = 30,000 System Gates
AGL060 = 60,000 System Gates
AGL125 = 125,000 System Gates
AGL250 = 250,000 System Gates
AGL400 = 400,000 System Gates
AGL600 = 600,000 System Gates
AGL1000 = 1,000,000 System Gates

**IGLOO Devices with Cortex-M1**

M1AGL250 = 250,000 System Gates
M1AGL600 = 600,000 System Gates
M1AGL1000 = 1,000,000 System Gates

*Note: Marking Information: IGLOO V2 devices do not have V2 marking, but IGLOO V5 devices are marked accordingly.*

# Temperature Grade Offerings

| Package | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | AGL400 | AGL600 | AGL1000 |
|---|---|---|---|---|---|---|---|---|
| | | | | | M1AGL250 | | M1AGL600 | M1AGL1000 |
| **QN48** | – | C, I | – | – | – | – | – | – |
| **QN68** | C, I | – | – | – | – | – | – | – |
| **UC81** | – | C, I | – | – | – | – | – | – |
| **CS81** | – | C, I | – | – | C, I | – | – | – |
| **CS121** | – | – | C, I | C, I | – | – | – | – |
| **VQ100** | – | C, I | C, I | C, I | C, I | – | – | – |
| **QN132** | – | C, I | C, I | C, I | C, I | – | – | – |
| **CS196** | – | – | – | C, I | C, I | C, I | – | – |
| **FG144** | – | – | C, I | C, I | C, I | C, I | C, I | C, I |
| **FG256** | – | – | – | – | – | C, I | C, I | C, I |
| **CS281** | – | – | – | – | – | – | C, I | C, I |
| **FG484** | – | – | – | – | – | C, I | C, I | C, I |

*C = Commercial temperature range: 0°C to 70°C ambient temperature.*
*I = Industrial temperature range: –40°C to 85°C ambient temperature.*

# IGLOO Device Status

| IGLOO Devices | Status | M1 IGLOO Devices | Status |
|---|---|---|---|
| AGL015 | Production | | |
| AGL030 | Production | | |
| AGL060 | Production | | |
| AGL125 | Production | | |
| AGL250 | Production | M1AGL250 | Production |
| AGL400 | Production | | |
| AGL600 | Production | M1AGL600 | Production |
| AGL1000 | Production | M1AGL1000 | Production |

References made to IGLOO devices also apply to ARM-enabled IGLOOe devices. The ARM-enabled part numbers start with M1 (Cortex-M1).

Contact your local Microsemi SoC Products Group (formerly Actel) representative for device availability: http://www.microsemi.com/soc/contact/default.aspx.

### *AGL015 and AGL030*

The AGL015 and AGL030 are architecturally compatible; there are no RAM or PLL features.

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# 1 – IGLOO Device Family Overview

## General Description

The IGLOO family of flash FPGAs, based on a 130-nm flash process, offers the lowest power FPGA, a single-chip solution, small footprint packages, reprogrammability, and an abundance of advanced features.

The Flash*Freeze technology used in IGLOO devices enables entering and exiting an ultra-low power mode that consumes as little as 5 µW while retaining SRAM and register data. Flash*Freeze technology simplifies power management through I/O and clock management with rapid recovery to operation mode.

The Low Power Active capability (static idle) allows for ultra-low power consumption (from 12 µW) while the IGLOO device is completely functional in the system. This allows the IGLOO device to control system power management based on external inputs (e.g., scanning for keyboard stimulus) while consuming minimal power.

Nonvolatile flash technology gives IGLOO devices the advantage of being a secure, low power, single-chip solution that is live at power-up (LAPU). IGLOO is reprogrammable and offers time-to-market benefits at an ASIC-level unit cost.

These features enable designers to create high-density systems using existing ASIC or FPGA design flows and tools.

IGLOO devices offer 1 kbit of on-chip, reprogrammable, nonvolatile FlashROM storage as well as clock conditioning circuitry based on an integrated phase-locked loop (PLL). The AGL015 and AGL030 devices have no PLL or RAM support. IGLOO devices have up to 1 million system gates, supported with up to 144 kbits of true dual-port SRAM and up to 300 user I/Os.

M1 IGLOO devices support the high-performance, 32-bit Cortex-M1 processor developed by ARM for implementation in FPGAs. Cortex-M1 is a soft processor that is fully implemented in the FPGA fabric. It has a three-stage pipeline that offers a good balance between low power consumption and speed when implemented in an M1 IGLOO device. The processor runs the ARMv6-M instruction set, has a configurable nested interrupt controller, and can be implemented with or without the debug block. Cortex-M1 is available for free from Microsemi for use in M1 IGLOO FPGAs.

The ARM-enabled devices have ordering numbers that begin with M1AGL and do not support AES decryption.

### Flash*Freeze Technology

The IGLOO device offers unique Flash*Freeze technology, allowing the device to enter and exit ultra-low power Flash*Freeze mode. IGLOO devices do not need additional components to turn off I/Os or clocks while retaining the design information, SRAM content, and registers. Flash*Freeze technology is combined with in-system programmability, which enables users to quickly and easily upgrade and update their designs in the final stages of manufacturing or in the field. The ability of IGLOO V2 devices to support a wide range of core voltage (1.2 V to 1.5 V) allows further reduction in power consumption, thus achieving the lowest total system power.

When the IGLOO device enters Flash*Freeze mode, the device automatically shuts off the clocks and inputs to the FPGA core; when the device exits Flash*Freeze mode, all activity resumes and data is retained.

The availability of low power modes, combined with reprogrammability, a single-chip and single-voltage solution, and availability of small-footprint, high pin-count packages, make IGLOO devices the best fit for portable electronics.

## Flash Advantages

### Low Power

Flash-based IGLOO devices exhibit power characteristics similar to those of an ASIC, making them an ideal choice for power-sensitive applications. IGLOO devices have only a very limited power-on current surge and no high-current transition period, both of which occur on many FPGAs.

IGLOO devices also have low dynamic power consumption to further maximize power savings; power is even further reduced by the use of a 1.2 V core voltage.

Low dynamic power consumption, combined with low static power consumption and Flash*Freeze technology, gives the IGLOO device the lowest total system power offered by any FPGA.

### Security

Nonvolatile, flash-based IGLOO devices do not require a boot PROM, so there is no vulnerable external bitstream that can be easily copied. IGLOO devices incorporate FlashLock, which provides a unique combination of reprogrammability and design security without external overhead, advantages that only an FPGA with nonvolatile flash programming can offer.

IGLOO devices utilize a 128-bit flash-based lock and a separate AES key to provide the highest level of protection in the FPGA industry for intellectual property and configuration data. In addition, all FlashROM data in IGLOO devices can be encrypted prior to loading, using the industry-leading AES-128 (FIPS192) bit block cipher encryption standard. AES was adopted by the National Institute of Standards and Technology (NIST) in 2000 and replaces the 1977 DES standard. IGLOO devices have a built-in AES decryption engine and a flash-based AES key that make them the most comprehensive programmable logic device security solution available today. IGLOO devices with AES-based security provide a high level of protection for remote field updates over public networks such as the Internet, and are designed to ensure that valuable IP remains out of the hands of system overbuilders, system cloners, and IP thieves. The contents of a programmed IGLOO device cannot be read back, although secure design verification is possible.

Security, built into the FPGA fabric, is an inherent component of the IGLOO family. The flash cells are located beneath seven metal layers, and many device design and layout techniques have been used to make invasive attacks extremely difficult. The IGLOO family, with FlashLock and AES security, is unique in being highly resistant to both invasive and noninvasive attacks. Your valuable IP is protected with industry-standard security, making remote ISP possible. An IGLOO device provides the best available security for programmable logic designs.

### Single Chip

Flash-based FPGAs store their configuration information in on-chip flash cells. Once programmed, the configuration data is an inherent part of the FPGA structure, and no external configuration data needs to be loaded at system power-up (unlike SRAM-based FPGAs). Therefore, flash-based IGLOO FPGAs do not require system configuration components such as EEPROMs or microcontrollers to load device configuration data. This reduces bill-of-materials costs and PCB area, and increases security and system reliability.

### Live at Power-Up

Flash-based IGLOO devices support Level 0 of the LAPU classification standard. This feature helps in system component initialization, execution of critical tasks before the processor wakes up, setup and configuration of memory blocks, clock generation, and bus activity management. The LAPU feature of flash-based IGLOO devices greatly simplifies total system design and reduces total system cost, often eliminating the need for CPLDs and clock generation PLLs. In addition, glitches and brownouts in system power will not corrupt the IGLOO device's flash configuration, and unlike SRAM-based FPGAs, the device will not have to be reloaded when system power is restored. This enables the reduction or complete removal of the configuration PROM, expensive voltage monitor, brownout detection, and clock generator devices from the PCB design. Flash-based IGLOO devices simplify total system design and reduce cost and design risk while increasing system reliability and improving system initialization time.

IGLOO flash FPGAs allow the user to quickly enter and exit Flash*Freeze mode. This is done almost instantly (within 1 µs) and the device retains configuration and data in registers and RAM. Unlike SRAM-based FPGAs the device does not need to reload configuration and design state from external memory components; instead it retains all necessary information to resume operation immediately.

## Reduced Cost of Ownership

Advantages to the designer extend beyond low unit cost, performance, and ease of use. Unlike SRAM-based FPGAs, Flash-based IGLOO devices allow all functionality to be live at power-up; no external boot PROM is required. On-board security mechanisms prevent access to all the programming information and enable secure remote updates of the FPGA logic. Designers can perform secure remote in-system reprogramming to support future design iterations and field upgrades with confidence that valuable intellectual property cannot be compromised or copied. Secure ISP can be performed using the industry-standard AES algorithm. The IGLOO family device architecture mitigates the need for ASIC migration at higher user volumes. This makes the IGLOO family a cost-effective ASIC replacement solution, especially for applications in the consumer, networking/communications, computing, and avionics markets.

## Firm-Error Immunity

Firm errors occur most commonly when high-energy neutrons, generated in the upper atmosphere, strike a configuration cell of an SRAM FPGA. The energy of the collision can change the state of the configuration cell and thus change the logic, routing, or I/O behavior in an unpredictable way. These errors are impossible to prevent in SRAM FPGAs. The consequence of this type of error can be a complete system failure. Firm errors do not exist in the configuration memory of IGLOO flash-based FPGAs. Once it is programmed, the flash cell configuration element of IGLOO FPGAs cannot be altered by high-energy neutrons and is therefore immune to them. Recoverable (or soft) errors occur in the user data SRAM of all FPGA devices. These can easily be mitigated by using error detection and correction (EDAC) circuitry built into the FPGA fabric.

## Advanced Flash Technology

The IGLOO family offers many benefits, including nonvolatility and reprogrammability, through an advanced flash-based, 130-nm LVCMOS process with seven layers of metal. Standard CMOS design techniques are used to implement logic and control functions. The combination of fine granularity, enhanced flexible routing resources, and abundant flash switches allows for very high logic utilization without compromising device routability or performance. Logic functions within the device are interconnected through a four-level routing hierarchy.

IGLOO family FPGAs utilize design and process techniques to minimize power consumption in all modes of operation.

## Advanced Architecture

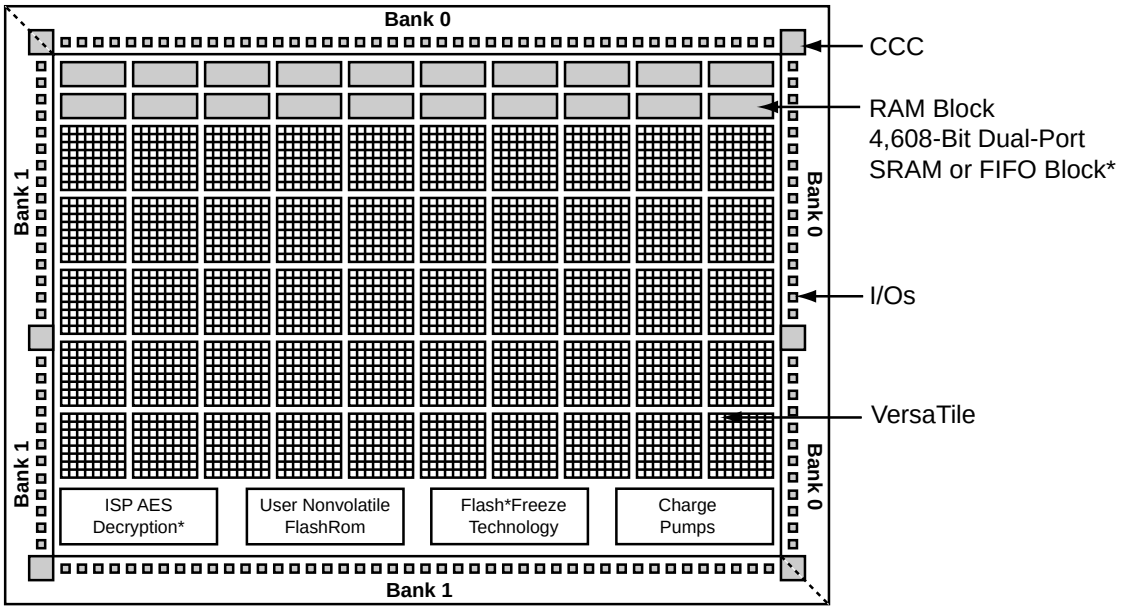
The proprietary IGLOO architecture provides granularity comparable to standard-cell ASICs. The IGLOO device consists of five distinct and programmable architectural features (Figure 1-1 on page 1-4 and Figure 1-2 on page 1-4):

- Flash*Freeze technology
- FPGA VersaTiles
- Dedicated FlashROM
- Dedicated SRAM/FIFO memory†
- Extensive CCCs and PLLs†
- Advanced I/O structure

The FPGA core consists of a sea of VersaTiles. Each VersaTile can be configured as a three-input logic function, a D-flip-flop (with or without enable), or a latch by programming the appropriate flash switch interconnections. The versatility of the IGLOO core tile as either a three-input lookup table (LUT) equivalent or a D-flip-flop/latch with enable allows for efficient use of the FPGA fabric. The VersaTile capability is unique to the ProASIC® family of third-generation-architecture flash FPGAs.

*† The AGL015 and AGL030 do not support PLL or SRAM.*

VersaTiles are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Maximum core utilization is possible for virtually any design.




* *Not supported by AGL015 and AGL030 devices*

***Figure 1-1 •*** **IGLOO Device Architecture Overview with Two I/O Banks (AGL015, AGL030, AGL060, and AGL125)**

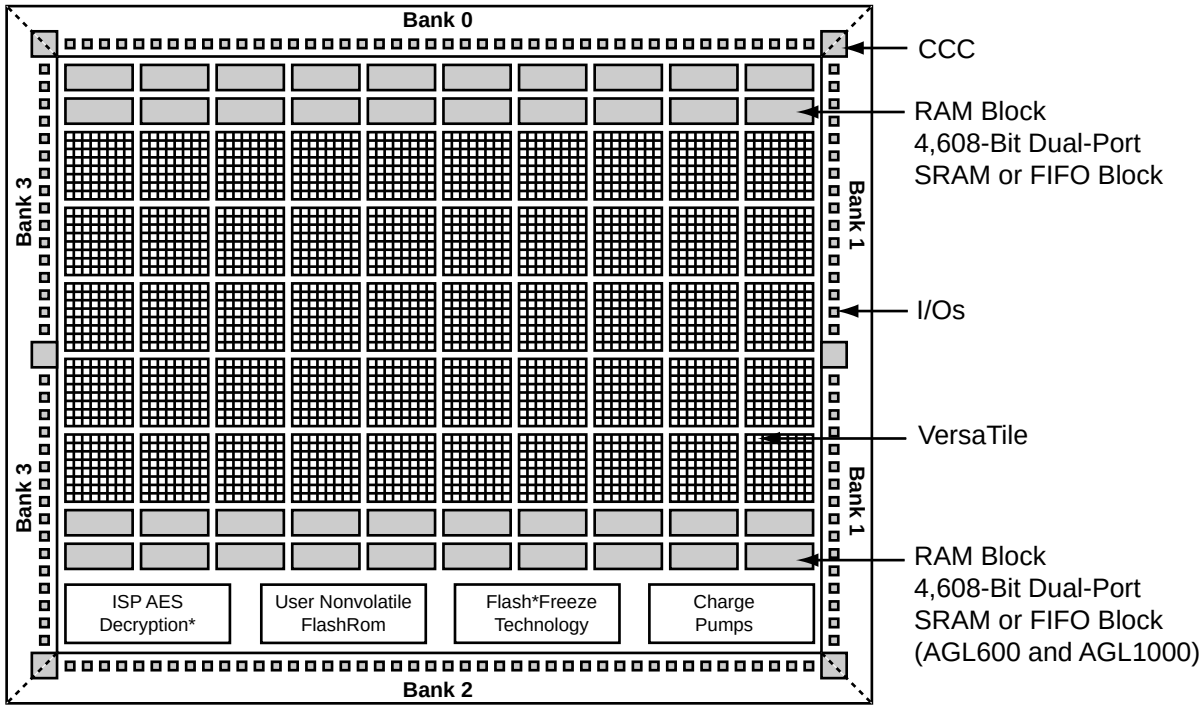



***Figure 1-2 •*** **IGLOO Device Architecture Overview with Four I/O Banks (AGL250, AGL600, AGL400, and AGL1000)**

## Flash*Freeze Technology

The IGLOO device has an ultra-low power static mode, called Flash*Freeze mode, which retains all SRAM and register information and can still quickly return to normal operation. Flash*Freeze technology enables the user to quickly (within 1 µs) enter and exit Flash*Freeze mode by activating the Flash*Freeze pin while all power supplies are kept at their original values. In addition, I/Os and global I/Os can still be driven and can be toggling without impact on power consumption, clocks can still be driven or can be toggling without impact on power consumption, and the device retains all core registers, SRAM information, and states. I/O states are tristated during Flash*Freeze mode or can be set to a certain state using weak pull-up or pull-down I/O attribute configuration. No power is consumed by the I/O banks, clocks, JTAG pins, or PLL, and the device consumes as little as 5 µW in this mode.

Flash*Freeze technology allows the user to switch to active mode on demand, thus simplifying the power management of the device.

The Flash*Freeze pin (active low) can be routed internally to the core to allow the user's logic to decide when it is safe to transition to this mode. It is also possible to use the Flash*Freeze pin as a regular I/O if Flash*Freeze mode usage is not planned, which is advantageous because of the inherent low power static (as low as 12 µW) and dynamic capabilities of the IGLOO device. Refer to Figure 1-3 for an illustration of entering/exiting Flash*Freeze mode.

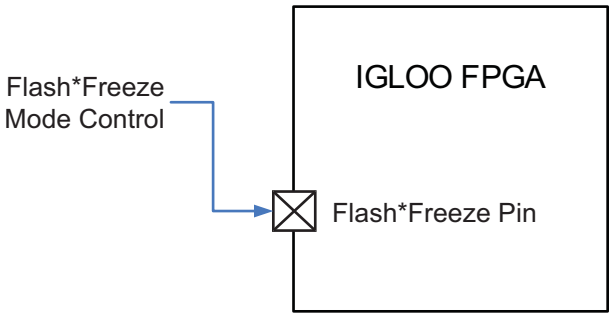



***Figure 1-3 •*** **IGLOO Flash*Freeze Mode**

## VersaTiles

The IGLOO core consists of VersaTiles, which have been enhanced beyond the ProASIC[PLUS]® core tiles. The IGLOO VersaTile supports the following:

- All 3-input logic functions—LUT-3 equivalent
- Latch with clear or set
- D-flip-flop with clear or set
- Enable D-flip-flop with clear or set

Refer to Figure 1-4 for VersaTile configurations.

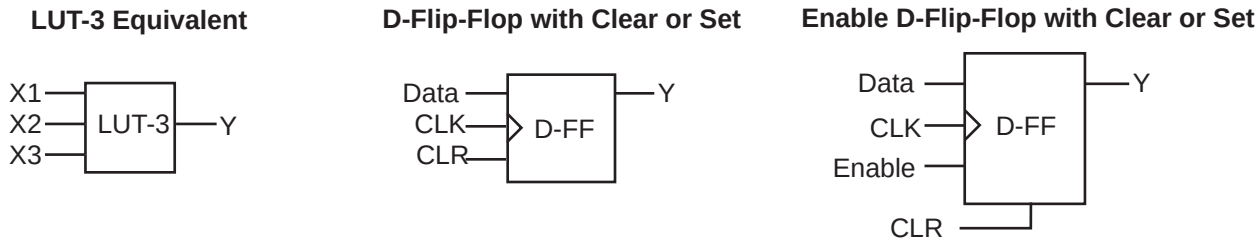



***Figure 1-4 •*** **VersaTile Configurations**

## User Nonvolatile FlashROM

IGLOO devices have 1 kbit of on-chip, user-accessible, nonvolatile FlashROM. The FlashROM can be used in diverse system applications:

- Internet protocol addressing (wireless or fixed)
- System calibration settings
- Device serialization and/or inventory control
- Subscription-based business models (for example, set-top boxes)
- Secure key storage for secure communications algorithms
- Asset management/tracking
- Date stamping
- Version management

The FlashROM is written using the standard IGLOO IEEE 1532 JTAG programming interface. The core can be individually programmed (erased and written), and on-chip AES decryption can be used selectively to securely load data over public networks (except in the AGL015 and AGL030 devices), as in security keys stored in the FlashROM for a user design.

The FlashROM can be programmed via the JTAG programming interface, and its contents can be read back either through the JTAG programming interface or via direct FPGA core addressing. Note that the FlashROM can only be programmed from the JTAG interface and cannot be programmed from the internal logic array.

The FlashROM is programmed as 8 banks of 128 bits; however, reading is performed on a byte-by-byte basis using a synchronous interface. A 7-bit address from the FPGA core defines which of the 8 banks and which of the 16 bytes within that bank are being read. The three most significant bits (MSBs) of the FlashROM address determine the bank, and the four least significant bits (LSBs) of the FlashROM address define the byte.

The Microsemi development software solutions, Libero® Integrated Design Environment (IDE) and Designer, have extensive support for the FlashROM. One such feature is auto-generation of sequential programming files for applications requiring a unique serial number in each part. Another feature allows the inclusion of static data for system version control. Data for the FlashROM can be generated quickly and easily using Libero IDE and Designer software tools. Comprehensive programming file support is also included to allow for easy programming of large numbers of parts with differing FlashROM contents.

## SRAM and FIFO

IGLOO devices (except the AGL015 and AGL030 devices) have embedded SRAM blocks along their north and south sides. Each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are 256×18, 512×9, 1k×4, 2k×2, and 4k×1 bits. The individual blocks have independent read and write ports that can be configured with different bit widths on each port. For example, data can be sent through a 4-bit port and read as a single bitstream. The embedded SRAM blocks can be initialized via the device JTAG port (ROM emulation mode) using the UJTAG macro (except in the AGL015 and AGL030 devices).

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using additional core VersaTiles. The FIFO width and depth are programmable. The FIFO also features programmable Almost Empty (AEMPTY) and Almost Full (AFULL) flags in addition to the normal Empty and Full flags. The embedded FIFO control unit contains the counters necessary for generation of the read and write address pointers. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

## PLL and CCC

IGLOO devices provide designers with very flexible clock conditioning circuit (CCC) capabilities. Each member of the IGLOO family contains six CCCs. One CCC (center west side) has a PLL. The AGL015 and AGL030 do not have a PLL.

The six CCC blocks are located at the four corners and the centers of the east and west sides. One CCC (center west side) has a PLL.

All six CCC blocks are usable; the four corner CCCs and the east CCC allow simple clock delay operations as well as clock spine access.

The inputs of the six CCC blocks are accessible from the FPGA core or from one of several inputs located near the CCC that have dedicated connections to the CCC block.

The CCC block has these key features:

- Wide input frequency range ($f_{IN_CCC}$) = 1.5 MHz up to 250 MHz
- Output frequency range ($f_{OUT_CCC}$) = 0.75 MHz up to 250 MHz
- 2 programmable delay types for clock skew minimization
- Clock frequency synthesis (for PLL only)

Additional CCC specifications:

- Internal phase shift = 0°, 90°, 180°, and 270°. Output phase shift depends on the output divider configuration (for PLL only).
- Output duty cycle = 50% ± 1.5% or better (for PLL only)
- Low output jitter: worst case < 2.5% × clock period peak-to-peak period jitter when single global network used (for PLL only)
- Maximum acquisition time is 300 µs (for PLL only)
- Exceptional tolerance to input period jitter—allowable input jitter is up to 1.5 ns (for PLL only)
- Four precise phases; maximum misalignment between adjacent phases of 40 ps × 250 MHz / $f_{OUT_CCC}$ (for PLL only)

### Global Clocking

IGLOO devices have extensive support for multiple clocking domains. In addition to the CCC and PLL support described above, there is a comprehensive global clock distribution network.

Each VersaTile input and output port has access to nine VersaNets: six chip (main) and three quadrant global networks. The VersaNets can be driven by the CCC or directly accessed from the core via multiplexers (MUXes). The VersaNets can be used to distribute low-skew clock signals or for rapid distribution of high-fanout nets.

## I/Os with Advanced I/O Standards

The IGLOO family of FPGAs features a flexible I/O structure, supporting a range of voltages (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.0 V wide range, and 3.3 V). IGLOO FPGAs support many different I/O standards—single-ended and differential.

The I/Os are organized into banks, with two or four banks per device. The configuration of these banks determines the I/O standards supported (Table 1-1).

***Table 1-1* • I/O Standards Supported**

| I/O Bank Type | Device and Bank Location | I/O Standards Supported | | |
|---|---|---|---|---|
| | | LVTTL/ LVCMOS | PCI/PCI-X | LVPECL, LVDS, B-LVDS, M-LVDS |
| Advanced | East and west banks of AGL250 and larger devices | ✓ | ✓ | ✓ |
| Standard Plus | North and south banks of AGL250 and larger devices<br>All banks of AGL060 and AGL125K | ✓ | ✓ | Not supported |
| Standard | All banks of AGL015 and AGL030 | ✓ | Not supported | Not supported |

Each I/O module contains several input, output, and enable registers. These registers allow the implementation of the following:

- Single-Data-Rate applications
- Double-Data-Rate applications—DDR LVDS, B-LVDS, and M-LVDS I/Os for point-to-point communications

IGLOO banks for the AGL250 device and above support LVPECL, LVDS, B-LVDS, and M-LVDS. B-LVDS and M-LVDS can support up to 20 loads.

Hot-swap (also called hot-plug, or hot-insertion) is the operation of hot-insertion or hot-removal of a card in a powered-up system.

Cold-sparing (also called cold-swap) refers to the ability of a device to leave system data undisturbed when the system is powered up, while the component itself is powered down, or when power supplies are floating.

## Wide Range I/O Support

IGLOO devices support JEDEC-defined wide range I/O operation. IGLOO devices support both the JESD8-B specification, covering 3 V and 3.3 V supplies, for an effective operating range of 2.7 V to 3.6 V, and JESD8-12 with its 1.2 V nominal, supporting an effective operating range of 1.14 V to 1.575 V.

Wider I/O range means designers can eliminate power supplies or power conditioning components from the board or move to less costly components with greater tolerances. Wide range eases I/O bank management and provides enhanced protection from system voltage spikes, while providing the flexibility to easily run custom voltage applications.

## Specifying I/O States During Programming

You can modify the I/O states during programming in FlashPro. In FlashPro, this feature is supported for PDB files generated from Designer v8.5 or greater. See the *FlashPro User's Guide* for more information.

Note: PDB files generated from Designer v8.1 to Designer v8.4 (including all service packs) have limited display of Pin Numbers only.

1. Load a PDB from the FlashPro GUI. You must have a PDB loaded to modify the I/O states during programming.
2. From the FlashPro GUI, click PDB Configuration. A FlashPoint – Programming File Generator window appears.
3. Click the Specify I/O States During Programming button to display the Specify I/O States During Programming dialog box.
4. Sort the pins as desired by clicking any of the column headers to sort the entries by that header. Select the I/Os you wish to modify (Figure 1-5 on page 1-9).
5. Set the I/O Output State. You can set Basic I/O settings if you want to use the default I/O settings for your pins, or use Custom I/O settings to customize the settings for each pin. Basic I/O state settings:

   1 – I/O is set to drive out logic High

   0 – I/O is set to drive out logic Low

   Last Known State – I/O is set to the last value that was driven out prior to entering the programming mode, and then held at that value during programming

   Z -Tri-State: I/O is tristated

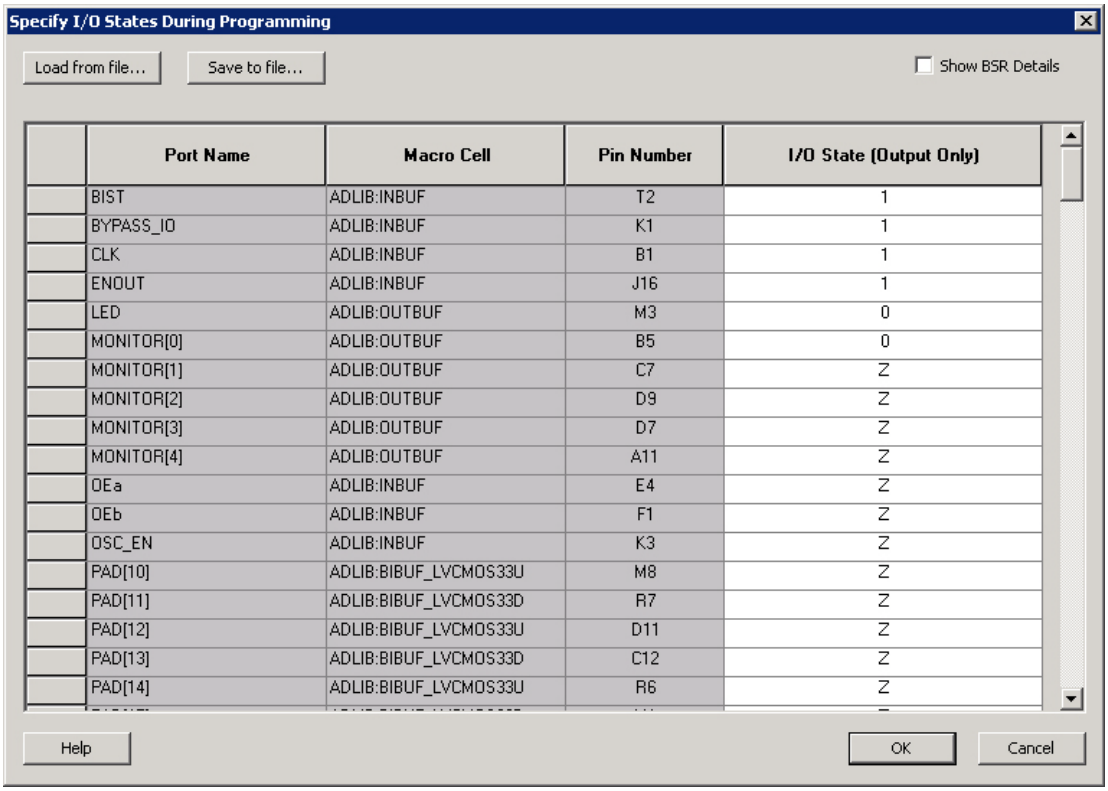



***Figure 1-5 •*** **I/O States During Programming Window**

6. Click OK to return to the FlashPoint – Programming File Generator window.

Note: I/O States During programming are saved to the ADB and resulting programming files after completing programming file generation.

# 2 – IGLOO DC and Switching Characteristics

## General Specifications

### Operating Conditions

Stresses beyond those listed in Table 2-1 may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Absolute Maximum Ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions specified in Table 2-2 on page 2-2 is not implied.

***Table 2-1 •*** **Absolute Maximum Ratings**

| Symbol | Parameter | Limits[1] | Units |
|---|---|---|---|
| VCC | DC core supply voltage | –0.3 to 1.65 | V |
| VJTAG | JTAG DC voltage | –0.3 to 3.75 | V |
| VPUMP | Programming voltage | –0.3 to 3.75 | V |
| VCCPLL | Analog power supply (PLL) | –0.3 to 1.65 | V |
| VCCI and VMV [2] | DC I/O buffer supply voltage | –0.3 to 3.75 | V |
| VI | I/O input voltage | –0.3 V to 3.6 V (when I/O hot insertion mode is enabled)<br>–0.3 V to (VCCI + 1 V) or 3.6 V, whichever voltage is lower (when I/O hot-insertion mode is disabled) | V |
| $T_{STG}$ [3] | Storage Temperature | –65 to +150 | °C |
| $T_J$ [3] | Junction Temperature | +125 | °C |

*Notes:*

1. *The device should be operated within the limits specified by the datasheet. During transitions, the input signal may undershoot or overshoot according to the limits shown in Table 2-4 on page 2-3.*
2. *VMV pins must be connected to the corresponding VCCI pins. See the "Pin Descriptions" chapter of the* IGLOO FPGA Fabric User's Guide *for further information.*
3. *For flash programming and retention, maximum limits refer to Table 2-3 on page 2-2, and for recommended operating limits, refer to Table 2-2 on page 2-2.*

**Table 2-2 • Recommended Operating Conditions [1]**

| Symbol | Parameter | | Commercial | Industrial | Units |
|---|---|---|---|---|---|
| $T_A$ | Ambient Temperature | | 0 to +70 | –40 to +85 | °C |
| $T_J$ | Junction Temperature [2] | | 0 to +85 | –40 to +100 | °C |
| VCC[3] | 1.5 V DC core supply voltage[5] | | 1.425 to 1.575 | 1.425 to 1.575 | V |
| | 1.2 V–1.5 V wide range DC core supply voltage [4,6] | | 1.14 to 1.575 | 1.14 to 1.575 | V |
| VJTAG | JTAG DC voltage | | 1.4 to 3.6 | 1.4 to 3.6 | V |
| VPUMP | Programming voltage | Programming Mode | 3.15 to 3.45 | 3.15 to 3.45 | V |
| | | Operation [7] | 0 to 3.6 | 0 to 3.6 | V |
| VCCPLL[8] | Analog power supply (PLL) | 1.5 V DC core supply voltage[5] | 1.425 to 1.575 | 1.425 to 1.575 | V |
| | | 1.2 V – 1.5 V DC core supply voltage[4,6] | 1.14 to 1.575 | 1.14 to 1.575 | V |
| VCCI and VMV [9] | 1.2 V DC core supply voltage[6] | | 1.14 to 1.26 | 1.14 to 1.26 | V |
| | 1.2 V DC wide range DC supply voltage[6] | | 1.14 to 1.575 | 1.14 to 1.575 | V |
| | 1.5 V DC supply voltage | | 1.425 to 1.575 | 1.425 to 1.575 | V |
| | 1.8 V DC supply voltage | | 1.7 to 1.9 | 1.7 to 1.9 | V |
| | 2.5 V DC supply voltage | | 2.3 to 2.7 | 2.3 to 2.7 | V |
| | 3.0 V DC supply voltage [10] | | 2.7 to 3.6 | 2.7 to 3.6 | V |
| | 3.3 V DC supply voltage | | 3.0 to 3.6 | 3.0 to 3.6 | V |
| | LVDS differential I/O | | 2.375 to 2.625 | 2.375 to 2.625 | V |
| | LVPECL differential I/O | | 3.0 to 3.6 | 3.0 to 3.6 | V |

*Notes:*

1. *All parameters representing voltages are measured with respect to GND unless otherwise specified.*
2. *To ensure targeted reliability standards are met across ambient and junction operating temperatures, Microsemi recommends that the user follow best design practices using Microsemi's timing and power simulation tools.*
3. *The ranges given here are for power supplies only. The recommended input voltage ranges specific to each I/O standard are given in Table 2-25 on page 2-24. VCCI should be at the same voltage within a given I/O bank.*
4. *All IGLOO devices (V5 and V2) must be programmed with the VCC core voltage at 1.5 V. Applications using the V2 devices powered by 1.2 V supply must switch the core supply to 1.5 V for in-system programming.*
5. *For IGLOO® V5 devices*
6. *For IGLOO V2 devices only, operating at VCCI ≥ VCC.*
7. *VPUMP can be left floating during operation (not programming mode).*
8. *VCCPLL pins should be tied to VCC pins. See the "Pin Descriptions" chapter of the IGLOO FPGA Fabric User's Guide for further information.*
9. *VMV pins must be connected to the corresponding VCCI pins. See the "Pin Descriptions" chapter of the IGLOO FPGA Fabric User's Guide for further information.*
10. *3.3 V wide range is compliant to the JESD-8B specification and supports 3.0 V VCCI operation.*

**Table 2-3 • Flash Programming Limits – Retention, Storage, and Operating Temperature[1]**

| Product Grade | Programming Cycles | Program Retention (biased/unbiased) | Maximum Storage Temperature $T_{STG}$ (°C) [2] | Maximum Operating Junction Temperature $T_J$ (°C) [2] |
|---|---|---|---|---|
| Commercial | 500 | 20 years | 110 | 100 |
| Industrial | 500 | 20 years | 110 | 100 |

*Notes:*

1. *This is a stress rating only; functional operation at any condition other than those indicated is not implied.*
2. *These limits apply for program/data retention only. Refer to Table 2-1 on page 2-1 and Table 2-2 for device operating conditions and absolute limits.*

***Table 2-4 •*** **Overshoot and Undershoot Limits [1]**

| VCCI | Average VCCI–GND Overshoot or Undershoot Duration as a Percentage of Clock Cycle[2] | Maximum Overshoot/ Undershoot[2] |
|---|---|---|
| 2.7 V or less | 10% | 1.4 V |
| | 5% | 1.49 V |
| 3 V | 10% | 1.1 V |
| | 5% | 1.19 V |
| 3.3 V | 10% | 0.79 V |
| | 5% | 0.88 V |
| 3.6 V | 10% | 0.45 V |
| | 5% | 0.54 V |

*Notes:*

1. *Based on reliability requirements at junction temperature at 85°C.*
2. *The duration is allowed at one out of six clock cycles. If the overshoot/undershoot occurs at one out of two cycles, the maximum overshoot/undershoot has to be reduced by 0.15 V.*
3. *This table does not provide PCI overshoot/undershoot limits.*

## I/O Power-Up and Supply Voltage Thresholds for Power-On Reset (Commercial and Industrial)

Sophisticated power-up management circuitry is designed into every IGLOO device. These circuits ensure easy transition from the powered-off state to the powered-up state of the device. The many different supplies can power up in any sequence with minimized current spikes or surges. In addition, the I/O will be in a known state through the power-up sequence. The basic principle is shown in Figure 2-1 on page 2-4 and Figure 2-2 on page 2-5.

There are five regions to consider during power-up.

IGLOO I/Os are activated only if ALL of the following three conditions are met:

1. VCC and VCCI are above the minimum specified trip points (Figure 2-1 on page 2-4 and Figure 2-2 on page 2-5).
2. VCCI > VCC – 0.75 V (typical)
3. Chip is in the operating mode.

**V**CCI **Trip Point:**
Ramping up (V5 devices): 0.6 V < trip_point_up < 1.2 V
Ramping down (V5 Devices): 0.5 V < trip_point_down < 1.1 V
Ramping up (V2 devices): 0.75 V < trip_point_up < 1.05 V
Ramping down (V2 devices): 0.65 V < trip_point_down < 0.95 V

**V**CC **Trip Point:**
Ramping up (V5 devices): 0.6 V < trip_point_up < 1.1 V
Ramping down (V5 devices): 0.5 V < trip_point_down < 1.0 V
Ramping up (V2 devices): 0.65 V < trip_point_up < 1.05 V
Ramping down (V2 devices): 0.55 V < trip_point_down < 0.95 V

VCC and VCCI ramp-up trip points are about 100 mV higher than ramp-down trip points. This specifically built-in hysteresis prevents undesirable power-up oscillations and current surges. Note the following:

- During programming, I/Os become tristated and weakly pulled up to VCCI.
- JTAG supply, PLL power supplies, and charge pump VPUMP supply have no influence on I/O behavior.

## PLL Behavior at Brownout Condition

Microsemi recommends using monotonic power supplies or voltage regulators to ensure proper power-up behavior. Power ramp-up should be monotonic at least until VCC and VCCPLX exceed brownout activation levels (see Figure 2-1 and Figure 2-2 on page 2-5 for more details).

When PLL power supply voltage and/or VCC levels drop below the VCC brownout levels (0.75 V ± 0.25 V for V5 devices, and 0.75 V ± 0.2 V for V2 devices), the PLL output lock signal goes low and/or the output clock is lost. Refer to the Brownout Voltage section in the "Power-Up/-Down Behavior of Low Power Flash Devices" chapter of the *ProASIC®3* and *ProASIC3E* FPGA fabric user's guides for information on clock and lock recovery.

## Internal Power-Up Activation Sequence

1. Core
2. Input buffers
3. Output buffers, after 200 ns delay from input buffer activation

To make sure the transition from input buffers to output buffers is clean, ensure that there is no path longer than 100 ns from input buffer to output buffer in your design.

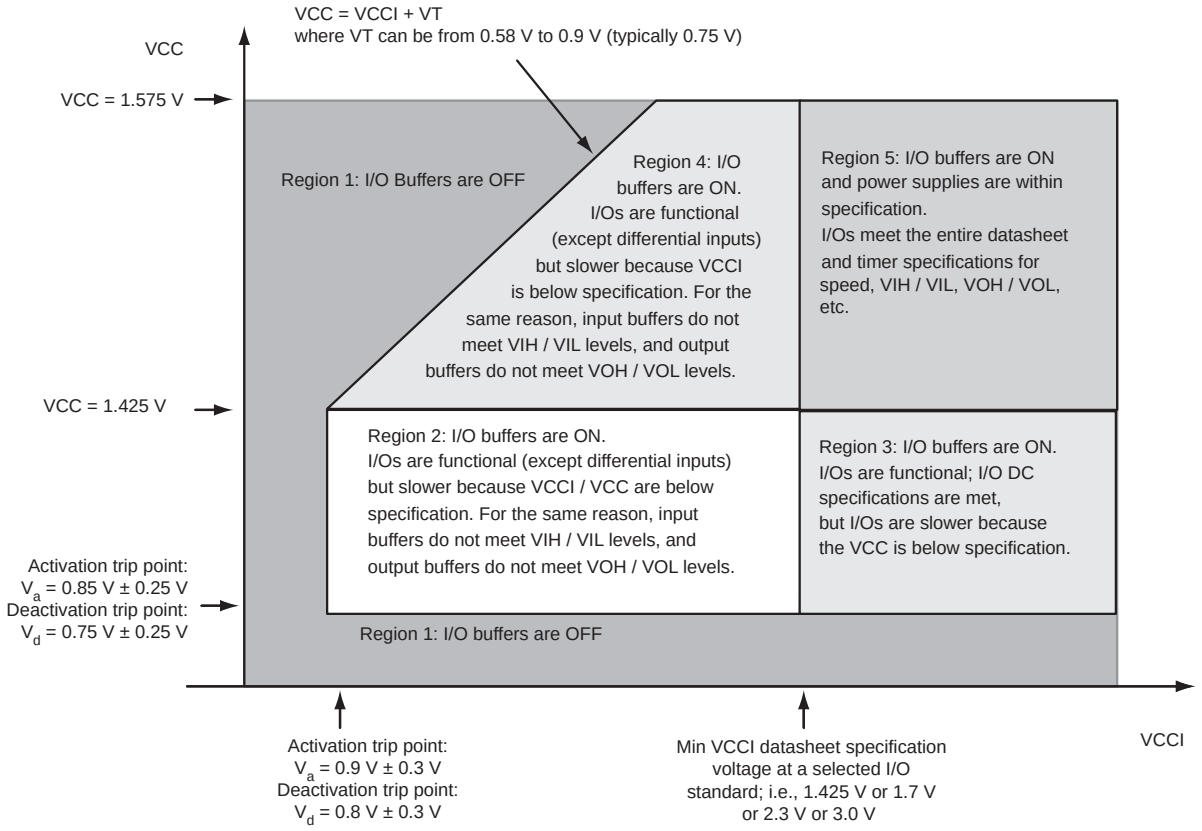



***Figure 2-1 •*** **V5 Devices – I/O State as a Function of VCCI and VCC Voltage Levels**

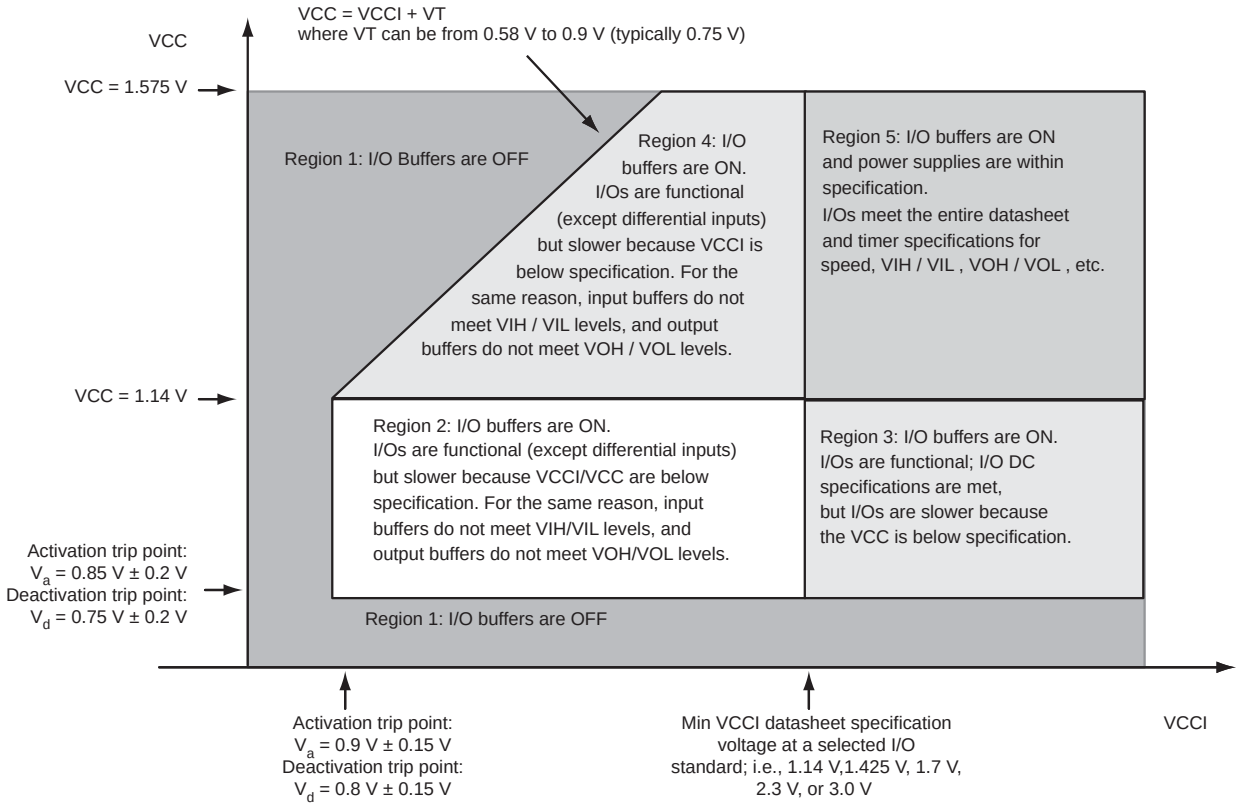



***Figure 2-2 •*** **V2 Devices – I/O State as a Function of VCCI and VCC Voltage Levels**

# Thermal Characteristics

## *Introduction*

The temperature variable in the Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction to be higher than the ambient temperature.

EQ 1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_A$$

*EQ 1*

where:

$T_A$ = Ambient Temperature

$\Delta T$ = Temperature gradient between junction (silicon) and ambient $\Delta T = \theta_{ja} * P$

$\theta_{ja}$ = Junction-to-ambient of the package. $\theta_{ja}$ numbers are located in Table 2-5 on page 2-6.

P = Power dissipation

## Package Thermal Characteristics

The device junction-to-case thermal resistivity is $\theta_{jc}$ and the junction-to-ambient air thermal resistivity is $\theta_{ja}$. The thermal characteristics for $\theta_{ja}$ are shown for two air flow rates. The absolute maximum junction temperature is 100°C. EQ 2 shows a sample calculation of the absolute maximum power dissipation allowed for the AGL1000-FG484 package at commercial temperature and in still air.

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}(\text{°C/W})} = \frac{100\text{°C} - 70\text{°C}}{23.3\text{°C/W}} = 1.28\ \text{W}$$

*EQ 2*

***Table 2-5 •*** **Package Thermal Resistivities**

| Package Type | Device | Pin Count | $\theta_{jc}$ | $\theta_{ja}$ | | | Unit |
|---|---|---|---|---|---|---|---|
| | | | | Still Air | 1 m/s | 2.5 m/s | |
| Quad Flat No Lead (QN) | AGL030 | 132 | 13.1 | 21.4 | 16.8 | 15.3 | C/W |
| | AGL060 | 132 | 11.0 | 21.2 | 16.6 | 15.0 | C/W |
| | AGL125 | 132 | 9.2 | 21.1 | 16.5 | 14.9 | C/W |
| | AGL250 | 132 | 8.9 | 21.0 | 16.4 | 14.8 | C/W |
| | AGL030 | 68 | 13.4 | 68.4 | 45.8 | 43.1 | C/W |
| Very Thin Quad Flat Pack (VQ)* | | 100 | 10.0 | 35.3 | 29.4 | 27.1 | C/W |
| Chip Scale Package (CS) | AGL1000 | 281 | 6.0 | 28.0 | 22.8 | 21.5 | C/W |
| | AGL400 | 196 | 7.2 | 37.1 | 31.1 | 28.9 | C/W |
| | AGL250 | 196 | 7.6 | 38.3 | 32.2 | 30.0 | C/W |
| | AGL125 | 196 | 8.0 | 39.5 | 33.4 | 31.1 | C/W |
| | AGL030 | 81 | 12.4 | 32.8 | 28.5 | 27.2 | C/W |
| | AGL060 | 81 | 11.1 | 28.8 | 24.8 | 23.5 | C/W |
| | AGL250 | 81 | 10.4 | 26.9 | 22.3 | 20.9 | C/W |
| Micro Chip Scale Package (UC) | AGL030 | 81 | 16.9 | 40.6 | 35.2 | 33.7 | C/W |
| Fine Pitch Ball Grid Array (FG) | AGL060 | 144 | 18.6 | 55.2 | 49.4 | 47.2 | C/W |
| | AGL1000 | 144 | 6.3 | 31.6 | 26.2 | 24.2 | C/W |
| | AGL400 | 144 | 6.8 | 37.6 | 31.2 | 29.0 | C/W |
| | AGL250 | 256 | 12.0 | 38.6 | 34.7 | 33.0 | C/W |
| | AGL1000 | 256 | 6.6 | 28.1 | 24.4 | 22.7 | C/W |
| | AGL1000 | 484 | 8.0 | 23.3 | 19.0 | 16.7 | C/W |

*Note: *Thermal resistances for other device-package combinations will be posted in a later revision.*

### Disclaimer:

The simulation for determining the junction-to-air thermal resistance is based on JEDEC standards (JESD51) and assumptions made in building the model. Junction-to-case is based on SEMI G38-88. JESD51 is only used for comparing one package to another package, provided the two tests uses the same condition. They have little relevance in actual application and therefore should be used with a degree of caution.

### Temperature and Voltage Derating Factors

**Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays (normalized to $T_J$ = 70°C, VCC = 1.425 V)**
**For IGLOO V2 or V5 devices, 1.5 V DC Core Supply Voltage**

| Array Voltage VCC (V) | Junction Temperature (°C) | | | | | |
|---|---|---|---|---|---|---|
| | –40°C | 0°C | 25°C | 70°C | 85°C | 100°C |
| 1.425 | 0.934 | 0.953 | 0.971 | 1.000 | 1.007 | 1.013 |
| 1.500 | 0.855 | 0.874 | 0.891 | 0.917 | 0.924 | 0.929 |
| 1.575 | 0.799 | 0.816 | 0.832 | 0.857 | 0.864 | 0.868 |

**Table 2-7 • Temperature and Voltage Derating Factors for Timing Delays (normalized to $T_J$ = 70°C, VCC = 1.14 V)**
**For IGLOO V2, 1.2 V DC Core Supply Voltage**

| Array Voltage VCC (V) | Junction Temperature (°C) | | | | | |
|---|---|---|---|---|---|---|
| | –40°C | 0°C | 25°C | 70°C | 85°C | 100°C |
| 1.14 | 0.967 | 0.978 | 0.991 | 1.000 | 1.006 | 1.010 |
| 1.20 | 0.864 | 0.874 | 0.885 | 0.894 | 0.899 | 0.902 |
| 1.26 | 0.794 | 0.803 | 0.814 | 0.821 | 0.827 | 0.830 |

# Calculating Power Dissipation

## Quiescent Supply Current

Quiescent supply current (IDD) calculation depends on multiple factors, including operating voltages (VCC, VCCI, and VJTAG), operating temperature, system clock frequency, and power modes usage. Microsemi recommends using the PowerCalculator and SmartPower software estimation tools to evaluate the projected static and active power based on the user design, power mode usage, operating voltage, and temperature.

**Table 2-8 • Power Supply State per Mode**

| | Power Supply Configurations | | | | |
|---|---|---|---|---|---|
| Modes/power supplies | VCC | VCCPLL | VCCI | VJTAG | VPUMP |
| Flash*Freeze | On | On | On | On | On/off/floating |
| Sleep | Off | Off | On | Off | Off |
| Shutdown | Off | Off | Off | Off | Off |
| No Flash*Freeze | On | On | On | On | On/off/floating |

*Note: Off: Power supply level = 0 V*

**Table 2-9 • Quiescent Supply Current (IDD) Characteristics, IGLOO Flash*Freeze Mode***

| | Core Voltage | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | AGL400 | AGL600 | AGL1000 | Units |
|---|---|---|---|---|---|---|---|---|---|---|
| Typical (25°C) | 1.2 V | 4 | 4 | 8 | 13 | 20 | 27 | 30 | 44 | µA |
| | 1.5 V | 6 | 6 | 10 | 18 | 34 | 51 | 72 | 127 | µA |

*Note: *IDD includes VCC, VPUMP, VCCI, VCCPLL, and VMV currents. Values do not include I/O static contribution, which is shown in Table 2-13 on page 2-10 through Table 2-15 on page 2-11 and Table 2-16 on page 2-11 through Table 2-18 on page 2-12 (PDC6 and PDC7).*

**Table 2-10 • Quiescent Supply Current (IDD) Characteristics, IGLOO Sleep Mode***

| | Core Voltage | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | AGL400 | AGL600 | AGL1000 | Units |
|---|---|---|---|---|---|---|---|---|---|---|
| VCCI/VJTAG = 1.2 V (per bank) Typical (25°C) | 1.2 V | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | µA |
| VCCI/VJTAG = 1.5 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | µA |
| VCCI/VJTAG = 1.8 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | µA |
| VCCI/VJTAG = 2.5 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | µA |
| VCCI/VJTAG = 3.3 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | µA |

*Note: IDD = $N_{BANKS}$ × ICCI. Values do not include I/O static contribution, which is shown in Table 2-13 on page 2-10 through Table 2-15 on page 2-11 and Table 2-16 on page 2-11 through Table 2-18 on page 2-12 (PDC6 and PDC7).*

**Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO Shutdown Mode**

| | Core Voltage | AGL015 | AGL030 | Units |
|---|---|---|---|---|
| Typical (25°C) | 1.2 V / 1.5 V | 0 | 0 | µA |

***Table 2-12 •*** **Quiescent Supply Current (IDD), No IGLOO Flash*Freeze Mode[1]**

| | Core Voltage | AGL015 | AGL030 | AGL060 | AGL125 | AGL250 | AGL400 | AGL600 | AGL1000 | Units |
|---|---|---|---|---|---|---|---|---|---|---|
| **ICCA Current[2]** | | | | | | | | | | |
| Typical (25°C) | 1.2 V | 5 | 6 | 10 | 13 | 18 | 25 | 28 | 42 | µA |
| | 1.5 V | 14 | 16 | 20 | 28 | 44 | 66 | 82 | 137 | µA |
| **ICCI or IJTAG Current[3]** | | | | | | | | | | |
| VCCI/VJTAG = 1.2 V (per bank) Typical (25°C) | 1.2 V | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | 1.7 | µA |
| VCCI/VJTAG = 1.5 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 | µA |
| VCCI/VJTAG = 1.8 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 | µA |
| VCCI/VJTAG = 2.5 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 | µA |
| VCCI/VJTAG = 3.3 V (per bank) Typical (25°C) | 1.2 V / 1.5 V | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | 2.5 | µA |

*Notes:*

1. *IDD = $N_{BANKS}$ × ICCI + ICCA. JTAG counts as one bank when powered.*
2. *Includes VCC, VPUMP, and VCCPLL currents.*
3. *Values do not include I/O static contribution (PDC6 and PDC7).*

## Power per I/O Pin

**Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings Applicable to Advanced I/O Banks**

| | VCCI (V) | Static Power PDC6 (mW)[1] | Dynamic Power PAC9 (µW/MHz)[2] |
|---|---|---|---|
| **Single-Ended** | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 3.3 | – | 16.27 |
| 3.3V LVCMOS Wide Range[3] | 3.3 | – | 16.27 |
| 2.5 V LVCMOS | 2.5 | – | 4.65 |
| 1.8 V LVCMOS | 1.8 | – | 1.61 |
| 1.5 V LVCMOS (JESD8-11) | 1.5 | – | 0.96 |
| 1.2 V LVCMOS[4] | 1.2 | – | 0.58 |
| 1.2 V LVCMOS Wide Range[4] | 1.2 | – | 0.58 |
| 3.3 V PCI | 3.3 | – | 17.67 |
| 3.3 V PCI-X | 3.3 | – | 17.67 |
| **Differential** | | | |
| LVDS | 2.5 | 2.26 | 23.39 |
| LVPECL | 3.3 | 5.72 | 59.05 |

*Notes:*

1. *$P_{DC6}$ is the static power (where applicable) measured on VCCI.*
2. *$P_{AC9}$ is the total dynamic power measured on VCCI.*
3. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
4. *Applicable for IGLOO V2 devices only*

**Table 2-14 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings Applicable to Standard Plus I/O Banks**

| | VCCI (V) | Static Power PDC6 (mW)[1] | Dynamic Power PAC9 (µW/MHz)[2] |
|---|---|---|---|
| **Single-Ended** | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 3.3 | – | 16.41 |
| 3.3V LVCMOS Wide Range[3] | 3.3 | – | 16.41 |
| 2.5 V LVCMOS | 2.5 | – | 4.75 |
| 1.8 V LVCMOS | 1.8 | – | 1.66 |
| 1.5 V LVCMOS (JESD8-11) | 1.5 | – | 1.00 |
| 1.2 V LVCMOS[4] | 1.2 | – | 0.61 |
| 1.2 V LVCMOS Wide Range[4] | 1.2 | – | 0.61 |
| 3.3 V PCI | 3.3 | – | 17.78 |
| 3.3 V PCI-X | 3.3 | – | 17.78 |

*Notes:*

1. *PDC6 is the static power (where applicable) measured on VCCI.*
2. *PAC9 is the total dynamic power measured on VCCI.*
3. *Applicable for IGLOO V2 devices only.*
4. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*

**Table 2-15 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings Applicable to Standard I/O Banks**

| | VCCI (V) | Static Power PDC6 (mW)[1] | Dynamic Power PAC9 (µW/MHz)[2] |
|---|---|---|---|
| **Single-Ended** | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 3.3 | – | 17.24 |
| 3.3V LVCMOS Wide Range[3] | 3.3 | – | 17.24 |
| 2.5 V LVCMOS | 2.5 | – | 5.64 |
| 1.8 V LVCMOS | 1.8 | – | 2.63 |
| 1.5 V LVCMOS (JESD8-11) | 1.5 | – | 1.97 |
| 1.2 V LVCMOS[4] | 1.2 | – | 0.57 |
| 1.2 V LVCMOS Wide Range[4] | 1.2 | – | 0.57 |

*Notes:*

1. *PDC6 is the static power (where applicable) measured on VCCI.*
2. *PAC9 is the total dynamic power measured on VCCI.*
3. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
4. *Applicable for IGLOO V2 devices only.*

**Table 2-16 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings[1] Applicable to Advanced I/O Banks**

| | $C_{LOAD}$ (pF) | VCCI (V) | Static Power PDC7 (mW)[2] | Dynamic Power PAC10 (µW/MHz)[3] |
|---|---|---|---|---|
| **Single-Ended** | | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 5 | 3.3 | – | 136.95 |
| 3.3V LVCMOS Wide Range[4] | 5 | 3.3 | – | 136.95 |
| 2.5 V LVCMOS | 5 | 2.5 | – | 76.84 |
| 1.8 V LVCMOS | 5 | 1.8 | – | 49.31 |
| 1.5 V LVCMOS (JESD8-11) | 5 | 1.5 | – | 33.36 |
| 1.2 V LVCMOS[5] | 5 | 1.2 | – | 16.24 |
| 1.2 V LVCMOS Wide Range[5] | 5 | 1.2 | – | 16.24 |
| 3.3 V PCI | 10 | 3.3 | – | 194.05 |
| 3.3 V PCI-X | 10 | 3.3 | – | 194.05 |
| **Differential** | | | | |
| LVDS | – | 2.5 | 7.74 | 156.22 |
| LVPECL | – | 3.3 | 19.54 | 339.35 |

*Notes:*

1. *Dynamic power consumption is given for standard load and software default drive strength and output slew.*
2. *PDC7 is the static power (where applicable) measured on VCCI.*
3. *PAC10 is the total dynamic power measured on VCCI.*
4. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
5. *Applicable for IGLOO V2 devices only.*

**Table 2-17 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings[1] Applicable to Standard Plus I/O Banks**

| | $C_{LOAD}$ (pF) | VCCI (V) | Static Power PDC7 (mW)[2] | Dynamic Power PAC10 (µW/MHz)[3] |
|---|---|---|---|---|
| **Single-Ended** | | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 5 | 3.3 | – | 122.16 |
| 3.3V LVCMOS Wide Range[4] | 5 | 3.3 | – | 122.16 |
| 2.5 V LVCMOS | 5 | 2.5 | – | 68.37 |
| 1.8 V LVCMOS | 5 | 1.8 | – | 34.53 |
| 1.5 V LVCMOS (JESD8-11) | 5 | 1.5 | – | 23.66 |
| 1.2 V LVCMOS[5] | 5 | 1.2 | – | 14.90 |
| 1.2 V LVCMOS Wide Range[5] | 5 | 1.2 | – | 14.90 |
| 3.3 V PCI | 10 | 3.3 | – | 181.06 |
| 3.3 V PCI-X | 10 | 3.3 | – | 181.06 |

*Notes:*

1. *Dynamic power consumption is given for standard load and software default drive strength and output slew.*
2. *$P_{DC7}$ is the static power (where applicable) measured on VCCI.*
3. *$P_{AC10}$ is the total dynamic power measured on VCCI.*
4. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
5. *Applicable for IGLOO V2 devices only.*

**Table 2-18 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings[1] Applicable to Standard I/O Banks**

| | $C_{LOAD}$ (pF) | VCCI (V) | Static Power PDC7 (mW)[2] | Dynamic Power PAC10 (µW/MHz)[3] |
|---|---|---|---|---|
| **Single-Ended** | | | | |
| 3.3 V LVTTL / 3.3 V LVCMOS | 5 | 3.3 | – | 104.38 |
| 3.3V LVCMOS Wide Range[4] | 5 | 3.3 | – | 104.38 |
| 2.5 V LVCMOS | 5 | 2.5 | – | 59.86 |
| 1.8 V LVCMOS | 5 | 1.8 | – | 31.26 |
| 1.5 V LVCMOS (JESD8-11) | 5 | 1.5 | – | 21.96 |
| 1.2 V LVCMOS[5] | 5 | 1.2 | – | 13.49 |
| 1.2 V LVCMOS Wide Range[5] | 5 | 1.2 | – | 13.49 |

*Notes:*

1. *Dynamic power consumption is given for standard load and software default drive strength and output slew.*
2. *PDC7 is the static power (where applicable) measured on VCCI.*
3. *PAC10 is the total dynamic power measured on VCCI.*
4. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
5. *Applicable for IGLOO V2 devices only.*

## Power Consumption of Various Internal Resources

***Table 2-19 •*** **Different Components Contributing to Dynamic Power Consumption in IGLOO Devices For IGLOO V2 or V5 Devices, 1.5 V DC Core Supply Voltage**

| Parameter | Definition | Device Specific Dynamic Power (µW/MHz) | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| | | AGL1000 | AGL600 | AGL400 | AGL250 | AGL125 | AGL060 | AGL030 | AGL015 |
| PAC1 | Clock contribution of a Global Rib | 14.48 | 12.77 | 12.77 | 11.03 | 11.03 | 9.3 | 9.3 | 9.3 |
| PAC2 | Clock contribution of a Global Spine | 2.48 | 1.85 | 1.58 | 1.58 | 0.81 | 0.81 | 0.41 | 0.41 |
| PAC3 | Clock contribution of a VersaTile row | 0.81 | | | | | | | |
| PAC4 | Clock contribution of a VersaTile used as a sequential module | 0.11 | | | | | | | |
| PAC5 | First contribution of a VersaTile used as a sequential module | 0.057 | | | | | | | |
| PAC6 | Second contribution of a VersaTile used as a sequential module | 0.207 | | | | | | | |
| PAC7 | Contribution of a VersaTile used as a combinatorial module | 0.17 | | | | | | | |
| PAC8 | Average contribution of a routing net | 0.7 | | | | | | | |
| PAC9 | Contribution of an I/O input pin (standard-dependent) | See Table 2-13 on page 2-10 through Table 2-15 on page 2-11. | | | | | | | |
| PAC10 | Contribution of an I/O output pin (standard-dependent) | See Table 2-16 on page 2-11 through Table 2-18 on page 2-12. | | | | | | | |
| PAC11 | Average contribution of a RAM block during a read operation | 25.00 | | | | | | | |
| PAC12 | Average contribution of a RAM block during a write operation | 30.00 | | | | | | | |
| PAC13 | Dynamic PLL contribution | 2.70 | | | | | | | |

*Note: For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero® Integrated Design Environment (IDE).*

**Table 2-20 • Different Components Contributing to the Static Power Consumption in IGLOO Devices For IGLOO V2 or V5 Devices, 1.5 V DC Core Supply Voltage**

| Parameter | Definition | Device-Specific Static Power (mW) | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| | | AGL1000 | AGL600 | AGL400 | AGL250 | AGL125 | AGL060 | AGL030 | AGL015 |
| PDC1 | Array static power in Active mode | See Table 2-12 on page 2-9. | | | | | | | |
| PDC2 | Array static power in Static (Idle) mode | See Table 2-11 on page 2-8. | | | | | | | |
| PDC3 | Array static power in Flash*Freeze mode | See Table 2-9 on page 2-7. | | | | | | | |
| PDC4 | Static PLL contribution | 1.84 | | | | | | | |
| PDC5 | Bank quiescent power ($V_{CCI}$-dependent) | See Table 2-12 on page 2-9. | | | | | | | |
| PDC6 | I/O input pin static power (standard-dependent) | See Table 2-13 on page 2-10 through Table 2-15 on page 2-11. | | | | | | | |
| PDC7 | I/O output pin static power (standard-dependent) | See Table 2-16 on page 2-11 through Table 2-18 on page 2-12. | | | | | | | |

* *For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero® Integrated Design Environment (IDE).*

***Table 2-21 •*** **Different Components Contributing to Dynamic Power Consumption in IGLOO Devices For IGLOO V2 Devices, 1.2 V DC Core Supply Voltage**

| Parameter | Definition | Device Specific Dynamic Power (µW/MHz) | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| | | **AGL1000** | **AGL600** | **AGL400** | **AGL250** | **AGL125** | **AGL060** | **AGL030** | **AGL015** |
| PAC1 | Clock contribution of a Global Rib | 9.28 | 8.19 | 8.19 | 7.07 | 7.07 | 5.96 | 5.96 | 5.96 |
| PAC2 | Clock contribution of a Global Spine | 1.59 | 1.19 | 1.01 | 1.01 | 0.52 | 0.52 | 0.26 | 0.26 |
| PAC3 | Clock contribution of a VersaTile row | 0.52 | | | | | | | |
| PAC4 | Clock contribution of a VersaTile used as a sequential module | 0.07 | | | | | | | |
| PAC5 | First contribution of a VersaTile used as a sequential module | 0.045 | | | | | | | |
| PAC6 | Second contribution of a VersaTile used as a sequential module | 0.186 | | | | | | | |
| PAC7 | Contribution of a VersaTile used as a combinatorial module | 0.11 | | | | | | | |
| PAC8 | Average contribution of a routing net | 0.45 | | | | | | | |
| PAC9 | Contribution of an I/O input pin (standard-dependent) | See Table 2-13 on page 2-10 through Table 2-15 on page 2-11. | | | | | | | |
| PAC10 | Contribution of an I/O output pin (standard-dependent) | See Table 2-16 on page 2-11 through Table 2-18 on page 2-12. | | | | | | | |
| PAC11 | Average contribution of a RAM block during a read operation | 25.00 | | | | | | | |
| PAC12 | Average contribution of a RAM block during a write operation | 30.00 | | | | | | | |
| PAC13 | Dynamic PLL contribution | 2.10 | | | | | | | |

*Note: For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero IDE.*

**Table 2-22 • Different Components Contributing to the Static Power Consumption in IGLOO Device For IGLOO V2 Devices, 1.2 V DC Core Supply Voltage**

| Parameter | Definition | Device Specific Static Power (mW) | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| | | AGL1000 | AGL600 | AGL400 | AGL250 | AGL125 | AGL060 | AGL030 | AGL015 |
| PDC1 | Array static power in Active mode | See Table 2-12 on page 2-9. | | | | | | | |
| PDC2 | Array static power in Static (Idle) mode | See Table 2-11 on page 2-8. | | | | | | | |
| PDC3 | Array static power in Flash*Freeze mode | See Table 2-9 on page 2-7. | | | | | | | |
| PDC4 | Static PLL contribution | 0.90 | | | | | | | |
| PDC5 | Bank quiescent power (VCCI-Dependent) | See Table 2-12 on page 2-9. | | | | | | | |
| PDC6 | I/O input pin static power (standard-dependent) | See Table 2-13 on page 2-10 through Table 2-15 on page 2-11. | | | | | | | |
| PDC7 | I/O output pin static power (standard-dependent) | See Table 2-16 on page 2-11 through Table 2-18 on page 2-12. | | | | | | | |

*Note: For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero® Integrated Design Environment (IDE).*

# Power Calculation Methodology

This section describes a simplified method to estimate power consumption of an application. For more accurate and detailed power estimations, use the SmartPower tool in Microsemi Libero IDE software.

The power calculation methodology described below uses the following variables:

- The number of PLLs as well as the number and the frequency of each output clock generated
- The number of combinatorial and sequential cells used in the design
- The internal clock frequencies
- The number and the standard of I/O pins used in the design
- The number of RAM blocks used in the design
- Toggle rates of I/O pins as well as VersaTiles—guidelines are provided in Table 2-23 on page 2-19.
- Enable rates of output buffers—guidelines are provided for typical applications in Table 2-24 on page 2-19.
- Read rate and write rate to the memory—guidelines are provided for typical applications in Table 2-24 on page 2-19. The calculation should be repeated for each clock domain defined in the design.

## Methodology

### Total Power Consumption—$P_{TOTAL}$

$P_{TOTAL} = P_{STAT} + P_{DYN}$

$P_{STAT}$ is the total static power consumption.

$P_{DYN}$ is the total dynamic power consumption.

### Total Static Power Consumption—$P_{STAT}$

$P_{STAT} = (P_{DC1}$ or $P_{DC2}$ or $P_{DC3}) + N_{BANKS} * P_{DC5} + N_{INPUTS} * P_{DC6} + N_{OUTPUTS} * P_{DC7}$

$N_{INPUTS}$ is the number of I/O input buffers used in the design.

$N_{OUTPUTS}$ is the number of I/O output buffers used in the design.

$N_{BANKS}$ is the number of I/O banks powered in the design.

### Total Dynamic Power Consumption—$P_{DYN}$

$P_{DYN} = P_{CLOCK} + P_{S\text{-}CELL} + P_{C\text{-}CELL} + P_{NET} + P_{INPUTS} + P_{OUTPUTS} + P_{MEMORY} + P_{PLL}$

### Global Clock Contribution—$P_{CLOCK}$

$P_{CLOCK} = (P_{AC1} + N_{SPINE} * P_{AC2} + N_{ROW} * P_{AC3} + N_{S\text{-}CELL} * P_{AC4}) * F_{CLK}$

$N_{SPINE}$ is the number of global spines used in the user design—guidelines are provided in Table 2-23 on page 2-19.

$N_{ROW}$ is the number of VersaTile rows used in the design—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

$N_{S\text{-}CELL}$ is the number of VersaTiles used as sequential modules in the design.

$P_{AC1}$, $P_{AC2}$, $P_{AC3}$, and $P_{AC4}$ are device-dependent.

### Sequential Cells Contribution—$P_{S\text{-}CELL}$

$P_{S\text{-}CELL} = N_{S\text{-}CELL} * (P_{AC5} + \alpha_1 / 2 * P_{AC6}) * F_{CLK}$

$N_{S\text{-}CELL}$ is the number of VersaTiles used as sequential modules in the design. When a multi-tile sequential cell is used, it should be accounted for as 1.

$\alpha_1$ is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

### Combinatorial Cells Contribution—$P_{C\text{-}CELL}$

$P_{C\text{-}CELL} = N_{C\text{-}CELL} * \alpha_1 / 2 * P_{AC7} * F_{CLK}$

$N_{C\text{-}CELL}$ is the number of VersaTiles used as combinatorial modules in the design.

$\alpha_1$ is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

### *Routing Net Contribution—$P_{NET}$*

$P_{NET} = (N_{S\text{-}CELL} + N_{C\text{-}CELL}) * \alpha_1 / 2 * P_{AC8} * F_{CLK}$

$N_{S\text{-}CELL}$ is the number of VersaTiles used as sequential modules in the design.

$N_{C\text{-}CELL}$ is the number of VersaTiles used as combinatorial modules in the design.

$\alpha_1$ is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

### *I/O Input Buffer Contribution—$P_{INPUTS}$*

$P_{INPUTS} = N_{INPUTS} * \alpha_2 / 2 * P_{AC9} * F_{CLK}$

$N_{INPUTS}$ is the number of I/O input buffers used in the design.

$\alpha_2$ is the I/O buffer toggle rate—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

### *I/O Output Buffer Contribution—$P_{OUTPUTS}$*

$P_{OUTPUTS} = N_{OUTPUTS} * \alpha_2 / 2 * \beta_1 * P_{AC10} * F_{CLK}$

$N_{OUTPUTS}$ is the number of I/O output buffers used in the design.

$\alpha_2$ is the I/O buffer toggle rate—guidelines are provided in Table 2-23 on page 2-19.

$\beta_1$ is the I/O buffer enable rate—guidelines are provided in Table 2-24 on page 2-19.

$F_{CLK}$ is the global clock signal frequency.

### *RAM Contribution—$P_{MEMORY}$*

$P_{MEMORY} = P_{AC11} * N_{BLOCKS} * F_{READ\text{-}CLOCK} * \beta_2 + P_{AC12} * N_{BLOCK} * F_{WRITE\text{-}CLOCK} * \beta_3$

$N_{BLOCKS}$ is the number of RAM blocks used in the design.

$F_{READ\text{-}CLOCK}$ is the memory read clock frequency.

$\beta_2$ is the RAM enable rate for read operations.

$F_{WRITE\text{-}CLOCK}$ is the memory write clock frequency.

$\beta_3$ is the RAM enable rate for write operations—guidelines are provided in Table 2-24 on page 2-19.

### *PLL Contribution—$P_{PLL}$*

$P_{PLL} = P_{DC4} + P_{AC13} * F_{CLKOUT}$

$F_{CLKOUT}$ is the output clock frequency.†

† *If a PLL is used to generate more than one output clock, include each output clock in the formula by adding its corresponding contribution ($P_{AC13} * F_{CLKOUT}$ product) to the total PLL contribution.*

## Guidelines

### Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% because all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:
  - Bit 0 (LSB) = 100%
  - Bit 1 = 50%
  - Bit 2 = 25%
  - …
  - Bit 7 (MSB) = 0.78125%
  - Average toggle rate = (100% + 50% + 25% + 12.5% + . . . + 0.78125%) / 8

### Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

**Table 2-23 • Toggle Rate Guidelines Recommended for Power Calculation**

| Component | Definition | Guideline |
|---|---|---|
| $\alpha_1$ | Toggle rate of VersaTile outputs | 10% |
| $\alpha_2$ | I/O buffer toggle rate | 10% |

**Table 2-24 • Enable Rate Guidelines Recommended for Power Calculation**

| Component | Definition | Guideline |
|---|---|---|
| $\beta_1$ | I/O output buffer enable rate | 100% |
| $\beta_2$ | RAM enable rate for read operations | 12.5% |
| $\beta_3$ | RAM enable rate for write operations | 12.5% |

# User I/O Characteristics

## Timing Model

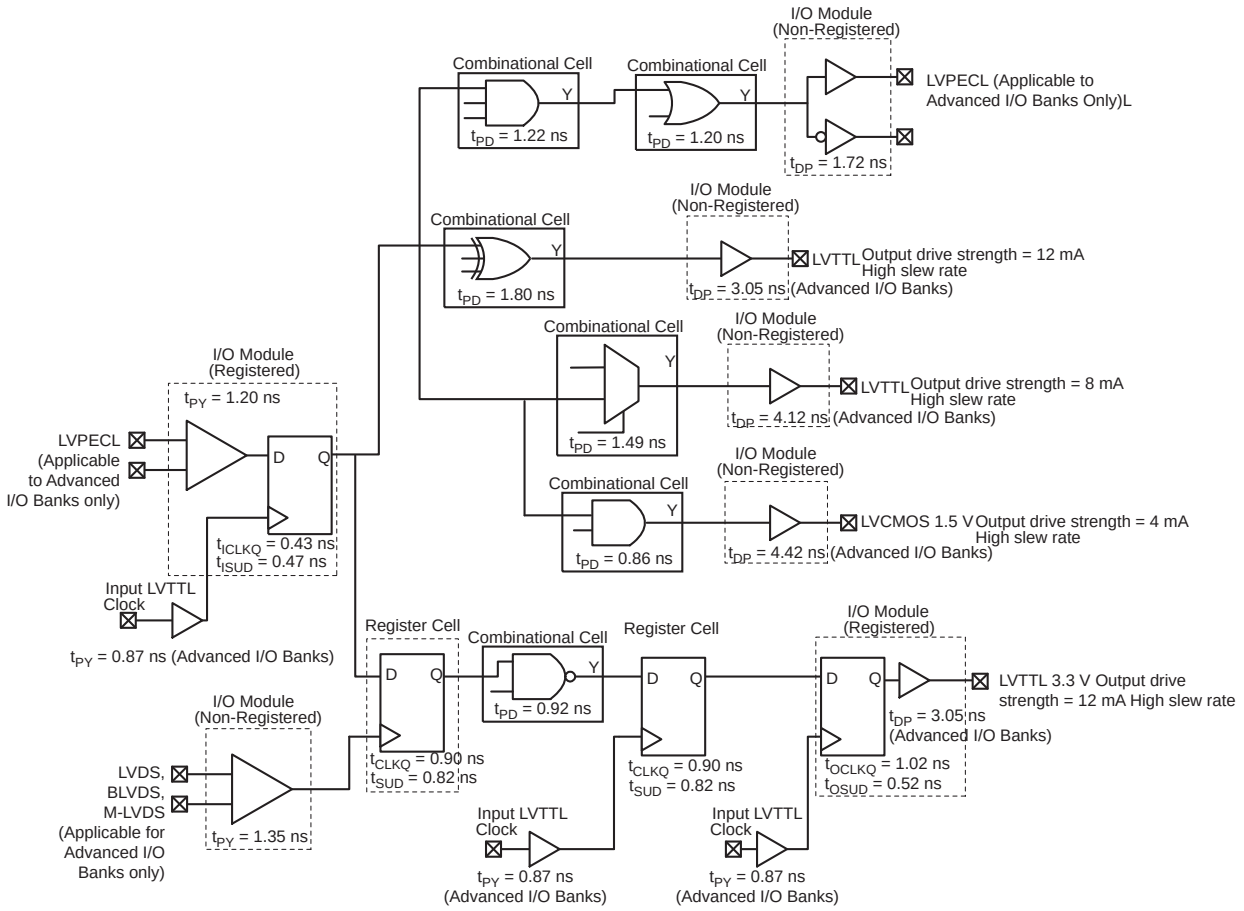



***Figure 2-3 •*** **Timing Model**
**Operating Conditions: Std. Speed, Commercial Temperature Range ($T_J$ = 70°C), Worst-Case VCC = 1.425 V, for DC 1.5 V Core Voltage, Applicable to V2 and V5 Devices**

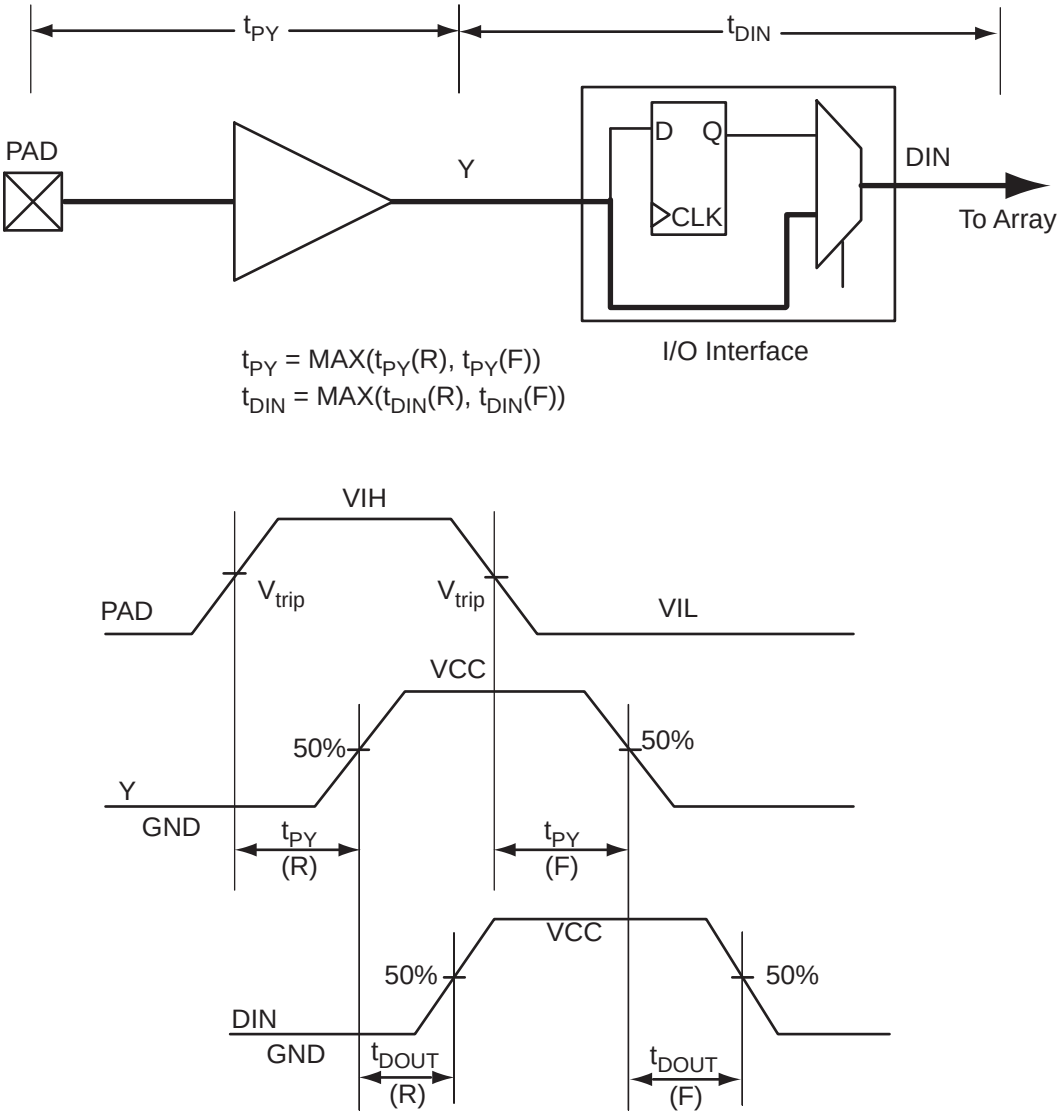



***Figure 2-4 •*** **Input Buffer Timing Model and Delays (example)**

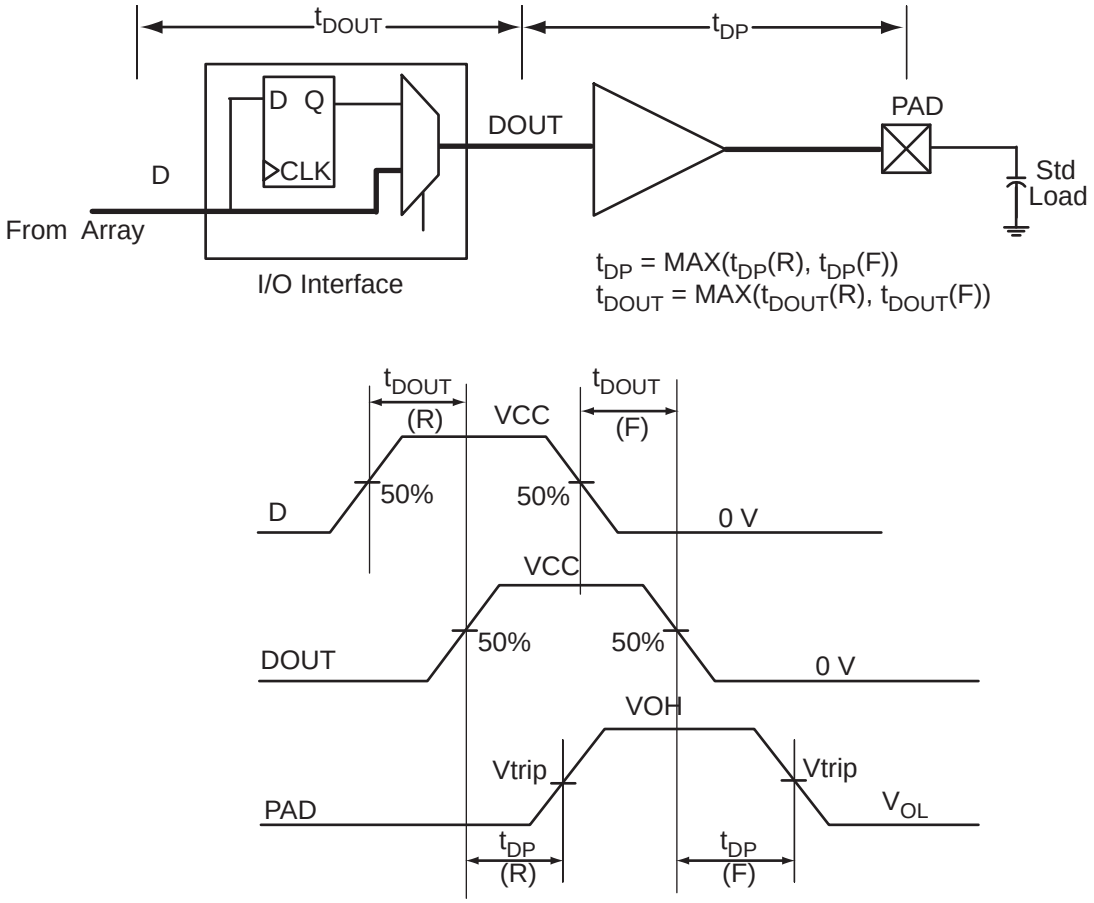



***Figure 2-5 •*** **Output Buffer Model and Delays (example)**

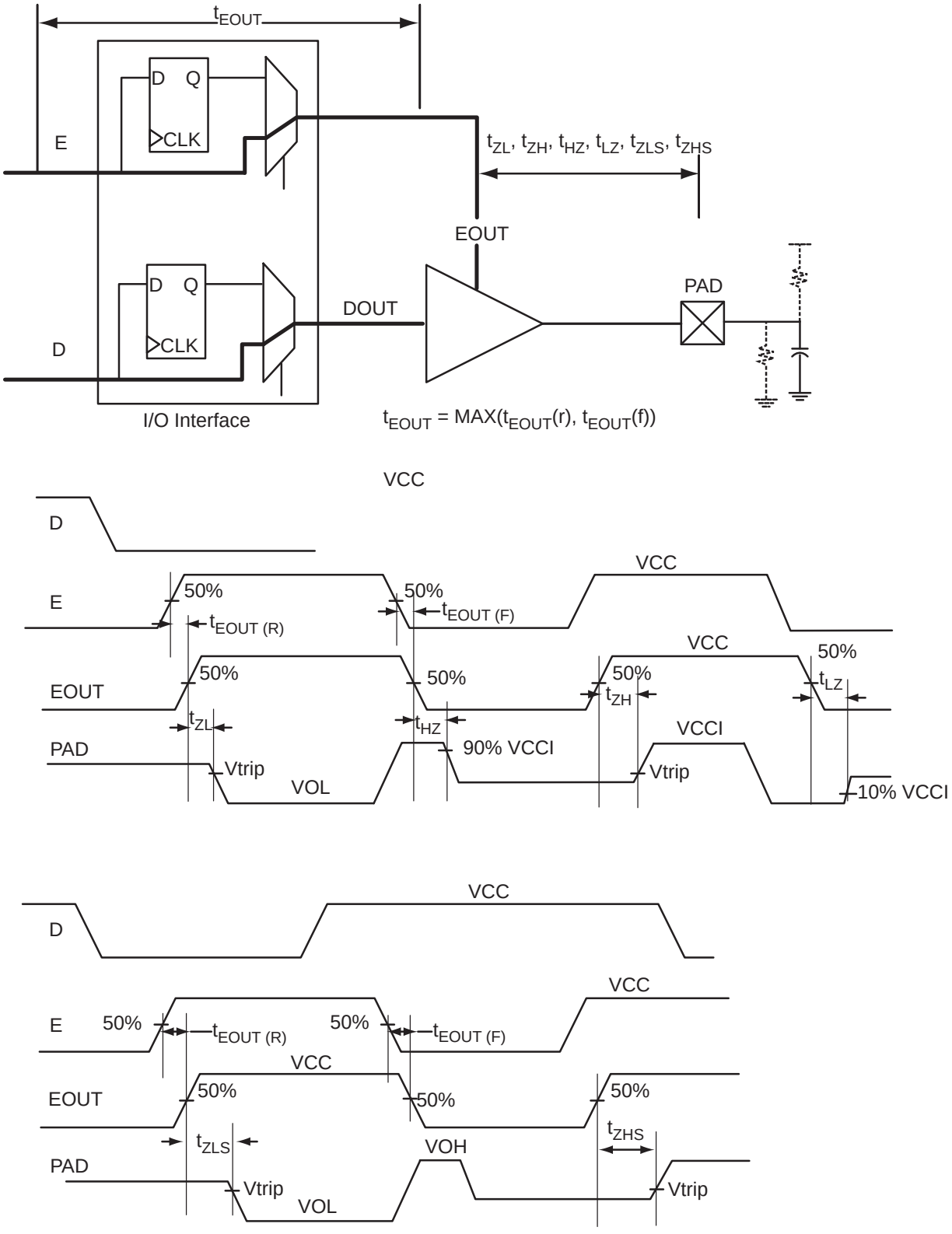



***Figure 2-6 •*** **Tristate Output Buffer Timing Model and Delays (example)**

## Overview of I/O Performance

### Summary of I/O DC Input and Output Levels – Default I/O Software Settings

**Table 2-25 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings Applicable to Advanced I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[2] | Slew Rate | VIL | | VIH | | VOL | VOH | IOL[1] | IOH[1] |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | Min.V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA |
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 12 | 12 |
| 3.3 V LVCMOS Wide Range[3] | 100 µA | 12 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VCCI – 0.2 | 0.1 | 0.1 |
| 2.5 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 12 | 12 |
| 1.8 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 12 | 12 |
| 1.5 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 12 | 12 |
| 1.2 V LVCMOS[4] | 2 mA | 2 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 |
| 1.2 V LVCMOS Wide Range[4,5] | 100 µA | 2 mA | High | –0.3 | 0.3 * VCCI | 0.7 * VCCI | 1.575 | 0.1 | VCCI – 0.1 | 0.1 | 0.1 |
| 3.3 V PCI | Per PCI specifications | | | | | | | | | | |
| 3.3 V PCI-X | Per PCI-X specifications | | | | | | | | | | |

*Notes:*

1. *Currents are measured at 85°C junction temperature.*
2. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
3. *All LVMCOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
4. *Applicable to V2 Devices operating at VCCI ≥ VCC.*
5. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.*

**Table 2-26 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings Applicable to Standard Plus I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[2] | Slew Rate | VIL | | VIH | | VOL | VOH | $I_{OL}$ | $I_{OH}$ |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA |
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 12 | 12 |
| 3.3 V LVCMOS Wide Range[3] | 100 µA | 12 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD-0.2 | 0.1 | 0.1 |
| 2.5 V LVCMOS | 12 mA | 12 mA | High | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 12 | 12 |
| 1.8 V LVCMOS | 8 mA | 8 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 8 | 8 |
| 1.5 V LVCMOS | 4 mA | 4 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 4 | 4 |
| 1.2 V LVCMOS[4] | 2 mA | 2 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 |
| 1.2 V LVCMOS Wide Range[4] | 100 µA | 2 mA | High | –0.3 | 0.3 * VCCI | 0.7 * VCCI | 1.575 | 0.1 | VCCI – 0.1 | 0.1 | 0.1 |
| 3.3 V PCI | Per PCI specifications | | | | | | | | | | |
| 3.3 V PCI-X | Per PCI-X specifications | | | | | | | | | | |

*Notes:*

1. *Currents are measured at 85°C junction temperature.*
2. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
3. *All LVMCOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
4. *Applicable to V2 Devices operating at VCCI ≥ VCC.*
5. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.*

**Table 2-27 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings Applicable to Standard I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[2] | Slew Rate | VIL | | $V_{IH}$ | | VOL | $V_{OH}$ | $I_{OL}$[1] | $I_{OH}$[1] |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA |
| 3.3 V LVTTL / 3.3 V LVCMOS | 8 mA | 8 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 8 | 8 |
| 3.3 V LVCMOS Wide Range[3] | 100 µA | 8 mA | High | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD-0.2 | 0.1 | 0.1 |
| 2.5 V LVCMOS | 8 mA | 8 mA | High | –0.3 | 0.7 | 1.7 | 3.6 | 0.7 | 1.7 | 8 | 8 |
| 1.8 V LVCMOS | 4 mA | 4 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.45 | VCCI – 0.45 | 4 | 4 |
| 1.5 V LVCMOS | 2 mA | 2 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 |
| 1.2 V LVCMOS[4] | 1 mA | 1 mA | High | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.25 * VCCI | 0.75 * VCCI | 1 | 1 |
| 1.2 V LVCMOS Wide Range[4,5] | 100 µA | 1 mA | High | –0.3 | 0.3 * VCCI | 0.7 * VCCI | 3.6 | 0.1 | VCCI – 0.1 | 0.1 | 0.1 |

*Notes:*

1. *Currents are measured at 85°C junction temperature.*
2. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
3. *All LVMCOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
4. *Applicable to V2 Devices operating at VCCI ≥ VCC.*
5. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.*

**Table 2-28 • Summary of Maximum and Minimum DC Input Levels Applicable to Commercial and Industrial Conditions**

| | Commercial[1] | | Industrial[2] | |
|---|---|---|---|---|
| | IIL[4] | IIH[5] | IIL[4] | IIH[5] |
| DC I/O Standards | µA | µA | µA | µA |
| 3.3 V LVTTL / 3.3 V LVCMOS | 10 | 10 | 15 | 15 |
| 3.3 V LVCMOS Wide Range | 10 | 10 | 15 | 15 |
| 2.5 V LVCMOS | 10 | 10 | 15 | 15 |
| 1.8 V LVCMOS | 10 | 10 | 15 | 15 |
| 1.5 V LVCMOS | 10 | 10 | 15 | 15 |
| 1.2 V LVCMOS[3] | 10 | 10 | 15 | 15 |
| 1.2 V LVCMOS Wide Range[3] | 10 | 10 | 15 | 15 |
| 3.3 V PCI | 10 | 10 | 15 | 15 |
| 3.3 V PCI-X | 10 | 10 | 15 | 15 |

*Notes:*

1. *Commercial range (0°C < $T_A$ < 70°C)*
2. *Industrial range (–40°C < $T_A$ < 85°C)*
3. *Applicable to V2 Devices operating at VCCI ≥ VCC.*
4. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
5. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*

## Summary of I/O Timing Characteristics – Default I/O Software Settings

**Table 2-29 • Summary of AC Measuring Points**

| Standard | Measuring Trip Point (Vtrip) |
|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 1.4 V |
| 3.3 V VCMOS Wide Range | 1.4 V |
| 2.5 V LVCMOS | 1.2 V |
| 1.8 V LVCMOS | 0.90 V |
| 1.5 V LVCMOS | 0.75 V |
| 1.2 V LVCMOS | 0.60 V |
| 1.2 V LVCMOS Wide Range | 0.60 V |
| 3.3 V PCI | 0.285 * VCCI (RR) |
| | 0.615 * VCCI (FF) |
| 3.3 V PCI-X | 0.285 * VCCI (RR) |
| | 0.615 * VCCI (FF) |

**Table 2-30 • I/O AC Parameter Definitions**

| Parameter | Parameter Definition |
|---|---|
| $t_{DP}$ | Data to Pad delay through the Output Buffer |
| $t_{PY}$ | Pad to Data delay through the Input Buffer |
| $t_{DOUT}$ | Data to Output Buffer delay through the I/O interface |
| $t_{EOUT}$ | Enable to Output Buffer Tristate Control delay through the I/O interface |
| $t_{DIN}$ | Input Buffer to Data delay through the I/O interface |
| $t_{HZ}$ | Enable to Pad delay through the Output Buffer—High to Z |
| $t_{ZH}$ | Enable to Pad delay through the Output Buffer—Z to High |
| $t_{LZ}$ | Enable to Pad delay through the Output Buffer—Low to Z |
| $t_{ZL}$ | Enable to Pad delay through the Output Buffer—Z to Low |
| $t_{ZHS}$ | Enable to Pad delay through the Output Buffer with delayed enable—Z to High |
| $t_{ZLS}$ | Enable to Pad delay through the Output Buffer with delayed enable—Z to Low |

**Table 2-31 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI (per standard)**
**Applicable to Advanced I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[1] (mA) | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | $t_{ZLS}$ (ns) | $t_{ZHS}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 2.09 | 0.18 | 0.85 | 0.66 | 2.14 | 1.68 | 2.67 | 3.05 | 5.73 | 5.27 | ns |
| 3.3 V LVCMOS Wide Range[2] | 100 µA | 12 | High | 5 | – | 0.97 | 2.93 | 0.18 | 1.19 | 0.66 | 2.95 | 2.27 | 3.81 | 4.30 | 6.54 | 5.87 | ns |
| 2.5 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 2.09 | 0.18 | 1.08 | 0.66 | 2.14 | 1.83 | 2.73 | 2.93 | 5.73 | 5.43 | ns |
| 1.8 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 2.24 | 0.18 | 1.01 | 0.66 | 2.29 | 2.00 | 3.02 | 3.40 | 5.88 | 5.60 | ns |
| 1.5 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 2.50 | 0.18 | 1.17 | 0.66 | 2.56 | 2.27 | 3.21 | 3.48 | 6.15 | 5.86 | ns |
| 3.3 V PCI | Per PCI spec | – | High | 10 | 25 [2] | 0.97 | 2.32 | 0.18 | 0.74 | 0.66 | 2.37 | 1.78 | 2.67 | 3.05 | 5.96 | 5.38 | ns |
| 3.3 V PCI-X | Per PCI-X spec | – | High | 10 | 25 [2] | 0.97 | 2.32 | 0.19 | 0.70 | 0.66 | 2.37 | 1.78 | 2.67 | 3.05 | 5.96 | 5.38 | ns |
| LVDS | 24 mA | – | High | – | – | 0.97 | 1.74 | 0.19 | 1.35 | – | – | – | – | – | – | – | ns |
| LVPECL | 24 mA | – | High | – | – | 0.97 | 1.68 | 0.19 | 1.16 | – | – | – | – | – | – | – | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *Resistance is used to measure I/O propagation delays as defined in PCI specifications. See Figure 2-12 on page 2-79 for connectivity. This resistor is not required during normal operation.*
4. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-32 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI (per standard)**
**Applicable to Standard Plus I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[1] (mA) | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | $t_{ZLS}$ (ns) | $t_{ZHS}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 1.75 | 0.18 | 0.85 | 0.66 | 1.79 | 1.40 | 2.36 | 2.79 | 5.38 | 4.99 | ns |
| 3.3 V LVCMOS Wide Range[2] | 100 µA | 12 | High | 5 | – | 0.97 | 2.45 | 0.18 | 1.20 | 0.66 | 2.47 | 1.92 | 3.33 | 3.90 | 6.06 | 5.51 | ns |
| 2.5 V LVCMOS | 12 mA | 12 | High | 5 | – | 0.97 | 1.75 | 0.18 | 1.08 | 0.66 | 1.79 | 1.52 | 2.38 | 2.70 | 5.39 | 5.11 | ns |
| 1.8 V LVCMOS | 8 mA | 8 | High | 5 | – | 0.97 | 1.97 | 0.18 | 1.01 | 0.66 | 2.02 | 1.76 | 2.46 | 2.66 | 5.61 | 5.36 | ns |
| 1.5 V LVCMOS | 4 mA | 4 | High | 5 | – | 0.97 | 2.25 | 0.18 | 1.18 | 0.66 | 2.30 | 2.00 | 2.53 | 2.68 | 5.89 | 5.59 | ns |
| 3.3 V PCI | Per PCI spec | – | High | 10 | 25 [2] | 0.97 | 1.97 | 0.18 | 0.73 | 0.66 | 2.01 | 1.50 | 2.36 | 2.79 | 5.61 | 5.10 | ns |
| 3.3 V PCI-X | Per PCI-X spec | – | High | 10 | 25 [2] | 0.97 | 1.97 | 0.19 | 0.70 | 0.66 | 2.01 | 1.50 | 2.36 | 2.79 | 5.61 | 5.10 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *Resistance is used to measure I/O propagation delays as defined in PCI specifications. See Figure 2-12 on page 2-79 for connectivity. This resistor is not required during normal operation.*
4. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-33 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI (per standard)**
**Applicable to Standard I/O Banks**

| I/O Standard | Drive Strength) | Equivalent Software Default Drive Strength Option[1] (mA) | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 8 mA | 8 | High | 5 | – | 0.97 | 1.85 | 0.18 | 0.83 | 0.66 | 1.89 | 1.46 | 1.96 | 2.26 | ns |
| 3.3 V LVCMOS Wide Range[2] | 100 µA | 8 | High | 5 | – | 0.97 | 2.62 | 0.18 | 1.17 | 0.66 | 2.63 | 2.02 | 2.79 | 3.17 | ns |
| 2.5 V LVCMOS | 8 mA | 8 | High | 5 | – | 0.97 | 1.88 | 0.18 | 1.04 | 0.66 | 1.92 | 1.63 | 1.95 | 2.15 | ns |
| 1.8 V LVCMOS | 4 mA | 4 | High | 5 | – | 0.97 | 2.18 | 0.18 | 0.98 | 0.66 | 2.22 | 1.93 | 1.97 | 2.06 | ns |
| 1.5 V LVCMOS | 2 mA | 2 | High | 5 | – | 0.97 | 2.51 | 0.18 | 1.14 | 0.66 | 2.56 | 2.21 | 1.99 | 2.03 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-34 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI (per standard)**
**Applicable to Advanced I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[1] | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | $t_{ZLS}$ (ns) | $t_{ZHS}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 mA | High | 5 | – | 1.55 | 2.67 | 0.26 | 0.98 | 1.10 | 2.71 | 2.18 | 3.25 | 3.93 | 8.50 | 7.97 | ns |
| 3.3 V LVCMOS Wide Range[2] | 100 µA | 12 mA | High | 5 | – | 1.55 | 3.73 | 0.26 | 1.32 | 1.10 | 3.73 | 2.91 | 4.51 | 5.43 | 9.52 | 8.69 | ns |
| 2.5 V LVCMOS | 12 mA | 12 mA | High | 5 | – | 1.55 | 2.64 | 0.26 | 1.20 | 1.10 | 2.67 | 2.29 | 3.30 | 3.79 | 8.46 | 8.08 | ns |
| 1.8 V LVCMOS | 12 mA | 12 mA | High | 5 | – | 1.55 | 2.72 | 0.26 | 1.11 | 1.10 | 2.76 | 2.43 | 3.58 | 4.19 | 8.55 | 8.22 | ns |
| 1.5 V LVCMOS | 12 mA | 12 mA | High | 5 | – | 1.55 | 2.96 | 0.26 | 1.27 | 1.10 | 3.00 | 2.70 | 3.75 | 4.23 | 8.78 | 8.48 | ns |
| 1.2 V LVCMOS | 2 mA | 2 mA | High | 5 | – | 1.55 | 3.60 | 0.26 | 1.60 | 1.10 | 3.47 | 3.36 | 3.93 | 3.65 | 9.26 | 9.14 | ns |
| 1.2 V LVCMOS Wide Range[3] | 100 µA | 2 mA | High | 5 | – | 1.55 | 3.60 | 0.26 | 1.60 | 1.10 | 3.47 | 3.36 | 3.93 | 3.65 | 9.26 | 9.14 | ns |
| 3.3 V PCI | Per PCI spec | – | High | 10 | 25[2] | 1.55 | 2.91 | 0.26 | 0.86 | 1.10 | 2.95 | 2.29 | 3.25 | 3.93 | 8.74 | 8.08 | ns |
| 3.3 V PCI-X | Per PCI-X spec | – | High | 10 | 25[2] | 1.55 | 2.91 | 0.25 | 0.86 | 1.10 | 2.95 | 2.29 | 3.25 | 3.93 | 8.74 | 8.08 | ns |
| LVDS | 24 mA | – | High | – | – | 1.55 | 2.27 | 0.25 | 1.57 | – | – | – | – | – | – | – | ns |
| LVPECL | 24 mA | – | High | – | – | 1.55 | 2.24 | 0.25 | 1.38 | – | – | – | – | – | – | – | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification*
4. *Resistance is used to measure I/O propagation delays as defined in PCI specifications. See Figure 2-12 on page 2-79 for connectivity. This resistor is not required during normal operation.*
5. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-35 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI (per standard)**
**Applicable to Standard Plus I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[1] (mA) | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | $t_{ZLS}$ (ns) | $t_{ZHS}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 12 mA | 12 | High | 5 | – | 1.55 | 2.31 | 0.26 | 0.97 | 1.10 | 2.34 | 1.86 | 2.93 | 3.64 | 8.12 | 7.65 | ns |
| 3.3 V LVCMOS Wide Range[2] | 100 µA | 12 | High | 5 | – | 1.55 | 3.20 | 0.26 | 1.32 | 1.10 | 3.20 | 2.52 | 4.01 | 4.97 | 8.99 | 8.31 | ns |
| 2.5 V LVCMOS | 12 mA | 12 | High | 5 | – | 1.55 | 2.29 | 0.26 | 1.19 | 1.10 | 2.32 | 1.94 | 2.94 | 3.52 | 8.10 | 7.73 | ns |
| 1.8 V LVCMOS | 8 mA | 8 | High | 5 | – | 1.55 | 2.43 | 0.26 | 1.11 | 1.10 | 2.47 | 2.16 | 2.99 | 3.39 | 8.25 | 7.94 | ns |
| 1.5 V LVCMOS | 4 mA | 4 | High | 5 | – | 1.55 | 2.68 | 0.26 | 1.27 | 1.10 | 2.72 | 2.39 | 3.07 | 3.37 | 8.50 | 8.18 | ns |
| 1.2 V LVCMOS | 2 mA | 2 | High | 5 | – | 1.55 | 3.22 | 0.26 | 1.59 | 1.10 | 3.11 | 2.78 | 3.29 | 3.48 | 8.90 | 8.57 | ns |
| 1.2 V LVCMOS Wide Range[3] | 100 µA | 2 | High | 5 | – | 1.55 | 3.22 | 0.26 | 1.59 | 1.10 | 3.11 | 2.78 | 3.29 | 3.48 | 8.90 | 8.57 | ns |
| 3.3 V PCI | Per PCI spec | – | High | 10 | 25[2] | 1.55 | 2.53 | 0.26 | 0.84 | 1.10 | 2.57 | 1.98 | 2.93 | 3.64 | 8.35 | 7.76 | ns |
| 3.3 V PCI-X | Per PCI-X spec | – | High | 10 | 25[2] | 1.55 | 2.53 | 0.25 | 0.85 | 1.10 | 2.57 | 1.98 | 2.93 | 3.64 | 8.35 | 7.76 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification*
4. *Resistance is used to measure I/O propagation delays as defined in PCI specifications. See Figure 2-12 on page 2-79 for connectivity. This resistor is not required during normal operation.*
5. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-36 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case $V_{CC}$ = 1.14 V, Worst-Case VCCI (per standard)**
**Applicable to Standard I/O Banks**

| I/O Standard | Drive Strength | Equivalent Software Default Drive Strength Option[1] (mA) | Slew Rate | Capacitive Load (pF) | External Resistor (Ω) | $t_{DOUT}$ (ns) | $t_{DP}$ (ns) | $t_{DIN}$ (ns) | $t_{PY}$ (ns) | $t_{EOUT}$ (ns) | $t_{ZL}$ (ns) | $t_{ZH}$ (ns) | $t_{LZ}$ (ns) | $t_{HZ}$ (ns) | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 8 mA | 8 | High | 5 | – | 1.55 | 2.38 | 0.26 | 0.94 | 1.10 | 2.41 | 1.92 | 2.40 | 2.96 | ns |
| 3.3 V LVCMOS Wide Range[3] | 100 µA | 8 | High | 5 | – | 1.55 | 3.33 | 0.26 | 1.29 | 1.10 | 3.33 | 2.62 | 3.34 | 4.07 | ns |
| 2.5 V LVCMOS | 8 mA | 8 | High | 5 | – | 1.55 | 2.39 | 0.26 | 1.15 | 1.10 | 2.42 | 2.05 | 2.38 | 2.80 | ns |
| 1.8 V LVCMOS | 4 mA | 4 | High | 5 | – | 1.55 | 2.60 | 0.26 | 1.08 | 1.10 | 2.64 | 2.33 | 2.38 | 2.62 | ns |
| 1.5 V LVCMOS | 2 mA | 2 | High | 5 | – | 1.55 | 2.92 | 0.26 | 1.22 | 1.10 | 2.96 | 2.60 | 2.40 | 2.56 | ns |
| 1.2 V LVCMOS | 1 mA | 1 | High | 5 | – | 1.55 | 3.59 | 0.26 | 1.53 | 1.10 | 3.47 | 3.06 | 2.51 | 2.49 | ns |
| 1.2 V LVCMOS Wide Range[3] | 100 µA | 1 | High | 5 | – | 1.55 | 3.59 | 0.26 | 1.53 | 1.10 | 3.47 | 3.06 | 2.51 | 2.49 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is ±100 µA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.*
3. *All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification*
4. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

## Detailed I/O DC Characteristics

***Table 2-37 •*** **Input Capacitance**

| Symbol | Definition | Conditions | Min. | Max. | Units |
|---|---|---|---|---|---|
| $C_{IN}$ | Input capacitance | VIN = 0, f = 1.0 MHz | | 8 | pF |
| $C_{INCLK}$ | Input capacitance on the clock pin | VIN = 0, f = 1.0 MHz | | 8 | pF |

***Table 2-38 •*** **I/O Output Buffer Maximum Resistances[1]**
**Applicable to Advanced I/O Banks**

| Standard | Drive Strength | $R_{PULL\text{-}DOWN}$ ($\Omega$)[2] | $R_{PULL\text{-}UP}$ ($\Omega$)[3] |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 100 | 300 |
| | 4 mA | 100 | 300 |
| | 6 mA | 50 | 150 |
| | 8 mA | 50 | 150 |
| | 12 mA | 25 | 75 |
| | 16 mA | 17 | 50 |
| | 24 mA | 11 | 33 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 100 | 200 |
| | 4 mA | 100 | 200 |
| | 6 mA | 50 | 100 |
| | 8 mA | 50 | 100 |
| | 12 mA | 25 | 50 |
| | 16 mA | 20 | 40 |
| 1.5 V LVCMOS | 2 mA | 200 | 224 |
| | 4 mA | 100 | 112 |
| | 6 mA | 67 | 75 |
| | 8 mA | 33 | 37 |
| | 12 mA | 33 | 37 |
| 1.2 V LVCMOS[4] | 2 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range[4] | 100 µA | TBD | TBD |
| 3.3 V PCI/PCI-X | Per PCI/PCI-X specification | 25 | 75 |

*Notes:*

1. *These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on VCCI, drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located at http://www.microsemi.com/soc/download/ibis/default.aspx.*
2. $R_{(PULL\text{-}DOWN\text{-}MAX)} = (VOLspec) / I_{OLspec}$
3. $R_{(PULL\text{-}UP\text{-}MAX)} = (VCCImax – VOHspec) / I_{OHspec}$
4. *Applicable to IGLOO V2 Devices operating at VCCI ≥ VCC*

**Table 2-39 • I/O Output Buffer Maximum Resistances[1] Applicable to Standard Plus I/O Banks**

| Standard | Drive Strength | $R_{PULL\text{-}DOWN}$ ($\Omega$)[2] | $R_{PULL\text{-}UP}$ ($\Omega$)[3] |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 100 | 300 |
| | 4 mA | 100 | 300 |
| | 6 mA | 50 | 150 |
| | 8 mA | 50 | 150 |
| | 12 mA | 25 | 75 |
| | 16 mA | 25 | 75 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 100 | 200 |
| | 4 mA | 100 | 200 |
| | 6 mA | 50 | 100 |
| | 8 mA | 50 | 100 |
| | 12 mA | 25 | 50 |
| 1.8 V LVCMOS | 2 mA | 200 | 225 |
| | 4 mA | 100 | 112 |
| | 6 mA | 50 | 56 |
| | 8 mA | 50 | 56 |
| 1.5 V LVCMOS | 2 mA | 200 | 224 |
| | 4 mA | 100 | 112 |
| 1.2 V LVCMOS[4] | 2 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range[4] | 100 µA | TBD | TBD |
| 3.3 V PCI/PCI-X | Per PCI/PCI-X specification | 25 | 75 |

*Notes:*

1. *These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on VCCI, drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located at http://www.microsemi.com/soc/download/ibis/default.aspx.*
2. $R_{(PULL\text{-}DOWN\text{-}MAX)}$ = (VOLspec) / $I_{OLspec}$
3. $R_{(PULL\text{-}UP\text{-}MAX)}$ = (VCCImax – VOHspec) / $I_{OHspec}$
4. *Applicable to IGLOO V2 Devices operating at VCCI ≥ VCC*

**Table 2-40 • I/O Output Buffer Maximum Resistances[1]**
**Applicable to Standard I/O Banks**

| Standard | Drive Strength | $R_{PULL\text{-}DOWN}$ (Ω)[2] | $R_{PULL\text{-}UP}$ (Ω)[3] |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 100 | 300 |
| | 4 mA | 100 | 300 |
| | 6 mA | 50 | 150 |
| | 8 mA | 50 | 150 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 100 | 200 |
| | 4 mA | 100 | 200 |
| | 6 mA | 50 | 100 |
| | 8 mA | 50 | 100 |
| 1.8 V LVCMOS | 2 mA | 200 | 225 |
| | 4 mA | 100 | 112 |
| 1.5 V LVCMOS | 2 mA | 200 | 224 |
| 1.2 V LVCMOS | 1 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range[4] | 100 µA | TBD | TBD |

*Notes:*

1. *These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on VCCI, drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located at http://www.microsemi.com/soc/download/ibis/default.aspx.*
2. $R_{(PULL\text{-}DOWN\text{-}MAX)} = (VOLspec) / I_{OLspec}$
3. $R_{(PULL\text{-}UP\text{-}MAX)} = (VCCImax - VOHspec) / I_{OHspec}$

**Table 2-41 • I/O Weak Pull-Up/Pull-Down Resistances**
**Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values**

| | $R_{(WEAK\ PULL\text{-}UP)}$[1] (Ω) | | $R_{(WEAK\ PULL\text{-}DOWN)}$[2] (Ω) | |
|---|---|---|---|---|
| VCCI | Min. | Max. | Min. | Max. |
| 3.3 V | 10 K | 45 K | 10 K | 45 K |
| 3.3 V Wide Range I/Os | 10 K | 45 K | 10 K | 45 K |
| 2.5 V | 11 K | 55 K | 12 K | 74 K |
| 1.8 V | 18 K | 70 K | 17 K | 110 K |
| 1.5 V | 19 K | 90 K | 19 K | 140 K |
| 1.2 V | 25 K | 110 K | 25 K | 150 K |
| 1.2 V Wide Range I/Os | 19 K | 110 K | 19 K | 150 K |

*Notes:*

1. $R_{(WEAK\ PULL\text{-}UP\text{-}MAX)} = (VCCImax - VOHspec) / I_{(WEAK\ PULL\text{-}UP\text{-}MIN)}$
2. $R_{(WEAK\ PULLDOWN\text{-}MAX)} = (VOLspec) / I_{(WEAK\ PULLDOWN\text{-}MIN)}$

**Table 2-42 • I/O Short Currents IOSH/IOSL
Applicable to Advanced I/O Banks**

| | Drive Strength | IOSL (mA)* | IOSH (mA)* |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 25 | 27 |
| | 4 mA | 25 | 27 |
| | 6 mA | 51 | 54 |
| | 8 mA | 51 | 54 |
| | 12 mA | 103 | 109 |
| | 16 mA | 132 | 127 |
| | 24 mA | 268 | 181 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 16 | 18 |
| | 4 mA | 16 | 18 |
| | 6 mA | 32 | 37 |
| | 8 mA | 32 | 37 |
| | 12 mA | 65 | 74 |
| | 16 mA | 83 | 87 |
| | 24 mA | 169 | 124 |
| 1.8 V LVCMOS | 2 mA | 9 | 11 |
| | 4 mA | 17 | 22 |
| | 6 mA | 35 | 44 |
| | 8 mA | 45 | 51 |
| | 12 mA | 91 | 74 |
| | 16 mA | 91 | 74 |
| 1.5 V LVCMOS | 2 mA | 13 | 16 |
| | 4 mA | 25 | 33 |
| | 6 mA | 32 | 39 |
| | 8 mA | 66 | 55 |
| | 12 mA | 66 | 55 |
| 1.2 V LVCMOS | 2 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 3.3 V PCI/PCI-X | Per PCI/PCI-X specification | 103 | 109 |

*Note: *$T_J$ = 100°C*

**Table 2-43 • I/O Short Currents IOSH/IOSL**
**Applicable to Standard Plus I/O Banks**

| | Drive Strength | IOSL (mA)* | IOSH (mA)* |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 25 | 27 |
| | 4 mA | 25 | 27 |
| | 6 mA | 51 | 54 |
| | 8 mA | 51 | 54 |
| | 12 mA | 103 | 109 |
| | 16 mA | 103 | 109 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 16 | 18 |
| | 4 mA | 16 | 18 |
| | 6 mA | 32 | 37 |
| | 8 mA | 32 | 37 |
| | 12 mA | 65 | 74 |
| 1.8 V LVCMOS | 2 mA | 9 | 11 |
| | 4 mA | 17 | 22 |
| | 6 mA | 35 | 44 |
| | 8 mA | 35 | 44 |
| 1.5 V LVCMOS | 2 mA | 13 | 16 |
| | 4 mA | 25 | 33 |
| 1.2 V LVCMOS | 2 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 3.3 V PCI/PCI-X | Per PCI/PCI-X specification | 103 | 109 |

*Note: *$T_J$ = 100°C*

**Table 2-44 • I/O Short Currents IOSH/IOSL Applicable to Standard I/O Banks**

| | Drive Strength | IOSL (mA)* | IOSH (mA)* |
|---|---|---|---|
| 3.3 V LVTTL / 3.3 V LVCMOS | 2 mA | 25 | 27 |
| | 4 mA | 25 | 27 |
| | 6 mA | 51 | 54 |
| | 8 mA | 51 | 54 |
| 3.3 V LVCMOS Wide Range | 100 µA | TBD | TBD |
| 2.5 V LVCMOS | 2 mA | 16 | 18 |
| | 4 mA | 16 | 18 |
| | 6 mA | 32 | 37 |
| | 8 mA | 32 | 37 |
| 1.8 V LVCMOS | 2 mA | 9 | 11 |
| | 4 mA | 17 | 22 |
| 1.5 V LVCMOS | 2 mA | 13 | 16 |
| 1.2 V LVCMOS | 1 mA | TBD | TBD |
| 1.2 V LVCMOS Wide Range | 100 µA | TBD | TBD |

*Note: *$T_J$ = 100°C*

The length of time an I/O can withstand $I_{OSH}/I_{OSL}$ events depends on the junction temperature. The reliability data below is based on a 3.3 V, 12 mA I/O setting, which is the worst case for this type of analysis.

For example, at 100°C, the short current condition would have to be sustained for more than six months to cause a reliability concern. The I/O design does not contain any short circuit protection, but such protection would only be needed in extremely prolonged stress conditions.

**Table 2-45 • Duration of Short Circuit Event before Failure**

| Temperature | Time before Failure |
|---|---|
| –40°C | > 20 years |
| –20°C | > 20 years |
| 0°C | > 20 years |
| 25°C | > 20 years |
| 70°C | 5 years |
| 85°C | 2 years |
| 100°C | 6 months |

**Table 2-46 • I/O Input Rise Time, Fall Time, and Related I/O Reliability**

| Input Buffer | Input Rise/Fall Time (min.) | Input Rise/Fall Time (max.) | Reliability |
|---|---|---|---|
| LVTTL/LVCMOS | No requirement | 10 ns * | 20 years (100°C) |
| LVDS/B-LVDS/M-LVDS/ LVPECL | No requirement | 10 ns * | 10 years (100°C) |

*Note: The maximum input rise/fall time is related to the noise induced into the input buffer trace. If the noise is low, then the rise time and fall time of input buffers can be increased beyond the maximum value. The longer the rise/fall times, the more susceptible the input signal is to the board noise. Microsemi recommends signal integrity evaluation/characterization of the system to ensure that there is no excessive noise coupling into input signals.*

## Single-Ended I/O Characteristics

### 3.3 V LVTTL / 3.3 V LVCMOS

Low-Voltage Transistor–Transistor Logic (LVTTL) is a general-purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer. Furthermore, all LVCMOS 3.3 V software macros comply with LVCMOS 3.3 V wide range as specified in the JESD8a specification.

**Table 2-47 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

| 3.3 V LVTTL / 3.3 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 2 | 2 | 25 | 27 | 10 | 10 |
| 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 4 | 4 | 25 | 27 | 10 | 10 |
| 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 6 | 6 | 51 | 54 | 10 | 10 |
| 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 8 | 8 | 51 | 54 | 10 | 10 |
| 12 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 12 | 12 | 103 | 109 | 10 | 10 |
| 16 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 16 | 16 | 132 | 127 | 10 | 10 |
| 24 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 24 | 24 | 268 | 181 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-48 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

| 3.3 V LVTTL / 3.3 V LVCMOS | VIL | | VIH | | $V_{OL}$ | VOH | IOL | IOH | IOSL | IOSH | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 2 | 2 | 25 | 27 | 10 | 10 |
| 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 4 | 4 | 25 | 27 | 10 | 10 |
| 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 6 | 6 | 51 | 54 | 10 | 10 |
| 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 8 | 8 | 51 | 54 | 10 | 10 |
| 12 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 12 | 12 | 103 | 109 | 10 | 10 |
| 16 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 16 | 16 | 103 | 109 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-49 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

| 3.3 V LVTTL / 3.3 V LVCMOS | VIL | | VIH | | $V_{OL}$ | VOH | IOL | IOH | IOSL | IOSH | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 2 | 2 | 25 | 27 | 10 | 10 |
| 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 4 | 4 | 25 | 27 | 10 | 10 |
| 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 6 | 6 | 51 | 54 | 10 | 10 |
| 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.4 | 2.4 | 8 | 8 | 51 | 54 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

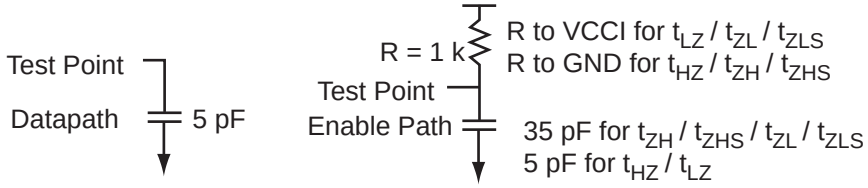



**Figure 2-7 • AC Loading**

**Table 2-50 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 3.3 | 1.4 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### *Applies to 1.5 V DC Core Voltage*

**Table 2-51 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 4.47 | 0.18 | 0.85 | 0.66 | 4.56 | 3.89 | 2.24 | 2.19 | 8.15 | 7.48 | ns |
| 6 mA | Std. | 0.97 | 3.74 | 0.18 | 0.85 | 0.66 | 3.82 | 3.37 | 2.49 | 2.63 | 7.42 | 6.96 | ns |
| 8 mA | Std. | 0.97 | 3.74 | 0.18 | 0.85 | 0.66 | 3.82 | 3.37 | 2.49 | 2.63 | 7.42 | 6.96 | ns |
| 12 mA | Std. | 0.97 | 3.23 | 0.18 | 0.85 | 0.66 | 3.30 | 2.98 | 2.66 | 2.91 | 6.89 | 6.57 | ns |
| 16 mA | Std. | 0.97 | 3.08 | 0.18 | 0.85 | 0.66 | 3.14 | 2.89 | 2.70 | 2.99 | 6.74 | 6.48 | ns |
| 24 mA | Std. | 0.97 | 3.00 | 0.18 | 0.85 | 0.66 | 3.06 | 2.91 | 2.74 | 3.27 | 6.66 | 6.50 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-52 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 2.73 | 0.18 | 0.85 | 0.66 | 2.79 | 2.22 | 2.25 | 2.32 | 6.38 | 5.82 | ns |
| 6 mA | Std. | 0.97 | 2.32 | 0.18 | 0.85 | 0.66 | 2.37 | 1.85 | 2.50 | 2.76 | 5.96 | 5.45 | ns |
| 8 mA | Std. | 0.97 | 2.32 | 0.18 | 0.85 | 0.66 | 2.37 | 1.85 | 2.50 | 2.76 | 5.96 | 5.45 | ns |
| 12 mA | Std. | 0.97 | 2.09 | 0.18 | 0.85 | 0.66 | 2.14 | 1.68 | 2.67 | 3.05 | 5.73 | 5.27 | ns |
| 16 mA | Std. | 0.97 | 2.05 | 0.18 | 0.85 | 0.66 | 2.10 | 1.64 | 2.70 | 3.12 | 5.69 | 5.24 | ns |
| 24 mA | Std. | 0.97 | 2.07 | 0.18 | 0.85 | 0.66 | 2.12 | 1.60 | 2.75 | 3.41 | 5.71 | 5.20 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-53 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 3.94 | 0.18 | 0.85 | 0.66 | 4.02 | 3.46 | 1.98 | 2.03 | 7.62 | 7.05 | ns |
| 6 mA | Std. | 0.97 | 3.24 | 0.18 | 0.85 | 0.66 | 3.31 | 2.99 | 2.21 | 2.42 | 6.90 | 6.59 | ns |
| 8 mA | Std. | 0.97 | 3.24 | 0.18 | 0.85 | 0.66 | 3.31 | 2.99 | 2.21 | 2.42 | 6.90 | 6.59 | ns |
| 12 mA | Std. | 0.97 | 2.76 | 0.18 | 0.85 | 0.66 | 2.82 | 2.63 | 2.36 | 2.68 | 6.42 | 6.22 | ns |
| 16 mA | Std. | 0.97 | 2.76 | 0.18 | 0.85 | 0.66 | 2.82 | 2.63 | 2.36 | 2.68 | 6.42 | 6.22 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-54 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 2.32 | 0.18 | 0.85 | 0.66 | 2.37 | 1.90 | 1.98 | 2.13 | 5.96 | 5.49 | ns |
| 6 mA | Std. | 0.97 | 1.94 | 0.18 | 0.85 | 0.66 | 1.99 | 1.57 | 2.20 | 2.53 | 5.58 | 5.16 | ns |
| 8 mA | Std. | 0.97 | 1.94 | 0.18 | 0.85 | 0.66 | 1.99 | 1.57 | 2.20 | 2.53 | 5.58 | 5.16 | ns |
| 12 mA | Std. | 0.97 | 1.75 | 0.18 | 0.85 | 0.66 | 1.79 | 1.40 | 2.36 | 2.79 | 5.38 | 4.99 | ns |
| 16 mA | Std. | 0.97 | 1.75 | 0.18 | 0.85 | 0.66 | 1.79 | 1.40 | 2.36 | 2.79 | 5.38 | 4.99 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-55 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 3.80 | 0.18 | 0.83 | 0.66 | 3.88 | 3.41 | 1.74 | 1.78 | ns |
| 4 mA | Std. | 0.97 | 3.80 | 0.18 | 0.83 | 0.66 | 3.88 | 3.41 | 1.74 | 1.78 | ns |
| 6 mA | Std. | 0.97 | 3.15 | 0.18 | 0.83 | 0.66 | 3.21 | 2.94 | 1.96 | 2.17 | ns |
| 8 mA | Std. | 0.97 | 3.15 | 0.18 | 0.83 | 0.66 | 3.21 | 2.94 | 1.96 | 2.17 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-56 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.19 | 0.18 | 0.83 | 0.66 | 2.24 | 1.79 | 1.74 | 1.87 | ns |
| 4 mA | Std. | 0.97 | 2.19 | 0.18 | 0.83 | 0.66 | 2.24 | 1.79 | 1.74 | 1.87 | ns |
| 6 mA | Std. | 0.97 | 1.85 | 0.18 | 0.83 | 0.66 | 1.89 | 1.46 | 1.96 | 2.26 | ns |
| 8 mA | Std. | 0.97 | 1.85 | 0.18 | 0.83 | 0.66 | 1.89 | 1.46 | 1.96 | 2.26 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### *Applies to 1.2 V DC Core Voltage*

**Table 2-57 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 5.12 | 0.26 | 0.98 | 1.10 | 5.20 | 4.46 | 2.81 | 3.02 | 10.99 | 10.25 | ns |
| 6 mA | Std. | 1.55 | 4.38 | 0.26 | 0.98 | 1.10 | 4.45 | 3.93 | 3.07 | 3.48 | 10.23 | 9.72 | ns |
| 8 mA | Std. | 1.55 | 4.38 | 0.26 | 0.98 | 1.10 | 4.45 | 3.93 | 3.07 | 3.48 | 10.23 | 9.72 | ns |
| 12 mA | Std. | 1.55 | 3.85 | 0.26 | 0.98 | 1.10 | 3.91 | 3.53 | 3.24 | 3.77 | 9.69 | 9.32 | ns |
| 16 mA | Std. | 1.55 | 3.69 | 0.26 | 0.98 | 1.10 | 3.75 | 3.44 | 3.28 | 3.84 | 9.54 | 9.23 | ns |
| 24 mA | Std. | 1.55 | 3.61 | 0.26 | 0.98 | 1.10 | 3.67 | 3.46 | 3.33 | 4.13 | 9.45 | 9.24 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-58 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 3.33 | 0.26 | 0.98 | 1.10 | 3.38 | 2.75 | 2.82 | 3.18 | 9.17 | 8.54 | ns |
| 6 mA | Std. | 1.55 | 2.91 | 0.26 | 0.98 | 1.10 | 2.95 | 2.37 | 3.07 | 3.64 | 8.73 | 8.15 | ns |
| 8 mA | Std. | 1.55 | 2.91 | 0.26 | 0.98 | 1.10 | 2.95 | 2.37 | 3.07 | 3.64 | 8.73 | 8.15 | ns |
| 12 mA | Std. | 1.55 | 2.67 | 0.26 | 0.98 | 1.10 | 2.71 | 2.18 | 3.25 | 3.93 | 8.50 | 7.97 | ns |
| 16 mA | Std. | 1.55 | 2.63 | 0.26 | 0.98 | 1.10 | 2.67 | 2.14 | 3.28 | 4.01 | 8.45 | 7.93 | ns |
| 24 mA | Std. | 1.55 | 2.65 | 0.26 | 0.98 | 1.10 | 2.69 | 2.10 | 3.33 | 4.31 | 8.47 | 7.89 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-59 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 4.56 | 0.26 | 0.97 | 1.10 | 4.63 | 3.98 | 2.54 | 2.83 | 10.42 | 9.76 | ns |
| 6 mA | Std. | 1.55 | 3.84 | 0.26 | 0.97 | 1.10 | 3.90 | 3.50 | 2.77 | 3.24 | 9.69 | 9.29 | ns |
| 8 mA | Std. | 1.55 | 3.84 | 0.26 | 0.97 | 1.10 | 3.90 | 3.50 | 2.77 | 3.24 | 9.69 | 9.29 | ns |
| 12 mA | Std. | 1.55 | 3.35 | 0.26 | 0.97 | 1.10 | 3.40 | 3.13 | 2.93 | 3.51 | 9.19 | 8.91 | ns |
| 16 mA | Std. | 1.55 | 3.35 | 0.26 | 0.97 | 1.10 | 3.40 | 3.13 | 2.93 | 3.51 | 9.19 | 8.91 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-60 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 2.89 | 0.26 | 0.97 | 1.10 | 2.93 | 2.38 | 2.53 | 2.96 | 8.72 | 8.17 | ns |
| 6 mA | Std. | 1.55 | 2.50 | 0.26 | 0.97 | 1.10 | 2.54 | 2.04 | 2.77 | 3.37 | 8.33 | 7.82 | ns |
| 8 mA | Std. | 1.55 | 2.50 | 0.26 | 0.97 | 1.10 | 2.54 | 2.04 | 2.77 | 3.37 | 8.33 | 7.82 | ns |
| 12 mA | Std. | 1.55 | 2.31 | 0.26 | 0.97 | 1.10 | 2.34 | 1.86 | 2.93 | 3.64 | 8.12 | 7.65 | ns |
| 16 mA | Std. | 1.55 | 2.31 | 0.26 | 0.97 | 1.10 | 2.34 | 1.86 | 2.93 | 3.64 | 8.12 | 7.65 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-61 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 4.39 | 0.26 | 0.94 | 1.10 | 4.46 | 3.91 | 2.17 | 2.44 | ns |
| 4 mA | Std. | 1.55 | 4.39 | 0.26 | 0.94 | 1.10 | 4.46 | 3.91 | 2.17 | 2.44 | ns |
| 6 mA | Std. | 1.55 | 3.72 | 0.26 | 0.94 | 1.10 | 3.78 | 3.43 | 2.40 | 2.85 | ns |
| 8 mA | Std. | 1.55 | 3.72 | 0.26 | 0.94 | 1.10 | 3.78 | 3.43 | 2.40 | 2.85 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-62 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 2.74 | 0.26 | 0.94 | 1.10 | 2.78 | 2.26 | 2.17 | 2.55 | ns |
| 4 mA | Std. | 1.55 | 2.74 | 0.26 | 0.94 | 1.10 | 2.78 | 2.26 | 2.17 | 2.55 | ns |
| 6 mA | Std. | 1.55 | 2.38 | 0.26 | 0.94 | 1.10 | 2.41 | 1.92 | 2.40 | 2.96 | ns |
| 8 mA | Std. | 1.55 | 2.38 | 0.26 | 0.94 | 1.10 | 2.41 | 1.92 | 2.40 | 2.96 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 3.3 V LVCMOS Wide Range

**Table 2-63 • Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range Applicable to Advanced I/O Banks**

| 3.3 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | µA | µA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 12 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 16 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 24 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-64 • Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range Applicable to Standard Plus I/O Banks**

| 3.3 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | µA | µA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 12 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 16 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-65 • Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range Applicable to Standard I/O Banks**

| 3.3 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | µA | µA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 2 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 4 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 6 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |
| 100 µA | 8 mA | –0.3 | 0.8 | 2 | 3.6 | 0.2 | VDD – 0.2 | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-66 • 3.3 V LVCMOS Wide Range AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 3.3 | 1.4 | 5 |

** Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### *Applies to 1.5 V DC Core Voltage*

**Table 2-67 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Advanced Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 0.97 | 6.61 | 0.18 | 1.19 | 0.66 | 6.63 | 5.63 | 3.15 | 2.98 | 10.22 | 9.23 | ns |
| 100 µA | 6 mA | Std. | 0.97 | 5.49 | 0.18 | 1.19 | 0.66 | 5.51 | 4.84 | 3.54 | 3.66 | 9.10 | 8.44 | ns |
| 100 µA | 8 mA | Std. | 0.97 | 5.49 | 0.18 | 1.19 | 0.66 | 5.51 | 4.84 | 3.54 | 3.66 | 9.10 | 8.44 | ns |
| 100 µA | 12 mA | Std. | 0.97 | 4.69 | 0.18 | 1.19 | 0.66 | 4.71 | 4.25 | 3.80 | 4.10 | 8.31 | 7.85 | ns |
| 100 µA | 16 mA | Std. | 0.97 | 4.46 | 0.18 | 1.19 | 0.66 | 4.48 | 4.11 | 3.86 | 4.21 | 8.07 | 7.71 | ns |
| 100 µA | 24 mA | Std. | 0.97 | 4.34 | 0.18 | 1.19 | 0.66 | 4.36 | 4.14 | 3.93 | 4.64 | 7.95 | 7.74 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-68 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Advanced Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 0.97 | 3.92 | 0.18 | 1.19 | 0.66 | 3.94 | 3.10 | 3.16 | 3.17 | 7.54 | 6.70 | ns |
| 100 µA | 6 mA | Std. | 0.97 | 3.28 | 0.18 | 1.19 | 0.66 | 3.30 | 2.54 | 3.54 | 3.86 | 6.90 | 6.14 | ns |
| 100 µA | 8 mA | Std. | 0.97 | 3.28 | 0.18 | 1.19 | 0.66 | 3.30 | 2.54 | 3.54 | 3.86 | 6.90 | 6.14 | ns |
| 100 µA | 12 mA | Std. | 0.97 | 2.93 | 0.18 | 1.19 | 0.66 | 2.95 | 2.27 | 3.81 | 4.30 | 6.54 | 5.87 | ns |
| 100 µA | 16 mA | Std. | 0.97 | 2.87 | 0.18 | 1.19 | 0.66 | 2.89 | 2.22 | 3.86 | 4.41 | 6.49 | 5.82 | ns |
| 100 µA | 24 mA | Std. | 0.97 | 2.90 | 0.18 | 1.19 | 0.66 | 2.92 | 2.16 | 3.94 | 4.86 | 6.51 | 5.75 | ns |

*Notes:*

1. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
2. *Software default selection highlighted in gray.*
3. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*

**Table 2-69 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 0.97 | 5.84 | 0.18 | 1.20 | 0.66 | 5.86 | 5.04 | 2.74 | 2.71 | 9.46 | 8.64 | ns |
| 100 µA | 6 mA | Std. | 0.97 | 4.76 | 0.18 | 1.20 | 0.66 | 4.78 | 4.33 | 3.09 | 3.33 | 8.37 | 7.93 | ns |
| 100 µA | 8 mA | Std. | 0.97 | 4.76 | 0.18 | 1.20 | 0.66 | 4.78 | 4.33 | 3.09 | 3.33 | 8.37 | 7.93 | ns |
| 100 µA | 12 mA | Std. | 0.97 | 4.02 | 0.18 | 1.20 | 0.66 | 4.04 | 3.78 | 3.33 | 3.73 | 7.64 | 7.37 | ns |
| 100 µA | 16 mA | Std. | 0.97 | 4.02 | 0.18 | 1.20 | 0.66 | 4.04 | 3.78 | 3.33 | 3.73 | 7.64 | 7.37 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-70 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 0.97 | 3.33 | 0.18 | 1.20 | 0.66 | 3.35 | 2.68 | 2.73 | 2.88 | 6.94 | 6.27 | ns |
| 100 µA | 6 mA | Std. | 0.97 | 2.75 | 0.18 | 1.20 | 0.66 | 2.77 | 2.17 | 3.08 | 3.50 | 6.36 | 5.77 | ns |
| 100 µA | 8 mA | Std. | 0.97 | 2.75 | 0.18 | 1.20 | 0.66 | 2.77 | 2.17 | 3.08 | 3.50 | 6.36 | 5.77 | ns |
| 100 µA | 12 mA | Std. | 0.97 | 2.45 | 0.18 | 1.20 | 0.66 | 2.47 | 1.92 | 3.33 | 3.90 | 6.06 | 5.51 | ns |
| 100 µA | 16 mA | Std. | 0.97 | 2.45 | 0.18 | 1.20 | 0.66 | 2.47 | 1.92 | 3.33 | 3.90 | 6.06 | 5.51 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
3. *Software default selection highlighted in gray.*

**Table 2-71 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Standard Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 2 mA | Std. | 0.97 | 5.64 | 0.18 | 1.17 | 0.66 | 5.65 | 4.98 | 2.45 | 2.42 | ns |
| 100 µA | 4 mA | Std. | 0.97 | 5.64 | 0.18 | 1.17 | 0.66 | 5.65 | 4.98 | 2.45 | 2.42 | ns |
| 100 µA | 6 mA | Std. | 0.97 | 4.63 | 0.18 | 1.17 | 0.66 | 4.64 | 4.26 | 2.80 | 3.02 | ns |
| 100 µA | 8 mA | Std. | 0.97 | 4.63 | 0.18 | 1.17 | 0.66 | 4.64 | 4.26 | 2.80 | 3.02 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-72 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V**
**Applicable to Standard Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 2 mA | 0.97 | 3.16 | 0.18 | 1.17 | 0.66 | 3.17 | 2.53 | 2.45 | 2.56 | 0.97 | ns |
| 100 µA | 4 mA | 0.97 | 3.16 | 0.18 | 1.17 | 0.66 | 3.17 | 2.53 | 2.45 | 2.56 | 0.97 | ns |
| 100 µA | 6 mA | 0.97 | 2.62 | 0.18 | 1.17 | 0.66 | 2.63 | 2.02 | 2.79 | 3.17 | 0.97 | ns |
| 100 µA | 8 mA | 0.97 | 2.62 | 0.18 | 1.17 | 0.66 | 2.63 | 2.02 | 2.79 | 3.17 | 0.97 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
3. *Software default selection highlighted in gray.*

### *Applies to 1.2 V DC Core Voltage*

**Table 2-73 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7 V**
**Applicable to Advanced Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 1.55 | 7.52 | 0.26 | 1.32 | 1.10 | 7.52 | 6.38 | 3.84 | 4.02 | 13.31 | 12.16 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 6.37 | 0.26 | 1.32 | 1.10 | 6.37 | 5.57 | 4.23 | 4.73 | 12.16 | 11.35 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 6.37 | 0.26 | 1.32 | 1.10 | 6.37 | 5.57 | 4.23 | 4.73 | 12.16 | 11.35 | ns |
| 100 µA | 12 mA | Std. | 1.55 | 5.55 | 0.26 | 1.32 | 1.10 | 5.55 | 4.96 | 4.50 | 5.18 | 11.34 | 10.75 | ns |
| 100 µA | 16 mA | Std. | 1.55 | 5.32 | 0.26 | 1.32 | 1.10 | 5.32 | 4.82 | 4.56 | 5.29 | 11.10 | 10.61 | ns |
| 100 µA | 24 mA | Std. | 1.55 | 5.19 | 0.26 | 1.32 | 1.10 | 5.19 | 4.85 | 4.63 | 5.74 | 10.98 | 10.63 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-74 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7**
**Applicable to Advanced Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 1.55 | 4.75 | 0.26 | 1.32 | 1.10 | 4.75 | 3.77 | 3.84 | 4.27 | 10.54 | 9.56 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 4.10 | 0.26 | 1.32 | 1.10 | 4.10 | 3.19 | 4.24 | 4.98 | 9.88 | 8.98 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 4.10 | 0.26 | 1.32 | 1.10 | 4.10 | 3.19 | 4.24 | 4.98 | 9.88 | 8.98 | ns |
| 100 µA | 12 mA | Std. | 1.55 | 3.73 | 0.26 | 1.32 | 1.10 | 3.73 | 2.91 | 4.51 | 5.43 | 9.52 | 8.69 | ns |
| 100 µA | 16 mA | Std. | 1.55 | 3.67 | 0.26 | 1.32 | 1.10 | 3.67 | 2.85 | 4.57 | 5.55 | 9.46 | 8.64 | ns |
| 100 µA | 24 mA | Std. | 1.55 | 3.70 | 0.26 | 1.32 | 1.10 | 3.70 | 2.79 | 4.65 | 6.01 | 9.49 | 8.58 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
3. *Software default selection highlighted in gray.*

**Table 2-75 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7**
**Applicable to Standard Plus Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 1.55 | 6.69 | 0.26 | 1.32 | 1.10 | 6.69 | 5.73 | 3.41 | 3.72 | 12.48 | 11.52 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 5.58 | 0.26 | 1.32 | 1.10 | 5.58 | 5.01 | 3.77 | 4.35 | 11.36 | 10.79 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 5.58 | 0.26 | 1.32 | 1.10 | 5.58 | 5.01 | 3.77 | 4.35 | 11.36 | 10.79 | ns |
| 100 µA | 12 mA | Std. | 1.55 | 4.82 | 0.26 | 1.32 | 1.10 | 4.82 | 4.44 | 4.02 | 4.76 | 10.61 | 10.23 | ns |
| 100 µA | 16 mA | Std. | 1.55 | 4.82 | 0.26 | 1.32 | 1.10 | 4.82 | 4.44 | 4.02 | 4.76 | 10.61 | 10.23 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-76 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7**
**Applicable to Standard Plus Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 4 mA | Std. | 1.55 | 4.10 | 0.26 | 1.32 | 1.10 | 4.10 | 3.30 | 3.40 | 3.92 | 9.89 | 9.09 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 3.51 | 0.26 | 1.32 | 1.10 | 3.51 | 2.79 | 3.76 | 4.56 | 9.30 | 8.57 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 3.51 | 0.26 | 1.32 | 1.10 | 3.51 | 2.79 | 3.76 | 4.56 | 9.30 | 8.57 | ns |
| 100 µA | 12 mA | Std. | 1.55 | 3.20 | 0.26 | 1.32 | 1.10 | 3.20 | 2.52 | 4.01 | 4.97 | 8.99 | 8.31 | ns |
| 100 µA | 16 mA | Std. | 1.55 | 3.20 | 0.26 | 1.32 | 1.10 | 3.20 | 2.52 | 4.01 | 4.97 | 8.99 | 8.31 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
3. *Software default selection highlighted in gray.*

**Table 2-77 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case $V_{CC}$ = 1.14 V, Worst-Case VCCI = 2.7**
**Applicable to Standard Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 2 mA | Std. | 1.55 | 6.44 | 0.26 | 1.29 | 1.10 | 6.44 | 5.64 | 2.99 | 3.28 | ns |
| 100 µA | 4 mA | Std. | 1.55 | 6.44 | 0.26 | 1.29 | 1.10 | 6.44 | 5.64 | 2.99 | 3.28 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 5.41 | 0.26 | 1.29 | 1.10 | 5.41 | 4.91 | 3.35 | 3.89 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 5.41 | 0.26 | 1.29 | 1.10 | 5.41 | 4.91 | 3.35 | 3.89 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-78 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.7**
**Applicable to Standard Banks**

| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 100 µA | 2 mA | Std. | 1.55 | 3.89 | 0.26 | 1.29 | 1.10 | 3.89 | 3.13 | 2.99 | 3.45 | ns |
| 100 µA | 4 mA | Std. | 1.55 | 3.89 | 0.26 | 1.29 | 1.10 | 3.89 | 3.13 | 2.99 | 3.45 | ns |
| 100 µA | 6 mA | Std. | 1.55 | 3.33 | 0.26 | 1.29 | 1.10 | 3.33 | 2.62 | 3.34 | 4.07 | ns |
| 100 µA | 8 mA | Std. | 1.55 | 3.33 | 0.26 | 1.29 | 1.10 | 3.33 | 2.62 | 3.34 | 4.07 | ns |

*Notes:*

1. *The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ± 100 µA. Drive strengths displayed in software are supported for normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
3. *Software default selection highlighted in gray.*

### 2.5 V LVCMOS

Low-Voltage CMOS for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications.

**Table 2-79 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

| 2.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 2 | 2 | 16 | 18 | 10 | 10 |
| 4 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 4 | 4 | 16 | 18 | 10 | 10 |
| 6 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 6 | 6 | 32 | 37 | 10 | 10 |
| 8 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 8 | 8 | 32 | 37 | 10 | 10 |
| 12 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 12 | 12 | 65 | 74 | 10 | 10 |
| 16 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 16 | 16 | 83 | 87 | 10 | 10 |
| 24 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 24 | 24 | 169 | 124 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-80 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

| 2.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 2 | 2 | 16 | 18 | 10 | 10 |
| 4 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 4 | 4 | 16 | 18 | 10 | 10 |
| 6 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 6 | 6 | 32 | 37 | 10 | 10 |
| 8 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 8 | 8 | 32 | 37 | 10 | 10 |
| 12 mA | –0.3 | 0.7 | 1.7 | 2.7 | 0.7 | 1.7 | 12 | 12 | 65 | 74 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-81 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

| 2.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.7 | 1.7 | 3.6 | 0.7 | 1.7 | 2 | 2 | 16 | 18 | 10 | 10 |
| 4 mA | –0.3 | 0.7 | 1.7 | 3.6 | 0.7 | 1.7 | 4 | 4 | 16 | 18 | 10 | 10 |
| 6 mA | –0.3 | 0.7 | 1.7 | 3.6 | 0.7 | 1.7 | 6 | 6 | 32 | 37 | 10 | 10 |
| 8 mA | –0.3 | 0.7 | 1.7 | 3.6 | 0.7 | 1.7 | 8 | 8 | 32 | 37 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

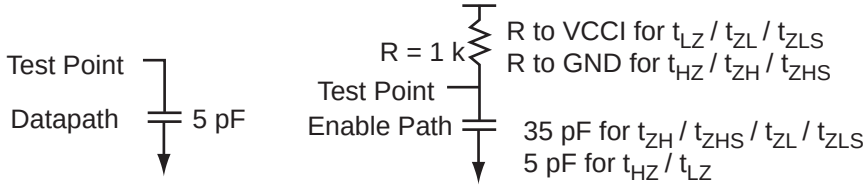



**Figure 2-8 • AC Loading**

**Table 2-82 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 2.5 | 1.2 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### *Applies to 1.5 V DC Core Voltage*

**Table 2-83 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 4.96 | 0.18 | 1.08 | 0.66 | 5.06 | 4.59 | 2.26 | 2.00 | 8.66 | 8.19 | ns |
| 6 mA | Std. | 0.97 | 4.15 | 0.18 | 1.08 | 0.66 | 4.24 | 3.94 | 2.54 | 2.51 | 7.83 | 7.53 | ns |
| 8 mA | Std. | 0.97 | 4.15 | 0.18 | 1.08 | 0.66 | 4.24 | 3.94 | 2.54 | 2.51 | 7.83 | 7.53 | ns |
| 12 mA | Std. | 0.97 | 3.57 | 0.18 | 1.08 | 0.66 | 3.65 | 3.47 | 2.73 | 2.84 | 7.24 | 7.06 | ns |
| 16 mA | Std. | 0.97 | 3.39 | 0.18 | 1.08 | 0.66 | 3.46 | 3.36 | 2.78 | 2.92 | 7.06 | 6.95 | ns |
| 24 mA | Std. | 0.97 | 3.38 | 0.18 | 1.08 | 0.66 | 3.38 | 3.38 | 2.83 | 3.25 | 6.98 | 6.98 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-84 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 2.77 | 0.18 | 1.08 | 0.66 | 2.83 | 2.60 | 2.26 | 2.08 | 6.42 | 6.19 | ns |
| 6 mA | Std. | 0.97 | 2.34 | 0.18 | 1.08 | 0.66 | 2.39 | 2.08 | 2.54 | 2.60 | 5.99 | 5.68 | ns |
| 8 mA | Std. | 0.97 | 2.34 | 0.18 | 1.08 | 0.66 | 2.39 | 2.08 | 2.54 | 2.60 | 5.99 | 5.68 | ns |
| 12 mA | Std. | 0.97 | 2.09 | 0.18 | 1.08 | 0.66 | 2.14 | 1.83 | 2.73 | 2.93 | 5.73 | 5.43 | ns |
| 16 mA | Std. | 0.97 | 2.05 | 0.18 | 1.08 | 0.66 | 2.09 | 1.78 | 2.78 | 3.02 | 5.69 | 5.38 | ns |
| 24 mA | Std. | 0.97 | 2.06 | 0.18 | 1.08 | 0.66 | 2.10 | 1.72 | 2.83 | 3.35 | 5.70 | 5.32 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-85 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 4.42 | 0.18 | 1.08 | 0.66 | 4.51 | 4.10 | 1.96 | 1.85 | 8.10 | 7.69 | ns |
| 6 mA | Std. | 0.97 | 3.62 | 0.18 | 1.08 | 0.66 | 3.70 | 3.52 | 2.21 | 2.32 | 7.29 | 7.11 | ns |
| 8 mA | Std. | 0.97 | 3.62 | 0.18 | 1.08 | 0.66 | 3.70 | 3.52 | 2.21 | 2.32 | 7.29 | 7.11 | ns |
| 12 mA | Std. | 0.97 | 3.09 | 0.18 | 1.08 | 0.66 | 3.15 | 3.09 | 2.39 | 2.61 | 6.74 | 6.68 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-86 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 0.97 | 2.36 | 0.18 | 1.08 | 0.66 | 2.41 | 2.21 | 1.96 | 1.92 | 6.01 | 5.81 | ns |
| 6 mA | Std. | 0.97 | 1.97 | 0.18 | 1.08 | 0.66 | 2.01 | 1.75 | 2.21 | 2.40 | 5.61 | 5.34 | ns |
| 8 mA | Std. | 0.97 | 1.97 | 0.18 | 1.08 | 0.66 | 2.01 | 1.75 | 2.21 | 2.40 | 5.61 | 5.34 | ns |
| 12 mA | Std. | 0.97 | 1.75 | 0.18 | 1.08 | 0.66 | 1.79 | 1.52 | 2.38 | 2.70 | 5.39 | 5.11 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-87 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 4.27 | 0.18 | 1.04 | 0.66 | 4.36 | 4.06 | 1.71 | 1.62 | ns |
| 4 mA | Std. | 0.97 | 4.27 | 0.18 | 1.04 | 0.66 | 4.36 | 4.06 | 1.71 | 1.62 | ns |
| 6 mA | Std. | 0.97 | 3.54 | 0.18 | 1.04 | 0.66 | 3.61 | 3.48 | 1.95 | 2.08 | ns |
| 8 mA | Std. | 0.97 | 3.54 | 0.18 | 1.04 | 0.66 | 3.61 | 3.48 | 1.95 | 2.08 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-88 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.24 | 0.18 | 1.04 | 0.66 | 2.29 | 2.09 | 1.71 | 1.68 | ns |
| 4 mA | Std. | 0.97 | 2.24 | 0.18 | 1.04 | 0.66 | 2.29 | 2.09 | 1.71 | 1.68 | ns |
| 6 mA | Std. | 0.97 | 1.88 | 0.18 | 1.04 | 0.66 | 1.92 | 1.63 | 1.95 | 2.15 | ns |
| 8 mA | Std. | 0.97 | 1.88 | 0.18 | 1.04 | 0.66 | 1.92 | 1.63 | 1.95 | 2.15 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### *Applies to 1.2 V Core Voltage*

**Table 2-89 • 2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 5.59 | 0.26 | 1.20 | 1.10 | 5.68 | 5.14 | 2.82 | 2.80 | 11.47 | 10.93 | ns |
| 6 mA | Std. | 1.55 | 4.76 | 0.26 | 1.20 | 1.10 | 4.84 | 4.47 | 3.10 | 3.33 | 10.62 | 10.26 | ns |
| 8 mA | Std. | 1.55 | 4.76 | 0.26 | 1.20 | 1.10 | 4.84 | 4.47 | 3.10 | 3.33 | 10.62 | 10.26 | ns |
| 12 mA | Std. | 1.55 | 4.17 | 0.26 | 1.20 | 1.10 | 4.23 | 3.99 | 3.30 | 3.67 | 10.02 | 9.77 | ns |
| 16 mA | Std. | 1.55 | 3.98 | 0.26 | 1.20 | 1.10 | 4.04 | 3.88 | 3.34 | 3.76 | 9.83 | 9.66 | ns |
| 24 mA | Std. | 1.55 | 3.90 | 0.26 | 1.20 | 1.10 | 3.96 | 3.90 | 3.40 | 4.09 | 9.75 | 9.68 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-90 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 3.33 | 0.26 | 1.20 | 1.10 | 3.38 | 3.09 | 2.82 | 2.91 | 9.17 | 8.88 | ns |
| 6 mA | Std. | 1.55 | 2.89 | 0.26 | 1.20 | 1.10 | 2.93 | 2.56 | 3.10 | 3.45 | 8.72 | 8.34 | ns |
| 8 mA | Std. | 1.55 | 2.89 | 0.26 | 1.20 | 1.10 | 2.93 | 2.56 | 3.10 | 3.45 | 8.72 | 8.34 | ns |
| 12 mA | Std. | 1.55 | 2.64 | 0.26 | 1.20 | 1.10 | 2.67 | 2.29 | 3.30 | 3.79 | 8.46 | 8.08 | ns |
| 16 mA | Std. | 1.55 | 2.59 | 0.26 | 1.20 | 1.10 | 2.63 | 2.24 | 3.34 | 3.88 | 8.41 | 8.03 | ns |
| 24 mA | Std. | 1.55 | 2.60 | 0.26 | 1.20 | 1.10 | 2.64 | 2.18 | 3.40 | 4.22 | 8.42 | 7.97 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-91 • 2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 5.02 | 0.26 | 1.19 | 1.10 | 5.11 | 4.60 | 2.50 | 2.62 | 10.89 | 10.38 | ns |
| 6 mA | Std. | 1.55 | 4.21 | 0.26 | 1.19 | 1.10 | 4.27 | 4.00 | 2.76 | 3.10 | 10.06 | 9.79 | ns |
| 8 mA | Std. | 1.55 | 4.21 | 0.26 | 1.19 | 1.10 | 4.27 | 4.00 | 2.76 | 3.10 | 10.06 | 9.79 | ns |
| 12 mA | Std. | 1.55 | 3.66 | 0.26 | 1.19 | 1.10 | 3.71 | 3.55 | 2.94 | 3.41 | 9.50 | 9.34 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-92 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 4 mA | Std. | 1.55 | 2.91 | 0.26 | 1.19 | 1.10 | 2.95 | 2.66 | 2.50 | 2.72 | 8.74 | 8.45 | ns |
| 6 mA | Std. | 1.55 | 2.51 | 0.26 | 1.19 | 1.10 | 2.54 | 2.18 | 2.75 | 3.21 | 8.33 | 7.97 | ns |
| 8 mA | Std. | 1.55 | 2.51 | 0.26 | 1.19 | 1.10 | 2.54 | 2.18 | 2.75 | 3.21 | 8.33 | 7.97 | ns |
| 12 mA | Std. | 1.55 | 2.29 | 0.26 | 1.19 | 1.10 | 2.32 | 1.94 | 2.94 | 3.52 | 8.10 | 7.73 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-93 • 2.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 4.85 | 0.26 | 1.15 | 1.10 | 4.93 | 4.55 | 2.13 | 2.24 | ns |
| 4 mA | Std. | 1.55 | 4.85 | 0.26 | 1.15 | 1.10 | 4.93 | 4.55 | 2.13 | 2.24 | ns |
| 6 mA | Std. | 1.55 | 4.09 | 0.26 | 1.15 | 1.10 | 4.16 | 3.95 | 2.38 | 2.71 | ns |
| 8 mA | Std. | 1.55 | 4.09 | 0.26 | 1.15 | 1.10 | 4.16 | 3.95 | 2.38 | 2.71 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-94 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 2.76 | 0.26 | 1.15 | 1.10 | 2.80 | 2.52 | 2.13 | 2.32 | ns |
| 4 mA | Std. | 1.55 | 2.76 | 0.26 | 1.15 | 1.10 | 2.80 | 2.52 | 2.13 | 2.32 | ns |
| 6 mA | Std. | 1.55 | 2.39 | 0.26 | 1.15 | 1.10 | 2.42 | 2.05 | 2.38 | 2.80 | ns |
| 8 mA | Std. | 1.55 | 2.39 | 0.26 | 1.15 | 1.10 | 2.42 | 2.05 | 2.38 | 2.80 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 1.8 V LVCMOS

Low-voltage CMOS for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 1.8 V input buffer and a push-pull output buffer.

**Table 2-95 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

| 1.8 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 2 | 2 | 9 | 11 | 10 | 10 |
| 4 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 4 | 4 | 17 | 22 | 10 | 10 |
| 6 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 6 | 6 | 35 | 44 | 10 | 10 |
| 8 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 8 | 8 | 45 | 51 | 10 | 10 |
| 12 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 12 | 12 | 91 | 74 | 10 | 10 |
| 16 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 16 | 16 | 91 | 74 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-96 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

| 1.8 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 2 | 2 | 9 | 11 | 10 | 10 |
| 4 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 4 | 4 | 17 | 22 | 10 | 10 |
| 6 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 6 | 6 | 35 | 44 | 10 | 10 |
| 8 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.9 | 0.45 | VCCI – 0.45 | 8 | 8 | 35 | 44 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-97 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

| 1.8 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.45 | VCCI – 0.45 | 2 | 2 | 9 | 11 | 10 | 10 |
| 4 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.45 | VCCI – 0.45 | 4 | 4 | 17 | 22 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

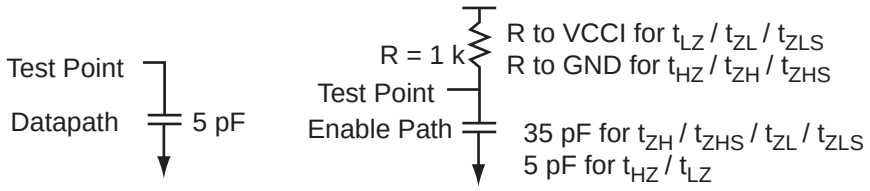



**Figure 2-9 • AC Loading**

**Table 2-98 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 1.8 | 0.9 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

### Timing Characteristics

#### 1.5 V DC Core Voltage

**Table 2-99 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 6.38 | 0.18 | 1.01 | 0.66 | 6.51 | 5.93 | 2.33 | 1.56 | 10.10 | 9.53 | ns |
| 4 mA | Std. | 0.97 | 5.35 | 0.18 | 1.01 | 0.66 | 5.46 | 5.04 | 2.67 | 2.38 | 9.05 | 8.64 | ns |
| 6 mA | Std. | 0.97 | 4.62 | 0.18 | 1.01 | 0.66 | 4.71 | 4.44 | 2.90 | 2.79 | 8.31 | 8.04 | ns |
| 8 mA | Std. | 0.97 | 4.37 | 0.18 | 1.01 | 0.66 | 4.46 | 4.31 | 2.95 | 2.89 | 8.05 | 7.90 | ns |
| 12 mA | Std. | 0.97 | 4.32 | 0.18 | 1.01 | 0.66 | 4.37 | 4.32 | 3.03 | 3.30 | 7.97 | 7.92 | ns |
| 16 mA | Std. | 0.97 | 4.32 | 0.18 | 1.01 | 0.66 | 4.37 | 4.32 | 3.03 | 3.30 | 7.97 | 7.92 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-100 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 3.25 | 0.18 | 1.01 | 0.66 | 3.21 | 3.25 | 2.33 | 1.61 | 6.80 | 6.85 | ns |
| 4 mA | Std. | 0.97 | 2.62 | 0.18 | 1.01 | 0.66 | 2.68 | 2.51 | 2.66 | 2.46 | 6.27 | 6.11 | ns |
| 6 mA | Std. | 0.97 | 2.31 | 0.18 | 1.01 | 0.66 | 2.36 | 2.15 | 2.90 | 2.87 | 5.95 | 5.75 | ns |
| 8 mA | Std. | 0.97 | 2.25 | 0.18 | 1.01 | 0.66 | 2.30 | 2.08 | 2.95 | 2.98 | 5.89 | 5.68 | ns |
| 12 mA | Std. | 0.97 | 2.24 | 0.18 | 1.01 | 0.66 | 2.29 | 2.00 | 3.02 | 3.40 | 5.88 | 5.60 | ns |
| 16 mA | Std. | 0.97 | 2.24 | 0.18 | 1.01 | 0.66 | 2.29 | 2.00 | 3.02 | 3.40 | 5.88 | 5.60 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-101 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 5.78 | 0.18 | 1.01 | 0.66 | 5.90 | 5.32 | 1.95 | 1.47 | 9.49 | 8.91 | ns |
| 4 mA | Std. | 0.97 | 4.75 | 0.18 | 1.01 | 0.66 | 4.85 | 4.54 | 2.25 | 2.21 | 8.44 | 8.13 | ns |
| 6 mA | Std. | 0.97 | 4.07 | 0.18 | 1.01 | 0.66 | 4.15 | 3.98 | 2.46 | 2.58 | 7.75 | 7.57 | ns |
| 8 mA | Std. | 0.97 | 4.07 | 0.18 | 1.01 | 0.66 | 4.15 | 3.98 | 2.46 | 2.58 | 7.75 | 7.57 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-102 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.76 | 0.18 | 1.01 | 0.66 | 2.79 | 2.76 | 1.94 | 1.51 | 6.39 | 6.35 | ns |
| 4 mA | Std. | 0.97 | 2.25 | 0.18 | 1.01 | 0.66 | 2.30 | 2.09 | 2.24 | 2.29 | 5.89 | 5.69 | ns |
| 6 mA | Std. | 0.97 | 1.97 | 0.18 | 1.01 | 0.66 | 2.02 | 1.76 | 2.46 | 2.66 | 5.61 | 5.36 | ns |
| 8 mA | Std. | 0.97 | 1.97 | 0.18 | 1.01 | 0.66 | 2.02 | 1.76 | 2.46 | 2.66 | 5.61 | 5.36 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-103 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 5.63 | 0.18 | 0.98 | 0.66 | 5.74 | 5.30 | 1.68 | 1.24 | ns |
| 4 mA | Std. | 0.97 | 4.69 | 0.18 | 0.98 | 0.66 | 4.79 | 4.52 | 1.97 | 1.98 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-104 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 2.62 | 0.18 | 0.98 | 0.66 | 2.67 | 2.59 | 1.67 | 1.29 | 2.62 | ns |
| 4 mA | Std. | 2.18 | 0.18 | 0.98 | 0.66 | 2.22 | 1.93 | 1.97 | 2.06 | 2.18 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-105 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 6.97 | 0.26 | 1.11 | 1.10 | 7.08 | 6.48 | 2.87 | 2.29 | 12.87 | 12.27 | ns |
| 4 mA | Std. | 1.55 | 5.91 | 0.26 | 1.11 | 1.10 | 6.01 | 5.57 | 3.21 | 3.14 | 11.79 | 11.36 | ns |
| 6 mA | Std. | 1.55 | 5.16 | 0.26 | 1.11 | 1.10 | 5.24 | 4.95 | 3.45 | 3.55 | 11.03 | 10.74 | ns |
| 8 mA | Std. | 1.55 | 4.90 | 0.26 | 1.11 | 1.10 | 4.98 | 4.81 | 3.50 | 3.66 | 10.77 | 10.60 | ns |
| 12 mA | Std. | 1.55 | 4.83 | 0.26 | 1.11 | 1.10 | 4.90 | 4.83 | 3.58 | 4.08 | 10.68 | 10.61 | ns |
| 16 mA | Std. | 1.55 | 4.83 | 0.26 | 1.11 | 1.10 | 4.90 | 4.83 | 3.58 | 4.08 | 10.68 | 10.61 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-106 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.73 | 0.26 | 1.11 | 1.10 | 3.71 | 3.73 | 2.86 | 2.34 | 9.49 | 9.51 | ns |
| 4 mA | Std. | 1.55 | 3.12 | 0.26 | 1.11 | 1.10 | 3.16 | 2.97 | 3.21 | 3.22 | 8.95 | 8.75 | ns |
| 6 mA | Std. | 1.55 | 2.79 | 0.26 | 1.11 | 1.10 | 2.83 | 2.59 | 3.45 | 3.65 | 8.62 | 8.38 | ns |
| 8 mA | Std. | 1.55 | 2.73 | 0.26 | 1.11 | 1.10 | 2.77 | 2.52 | 3.50 | 3.75 | 8.56 | 8.30 | ns |
| 12 mA | Std. | 1.55 | 2.72 | 0.26 | 1.11 | 1.10 | 2.76 | 2.43 | 3.58 | 4.19 | 8.55 | 8.22 | ns |
| 16 mA | Std. | 1.55 | 2.72 | 0.26 | 1.11 | 1.10 | 2.76 | 2.43 | 3.58 | 4.19 | 8.55 | 8.22 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-107 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 6.32 | 0.26 | 1.11 | 1.10 | 6.43 | 5.81 | 2.47 | 2.16 | 12.22 | 11.60 | ns |
| 4 mA | Std. | 1.55 | 5.27 | 0.26 | 1.11 | 1.10 | 5.35 | 5.01 | 2.78 | 2.92 | 11.14 | 10.79 | ns |
| 6 mA | Std. | 1.55 | 4.56 | 0.26 | 1.11 | 1.10 | 4.64 | 4.44 | 3.00 | 3.30 | 10.42 | 10.22 | ns |
| 8 mA | Std. | 1.55 | 4.56 | 0.26 | 1.11 | 1.10 | 4.64 | 4.44 | 3.00 | 3.30 | 10.42 | 10.22 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-108 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.22 | 0.26 | 1.11 | 1.10 | 3.26 | 3.18 | 2.47 | 2.20 | 9.05 | 8.97 | ns |
| 4 mA | Std. | 1.55 | 2.72 | 0.26 | 1.11 | 1.10 | 2.75 | 2.50 | 2.78 | 3.01 | 8.54 | 8.29 | ns |
| 6 mA | Std. | 1.55 | 2.43 | 0.26 | 1.11 | 1.10 | 2.47 | 2.16 | 2.99 | 3.39 | 8.25 | 7.94 | ns |
| 8 mA | Std. | 1.55 | 2.43 | 0.26 | 1.11 | 1.10 | 2.47 | 2.16 | 2.99 | 3.39 | 8.25 | 7.94 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-109 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 6.13 | 0.26 | 1.08 | 1.10 | 6.24 | 5.79 | 2.08 | 1.78 | ns |
| 4 mA | Std. | 1.55 | 5.17 | 0.26 | 1.08 | 1.10 | 5.26 | 4.98 | 2.38 | 2.54 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-110 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 3.06 | 0.26 | 1.08 | 1.10 | 3.10 | 3.01 | 2.08 | 1.83 | 3.06 | ns |
| 4 mA | Std. | 2.60 | 0.26 | 1.08 | 1.10 | 2.64 | 2.33 | 2.38 | 2.62 | 2.60 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 1.5 V LVCMOS (JESD8-11)

Low-Voltage CMOS for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 1.5 V input buffer and a push-pull output buffer.

**Table 2-111 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

| 1.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 | 13 | 16 | 10 | 10 |
| 4 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 4 | 4 | 25 | 33 | 10 | 10 |
| 6 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 6 | 6 | 32 | 39 | 10 | 10 |
| 8 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 8 | 8 | 66 | 55 | 10 | 10 |
| 12 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 12 | 12 | 66 | 55 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-112 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

| 1.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 | 13 | 16 | 10 | 10 |
| 4 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.575 | 0.25 * VCCI | 0.75 * VCCI | 4 | 4 | 25 | 33 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-113 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

| 1.5 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 | 13 | 16 | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN <V CCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

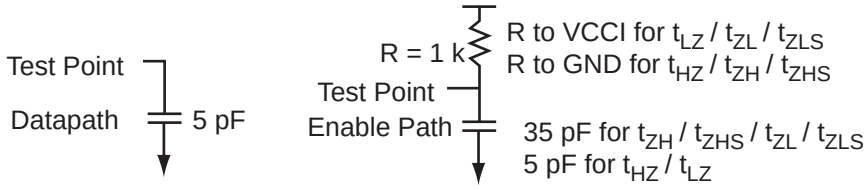



**Figure 2-10 • AC Loading**

**Table 2-114 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 1.5 | 0.75 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-115 • 1.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 6.62 | 0.18 | 1.17 | 0.66 | 6.75 | 6.06 | 2.79 | 2.31 | 10.35 | 9.66 | ns |
| 4 mA | Std. | 0.97 | 5.75 | 0.18 | 1.17 | 0.66 | 5.86 | 5.34 | 3.06 | 2.78 | 9.46 | 8.93 | ns |
| 6 mA | Std. | 0.97 | 5.43 | 0.18 | 1.17 | 0.66 | 5.54 | 5.19 | 3.12 | 2.90 | 9.13 | 8.78 | ns |
| 8 mA | Std. | 0.97 | 5.35 | 0.18 | 1.17 | 0.66 | 5.46 | 5.20 | 2.63 | 3.36 | 9.06 | 8.79 | ns |
| 12 mA | Std. | 0.97 | 5.35 | 0.18 | 1.17 | 0.66 | 5.46 | 5.20 | 2.63 | 3.36 | 9.06 | 8.79 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-116 • 1.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.97 | 0.18 | 1.17 | 0.66 | 3.04 | 2.90 | 2.78 | 2.40 | 6.63 | 6.50 | ns |
| 4 mA | Std. | 0.97 | 2.60 | 0.18 | 1.17 | 0.66 | 2.65 | 2.45 | 3.05 | 2.88 | 6.25 | 6.05 | ns |
| 6 mA | Std. | 0.97 | 2.53 | 0.18 | 1.17 | 0.66 | 2.58 | 2.37 | 3.11 | 3.00 | 6.18 | 5.96 | ns |
| 8 mA | Std. | 0.97 | 2.50 | 0.18 | 1.17 | 0.66 | 2.56 | 2.27 | 3.21 | 3.48 | 6.15 | 5.86 | ns |
| 12 mA | Std. | 0.97 | 2.50 | 0.18 | 1.17 | 0.66 | 2.56 | 2.27 | 3.21 | 3.48 | 6.15 | 5.86 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-117 • 1.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 5.93 | 0.18 | 1.18 | 0.66 | 6.04 | 5.46 | 2.30 | 2.15 | 9.64 | 9.06 | ns |
| 4 mA | Std. | 0.97 | 5.11 | 0.18 | 1.18 | 0.66 | 5.21 | 4.80 | 2.54 | 2.58 | 8.80 | 8.39 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-118 • 1.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.58 | 0.18 | 1.18 | 0.66 | 2.64 | 2.41 | 2.29 | 2.24 | 6.23 | 6.01 | ns |
| 4 mA | Std. | 0.97 | 2.25 | 0.18 | 1.18 | 0.66 | 2.30 | 2.00 | 2.53 | 2.68 | 5.89 | 5.59 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-119 • 1.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 5.88 | 0.18 | 1.14 | 0.66 | 6.00 | 5.45 | 2.00 | 1.94 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-120 • 1.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 0.97 | 2.51 | 0.18 | 1.14 | 0.66 | 2.56 | 2.21 | 1.99 | 2.03 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-121 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 7.17 | 0.26 | 1.27 | 1.10 | 7.29 | 6.60 | 3.33 | 3.03 | 13.07 | 12.39 | ns |
| 4 mA | Std. | 1.55 | 6.27 | 0.26 | 1.27 | 1.10 | 6.37 | 5.86 | 3.61 | 3.51 | 12.16 | 11.64 | ns |
| 6 mA | Std. | 1.55 | 5.94 | 0.26 | 1.27 | 1.10 | 6.04 | 5.70 | 3.67 | 3.64 | 11.82 | 11.48 | ns |
| 8 mA | Std. | 1.55 | 5.86 | 0.26 | 1.27 | 1.10 | 5.96 | 5.71 | 2.83 | 4.11 | 11.74 | 11.50 | ns |
| 12 mA | Std. | 1.55 | 5.86 | 0.26 | 1.27 | 1.10 | 5.96 | 5.71 | 2.83 | 4.11 | 11.74 | 11.50 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-122 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.44 | 0.26 | 1.27 | 1.10 | 3.49 | 3.35 | 3.32 | 3.12 | 9.28 | 9.14 | ns |
| 4 mA | Std. | 1.55 | 3.06 | 0.26 | 1.27 | 1.10 | 3.10 | 2.89 | 3.60 | 3.61 | 8.89 | 8.67 | ns |
| 6 mA | Std. | 1.55 | 2.98 | 0.26 | 1.27 | 1.10 | 3.02 | 2.80 | 3.66 | 3.74 | 8.81 | 8.58 | ns |
| 8 mA | Std. | 1.55 | 2.96 | 0.26 | 1.27 | 1.10 | 3.00 | 2.70 | 3.75 | 4.23 | 8.78 | 8.48 | ns |
| 12 mA | Std. | 1.55 | 2.96 | 0.26 | 1.27 | 1.10 | 3.00 | 2.70 | 3.75 | 4.23 | 8.78 | 8.48 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-123 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 6.43 | 0.26 | 1.27 | 1.10 | 6.54 | 5.95 | 2.82 | 2.83 | 12.32 | 11.74 | ns |
| 4 mA | Std. | 1.55 | 5.59 | 0.26 | 1.27 | 1.10 | 5.68 | 5.27 | 3.07 | 3.27 | 11.47 | 11.05 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-124 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Plus Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.02 | 0.26 | 1.27 | 1.10 | 3.07 | 2.81 | 2.82 | 2.92 | 8.85 | 8.59 | ns |
| 4 mA | Std. | 1.55 | 2.68 | 0.26 | 1.27 | 1.10 | 2.72 | 2.39 | 3.07 | 3.37 | 8.50 | 8.18 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-125 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 6.35 | 0.26 | 1.22 | 1.10 | 6.46 | 5.93 | 2.40 | 2.46 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-126 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 2.92 | 0.26 | 1.22 | 1.10 | 2.96 | 2.60 | 2.40 | 2.56 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 1.2 V LVCMOS (JESD8-12A)

Low-Voltage CMOS for 1.2 V complies with the LVCMOS standard JESD8-12A for general purpose 1.2 V applications. It uses a 1.2 V input buffer and a push-pull output buffer. Furthermore, all LVCMOS 1.2 V software macros comply with LVCMOS 1.2 V wide range as specified in the JESD8-12A specification.

**Table 2-127 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

| 1.2 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 | TBD | TBD | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-128 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

| 1.2 V LVCMOS | VIL | | VIH | | VOL | VOH | $I_{OL}$ | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 2 | 2 | TBD | TBD | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

**Table 2-129 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

| 1.2 V LVCMOS | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL[1] | IIH[2] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[3] | Max. mA[3] | µA[4] | µA[4] |
| 1 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.25 * VCCI | 0.75 * VCCI | 1 | 1 | TBD | TBD | 10 | 10 |

*Notes:*

1. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
2. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
3. *Currents are measured at 100°C junction temperature and maximum voltage.*
4. *Currents are measured at 85°C junction temperature.*
5. *Software default selection highlighted in gray.*

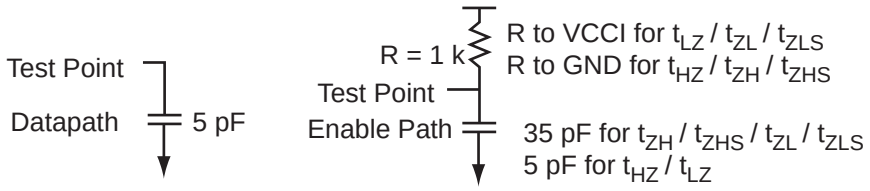



***Figure 2-11 •*** **AC Loading**

***Table 2-130 •*** **AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 1.2 | 0.6 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### 1.2 V DC Core Voltage

**Table 2-131 • 1.2 V LVCMOS Low Slew**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 8.37 | 0.26 | 1.60 | 1.10 | 8.04 | 7.17 | 3.94 | 3.52 | 13.82 | 12.95 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-132 • 1.2 V LVCMOS High Slew**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V**
**Applicable to Advanced I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.60 | 0.26 | 1.60 | 1.10 | 3.47 | 3.36 | 3.93 | 3.65 | 9.26 | 9.14 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-133 • 1.2 V LVCMOS High Slew**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V**
**Applicable to Standard Plus I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 7.59 | 0.26 | 1.59 | 1.10 | 7.29 | 6.54 | 3.30 | 3.35 | 13.08 | 12.33 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-134 • 1.2 V LVCMOS High Slew**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V**
**Applicable to Standard Plus I/O Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2 mA | Std. | 1.55 | 3.22 | 0.26 | 1.59 | 1.10 | 3.11 | 2.78 | 3.29 | 3.48 | 8.90 | 8.57 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-135 • 1.2 V LVCMOS High Slew**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 mA | Std. | 1.55 | 8.57 | 0.26 | 1.53 | 1.10 | 8.23 | 7.38 | 2.51 | 2.39 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-136 • 1.2 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V**
**Applicable to Standard Banks**

| Drive Strength | Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 1 mA | Std. | 1.55 | 3.59 | 0.26 | 1.53 | 1.10 | 3.47 | 3.06 | 2.51 | 2.49 | ns |

*Notes:*

1. *Software default selection highlighted in gray.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 1.2 V LVCMOS Wide Range

**Table 2-137 • Minimum and Maximum DC Input and Output Levels for LVCMOS 1.2 V Wide Range Applicable to Advanced I/O Banks**

| 1.2 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 2 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for the default LVCMOS 1.2 V software configuration when run in wide range is ± 100 µA. The drive strength displayed in software is supported in normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-138 • Minimum and Maximum DC Input and Output Levels for LVCMOS 1.2 V Wide Range Applicable to Standard Plus I/O Banks**

| 1.2 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 2mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 1.26 | 0.25 * VCCI | 0.75 * VCCI | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for the default LVCMOS 1.2 V software configuration when run in wide range is ± 100 µA. The drive strength displayed in software is supported in normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-139 • Minimum and Maximum DC Input and Output Levels for LVCMOS 1.2 V Wide Range Applicable to Standard I/O Banks**

| 1.2 V LVCMOS Wide Range | | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSL | IOSH | IIL[2] | IIH[3] |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Equivalent Software Default Drive Strength Option[1] | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[4] | Max. mA[4] | µA[5] | µA[5] |
| 100 µA | 1 mA | –0.3 | 0.35 * VCCI | 0.65 * VCCI | 3.6 | 0.25 * VCCI | 0.75 * VCCI | 100 | 100 | TBD | TBD | 10 | 10 |

*Notes:*

1. *The minimum drive strength for the default LVCMOS 1.2 V software configuration when run in wide range is ± 100 µA. The drive strength displayed in software is supported in normal range only. For a detailed I/V curve, refer to the IBIS models.*
2. *IIL is the input leakage current per I/O pin over recommended operation conditions where –0.3 V < VIN < VIL.*
3. *IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges*
4. *Currents are measured at 100°C junction temperature and maximum voltage.*
5. *Currents are measured at 85°C junction temperature.*
6. *Software default selection highlighted in gray.*

**Table 2-140 • 1.2 V LVCMOS Wide Range AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 1.2 | 0.6 | 5 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

### Timing Characteristics

Refer to LVCMOS 1.2 V (normal range) "Timing Characteristics" on page 2-76 for worst-case timing.

### 3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for 33 MHz and 66 MHz PCI Bus applications.

**Table 2-141 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced and Standard Plus I/Os**

| 3.3 V PCI/PCI-X | VIL | | VIH | | VOL | VOH | IOL | IOH | IOSH | IOSL | IIL | IIH |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Drive Strength | Min. V | Max. V | Min. V | Max. V | Max. V | Min. V | mA | mA | Max. mA[1] | Max. mA[1] | µA[2] | µA[2] |
| Per PCI specification | Per PCI curves | | | | | | | | | | 10 | 10 |

*Notes:*

1. *Currents are measured at 100°C junction temperature and maximum voltage.*
2. *Currents are measured at 85°C junction temperature.*

AC loadings are defined per the PCI/PCI-X specifications for the datapath; Microsemi loadings for enable path characterization are described in Figure 2-12.

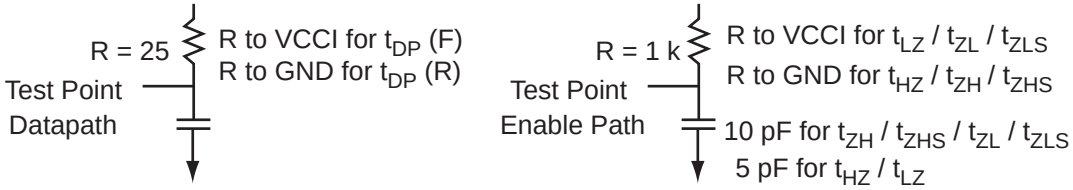



**Figure 2-12 • AC Loading**

AC loadings are defined per PCI/PCI-X specifications for the datapath; Microsemi loading for tristate is described in Table 2-142.

**Table 2-142 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) | $C_{LOAD}$ (pF) |
|---|---|---|---|
| 0 | 3.3 | 0.285 * VCCI for $t_{DP(R)}$<br>0.615 * VCCI for $t_{DP(F)}$ | 10 |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-143 • 3.3 V PCI/PCI-X**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Std. | 0.97 | 2.32 | 0.19 | 0.70 | 0.66 | 2.37 | 1.78 | 2.67 | 3.05 | 5.96 | 5.38 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-144 • 3.3 V PCI/PCI-X**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus I/O Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Std. | 0.97 | 1.97 | 0.19 | 0.70 | 0.66 | 2.01 | 1.50 | 2.36 | 2.79 | 5.61 | 5.10 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-145 • 3.3 V PCI/PCI-X**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Advanced I/O Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Std. | 1.55 | 2.91 | 0.25 | 0.86 | 1.10 | 2.95 | 2.29 | 3.25 | 3.93 | 8.74 | 8.08 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

**Table 2-146 • 3.3 V PCI/PCI-X**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Plus I/O Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | $t_{EOUT}$ | $t_{ZL}$ | $t_{ZH}$ | $t_{LZ}$ | $t_{HZ}$ | $t_{ZLS}$ | $t_{ZHS}$ | Units |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| Std. | 1.55 | 2.53 | 0.25 | 0.85 | 1.10 | 2.57 | 1.98 | 2.93 | 3.64 | 8.35 | 7.76 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## Differential I/O Characteristics

### Physical Implementation

Configuration of the I/O modules as a differential pair is handled by Microsemi Designer software when the user instantiates a differential I/O macro in the design.

Differential I/Os can also be used in conjunction with the embedded Input Register (InReg), Output Register (OutReg), Enable Register (EnReg), and Double Data Rate (DDR). However, there is no support for bidirectional I/Os or tristates with the LVPECL standards.

### LVDS

Low-Voltage Differential Signaling (ANSI/TIA/EIA-644) is a high-speed, differential I/O standard. It requires that one data bit be carried through two signal lines, so two pins are needed. It also requires external resistor termination.

The full implementation of the LVDS transmitter and receiver is shown in an example in Figure 2-13. The building blocks of the LVDS transmitter-receiver are one transmitter macro, one receiver macro, three board resistors at the transmitter end, and one resistor at the receiver end. The values for the three driver resistors are different from those used in the LVPECL implementation because the output standard specifications are different.

Along with LVDS I/O, IGLOO also supports Bus LVDS structure and Multipoint LVDS (M-LVDS) configuration (up to 40 nodes).

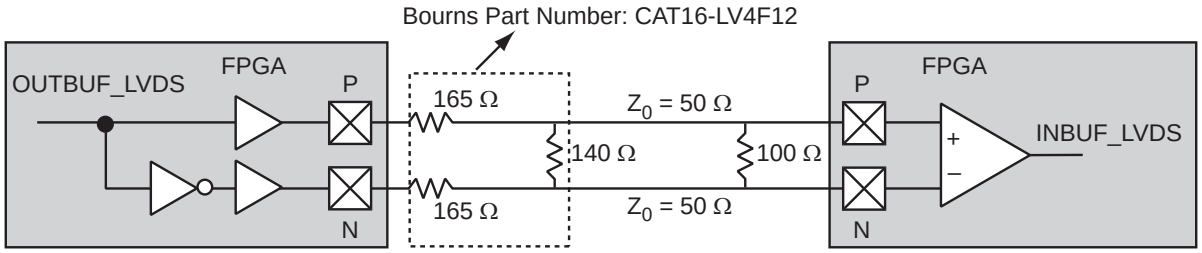



***Figure 2-13 •*** **LVDS Circuit Diagram and Board-Level Implementation**

**Table 2-147 • Minimum and Maximum DC Input and Output Levels**

| DC Parameter | Description | Min. | Typ. | Max. | Units |
|---|---|---|---|---|---|
| VCCI | Supply Voltage | 2.375 | 2.5 | 2.625 | V |
| VOL | Output Low Voltage | 0.9 | 1.075 | 1.25 | V |
| VOH | Output High Voltage | 1.25 | 1.425 | 1.6 | V |
| IOL[1] | Output Lower Current | 0.65 | 0.91 | 1.16 | mA |
| IOH[1] | Output High Current | 0.65 | 0.91 | 1.16 | mA |
| VI | Input Voltage | 0 | | 2.925 | V |
| IIH[2] | Input High Leakage Current | | | 10 | µA |
| IIL[2] | Input Low Leakage Current | | | 10 | µA |
| VODIFF | Differential Output Voltage | 250 | 350 | 450 | mV |
| VOCM | Output Common-Mode Voltage | 1.125 | 1.25 | 1.375 | V |
| VICM | Input Common-Mode Voltage | 0.05 | 1.25 | 2.35 | V |
| VIDIFF[4] | Input Differential Voltage | 100 | 350 | | mV |

*Notes:*

1. *IOL/IOH is defined by VODIFF/(resistor network)*
2. *Currents are measured at 85°C junction temperature.*

**Table 2-148 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) |
|---|---|---|
| 1.075 | 1.325 | Cross point |

* *Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.*

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-149 • LVDS – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | Units |
|---|---|---|---|---|---|
| Std. | 0.97 | 1.67 | 0.19 | 1.31 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 and Table 2-7 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-150 • LVDS – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V**
**Applicable to Standard Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | Units |
|---|---|---|---|---|---|
| Std. | 1.55 | 2.19 | 0.25 | 1.52 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 and Table 2-7 on page 2-7 for derating values.*

### B-LVDS/M-LVDS

Bus LVDS (B-LVDS) and Multipoint LVDS (M-LVDS) specifications extend the existing LVDS standard to high-performance multipoint bus applications. Multidrop and multipoint bus configurations may contain any combination of drivers, receivers, and transceivers. Microsemi LVDS drivers provide the higher drive current required by B-LVDS and M-LVDS to accommodate the loading. The drivers require series terminations for better signal quality and to control voltage swing. Termination is also required at both ends of the bus since the driver can be located anywhere on the bus. These configurations can be implemented using the TRIBUF_LVDS and BIBUF_LVDS macros along with appropriate terminations. Multipoint designs using Microsemi LVDS macros can achieve up to 200 MHz with a maximum of 20 loads. A sample application is given in Figure 2-14. The input and output buffer delays are available in the LVDS section in Table 2-149 on page 2-82 and Table 2-150 on page 2-82.

Example: For a bus consisting of 20 equidistant loads, the following terminations provide the required differential voltage, in worst-case Industrial operating conditions, at the farthest receiver: $R_S$ = 60 Ω and $R_T$ = 70 Ω, given $Z_0$ = 50 Ω (2") and $Z_{stub}$ = 50 Ω (~1.5").

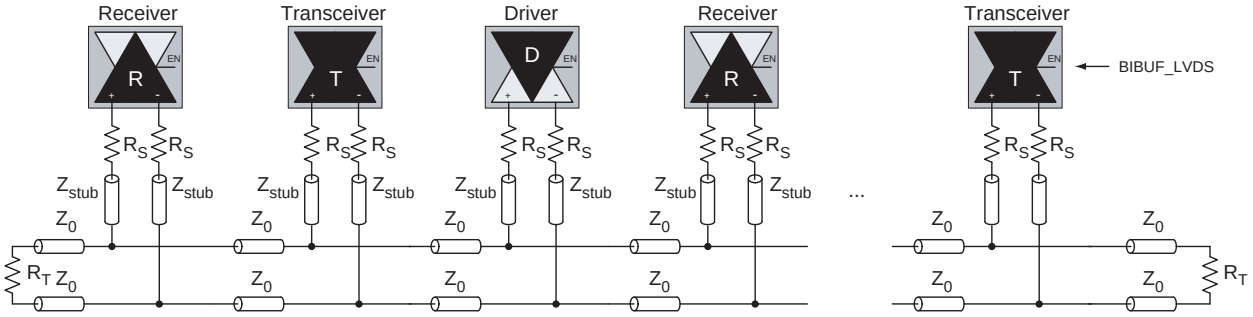



***Figure 2-14 •*** **B-LVDS/M-LVDS Multipoint Application Using LVDS I/O Buffers**

### LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit be carried through two signal lines. Like LVDS, two pins are needed. It also requires external resistor termination.

The full implementation of the LVDS transmitter and receiver is shown in an example in Figure 2-15. The building blocks of the LVPECL transmitter-receiver are one transmitter macro, one receiver macro, three board resistors at the transmitter end, and one resistor at the receiver end. The values for the three driver resistors are different from those used in the LVDS implementation because the output standard specifications are different.

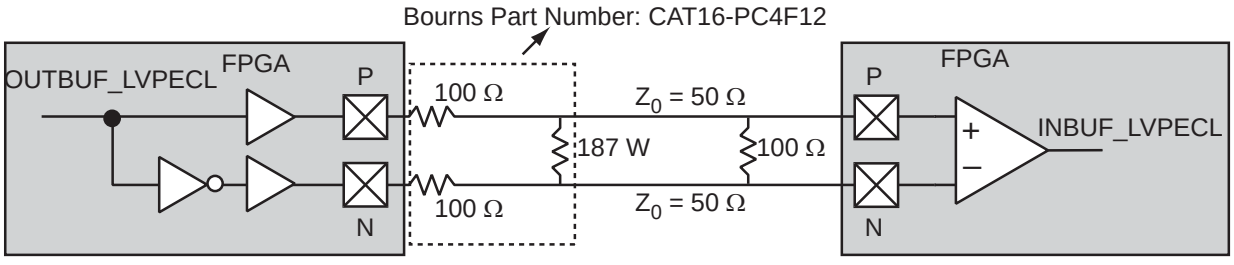



***Figure 2-15 •*** **LVPECL Circuit Diagram and Board-Level Implementation**

***Table 2-151 •*** **Minimum and Maximum DC Input and Output Levels**

| DC Parameter | Description | Min. | Max. | Min. | Max. | Min. | Max. | Units |
|---|---|---|---|---|---|---|---|---|
| VCCI | Supply Voltage | 3.0 | | 3.3 | | 3.6 | | V |
| VOL | Output Low Voltage | 0.96 | 1.27 | 1.06 | 1.43 | 1.30 | 1.57 | V |

**Table 2-151 • Minimum and Maximum DC Input and Output Levels**

| DC Parameter | Description | Min. | Max. | Min. | Max. | Min. | Max. | Units |
|---|---|---|---|---|---|---|---|---|
| VOH | Output High Voltage | 1.8 | 2.11 | 1.92 | 2.28 | 2.13 | 2.41 | V |
| VIL, VIH | Input Low, Input High Voltages | 0 | 3.3 | 0 | 3.6 | 0 | 3.9 | V |
| $V_{ODIFF}$ | Differential Output Voltage | 0.625 | 0.97 | 0.625 | 0.97 | 0.625 | 0.97 | V |
| $V_{OCM}$ | Output Common-Mode Voltage | 1.762 | 1.98 | 1.762 | 1.98 | 1.762 | 1.98 | V |
| $V_{ICM}$ | Input Common-Mode Voltage | 1.01 | 2.57 | 1.01 | 2.57 | 1.01 | 2.57 | V |
| $V_{IDIFF}$ | Input Differential Voltage | 300 | | 300 | | 300 | | mV |

**Table 2-152 • AC Waveforms, Measuring Points, and Capacitive Loads**

| Input Low (V) | Input High (V) | Measuring Point* (V) |
|---|---|---|
| 1.64 | 1.94 | Cross point |

* *Measuring point = Vtrip. See Table 2-28 on page 2-104 for a complete table of trip points.*

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-153 • LVPECL – Applies to 1.5 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | Units |
|---|---|---|---|---|---|
| Std. | 0.97 | 1.67 | 0.19 | 1.16 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-154 • LVPECL – Applies to 1.2 V DC Core Voltage**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V**
**Applicable to Standard Banks**

| Speed Grade | $t_{DOUT}$ | $t_{DP}$ | $t_{DIN}$ | $t_{PY}$ | Units |
|---|---|---|---|---|---|
| Std. | 1.55 | 2.24 | 0.25 | 1.37 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## I/O Register Specifications

### *Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Preset*

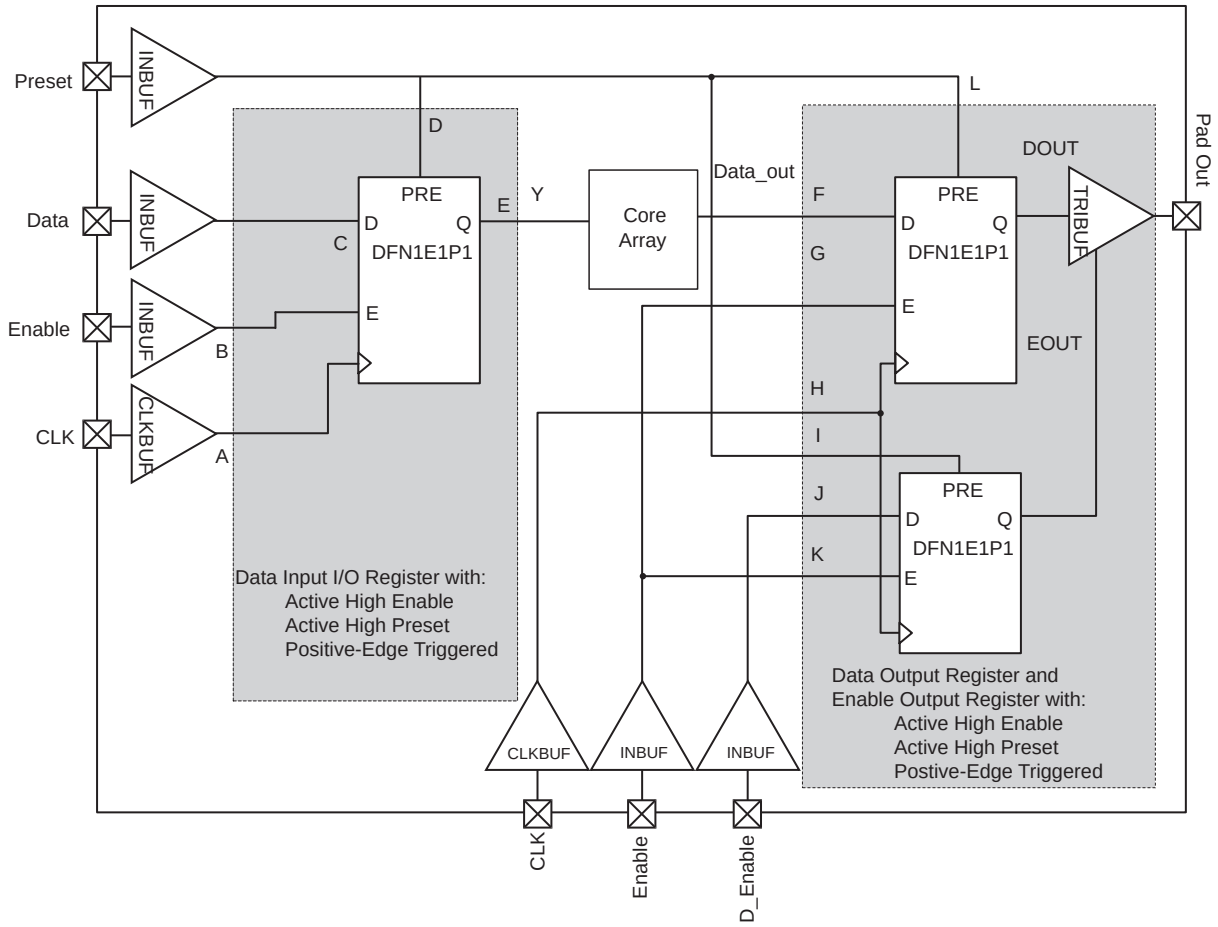



***Figure 2-16 •*** **Timing Model of Registered I/O Buffers with Synchronous Enable and Asynchronous Preset**

***Table 2-155* • Parameter Definition and Measuring Nodes**

| Parameter Name | Parameter Definition | Measuring Nodes (from, to)* |
|---|---|---|
| $t_{OCLKQ}$ | Clock-to-Q of the Output Data Register | H, DOUT |
| $t_{OSUD}$ | Data Setup Time for the Output Data Register | F, H |
| $t_{OHD}$ | Data Hold Time for the Output Data Register | F, H |
| $t_{OSUE}$ | Enable Setup Time for the Output Data Register | G, H |
| $t_{OHE}$ | Enable Hold Time for the Output Data Register | G, H |
| $t_{OPRE2Q}$ | Asynchronous Preset-to-Q of the Output Data Register | L, DOUT |
| $t_{OREMPRE}$ | Asynchronous Preset Removal Time for the Output Data Register | L, H |
| $t_{ORECPRE}$ | Asynchronous Preset Recovery Time for the Output Data Register | L, H |
| $t_{OECLKQ}$ | Clock-to-Q of the Output Enable Register | H, EOUT |
| $t_{OESUD}$ | Data Setup Time for the Output Enable Register | J, H |
| $t_{OEHD}$ | Data Hold Time for the Output Enable Register | J, H |
| $t_{OESUE}$ | Enable Setup Time for the Output Enable Register | K, H |
| $t_{OEHE}$ | Enable Hold Time for the Output Enable Register | K, H |
| $t_{OEPRE2Q}$ | Asynchronous Preset-to-Q of the Output Enable Register | I, EOUT |
| $t_{OEREMPRE}$ | Asynchronous Preset Removal Time for the Output Enable Register | I, H |
| $t_{OERECPRE}$ | Asynchronous Preset Recovery Time for the Output Enable Register | I, H |
| $t_{ICLKQ}$ | Clock-to-Q of the Input Data Register | A, E |
| $t_{ISUD}$ | Data Setup Time for the Input Data Register | C, A |
| $t_{IHD}$ | Data Hold Time for the Input Data Register | C, A |
| $t_{ISUE}$ | Enable Setup Time for the Input Data Register | B, A |
| $t_{IHE}$ | Enable Hold Time for the Input Data Register | B, A |
| $t_{IPRE2Q}$ | Asynchronous Preset-to-Q of the Input Data Register | D, E |
| $t_{IREMPRE}$ | Asynchronous Preset Removal Time for the Input Data Register | D, A |
| $t_{IRECPRE}$ | Asynchronous Preset Recovery Time for the Input Data Register | D, A |

* *See Figure 2-16 on page 2-85 for more information.*

## Fully Registered I/O Buffers with Synchronous Enable and Asynchronous Clear

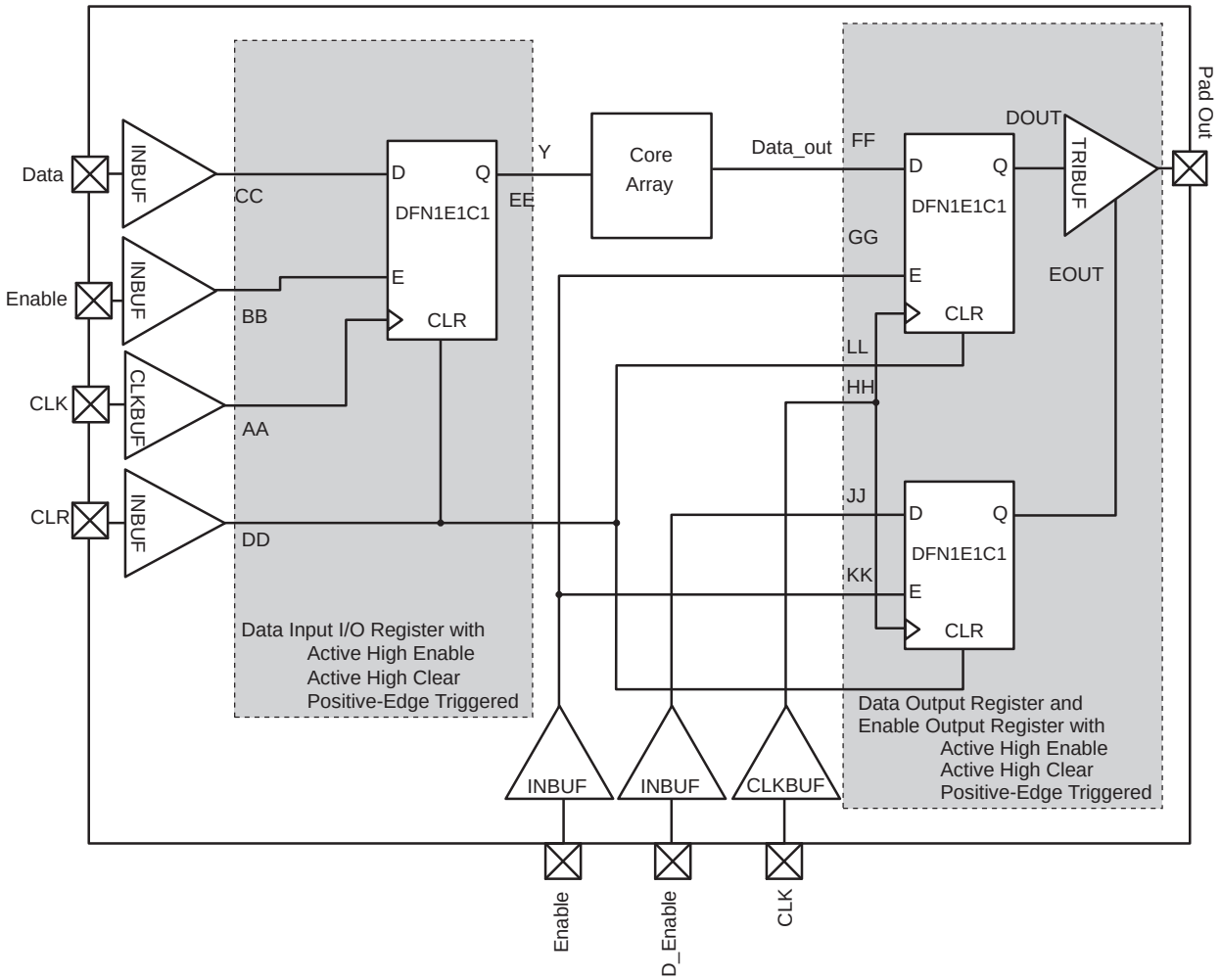



***Figure 2-17 •*** **Timing Model of the Registered I/O Buffers with Synchronous Enable and Asynchronous Clear**

***Table 2-156* • Parameter Definition and Measuring Nodes**

| Parameter Name | Parameter Definition | Measuring Nodes (from, to)* |
|---|---|---|
| $t_{OCLKQ}$ | Clock-to-Q of the Output Data Register | HH, DOUT |
| $t_{OSUD}$ | Data Setup Time for the Output Data Register | FF, HH |
| $t_{OHD}$ | Data Hold Time for the Output Data Register | FF, HH |
| $t_{OSUE}$ | Enable Setup Time for the Output Data Register | GG, HH |
| $t_{OHE}$ | Enable Hold Time for the Output Data Register | GG, HH |
| $t_{OCLR2Q}$ | Asynchronous Clear-to-Q of the Output Data Register | LL, DOUT |
| $t_{OREMCLR}$ | Asynchronous Clear Removal Time for the Output Data Register | LL, HH |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Data Register | LL, HH |
| $t_{OECLKQ}$ | Clock-to-Q of the Output Enable Register | HH, EOUT |
| $t_{OESUD}$ | Data Setup Time for the Output Enable Register | JJ, HH |
| $t_{OEHD}$ | Data Hold Time for the Output Enable Register | JJ, HH |
| $t_{OESUE}$ | Enable Setup Time for the Output Enable Register | KK, HH |
| $t_{OEHE}$ | Enable Hold Time for the Output Enable Register | KK, HH |
| $t_{OECLR2Q}$ | Asynchronous Clear-to-Q of the Output Enable Register | II, EOUT |
| $t_{OEREMCLR}$ | Asynchronous Clear Removal Time for the Output Enable Register | II, HH |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Enable Register | II, HH |
| $t_{ICLKQ}$ | Clock-to-Q of the Input Data Register | AA, EE |
| $t_{ISUD}$ | Data Setup Time for the Input Data Register | CC, AA |
| $t_{IHD}$ | Data Hold Time for the Input Data Register | CC, AA |
| $t_{ISUE}$ | Enable Setup Time for the Input Data Register | BB, AA |
| $t_{IHE}$ | Enable Hold Time for the Input Data Register | BB, AA |
| $t_{ICLR2Q}$ | Asynchronous Clear-to-Q of the Input Data Register | DD, EE |
| $t_{IREMCLR}$ | Asynchronous Clear Removal Time for the Input Data Register | DD, AA |
| $t_{IRECCLR}$ | Asynchronous Clear Recovery Time for the Input Data Register | DD, AA |

* *See Figure 2-17 on page 2-87 for more information.*

## Input Register

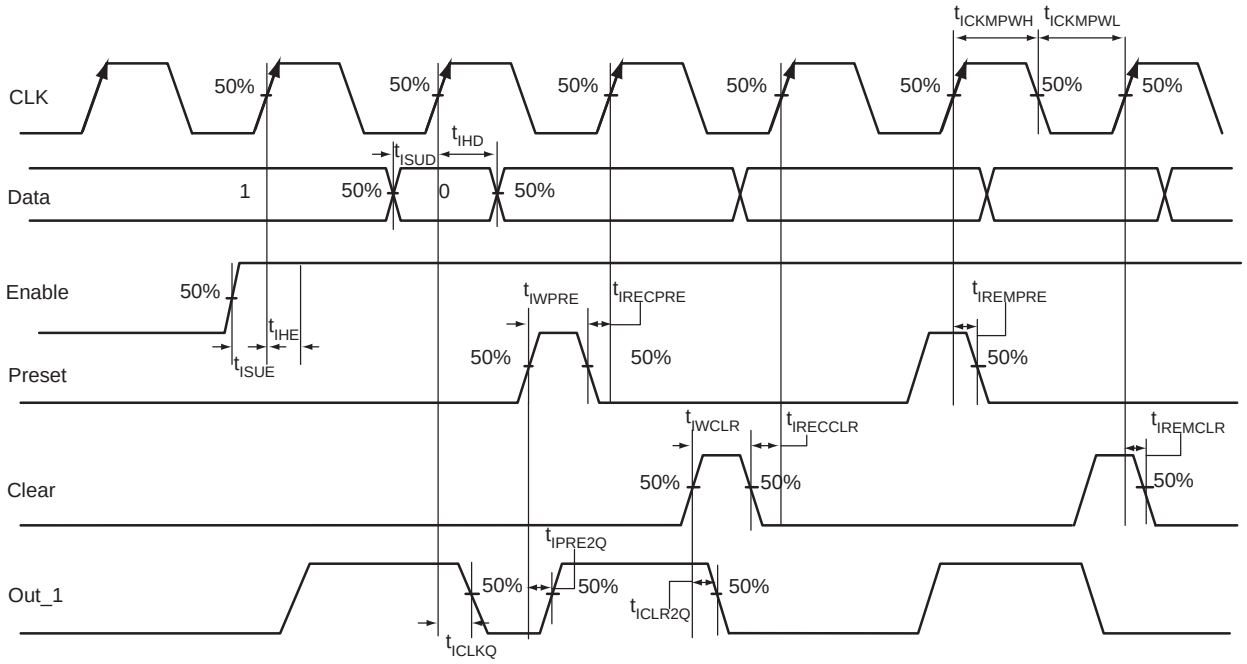



***Figure 2-18 •*** **Input Register Timing Diagram**

### Timing Characteristics

#### 1.5 V DC Core Voltage

***Table 2-157 •*** **Input Data Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{ICLKQ}$ | Clock-to-Q of the Input Data Register | 0.42 | ns |
| $t_{ISUD}$ | Data Setup Time for the Input Data Register | 0.47 | ns |
| $t_{IHD}$ | Data Hold Time for the Input Data Register | 0.00 | ns |
| $t_{ISUE}$ | Enable Setup Time for the Input Data Register | 0.67 | ns |
| $t_{IHE}$ | Enable Hold Time for the Input Data Register | 0.00 | ns |
| $t_{ICLR2Q}$ | Asynchronous Clear-to-Q of the Input Data Register | 0.79 | ns |
| $t_{IPRE2Q}$ | Asynchronous Preset-to-Q of the Input Data Register | 0.79 | ns |
| $t_{IREMCLR}$ | Asynchronous Clear Removal Time for the Input Data Register | 0.00 | ns |
| $t_{IRECCLR}$ | Asynchronous Clear Recovery Time for the Input Data Register | 0.24 | ns |
| $t_{IREMPRE}$ | Asynchronous Preset Removal Time for the Input Data Register | 0.00 | ns |
| $t_{IRECPRE}$ | Asynchronous Preset Recovery Time for the Input Data Register | 0.24 | ns |
| $t_{IWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Input Data Register | 0.19 | ns |
| $t_{IWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Input Data Register | 0.19 | ns |
| $t_{ICKMPWH}$ | Clock Minimum Pulse Width High for the Input Data Register | 0.31 | ns |
| $t_{ICKMPWL}$ | Clock Minimum Pulse Width Low for the Input Data Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-158 • Input Data Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{ICLKQ}$ | Clock-to-Q of the Input Data Register | 0.68 | ns |
| $t_{ISUD}$ | Data Setup Time for the Input Data Register | 0.97 | ns |
| $t_{IHD}$ | Data Hold Time for the Input Data Register | 0.00 | ns |
| $t_{ISUE}$ | Enable Setup Time for the Input Data Register | 1.02 | ns |
| $t_{IHE}$ | Enable Hold Time for the Input Data Register | 0.00 | ns |
| $t_{ICLR2Q}$ | Asynchronous Clear-to-Q of the Input Data Register | 1.19 | ns |
| $t_{IPRE2Q}$ | Asynchronous Preset-to-Q of the Input Data Register | 1.19 | ns |
| $t_{IREMCLR}$ | Asynchronous Clear Removal Time for the Input Data Register | 0.00 | ns |
| $t_{IRECCLR}$ | Asynchronous Clear Recovery Time for the Input Data Register | 0.24 | ns |
| $t_{IREMPRE}$ | Asynchronous Preset Removal Time for the Input Data Register | 0.00 | ns |
| $t_{IRECPRE}$ | Asynchronous Preset Recovery Time for the Input Data Register | 0.24 | ns |
| $t_{IWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Input Data Register | 0.19 | ns |
| $t_{IWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Input Data Register | 0.19 | ns |
| $t_{ICKMPWH}$ | Clock Minimum Pulse Width High for the Input Data Register | 0.31 | ns |
| $t_{ICKMPWL}$ | Clock Minimum Pulse Width Low for the Input Data Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## Output Register

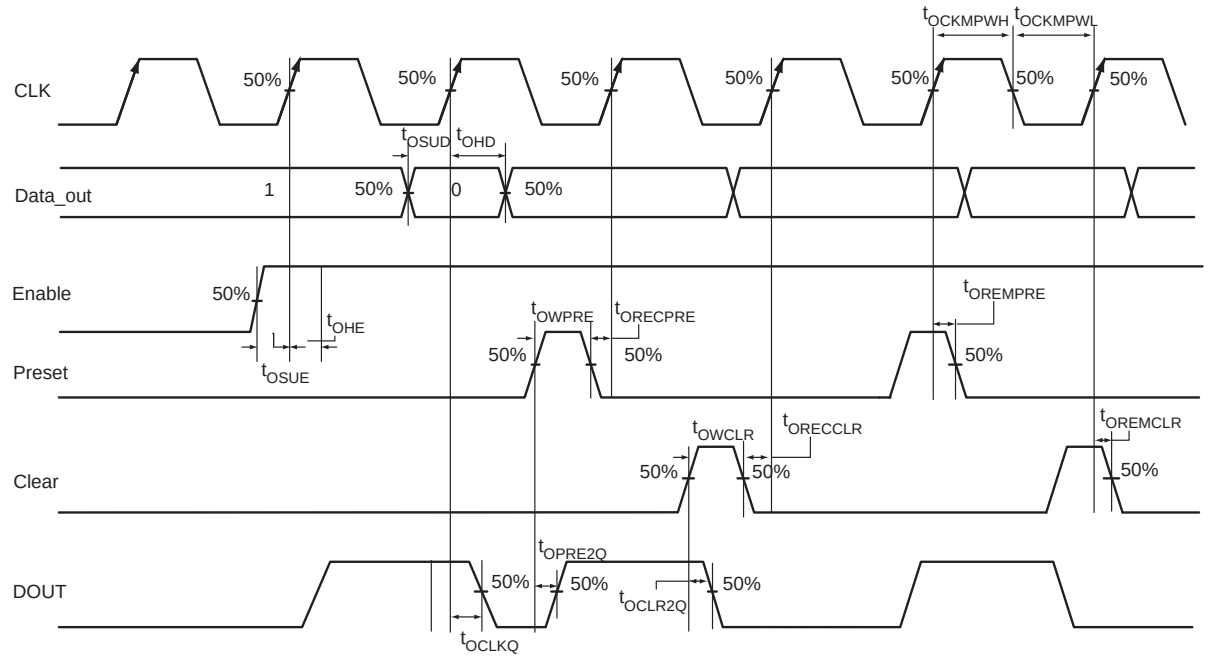



**Figure 2-19 • Output Register Timing Diagram**

### Timing Characteristics

#### 1.5 V DC Core Voltage

**Table 2-159 • Output Data Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{OCLKQ}$ | Clock-to-Q of the Output Data Register | 1.00 | ns |
| $t_{OSUD}$ | Data Setup Time for the Output Data Register | 0.51 | ns |
| $t_{OHD}$ | Data Hold Time for the Output Data Register | 0.00 | ns |
| $t_{OSUE}$ | Enable Setup Time for the Output Data Register | 0.70 | ns |
| $t_{OHE}$ | Enable Hold Time for the Output Data Register | 0.00 | ns |
| $t_{OCLR2Q}$ | Asynchronous Clear-to-Q of the Output Data Register | 1.34 | ns |
| $t_{OPRE2Q}$ | Asynchronous Preset-to-Q of the Output Data Register | 1.34 | ns |
| $t_{OREMCLR}$ | Asynchronous Clear Removal Time for the Output Data Register | 0.00 | ns |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Data Register | 0.24 | ns |
| $t_{OREMPRE}$ | Asynchronous Preset Removal Time for the Output Data Register | 0.00 | ns |
| $t_{ORECPRE}$ | Asynchronous Preset Recovery Time for the Output Data Register | 0.24 | ns |
| $t_{OWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Output Data Register | 0.19 | ns |
| $t_{OWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Output Data Register | 0.19 | ns |
| $t_{OCKMPWH}$ | Clock Minimum Pulse Width High for the Output Data Register | 0.31 | ns |
| $t_{OCKMPWL}$ | Clock Minimum Pulse Width Low for the Output Data Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

#### 1.2 V DC Core Voltage

**Table 2-160 • Output Data Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{OCLKQ}$ | Clock-to-Q of the Output Data Register | 1.52 | ns |
| $t_{OSUD}$ | Data Setup Time for the Output Data Register | 1.15 | ns |
| $t_{OHD}$ | Data Hold Time for the Output Data Register | 0.00 | ns |
| $t_{OSUE}$ | Enable Setup Time for the Output Data Register | 1.11 | ns |
| $t_{OHE}$ | Enable Hold Time for the Output Data Register | 0.00 | ns |
| $t_{OCLR2Q}$ | Asynchronous Clear-to-Q of the Output Data Register | 1.96 | ns |
| $t_{OPRE2Q}$ | Asynchronous Preset-to-Q of the Output Data Register | 1.96 | ns |
| $t_{OREMCLR}$ | Asynchronous Clear Removal Time for the Output Data Register | 0.00 | ns |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Data Register | 0.24 | ns |
| $t_{OREMPRE}$ | Asynchronous Preset Removal Time for the Output Data Register | 0.00 | ns |
| $t_{ORECPRE}$ | Asynchronous Preset Recovery Time for the Output Data Register | 0.24 | ns |
| $t_{OWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Output Data Register | 0.19 | ns |
| $t_{OWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Output Data Register | 0.19 | ns |
| $t_{OCKMPWH}$ | Clock Minimum Pulse Width High for the Output Data Register | 0.31 | ns |
| $t_{OCKMPWL}$ | Clock Minimum Pulse Width Low for the Output Data Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## Output Enable Register

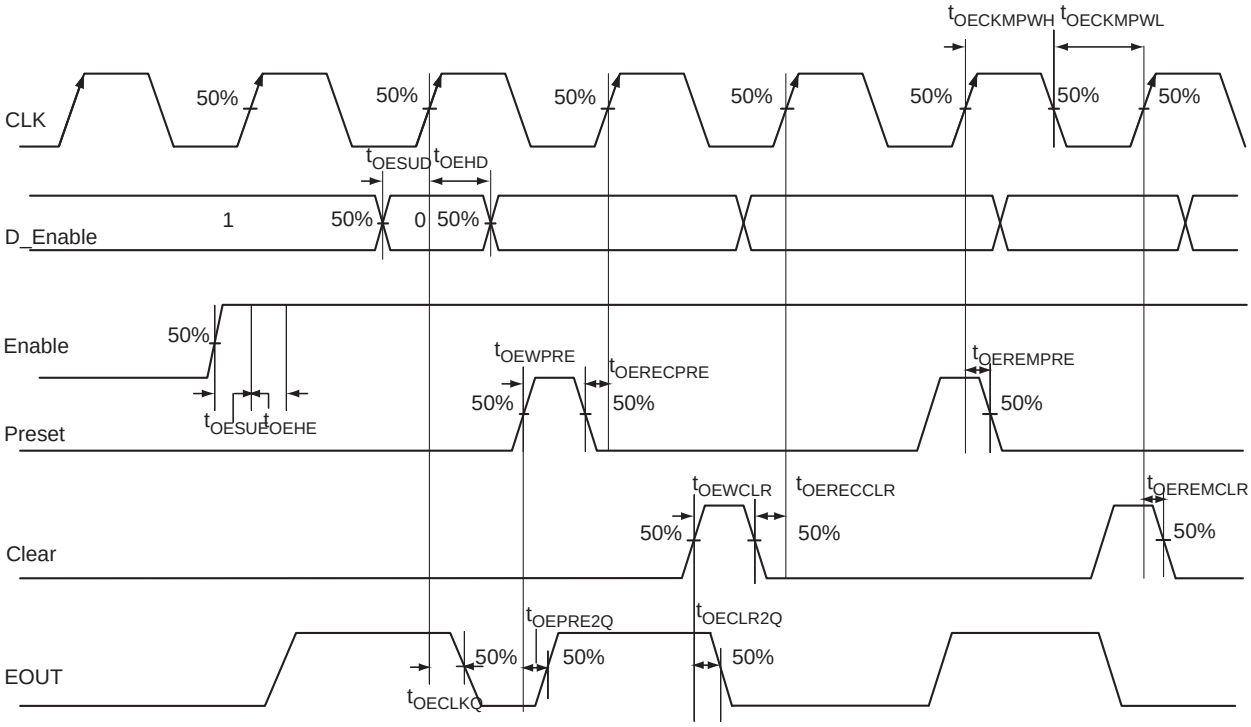



***Figure 2-20 •*** **Output Enable Register Timing Diagram**

### Timing Characteristics

#### 1.5 V DC Core Voltage

***Table 2-161 •*** **Output Enable Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{OECLKQ}$ | Clock-to-Q of the Output Enable Register | 0.75 | ns |
| $t_{OESUD}$ | Data Setup Time for the Output Enable Register | 0.51 | ns |
| $t_{OEHD}$ | Data Hold Time for the Output Enable Register | 0.00 | ns |
| $t_{OESUE}$ | Enable Setup Time for the Output Enable Register | 0.73 | ns |
| $t_{OEHE}$ | Enable Hold Time for the Output Enable Register | 0.00 | ns |
| $t_{OECLR2Q}$ | Asynchronous Clear-to-Q of the Output Enable Register | 1.13 | ns |
| $t_{OEPRE2Q}$ | Asynchronous Preset-to-Q of the Output Enable Register | 1.13 | ns |
| $t_{OEREMCLR}$ | Asynchronous Clear Removal Time for the Output Enable Register | 0.00 | ns |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Enable Register | 0.24 | ns |
| $t_{OEREMPRE}$ | Asynchronous Preset Removal Time for the Output Enable Register | 0.00 | ns |
| $t_{ORECPRE}$ | Asynchronous Preset Recovery Time for the Output Enable Register | 0.24 | ns |
| $t_{OEWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Output Enable Register | 0.19 | ns |
| $t_{OEWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Output Enable Register | 0.19 | ns |
| $t_{OECKMPWH}$ | Clock Minimum Pulse Width High for the Output Enable Register | 0.31 | ns |
| $t_{OECKMPWL}$ | Clock Minimum Pulse Width Low for the Output Enable Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-162 • Output Enable Register Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{OECLKQ}$ | Clock-to-Q of the Output Enable Register | 1.10 | ns |
| $t_{OESUD}$ | Data Setup Time for the Output Enable Register | 1.15 | ns |
| $t_{OEHD}$ | Data Hold Time for the Output Enable Register | 0.00 | ns |
| $t_{OESUE}$ | Enable Setup Time for the Output Enable Register | 1.22 | ns |
| $t_{OEHE}$ | Enable Hold Time for the Output Enable Register | 0.00 | ns |
| $t_{OECLR2Q}$ | Asynchronous Clear-to-Q of the Output Enable Register | 1.65 | ns |
| $t_{OEPRE2Q}$ | Asynchronous Preset-to-Q of the Output Enable Register | 1.65 | ns |
| $t_{OEREMCLR}$ | Asynchronous Clear Removal Time for the Output Enable Register | 0.00 | ns |
| $t_{ORECCLR}$ | Asynchronous Clear Recovery Time for the Output Enable Register | 0.24 | ns |
| $t_{OEREMPRE}$ | Asynchronous Preset Removal Time for the Output Enable Register | 0.00 | ns |
| $t_{ORECPRE}$ | Asynchronous Preset Recovery Time for the Output Enable Register | 0.24 | ns |
| $t_{OEWCLR}$ | Asynchronous Clear Minimum Pulse Width for the Output Enable Register | 0.19 | ns |
| $t_{OEWPRE}$ | Asynchronous Preset Minimum Pulse Width for the Output Enable Register | 0.19 | ns |
| $t_{OECKMPWH}$ | Clock Minimum Pulse Width High for the Output Enable Register | 0.31 | ns |
| $t_{OECKMPWL}$ | Clock Minimum Pulse Width Low for the Output Enable Register | 0.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## DDR Module Specifications

### *Input DDR Module*

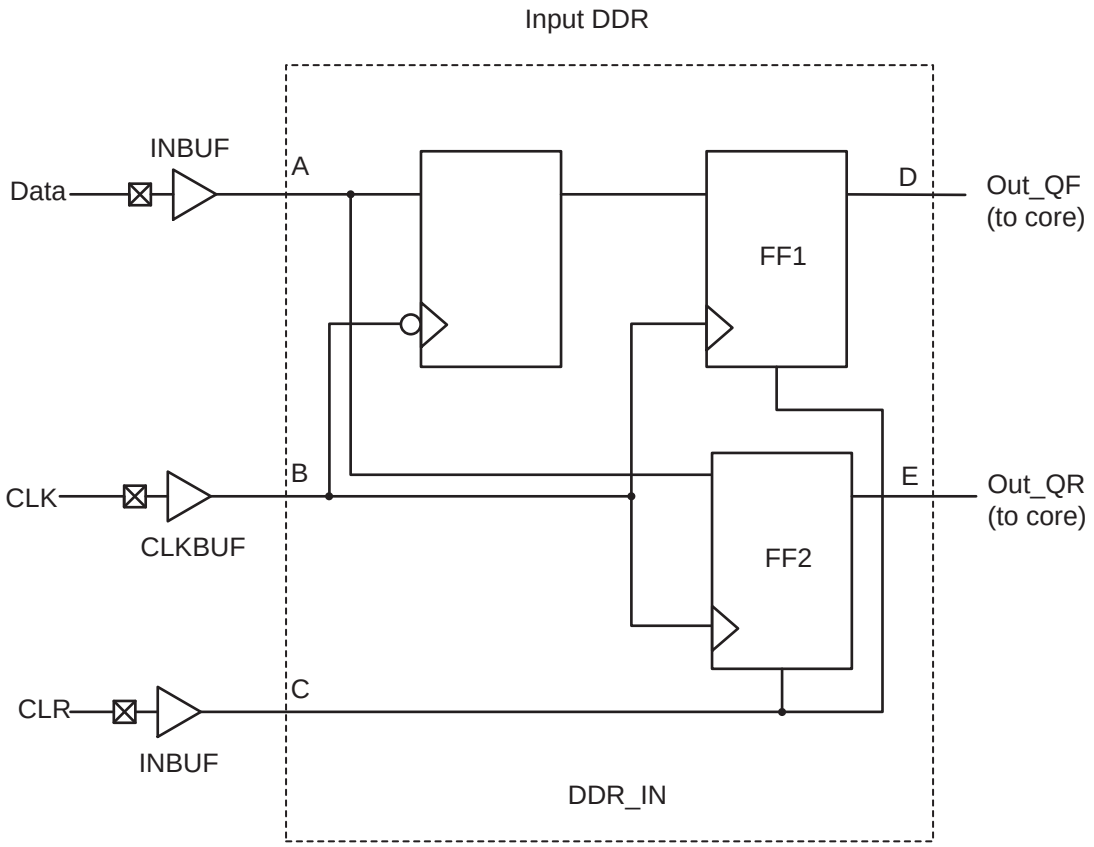



***Figure 2-21 •*** **Input DDR Timing Model**

***Table 2-163 •*** **Parameter Definitions**

| Parameter Name | Parameter Definition | Measuring Nodes (from, to) |
|---|---|---|
| $t_{DDRICLKQ1}$ | Clock-to-Out Out_QR | B, D |
| $t_{DDRICLKQ2}$ | Clock-to-Out Out_QF | B, E |
| $t_{DDRISUD}$ | Data Setup Time of DDR input | A, B |
| $t_{DDRIHD}$ | Data Hold Time of DDR input | A, B |
| $t_{DDRICLR2Q1}$ | Clear-to-Out Out_QR | C, D |
| $t_{DDRICLR2Q2}$ | Clear-to-Out Out_QF | C, E |
| $t_{DDRIREMCLR}$ | Clear Removal | C, B |
| $t_{DDRIRECCLR}$ | Clear Recovery | C, B |

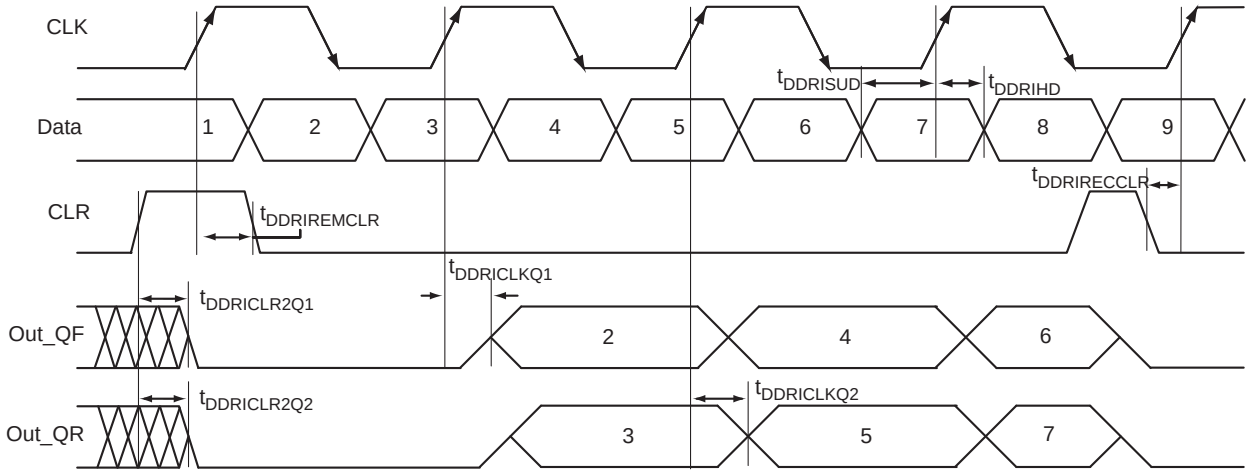



***Figure 2-22 •*** **Input DDR Timing Diagram**

### *Timing Characteristics*

#### *1.5 V DC Core Voltage*

***Table 2-164 •*** **Input DDR Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DDRICLKQ1}$ | Clock-to-Out Out_QR for Input DDR | 0.48 | ns |
| $t_{DDRICLKQ2}$ | Clock-to-Out Out_QF for Input DDR | 0.65 | ns |
| $t_{DDRISUD1}$ | Data Setup for Input DDR (negedge) | 0.50 | ns |
| $t_{DDRISUD2}$ | Data Setup for Input DDR (posedge) | 0.40 | ns |
| $t_{DDRIHD1}$ | Data Hold for Input DDR (negedge) | 0.00 | ns |
| $t_{DDRIHD2}$ | Data Hold for Input DDR (posedge) | 0.00 | ns |
| $t_{DDRICLR2Q1}$ | Asynchronous Clear-to-Out Out_QR for Input DDR | 0.82 | ns |
| $t_{DDRICLR2Q2}$ | Asynchronous Clear-to-Out Out_QF for Input DDR | 0.98 | ns |
| $t_{DDRIREMCLR}$ | Asynchronous Clear Removal Time for Input DDR | 0.00 | ns |
| $t_{DDRIRECCLR}$ | Asynchronous Clear Recovery Time for Input DDR | 0.23 | ns |
| $t_{DDRIWCLR}$ | Asynchronous Clear Minimum Pulse Width for Input DDR | 0.19 | ns |
| $t_{DDRICKMPWH}$ | Clock Minimum Pulse Width High for Input DDR | 0.31 | ns |
| $t_{DDRICKMPWL}$ | Clock Minimum Pulse Width Low for Input DDR | 0.28 | ns |
| $F_{DDRIMAX}$ | Maximum Frequency for Input DDR | 250.00 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-165 • Input DDR Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DDRICLKQ1}$ | Clock-to-Out Out_QR for Input DDR | 0.76 | ns |
| $t_{DDRICLKQ2}$ | Clock-to-Out Out_QF for Input DDR | 0.94 | ns |
| $t_{DDRISUD1}$ | Data Setup for Input DDR (negedge) | 0.93 | ns |
| $t_{DDRISUD2}$ | Data Setup for Input DDR (posedge) | 0.84 | ns |
| $t_{DDRIHD1}$ | Data Hold for Input DDR (negedge) | 0.00 | ns |
| $t_{DDRIHD2}$ | Data Hold for Input DDR (posedge) | 0.00 | ns |
| $t_{DDRICLR2Q1}$ | Asynchronous Clear-to-Out Out_QR for Input DDR | 1.23 | ns |
| $t_{DDRICLR2Q2}$ | Asynchronous Clear-to-Out Out_QF for Input DDR | 1.42 | ns |
| $t_{DDRIREMCLR}$ | Asynchronous Clear Removal Time for Input DDR | 0.00 | ns |
| $t_{DDRIRECCLR}$ | Asynchronous Clear Recovery Time for Input DDR | 0.24 | ns |
| $t_{DDRIWCLR}$ | Asynchronous Clear Minimum Pulse Width for Input DDR | 0.19 | ns |
| $t_{DDRICKMPWH}$ | Clock Minimum Pulse Width High for Input DDR | 0.31 | ns |
| $t_{DDRICKMPWL}$ | Clock Minimum Pulse Width Low for Input DDR | 0.28 | ns |
| $F_{DDRIMAX}$ | Maximum Frequency for Input DDR | 160.00 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## Output DDR Module

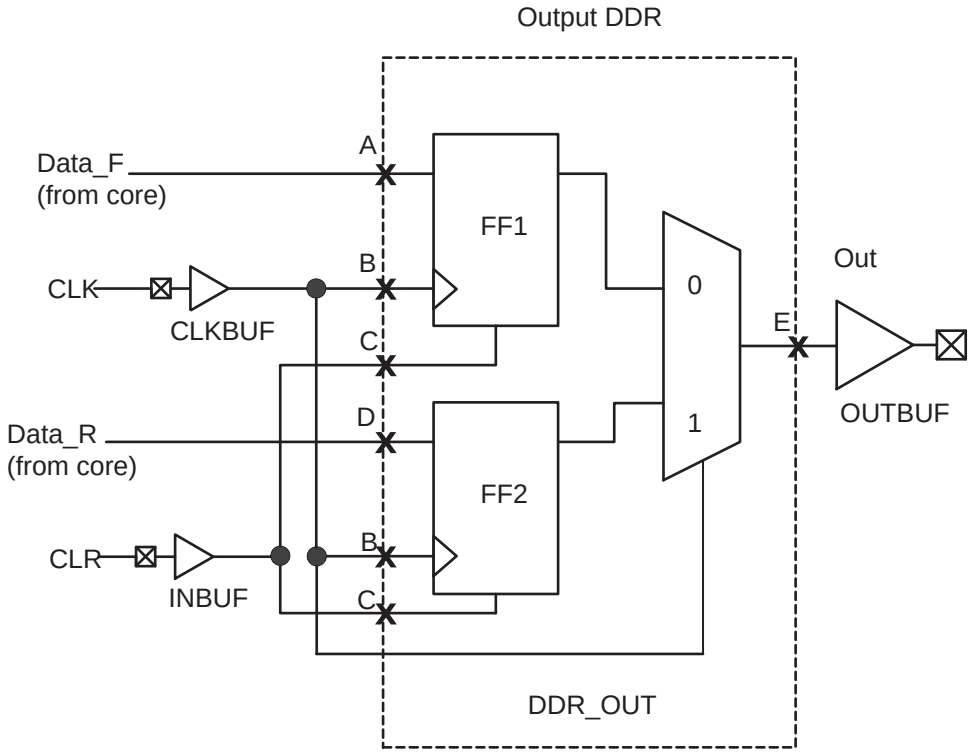



***Figure 2-23 •*** **Output DDR Timing Model**

***Table 2-166 •*** **Parameter Definitions**

| Parameter Name | Parameter Definition | Measuring Nodes (from, to) |
|---|---|---|
| $t_{DDROCLKQ}$ | Clock-to-Out | B, E |
| $t_{DDROCLR2Q}$ | Asynchronous Clear-to-Out | C, E |
| $t_{DDROREMCLR}$ | Clear Removal | C, B |
| $t_{DDRORECCLR}$ | Clear Recovery | C, B |
| $t_{DDROSUD1}$ | Data Setup Data_F | A, B |
| $t_{DDROSUD2}$ | Data Setup Data_R | D, B |
| $t_{DDROHD1}$ | Data Hold Data_F | A, B |
| $t_{DDROHD2}$ | Data Hold Data_R | D, B |

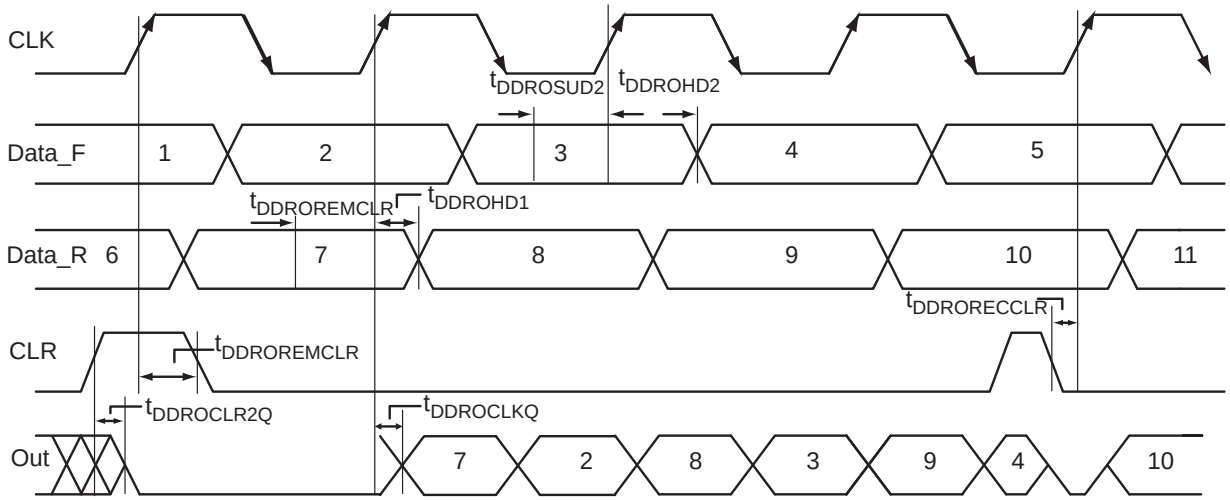



***Figure 2-24 •*** **Output DDR Timing Diagram**

### *Timing Characteristics*

#### *1.5 V DC Core Voltage*

***Table 2-167 •*** **Output DDR Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DDROCLKQ}$ | Clock-to-Out of DDR for Output DDR | 1.07 | ns |
| $t_{DDROSUD1}$ | Data_F Data Setup for Output DDR | 0.67 | ns |
| $t_{DDROSUD2}$ | Data_R Data Setup for Output DDR | 0.67 | ns |
| $t_{DDROHD1}$ | Data_F Data Hold for Output DDR | 0.00 | ns |
| $t_{DDROHD2}$ | Data_R Data Hold for Output DDR | 0.00 | ns |
| $t_{DDROCLR2Q}$ | Asynchronous Clear-to-Out for Output DDR | 1.38 | ns |
| $t_{DDROREMCLR}$ | Asynchronous Clear Removal Time for Output DDR | 0.00 | ns |
| $t_{DDRORECCLR}$ | Asynchronous Clear Recovery Time for Output DDR | 0.23 | ns |
| $t_{DDROWCLR1}$ | Asynchronous Clear Minimum Pulse Width for Output DDR | 0.19 | ns |
| $t_{DDROCKMPWH}$ | Clock Minimum Pulse Width High for the Output DDR | 0.31 | ns |
| $t_{DDROCKMPWL}$ | Clock Minimum Pulse Width Low for the Output DDR | 0.28 | ns |
| $F_{DDOMAX}$ | Maximum Frequency for the Output DDR | 250.00 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-168 • Output DDR Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DDROCLKQ}$ | Clock-to-Out of DDR for Output DDR | 1.60 | ns |
| $t_{DDROSUD1}$ | Data_F Data Setup for Output DDR | 1.09 | ns |
| $t_{DDROSUD2}$ | Data_R Data Setup for Output DDR | 1.16 | ns |
| $t_{DDROHD1}$ | Data_F Data Hold for Output DDR | 0.00 | ns |
| $t_{DDROHD2}$ | Data_R Data Hold for Output DDR | 0.00 | ns |
| $t_{DDROCLR2Q}$ | Asynchronous Clear-to-Out for Output DDR | 1.99 | ns |
| $t_{DDROREMCLR}$ | Asynchronous Clear Removal Time for Output DDR | 0.00 | ns |
| $t_{DDRORECCLR}$ | Asynchronous Clear Recovery Time for Output DDR | 0.24 | ns |
| $t_{DDROWCLR1}$ | Asynchronous Clear Minimum Pulse Width for Output DDR | 0.19 | ns |
| $t_{DDROCKMPWH}$ | Clock Minimum Pulse Width High for the Output DDR | 0.31 | ns |
| $t_{DDROCKMPWL}$ | Clock Minimum Pulse Width Low for the Output DDR | 0.28 | ns |
| $F_{DDOMAX}$ | Maximum Frequency for the Output DDR | 160.00 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

# VersaTile Characteristics

## VersaTile Specifications as a Combinatorial Module

The IGLOO library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *IGLOO, Fusion, and ProASIC3 Macro Library Guide*.

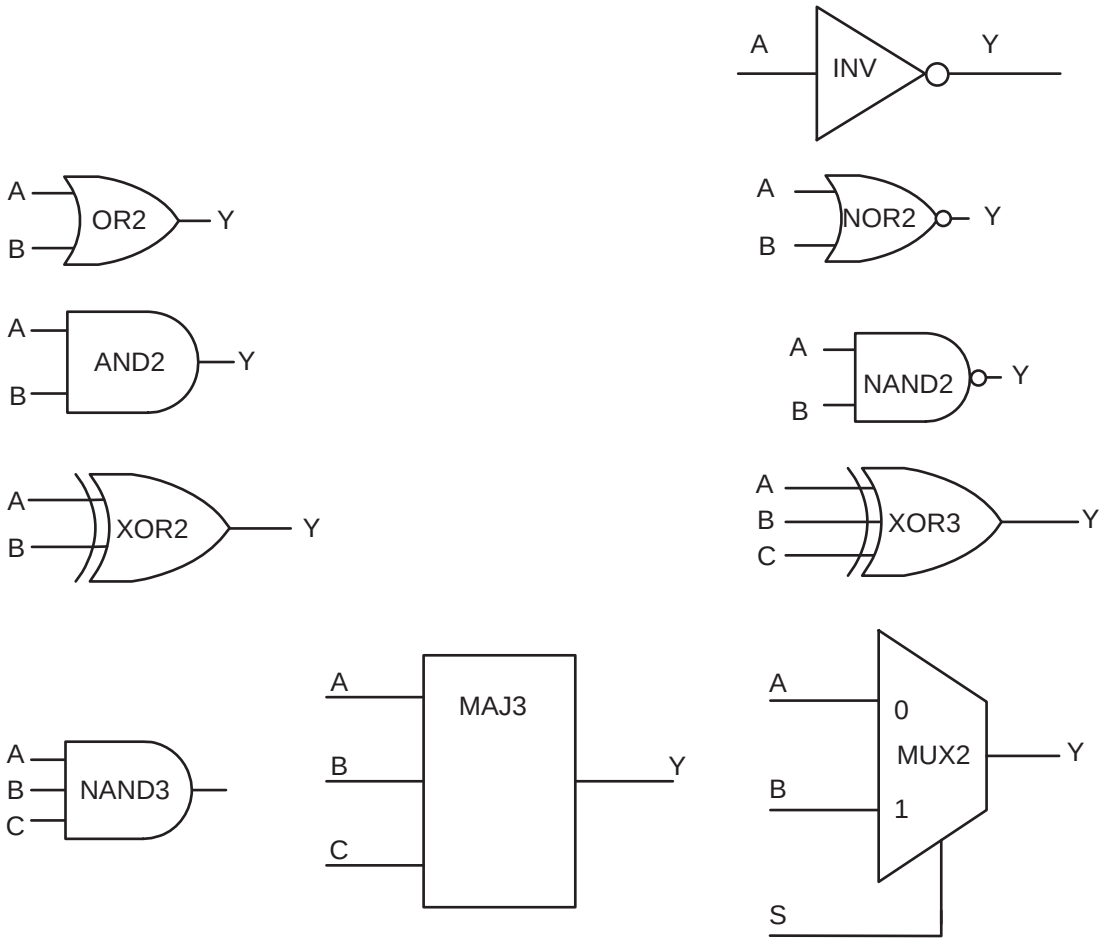



***Figure 2-25 •*** **Sample of Combinatorial Cells**

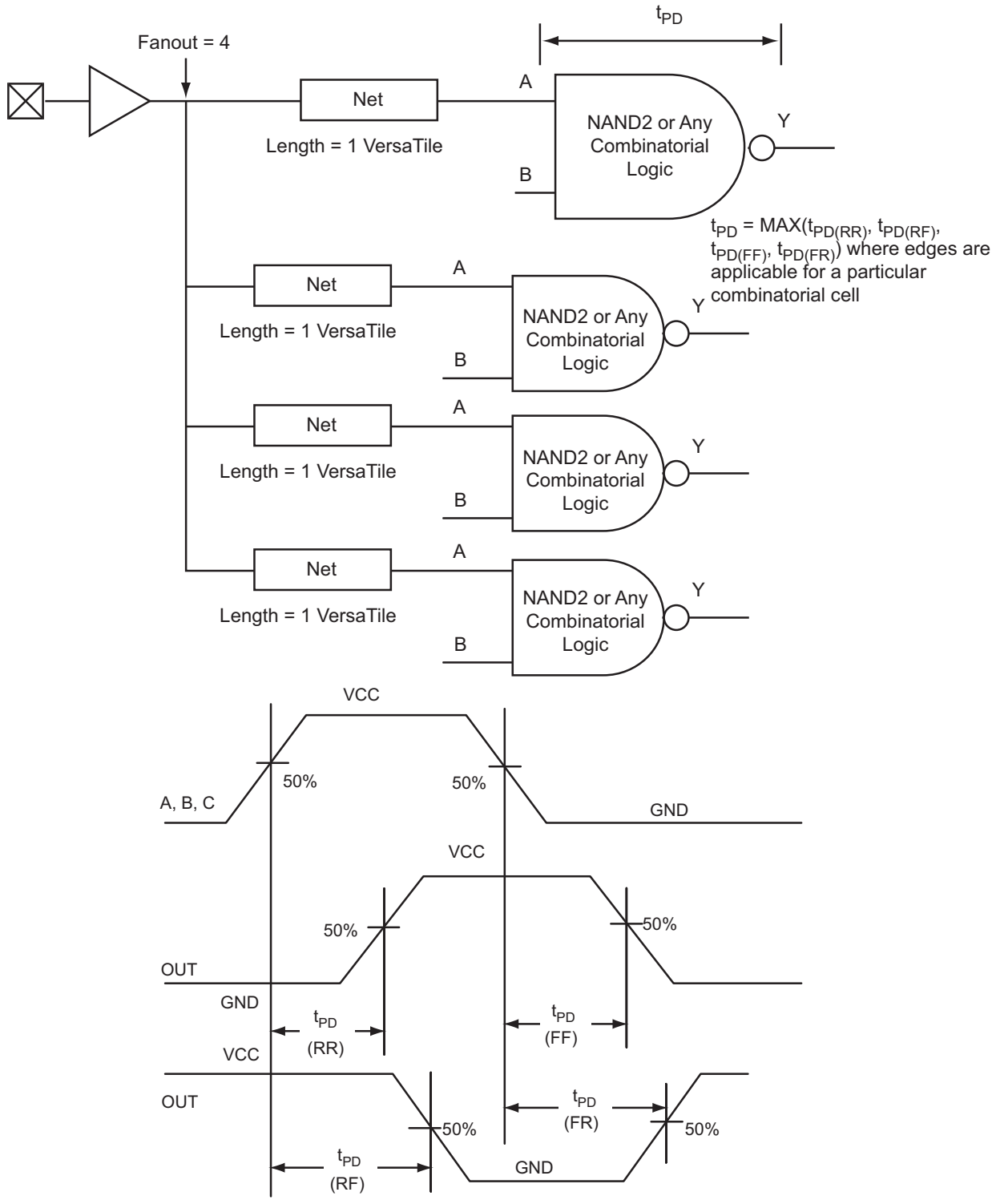



***Figure 2-26 •*** **Timing Model and Waveforms**

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-169 • Combinatorial Cell Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Combinatorial Cell | Equation | Parameter | Std. | Units |
|---|---|---|---|---|
| INV | Y =!A | $t_{PD}$ | 0.80 | ns |
| AND2 | Y = A · B | $t_{PD}$ | 0.84 | ns |
| NAND2 | Y =!(A · B) | $t_{PD}$ | 0.90 | ns |
| OR2 | Y = A + B | $t_{PD}$ | 1.19 | ns |
| NOR2 | Y = !(A + B) | $t_{PD}$ | 1.10 | ns |
| XOR2 | Y = A ⊕ B | $t_{PD}$ | 1.37 | ns |
| MAJ3 | Y = MAJ(A, B, C) | $t_{PD}$ | 1.33 | ns |
| XOR3 | Y = A ⊕ B ⊕ C | $t_{PD}$ | 1.79 | ns |
| MUX2 | Y = A !S + B S | $t_{PD}$ | 1.48 | ns |
| AND3 | Y = A · B · C | $t_{PD}$ | 1.21 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-170 • Combinatorial Cell Propagation Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Combinatorial Cell | Equation | Parameter | Std. | Units |
|---|---|---|---|---|
| INV | Y = !A | $t_{PD}$ | 1.34 | ns |
| AND2 | Y = A · B | $t_{PD}$ | 1.43 | ns |
| NAND2 | Y = !(A · B) | $t_{PD}$ | 1.59 | ns |
| OR2 | Y = A + B | $t_{PD}$ | 2.30 | ns |
| NOR2 | Y = !(A + B) | $t_{PD}$ | 2.07 | ns |
| XOR2 | Y = A ⊕ B | $t_{PD}$ | 2.46 | ns |
| MAJ3 | Y = MAJ(A, B, C) | $t_{PD}$ | 2.46 | ns |
| XOR3 | Y = A ⊕ B ⊕ C | $t_{PD}$ | 3.12 | ns |
| MUX2 | Y = A !S + B S | $t_{PD}$ | 2.83 | ns |
| AND3 | Y = A · B · C | $t_{PD}$ | 2.28 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

## VersaTile Specifications as a Sequential Module

The IGLOO library offers a wide variety of sequential cells, including flip-flops and latches. Each has a data input and optional enable, clear, or preset. In this section, timing characteristics are presented for a representative sample from the library. For more details, refer to the *IGLOO, Fusion, and ProASIC3 Macro Library Guide*.

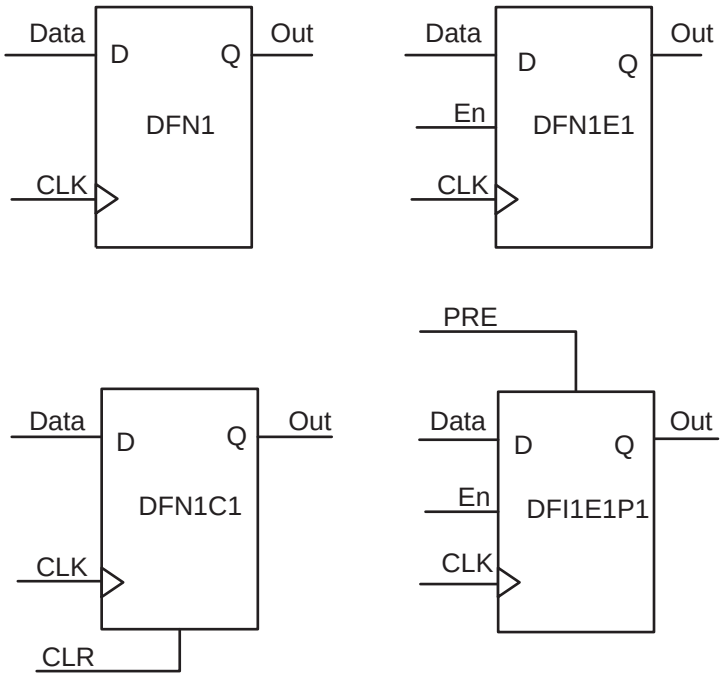



***Figure 2-27 •*** **Sample of Sequential Cells**

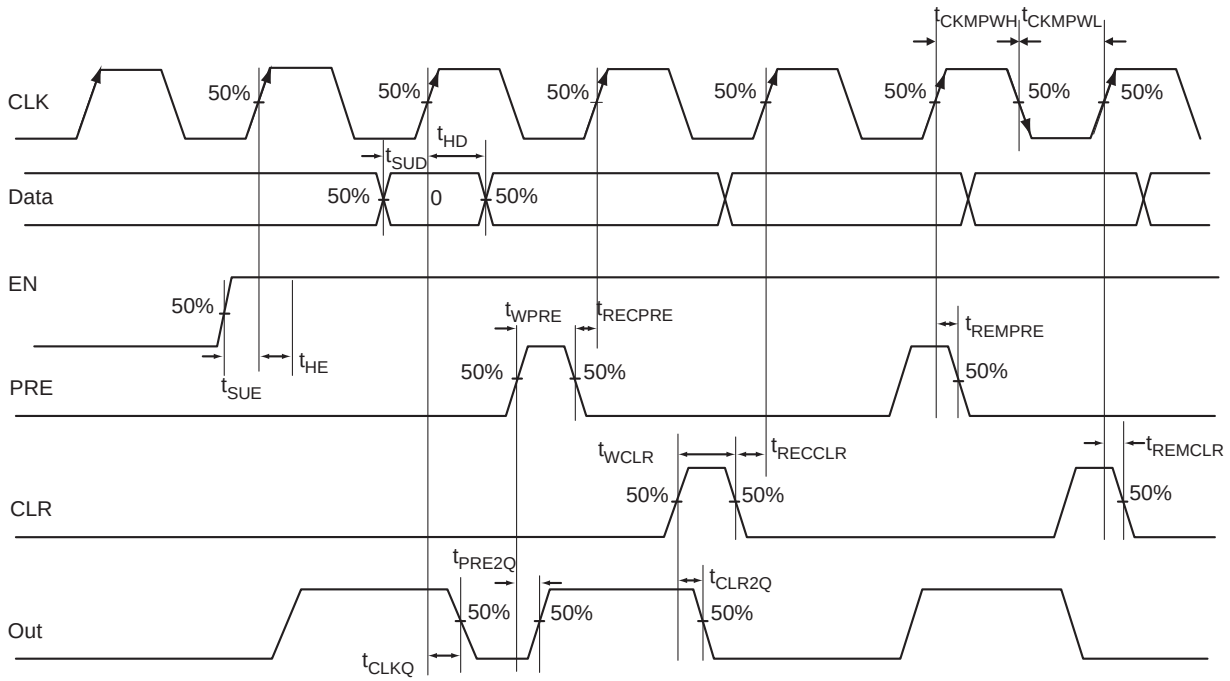



***Figure 2-28 •*** **Timing Model and Waveforms**

## Timing Characteristics

### 1.5 V DC Core Voltage

***Table 2-171 •*** **Register Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{CLKQ}$ | Clock-to-Q of the Core Register | 0.89 | ns |
| $t_{SUD}$ | Data Setup Time for the Core Register | 0.81 | ns |
| $t_{HD}$ | Data Hold Time for the Core Register | 0.00 | ns |
| $t_{SUE}$ | Enable Setup Time for the Core Register | 0.73 | ns |
| $t_{HE}$ | Enable Hold Time for the Core Register | 0.00 | ns |
| $t_{CLR2Q}$ | Asynchronous Clear-to-Q of the Core Register | 0.60 | ns |
| $t_{PRE2Q}$ | Asynchronous Preset-to-Q of the Core Register | 0.62 | ns |
| $t_{REMCLR}$ | Asynchronous Clear Removal Time for the Core Register | 0.00 | ns |
| $t_{RECCLR}$ | Asynchronous Clear Recovery Time for the Core Register | 0.24 | ns |
| $t_{REMPRE}$ | Asynchronous Preset Removal Time for the Core Register | 0.00 | ns |
| $t_{RECPRE}$ | Asynchronous Preset Recovery Time for the Core Register | 0.23 | ns |
| $t_{WCLR}$ | Asynchronous Clear Minimum Pulse Width for the Core Register | 0.30 | ns |
| $t_{WPRE}$ | Asynchronous Preset Minimum Pulse Width for the Core Register | 0.30 | ns |
| $t_{CKMPWH}$ | Clock Minimum Pulse Width High for the Core Register | 0.56 | ns |
| $t_{CKMPWL}$ | Clock Minimum Pulse Width Low for the Core Register | 0.56 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-172 • Register Delays**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{CLKQ}$ | Clock-to-Q of the Core Register | 1.61 | ns |
| $t_{SUD}$ | Data Setup Time for the Core Register | 1.17 | ns |
| $t_{HD}$ | Data Hold Time for the Core Register | 0.00 | ns |
| $t_{SUE}$ | Enable Setup Time for the Core Register | 1.29 | ns |
| $t_{HE}$ | Enable Hold Time for the Core Register | 0.00 | ns |
| $t_{CLR2Q}$ | Asynchronous Clear-to-Q of the Core Register | 0.87 | ns |
| $t_{PRE2Q}$ | Asynchronous Preset-to-Q of the Core Register | 0.89 | ns |
| $t_{REMCLR}$ | Asynchronous Clear Removal Time for the Core Register | 0.00 | ns |
| $t_{RECCLR}$ | Asynchronous Clear Recovery Time for the Core Register | 0.24 | ns |
| $t_{REMPRE}$ | Asynchronous Preset Removal Time for the Core Register | 0.00 | ns |
| $t_{RECPRE}$ | Asynchronous Preset Recovery Time for the Core Register | 0.24 | ns |
| $t_{WCLR}$ | Asynchronous Clear Minimum Pulse Width for the Core Register | 0.46 | ns |
| $t_{WPRE}$ | Asynchronous Preset Minimum Pulse Width for the Core Register | 0.46 | ns |
| $t_{CKMPWH}$ | Clock Minimum Pulse Width High for the Core Register | 0.95 | ns |
| $t_{CKMPWL}$ | Clock Minimum Pulse Width Low for the Core Register | 0.95 | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

# Global Resource Characteristics

## AGL250 Clock Tree Topology

Clock delays are device-specific. Figure 2-29 is an example of a global tree used for clock routing. The global tree presented in Figure 2-29 is driven by a CCC located on the west side of the AGL250 device. It is used to drive all D-flip-flops in the device.

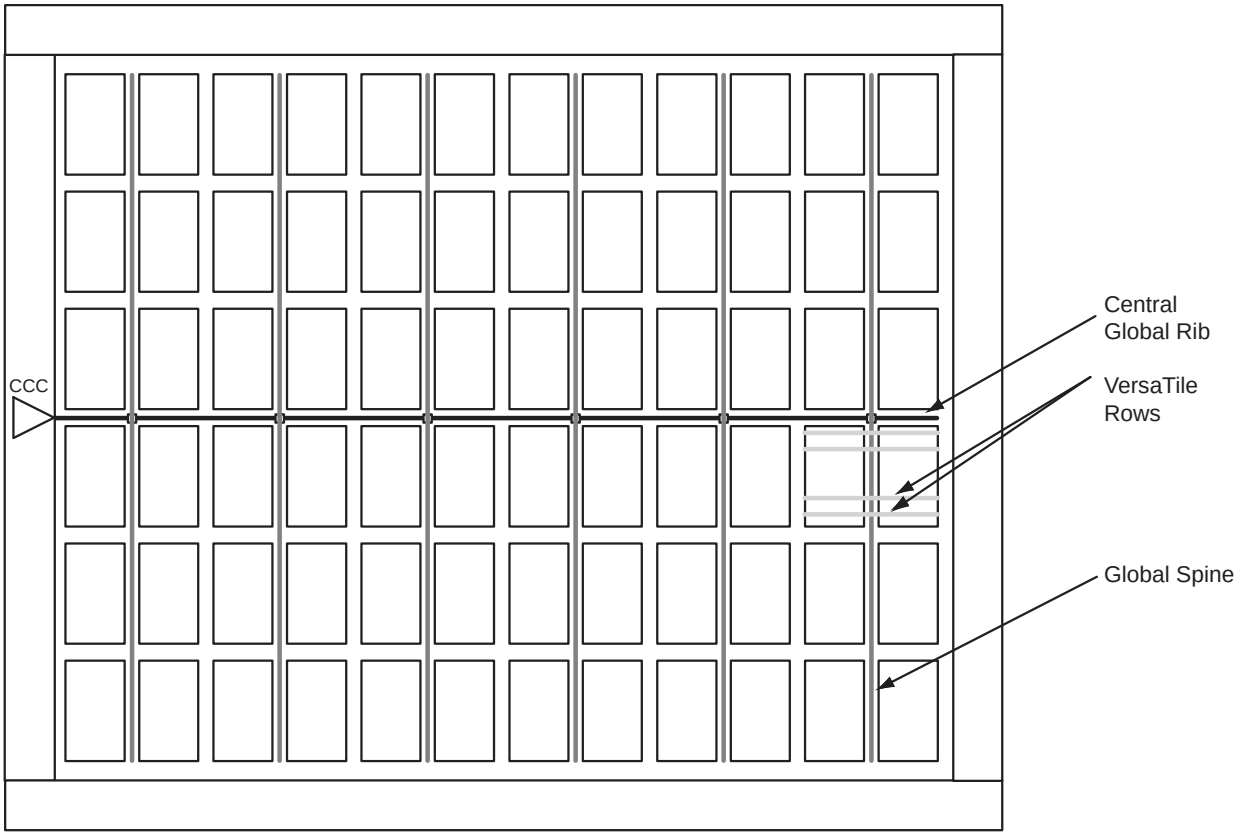



***Figure 2-29 •*** **Example of Global Tree Use in an AGL250 Device for Clock Routing**

## Global Tree Timing Characteristics

Global clock delays include the central rib delay, the spine delay, and the row delay. Delays do not include I/O input buffer clock delays, as these are I/O standard–dependent, and the clock may be driven and conditioned internally by the CCC module. For more details on clock conditioning capabilities, refer to the "Clock Conditioning Circuits" section on page 2-115. Table 2-173 to Table 2-188 on page 2-114 present minimum and maximum global clock delays within each device. Minimum and maximum delays are measured with minimum and maximum loading.

### Timing Characteristics

#### 1.5 V DC Core Voltage

**Table 2-173 • AGL015 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.21 | 1.42 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.23 | 1.49 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.27 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-174 • AGL030 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.21 | 1.42 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.23 | 1.49 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.27 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-175 • AGL060 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.33 | 1.55 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.35 | 1.62 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.27 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-176 • AGL125 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.36 | 1.71 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.39 | 1.82 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.43 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-177 • AGL250 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.39 | 1.73 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.41 | 1.84 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.43 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-178 • AGL400 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min. [1] | Max. [2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.45 | 1.79 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.48 | 1.91 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.43 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage-supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-179 • AGL600 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.48 | 1.82 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.52 | 1.94 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.42 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-180 • AGL1000 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.55 | 1.89 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.60 | 2.02 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.42 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

**Table 2-181 • AGL015 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.79 | 2.09 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.87 | 2.26 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.39 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-182 • AGL030 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 1.80 | 2.09 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 1.88 | 2.27 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.39 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-183 • AGL060 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.04 | 2.33 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.10 | 2.51 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.40 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-184 • AGL125 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.08 | 2.54 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.15 | 2.77 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.62 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-185 • AGL250 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.11 | 2.57 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.19 | 2.81 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.62 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-186 • AGL400 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.18 | 2.64 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.27 | 2.89 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.62 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-187 • AGL600 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.22 | 2.67 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.32 | 2.93 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.61 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-188 • AGL1000 Global Resource**
**Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | | Units |
|---|---|---|---|---|
| | | Min.[1] | Max.[2] | |
| $t_{RCKL}$ | Input Low Delay for Global Clock | 2.31 | 2.76 | ns |
| $t_{RCKH}$ | Input High Delay for Global Clock | 2.42 | 3.03 | ns |
| $t_{RCKMPWH}$ | Minimum Pulse Width High for Global Clock | | | ns |
| $t_{RCKMPWL}$ | Minimum Pulse Width Low for Global Clock | | | ns |
| $t_{RCKSW}$ | Maximum Skew for Global Clock | | 0.61 | ns |
| $F_{RMAX}$ | Maximum Frequency for Global Clock | | | MHz |

*Notes:*

1. *Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).*
2. *Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).*
3. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

# Clock Conditioning Circuits

## CCC Electrical Specifications

### Timing Characteristics

**Table 2-189 • IGLOO CCC/PLL Specification**
**For IGLOO V2 or V5 Devices, 1.5 V DC Core Supply Voltage**

| Parameter | Min. | Typ. | Max. | Units |
|---|---|---|---|---|
| Clock Conditioning Circuitry Input Frequency $f_{IN_CCC}$ | 1.5 | | 250 | MHz |
| Clock Conditioning Circuitry Output Frequency $f_{OUT_CCC}$ | 0.75 | | 250 | MHz |
| Delay Increments in Programmable Delay Blocks [1, 2] | | 360[3] | | ps |
| Number of Programmable Values in Each Programmable Delay Block | | | 32 | |
| Serial Clock (SCLK) for Dynamic PLL[4,5] | | | 100 | ns |
| Input Cycle-to-Cycle Jitter (peak magnitude) | | | 1 | ns |
| Acquisition Time | | | | |
| LockControl = 0 | | | 300 | µs |
| LockControl = 1 | | | 6.0 | ms |
| Tracking Jitter[5] | | | | |
| LockControl = 0 | | | 2.5 | ns |
| LockControl = 1 | | | 1.5 | ns |
| Output Duty Cycle | 48.5 | | 51.5 | % |
| Delay Range in Block: Programmable Delay 1 [1,2] | 1.25 | | 15.65 | ns |
| Delay Range in Block: Programmable Delay 2 [1,2] | 0.469 | | 15.65 | ns |
| Delay Range in Block: Fixed Delay [1, 2] | | 3.5 | | ns |
| CCC Output Peak-to-Peak Period Jitter $F_{CCC_OUT}$ | Maximum Peak-to-Peak Jitter Data[7,8] | | | |
| | SSO ≥ 4 | SSO ≥ 8 | SSO ≥ 16 | |
| 0.75 MHz to 50 MHz | 0.60% | 0.80% | 1.20% | |
| 50 MHz to 160 MHz | 4.00% | 6.00% | 12.00% | |

*Notes:*

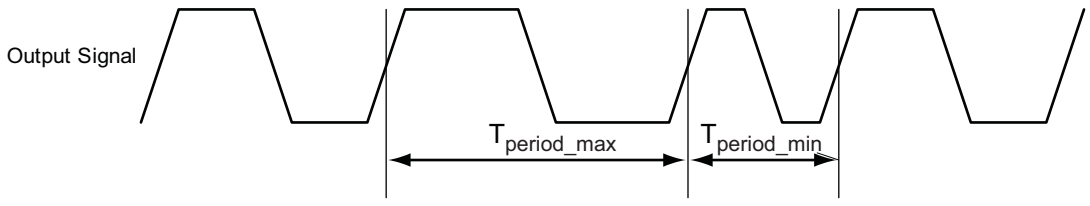
1. *This delay is a function of voltage and temperature. See Table 2-6 on page 2-7 and Table 2-7 on page 2-7 for deratings.*
2. *$T_J$ = 25°C, $V_{CC}$ = 1.5 V*
3. *When the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available. Refer to SmartGen online help for more information.*
4. *The AGL030 device does not support a PLL.*
5. *Maximum value obtained for a Std. speed grade device in Worst-Case Commercial Conditions. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
6. *Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to the PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.*
7. *Measurements done with LVTTL 3.3 V, 8 mA I/O drive strength, and high slew Rate. VCC/VCCPLL = 1.14 V, VQ/PQ/TQ type of packages, 20 pF load.*
8. *Switching I/Os are placed outside of the PLL bank.*

**Table 2-190 • IGLOO CCC/PLL Specification**
**For IGLOO V2 Devices, 1.2 V DC Core Supply Voltage**

| Parameter | Min. | Typ. | Max. | Units |
|---|---|---|---|---|
| Clock Conditioning Circuitry Input Frequency $f_{IN_CCC}$ | 1.5 | | 160 | MHz |
| Clock Conditioning Circuitry Output Frequency $f_{OUT_CCC}$ | 0.75 | | 160 | MHz |
| Delay Increments in Programmable Delay Blocks [1, 2] | | 580[3] | | ps |
| Number of Programmable Values in Each Programmable Delay Block | | | 32 | |
| Serial Clock (SCLK) for Dynamic PLL[4,5] | | | 60 | ns |
| Input Cycle-to-Cycle Jitter (peak magnitude) | | | 0.25 | ns |
| Acquisition Time | | | | |
| LockControl = 0 | | | 300 | µs |
| LockControl = 1 | | | 6.0 | ms |
| Tracking Jitter[6] | | | | |
| LockControl = 0 | | | 4 | ns |
| LockControl = 1 | | | 3 | ns |
| Output Duty Cycle | 48.5 | | 51.5 | % |
| Delay Range in Block: Programmable Delay 1[1,2] | 2.3 | | 20.86 | ns |
| Delay Range in Block: Programmable Delay 2[1,2] | 0.863 | | 20.86 | ns |
| Delay Range in Block: Fixed Delay [1, 2, 5] | | 5.7 | | ns |
| CCC Output Peak-to-Peak Period Jitter $F_{CCC_OUT}$ | Maximum Peak-to-Peak Jitter Data[7,8] | | | |
| | SSO ≥ 4 | SSO ≥ 8 | SSO ≥ 16 | |
| 0.75 MHz to 50 MHz | 1.20% | 2.00% | 3.00% | |
| 50 MHz to 160 MHz | 5.00% | 7.00% | 15.00% | |

*Notes:*

1. *This delay is a function of voltage and temperature. See Table 2-6 on page 2-7 and Table 2-7 on page 2-7 for deratings.*
2. *$T_J$ = 25°C, $V_{CC}$ = 1.2 V*
3. *When the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available. Refer to SmartGen online help for more information.*
4. *Maximum value obtained for a Std. speed grade device in Worst-Case Commercial Conditions. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*
5. *The AGL030 device does not support a PLL.*
6. *Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to the PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.*
7. *Measurements done with LVTTL 3.3 V 8 mA I/O drive strength and high slew rate. VCC/VCCPLL = 1.14 V, VQ/PQ/TQ type of packages, 20 pF load.*
8. *Switching I/Os are placed outside of the PLL bank.*




*Note: Peak-to-peak jitter measurements are defined by $T_{peak\text{-}to\text{-}peak} = T_{period_max} - T_{period_min}$.*

**Figure 2-30 • Peak-to-Peak Jitter Definition**

# Embedded SRAM and FIFO Characteristics

## SRAM

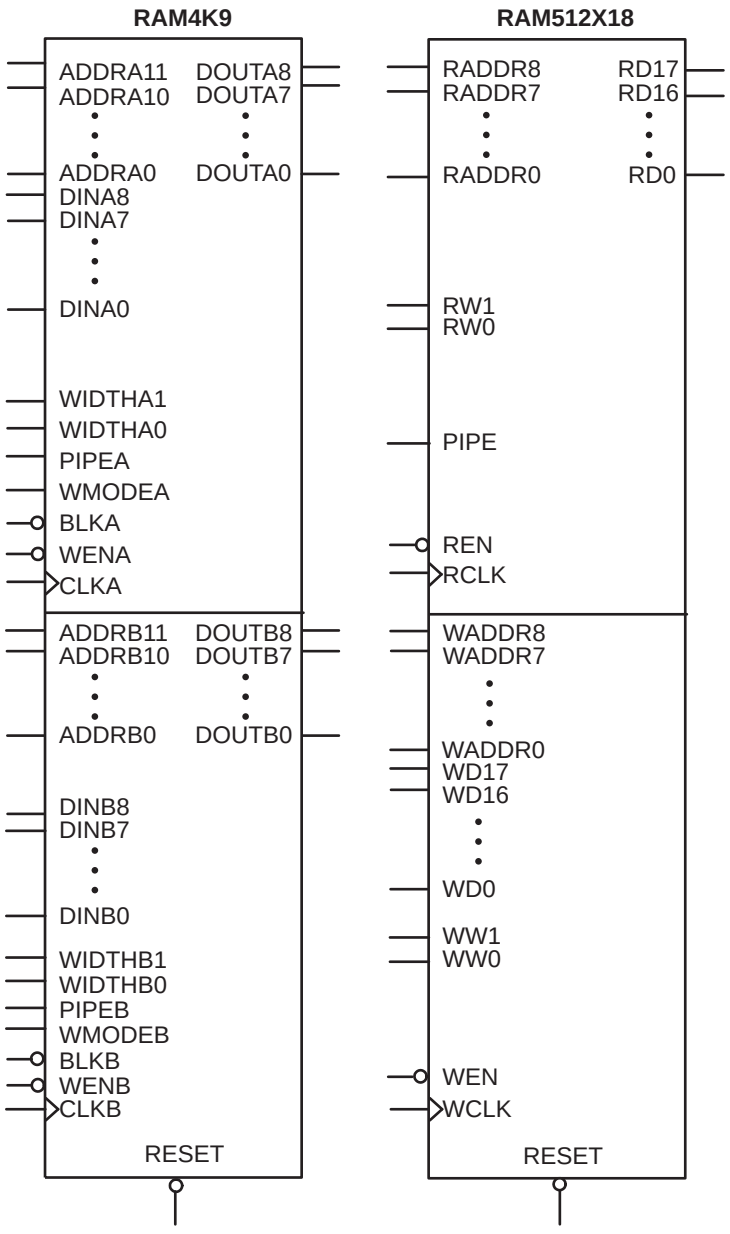



***Figure 2-31 •*** **RAM Models**

### Timing Waveforms

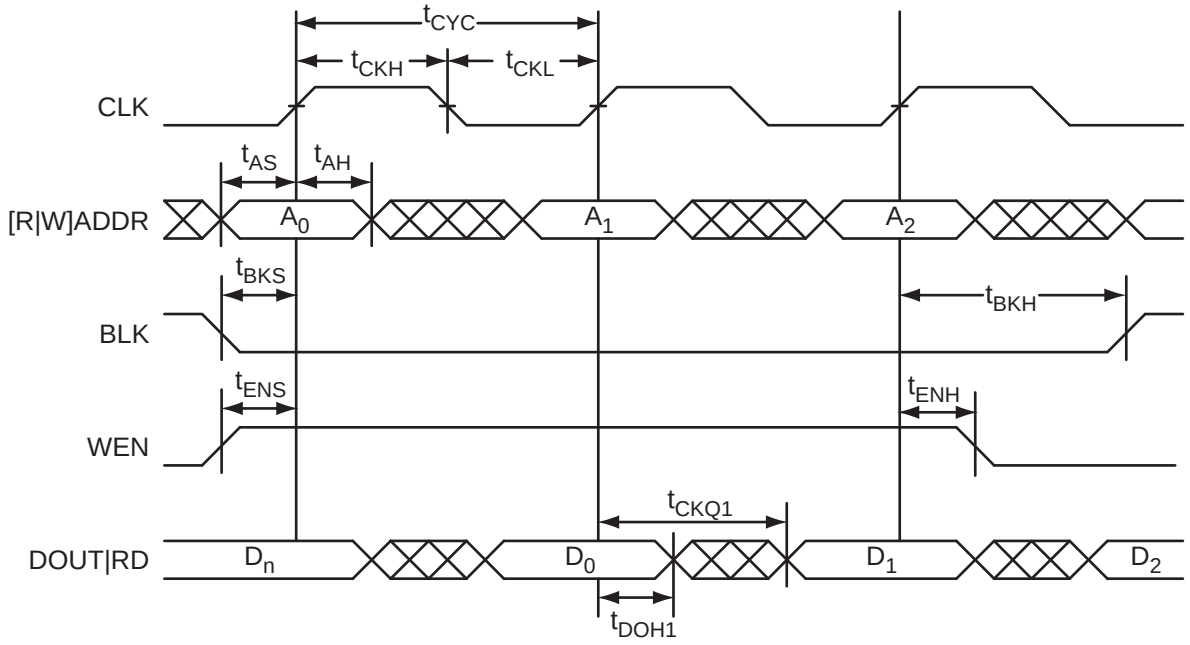



***Figure 2-32 •*** **RAM Read for Pass-Through Output. Applicable to Both RAM4K9 and RAM512x18.**

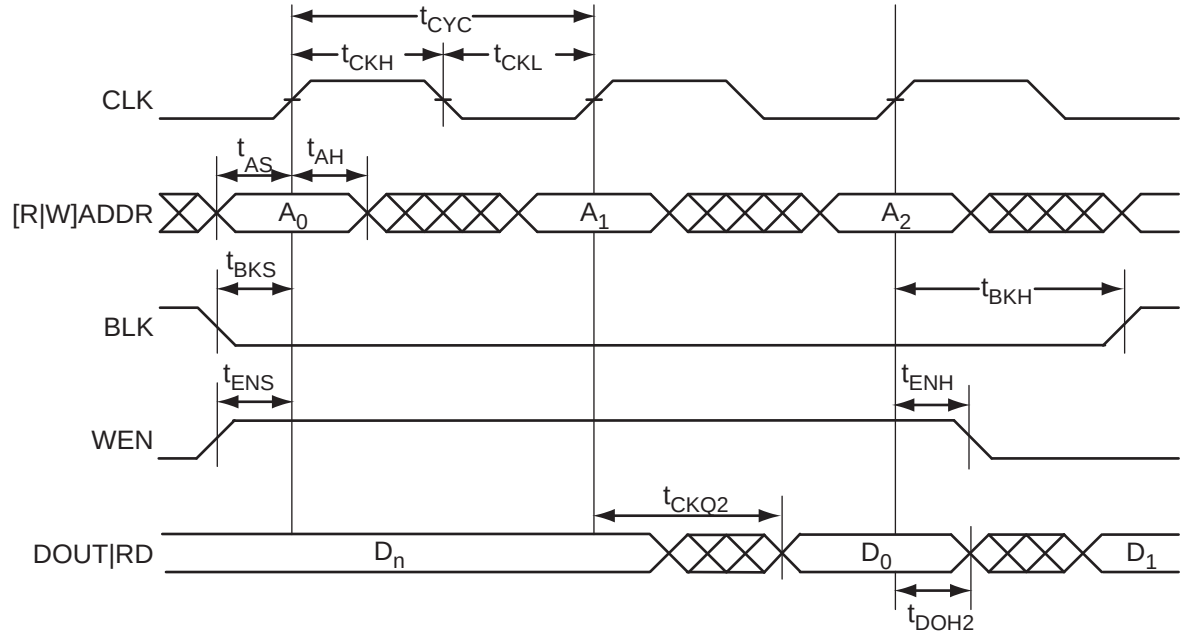



***Figure 2-33 •*** **RAM Read for Pipelined Output. Applicable to Both RAM4K9 and RAM512x18.**

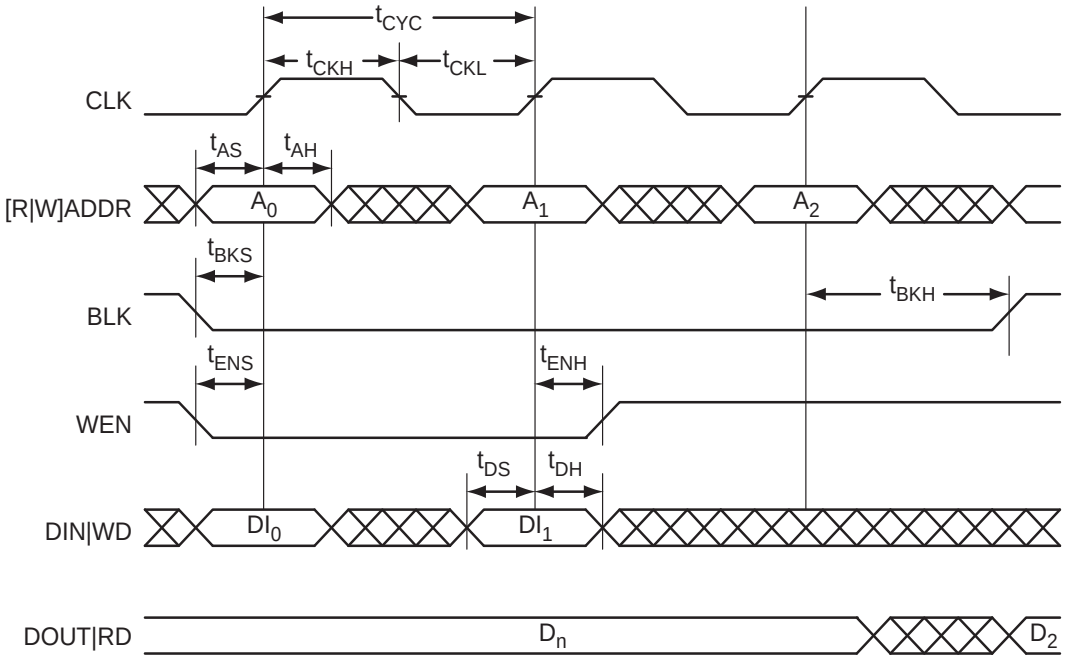



***Figure 2-34 •*** **RAM Write, Output Retained. Applicable to Both RAM4K9 and RAM512x18.**

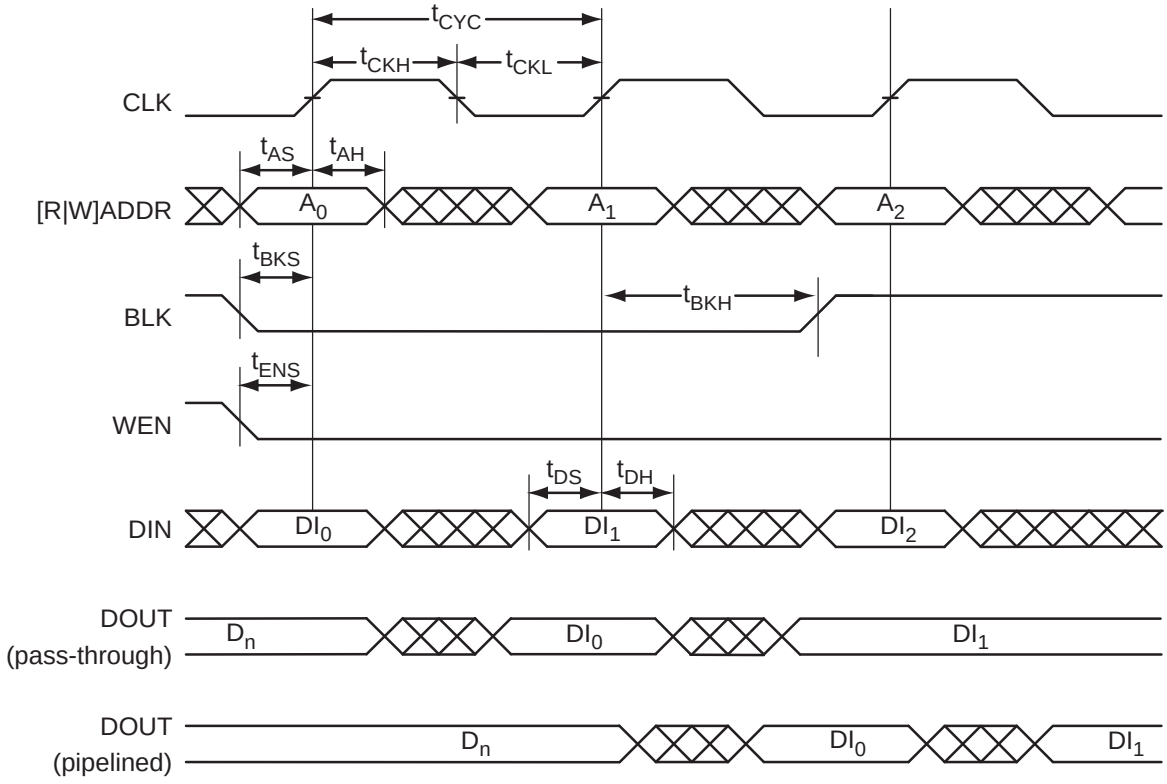



***Figure 2-35 •*** **RAM Write, Output as Write Data (WMODE = 1). Applicable to RAM4K9 only.**

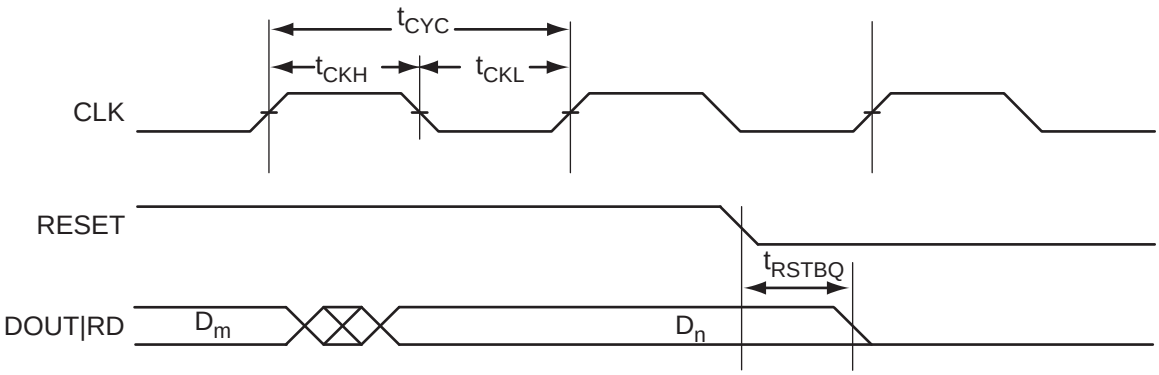



***Figure 2-36 •*** **RAM Reset. Applicable to Both RAM4K9 and RAM512x18.**

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-191 • RAM4K9**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{AS}$ | Address setup time | 0.83 | ns |
| $t_{AH}$ | Address hold time | 0.16 | ns |
| $t_{ENS}$ | REN, WEN setup time | 0.81 | ns |
| $t_{ENH}$ | REN, WEN hold time | 0.16 | ns |
| $t_{BKS}$ | BLK setup time | 1.65 | ns |
| $t_{BKH}$ | BLK hold time | 0.16 | ns |
| $t_{DS}$ | Input data (DIN) setup time | 0.71 | ns |
| $t_{DH}$ | Input data (DIN) hold time | 0.36 | ns |
| $t_{CKQ1}$ | Clock High to new data valid on DOUT (output retained, WMODE = 0) | 3.53 | ns |
| | Clock High to new data valid on DOUT (flow-through, WMODE = 1) | 3.06 | ns |
| $t_{CKQ2}$ | Clock High to new data valid on DOUT (pipelined) | 1.81 | ns |
| $t_{C2CWWL}$[1] | Address collision clk-to-clk delay for reliable write after write on same address – Applicable to Closing Edge | 0.23 | ns |
| $t_{C2CRWL}$[1] | Address collision clk-to-clk delay for reliable read access after write on same address – Applicable to Opening Edge | 0.35 | ns |
| $t_{C2CWRH}$[1] | Address collision clk-to-clk delay for reliable write access after read on same address – Applicable to Opening Edge | 0.41 | ns |
| $t_{RSTBQ}$ | RESET Low to data out Low on DOUT (flow-through) | 2.06 | ns |
| | RESET Low to data out Low on DOUT (pipelined) | 2.06 | ns |
| $t_{REMRSTB}$ | RESET removal | 0.61 | ns |
| $t_{RECRSTB}$ | RESET recovery | 3.21 | ns |
| $t_{MPWRSTB}$ | RESET minimum pulse width | 0.68 | ns |
| $t_{CYC}$ | Clock cycle time | 6.24 | ns |
| $F_{MAX}$ | Maximum frequency | 160 | MHz |

*Notes:*

1. *For more information, refer to the application note* Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs*.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-192 • RAM512X18**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{AS}$ | Address setup time | 0.83 | ns |
| $t_{AH}$ | Address hold time | 0.16 | ns |
| $t_{ENS}$ | REN, WEN setup time | 0.73 | ns |
| $t_{ENH}$ | REN, WEN hold time | 0.08 | ns |
| $t_{DS}$ | Input data (WD) setup time | 0.71 | ns |
| $t_{DH}$ | Input data (WD) hold time | 0.36 | ns |
| $t_{CKQ1}$ | Clock High to new data valid on RD (output retained) | 4.21 | ns |
| $t_{CKQ2}$ | Clock High to new data valid on RD (pipelined) | 1.71 | ns |
| $t_{C2CRWH}$[1] | Address collision clk-to-clk delay for reliable read access after write on same address - Applicable to Opening Edge | 0.35 | ns |
| $t_{C2CWRH}$[1] | Address collision clk-to-clk delay for reliable write access after read on same address - Applicable to Opening Edge | 0.42 | ns |
| $t_{RSTBQ}$ | RESET Low to data out Low on RD (flow-through) | 2.06 | ns |
| | RESET Low to data out Low on RD (pipelined) | 2.06 | ns |
| $t_{REMRSTB}$ | RESET removal | 0.61 | ns |
| $t_{RECRSTB}$ | RESET recovery | 3.21 | ns |
| $t_{MPWRSTB}$ | RESET minimum pulse width | 0.68 | ns |
| $t_{CYC}$ | Clock cycle time | 6.24 | ns |
| $F_{MAX}$ | Maximum frequency | 160 | MHz |

*Notes:*

1. *For more information, refer to the application note* Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

***Table 2-193* • RAM4K9**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{AS}$ | Address setup time | 1.53 | ns |
| $t_{AH}$ | Address hold time | 0.29 | ns |
| $t_{ENS}$ | REN WEN setup time | 1.50 | ns |
| $t_{ENH}$ | REN, WEN hold time | 0.29 | ns |
| $t_{BKS}$ | BLK setup time | 3.05 | ns |
| $t_{BKH}$ | BLK hold time | 0.29 | ns |
| $t_{DS}$ | Input data (DIN) setup time | 1.33 | ns |
| $t_{DH}$ | Input data (DIN) hold time | 0.66 | ns |
| $t_{CKQ1}$ | Clock High to new data valid on DOUT (output retained, WMODE = 0) | 6.61 | ns |
| | Clock High to new data valid on DOUT (flow-through, WMODE = 1) | 5.72 | ns |
| $t_{CKQ2}$ | Clock High to new data valid on DOUT (pipelined) | 3.38 | ns |
| $t_{C2CWWL}$[1] | Address collision clk-to-clk delay for reliable write after write on same address – Applicable to Closing Edge | 0.30 | ns |
| $t_{C2CRWH}$[1] | Address collision clk-to-clk delay for reliable read access after write on same address – Applicable to Opening Edge | 0.89 | ns |
| $t_{C2CWRH}$[1] | Address collision clk-to-clk delay for reliable write access after read on same address – Applicable to Opening Edge | 1.01 | ns |
| $t_{RSTBQ}$ | RESET Low to data out Low on DOUT (flow-through) | 3.86 | ns |
| | RESET Low to data out Low on DOUT (pipelined) | 3.86 | ns |
| $t_{REMRSTB}$ | RESET removal | 1.12 | ns |
| $t_{RECRSTB}$ | RESET recovery | 5.93 | ns |
| $t_{MPWRSTB}$ | RESET minimum pulse width | 1.18 | ns |
| $t_{CYC}$ | Clock cycle time | 10.90 | ns |
| $F_{MAX}$ | Maximum frequency | 92 | MHz |

*Notes:*

1. *For more information, refer to the application note* Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs*.*
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

**Table 2-194 • RAM512X18**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{AS}$ | Address setup time | 1.53 | ns |
| $t_{AH}$ | Address hold time | 0.29 | ns |
| $t_{ENS}$ | REN, WEN setup time | 1.36 | ns |
| $t_{ENH}$ | REN, WEN hold time | 0.15 | ns |
| $t_{DS}$ | Input data (WD) setup time | 1.33 | ns |
| $t_{DH}$ | Input data (WD) hold time | 0.66 | ns |
| $t_{CKQ1}$ | Clock High to new data valid on RD (output retained) | 7.88 | ns |
| $t_{CKQ2}$ | Clock High to new data valid on RD (pipelined) | 3.20 | ns |
| $t_{C2CRWH}$[1] | Address collision clk-to-clk delay for reliable read access after write on same address – Applicable to Opening Edge | 0.87 | ns |
| $t_{C2CWRH}$[1] | Address collision clk-to-clk delay for reliable write access after read on same address – Applicable to Opening Edge | 1.04 | ns |
| $t_{RSTBQ}$ | RESET Low to data out Low on RD (flow through) | 3.86 | ns |
| | RESET Low to data out Low on RD (pipelined) | 3.86 | ns |
| $t_{REMRSTB}$ | RESET removal | 1.12 | ns |
| $t_{RECRSTB}$ | RESET recovery | 5.93 | ns |
| $t_{MPWRSTB}$ | RESET minimum pulse width | 1.18 | ns |
| $t_{CYC}$ | Clock cycle time | 10.90 | ns |
| $F_{MAX}$ | Maximum frequency | 92 | MHz |

*Notes:*

1. *For more information, refer to the application note* Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
2. *For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

## FIFO

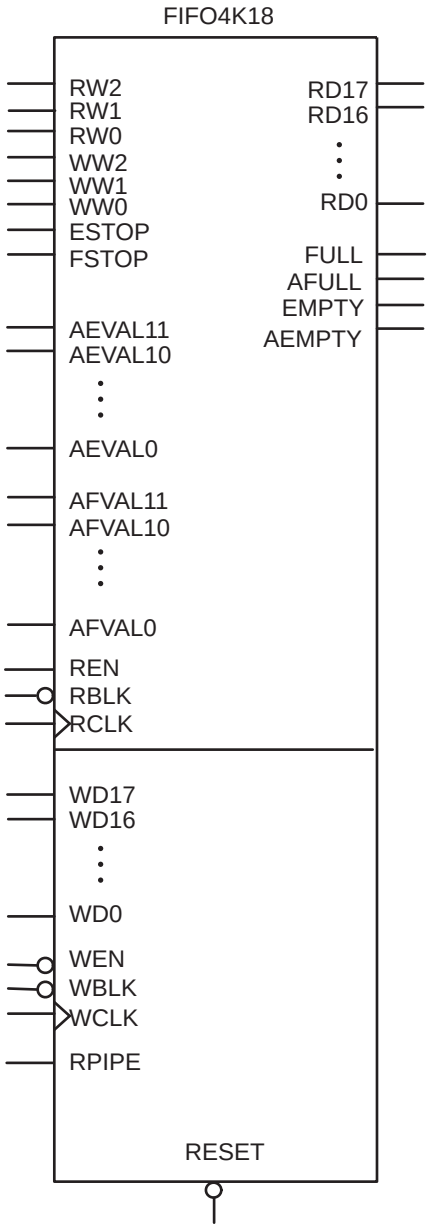



***Figure 2-37 •*** **FIFO Model**

### Timing Waveforms

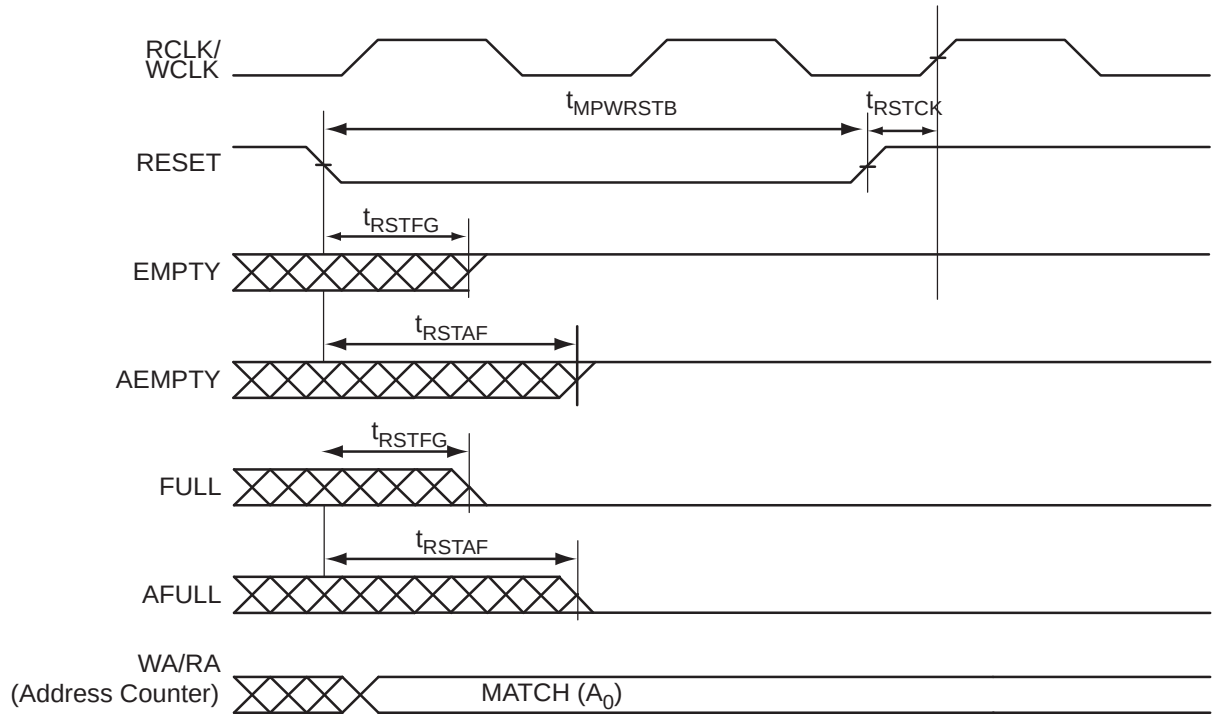



***Figure 2-38 •*** **FIFO Reset**

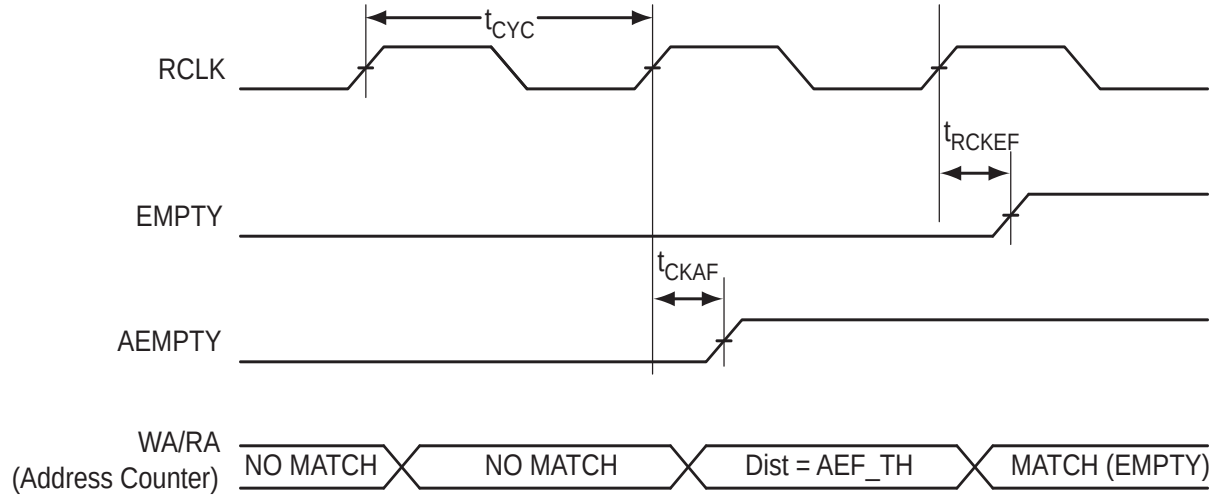



***Figure 2-39 •*** **FIFO EMPTY Flag and AEMPTY Flag Assertion**

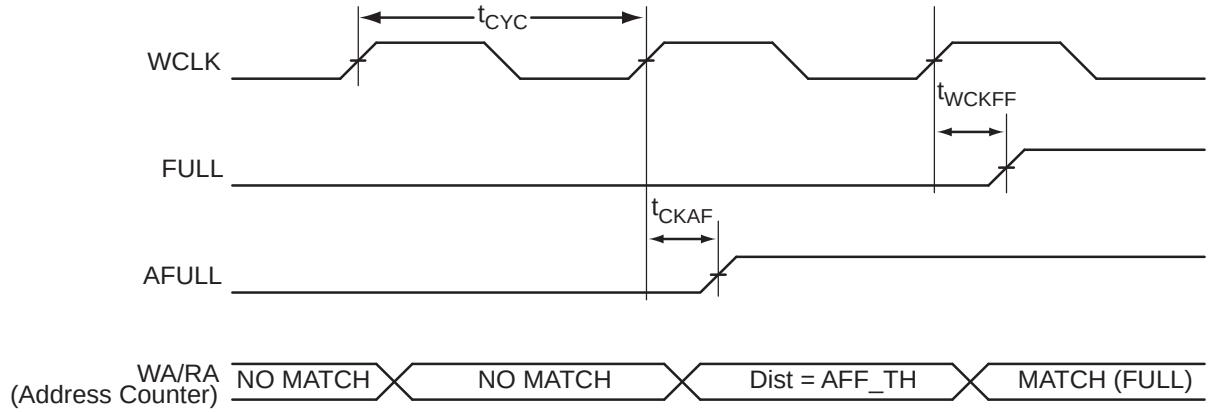



***Figure 2-40 •*** **FIFO FULL Flag and AFULL Flag Assertion**

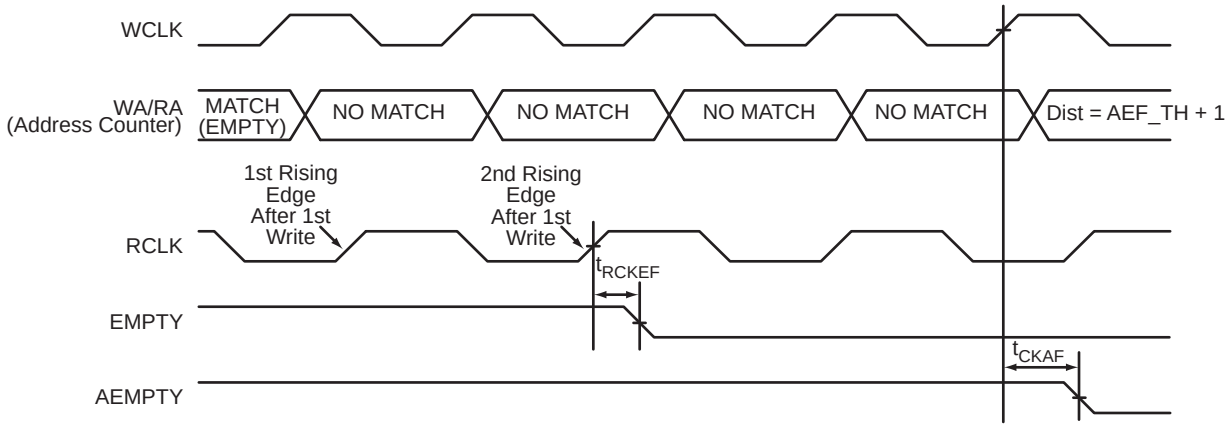



***Figure 2-41 •*** **FIFO EMPTY Flag and AEMPTY Flag Deassertion**

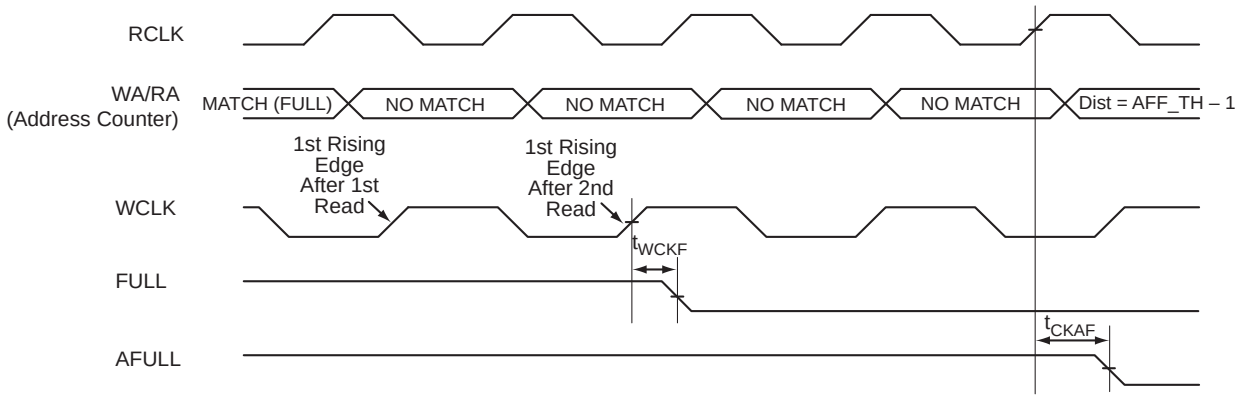



***Figure 2-42 •*** **FIFO FULL Flag and AFULL Flag Deassertion**

## Timing Characteristics

### 1.5 V DC Core Voltage

**Table 2-195 • FIFO**

**Worst Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{ENS}$ | REN, WEN Setup Time | 1.99 | ns |
| $t_{ENH}$ | REN, WEN Hold Time | 0.16 | ns |
| $t_{BKS}$ | BLK Setup Time | 0.30 | ns |
| $t_{BKH}$ | BLK Hold Time | 0.00 | ns |
| $t_{DS}$ | Input Data (WD) Setup Time | 0.76 | ns |
| $t_{DH}$ | Input Data (WD) Hold Time | 0.25 | ns |
| $t_{CKQ1}$ | Clock High to New Data Valid on RD (flow-through) | 3.33 | ns |
| $t_{CKQ2}$ | Clock High to New Data Valid on RD (pipelined) | 1.80 | ns |
| $t_{RCKEF}$ | RCLK High to Empty Flag Valid | 3.53 | ns |
| $t_{WCKFF}$ | WCLK High to Full Flag Valid | 3.35 | ns |
| $t_{CKAF}$ | Clock High to Almost Empty/Full Flag Valid | 12.85 | ns |
| $t_{RSTFG}$ | RESET Low to Empty/Full Flag Valid | 3.48 | ns |
| $t_{RSTAF}$ | RESET Low to Almost Empty/Full Flag Valid | 12.72 | ns |
| $t_{RSTBQ}$ | RESET Low to Data Out Low on RD (flow-through) | 2.02 | ns |
| | RESET Low to Data Out Low on RD (pipelined) | 2.02 | ns |
| $t_{REMRSTB}$ | RESET Removal | 0.61 | ns |
| $t_{RECRSTB}$ | RESET Recovery | 3.21 | ns |
| $t_{MPWRSTB}$ | RESET Minimum Pulse Width | 0.68 | ns |
| $t_{CYC}$ | Clock Cycle Time | 6.24 | ns |
| $F_{MAX}$ | Maximum Frequency for FIFO | 160 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

### 1.2 V DC Core Voltage

***Table 2-196* • FIFO**
**Worst Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{ENS}$ | REN, WEN Setup Time | 4.13 | ns |
| $t_{ENH}$ | REN, WEN Hold Time | 0.31 | ns |
| $t_{BKS}$ | BLK Setup Time | 0.47 | ns |
| $t_{BKH}$ | BLK Hold Time | 0.00 | ns |
| $t_{DS}$ | Input Data (WD) Setup Time | 1.56 | ns |
| $t_{DH}$ | Input Data (WD) Hold Time | 0.49 | ns |
| $t_{CKQ1}$ | Clock High to New Data Valid on RD (flow-through) | 6.80 | ns |
| $t_{CKQ2}$ | Clock High to New Data Valid on RD (pipelined) | 3.62 | ns |
| $t_{RCKEF}$ | RCLK High to Empty Flag Valid | 7.23 | ns |
| $t_{WCKFF}$ | WCLK High to Full Flag Valid | 6.85 | ns |
| $t_{CKAF}$ | Clock High to Almost Empty/Full Flag Valid | 26.61 | ns |
| $t_{RSTFG}$ | RESET Low to Empty/Full Flag Valid | 7.12 | ns |
| $t_{RSTAF}$ | RESET Low to Almost Empty/Full Flag Valid | 26.33 | ns |
| $t_{RSTBQ}$ | RESET Low to Data Out Low on RD (flow-through) | 4.09 | ns |
| | RESET Low to Data Out Low on RD (pipelined) | 4.09 | ns |
| $t_{REMRSTB}$ | RESET Removal | 1.23 | ns |
| $t_{RECRSTB}$ | RESET Recovery | 6.58 | ns |
| $t_{MPWRSTB}$ | RESET Minimum Pulse Width | 1.18 | ns |
| $t_{CYC}$ | Clock Cycle Time | 10.90 | ns |
| $F_{MAX}$ | Maximum Frequency for FIFO | 92 | MHz |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.*

# Embedded FlashROM Characteristics

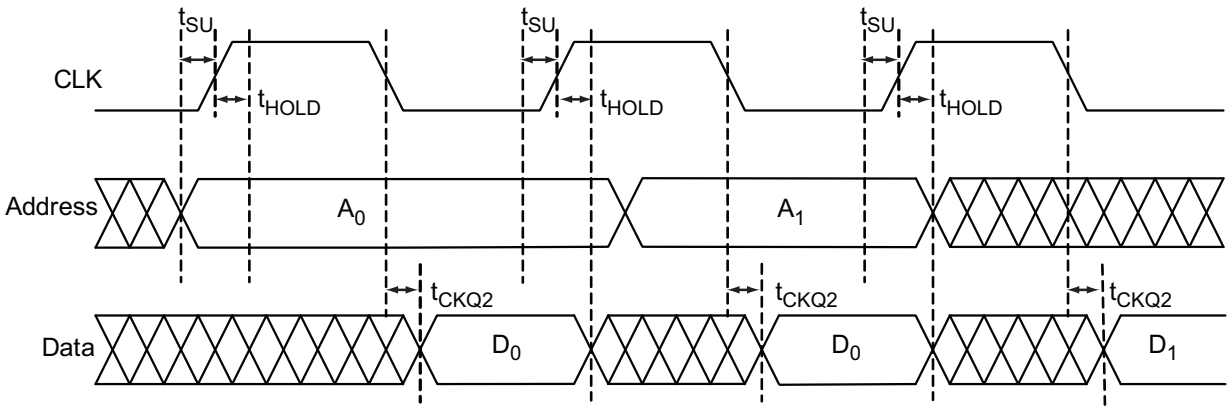



***Figure 2-43 •*** **Timing Diagram**

## Timing Characteristics

### 1.5 V DC Core Voltage

***Table 2-197 •*** **Embedded FlashROM Access Time**
**Worst Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{SU}$ | Address Setup Time | 0.57 | ns |
| $t_{HOLD}$ | Address Hold Time | 0.00 | ns |
| $t_{CK2Q}$ | Clock to Out | 34.14 | ns |
| $F_{MAX}$ | Maximum Clock Frequency | 15 | MHz |

### 1.2 V DC Core Voltage

***Table 2-198 •*** **Embedded FlashROM Access Time**
**Worst Commercial-Case Conditions: $T_J$ = 70°C, VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{SU}$ | Address Setup Time | 0.59 | ns |
| $t_{HOLD}$ | Address Hold Time | 0.00 | ns |
| $t_{CK2Q}$ | Clock to Out | 52.90 | ns |
| $F_{MAX}$ | Maximum Clock Frequency | 10 | MHz |

# JTAG 1532 Characteristics

JTAG timing delays do not include JTAG I/Os. To obtain complete JTAG timing, add I/O buffer delays to the corresponding standard selected; refer to the I/O timing characteristics in the "User I/O Characteristics" section on page 2-20 for more details.

## Timing Characteristics

***Table 2-199 •*** **JTAG 1532**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.425 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DISU}$ | Test Data Input Setup Time | 1.00 | ns |
| $t_{DIHD}$ | Test Data Input Hold Time | 2.00 | ns |
| $t_{TMSSU}$ | Test Mode Select Setup Time | 1.00 | ns |
| $t_{TMDHD}$ | Test Mode Select Hold Time | 2.00 | ns |
| $t_{TCK2Q}$ | Clock to Q (data out) | 8.00 | ns |
| $t_{RSTB2Q}$ | Reset to Q (data out) | 25.00 | ns |
| $F_{TCKMAX}$ | TCK Maximum Frequency | 15 | MHz |
| $t_{TRSTREM}$ | ResetB Removal Time | 0.58 | ns |
| $t_{TRSTREC}$ | ResetB Recovery Time | 0.00 | ns |
| $t_{TRSTMPW}$ | ResetB Minimum Pulse | TBD | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

***Table 2-200 •*** **JTAG 1532**
**Commercial-Case Conditions: $T_J$ = 70°C, Worst-Case VCC = 1.14 V**

| Parameter | Description | Std. | Units |
|---|---|---|---|
| $t_{DISU}$ | Test Data Input Setup Time | 1.50 | ns |
| $t_{DIHD}$ | Test Data Input Hold Time | 3.00 | ns |
| $t_{TMSSU}$ | Test Mode Select Setup Time | 1.50 | ns |
| $t_{TMDHD}$ | Test Mode Select Hold Time | 3.00 | ns |
| $t_{TCK2Q}$ | Clock to Q (data out) | 11.00 | ns |
| $t_{RSTB2Q}$ | Reset to Q (data out) | 30.00 | ns |
| $F_{TCKMAX}$ | TCK Maximum Frequency | 9.00 | MHz |
| $t_{TRSTREM}$ | ResetB Removal Time | 1.18 | ns |
| $t_{TRSTREC}$ | ResetB Recovery Time | 0.00 | ns |
| $t_{TRSTMPW}$ | ResetB Minimum Pulse | TBD | ns |

*Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.*

# 3 – Pin Descriptions

## Supply Pins

**GND** **Ground**

Ground supply voltage to the core, I/O outputs, and I/O logic.

**GNDQ** **Ground (quiet)**

Quiet ground supply voltage to input buffers of I/O banks. Within the package, the GNDQ plane is decoupled from the simultaneous switching noise originated from the output buffer ground domain. This minimizes the noise transfer within the package and improves input signal integrity. GNDQ must always be connected to GND on the board.

**VCC** **Core Supply Voltage**

Supply voltage to the FPGA core, nominally 1.5 V for IGLOO V5 devices, and 1.2 V or 1.5 V for IGLOO V2 devices. VCC is required for powering the JTAG state machine in addition to VJTAG. Even when a device is in bypass mode in a JTAG chain of interconnected devices, both VCC and VJTAG must remain powered to allow JTAG signals to pass through the device.

For IGLOO V2 devices, VCC can be switched dynamically from 1.2 V to 1.5 V or vice versa. This allows in-system programming (ISP) when VCC is at 1.5 V and the benefit of low power operation when VCC is at 1.2 V.

**VCCIBx** **I/O Supply Voltage**

Supply voltage to the bank's I/O output buffers and I/O logic. Bx is the I/O bank number. There are up to eight I/O banks on IGLOO devices plus a dedicated VJTAG bank. Each bank can have a separate VCCI connection. All I/Os in a bank will run off the same VCCIBx supply. VCCI can be 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V, nominal voltage. Unused I/O banks should have their corresponding VCCI pins tied to GND.

**VMVx** **I/O Supply Voltage (quiet)**

Quiet supply voltage to the input buffers of each I/O bank. *x* is the bank number. Within the package, the VMV plane is decoupled from the simultaneous switching noise originating from the output buffer VCCI domain. This minimizes the noise transfer within the package and improves input signal integrity. Each bank must have at least one VMV connection, and no VMV should be left unconnected. All I/Os in a bank run off the same VMVx supply. VMV is used to provide a quiet supply voltage to the input buffers of each I/O bank. VMVx can be 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V, nominal voltage. Unused I/O banks should have their corresponding VMV pins tied to GND. VMV and VCCI should be at the same voltage within a given I/O bank. Used VMV pins must be connected to the corresponding VCCI pins of the same bank (i.e., VMV0 to VCCIB0, VMV1 to VCCIB1, etc.).

**VCCPLA/B/C/D/E/F** **PLL Supply Voltage**

Supply voltage to analog PLL, nominally 1.5 V or 1.2 V.

- 1.5 V for IGLOO V5 devices
- 1.2 V or 1.5 V for IGLOO V2 devices

When the PLLs are not used, the Microsemi Designer place-and-route tool automatically disables the unused PLLs to lower power consumption. The user should tie unused VCCPLx and VCOMPLx pins to ground. Microsemi recommends tying VCCPLx to VCC and using proper filtering circuits to decouple VCC noise from the PLLs. Refer to the PLL Power Supply Decoupling section of the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed Signal FPGAs" chapter of the *IGLOO FPGA Fabric User's Guide* for a complete board solution for the PLL analog power supply and ground.

- There is one VCCPLF pin on IGLOO devices.

**VCOMPLA/B/C/D/E/F** **PLL Ground**

Ground to analog PLL power supplies. When the PLLs are not used, the Microsemi Designer place-and-route tool automatically disables the unused PLLs to lower power consumption. The user should tie unused VCCPLx and VCOMPLx pins to ground.

There is one VCOMPLF pin on IGLOO devices.

### VJTAG JTAG Supply Voltage

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND. It should be noted that VCC is required to be powered for JTAG operation; VJTAG alone is insufficient. If a device is in a JTAG chain of interconnected boards, the board containing the device can be powered down, provided both VJTAG and VCC to the part remain powered; otherwise, JTAG signals will not be able to transition the device, even in bypass mode.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

### VPUMP Programming Supply Voltage

IGLOO devices support single-voltage ISP of the configuration flash and FlashROM. For programming, VPUMP should be 3.3 V nominal. During normal device operation, VPUMP can be left floating or can be tied (pulled up) to any voltage between 0 V and the VPUMP maximum. Programming power supply voltage (VPUMP) range is listed in the datasheet.

When the VPUMP pin is tied to ground, it will shut off the charge pump circuitry, resulting in no sources of oscillation from the charge pump circuitry.

For proper programming, 0.01 µF and 0.33 µF capacitors (both rated at 16 V) are to be connected in parallel across VPUMP and GND, and positioned as close to the FPGA pins as possible.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

## User Pins

### I/O User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with the I/O standard selected.

During programming, I/Os become tristated and weakly pulled up to VCCI. With VCCI, VMV, and VCC supplies continuously powered up, when the device transitions from programming to operating mode, the I/Os are instantly configured to the desired user configuration.

Unused I/Os are configured as follows:

- Output buffer is disabled (with tristate value of high impedance)
- Input buffer is disabled (with tristate value of high impedance)
- Weak pull-up is programmed

### GL Globals

GL I/Os have access to certain clock conditioning circuitry (and the PLL) and/or have direct access to the global network (spines). Additionally, the global I/Os can be used as regular I/Os, since they have identical capabilities. Unused GL pins are configured as inputs with pull-up resistors.

See more detailed descriptions of global I/O connectivity in the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed Signal FPGAs" chapter of the *IGLOO FPGA Fabric User's Guide*. All inputs labeled GC/GF are direct inputs into the quadrant clocks. For example, if GAA0 is used for an input, GAA1 and GAA2 are no longer available for input to the quadrant globals. All inputs labeled GC/GF are direct inputs into the chip-level globals, and the rest are connected to the quadrant globals. The inputs to the global network are multiplexed, and only one input can be used as a global input.

Refer to the "I/O Structures in IGLOO and ProASIC3 Devices" chapter of the *IGLOO FPGA Fabric User's Guide* for an explanation of the naming of global pins.

### FF Flash*Freeze Mode Activation Pin

Flash*Freeze mode is available on IGLOO devices. The FF pin is a dedicated input pin used to enter and exit Flash*Freeze mode. The FF pin is active low, has the same characteristics as a single-ended I/O, and must meet the maximum rise and fall times. When Flash*Freeze mode is not used in the design, the FF pin is available as a regular I/O.

When Flash*Freeze mode is used, the FF pin must not be left floating to avoid accidentally entering Flash*Freeze mode. While in Flash*Freeze mode, the Flash*Freeze pin should be constantly asserted.

The Flash*Freeze pin can be used with any single-ended I/O standard supported by the I/O bank in which the pin is located, and input signal levels compatible with the I/O standard selected. The FF pin should be treated as a sensitive asynchronous signal. When defining pin placement and board layout, simultaneously switching outputs (SSOs) and their effects on sensitive asynchronous pins must be considered.

Unused FF or I/O pins are tristated with weak pull-up. This default configuration applies to both Flash*Freeze mode and normal operation mode. No user intervention is required.

Table 3-1 shows the Flash*Freeze pin location on the available packages for IGLOO a devices. The Flash*Freeze pin location is independent of device, allowing migration to larger or smaller IGLOO devices while maintaining the same pin location on the board. Refer to the "Flash*Freeze Technology and Low Power Modes" chapter of the *IGLOO FPGA Fabric User's Guide* for more information on I/O states during Flash*Freeze mode.

***Table 3-1* • Flash*Freeze Pin Location in IGLOO Family Packages (device-independent)**

| IGLOO Packages | Flash*Freeze Pin |
|---|---|
| CS81/UC81 | H2 |
| CS121 | J5 |
| CS196 | P3 |
| CS281 | W2 |
| QN48 | 14 |
| QN68 | 18 |
| QN132 | B12 |
| VQ100 | 27 |
| FG144 | L3 |
| FG256 | T3 |
| FG484 | W6 |

# JTAG Pins

IGLOO devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

### TCK Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/-down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 Ω to 1 kΩ will satisfy the requirements. Refer to Table 3-2 for more information.

***Table 3-2* • Recommended Tie-Off Values for the TCK and TRST Pins**

| VJTAG | Tie-Off Resistance [1,2] |
|---|---|
| VJTAG at 3.3 V | 200 Ω to 1 kΩ |
| VJTAG at 2.5 V | 200 Ω to 1 kΩ |
| VJTAG at 1.8 V | 500 Ω to 1 kΩ |
| VJTAG at 1.5 V | 500 Ω to 1 kΩ |

*Notes:*

1. *The TCK pin can be pulled-up or pulled-down.*
2. *The TRST pin is pulled-down.*
3. *Equivalent parallel resistance if more than one device is on the JTAG chain*

***Table 3-3* • TRST and TCK Pull-Down Recommendations**

| VJTAG | Tie-Off Resistance* |
|---|---|
| VJTAG at 3.3 V | 200 Ω to 1 kΩ |
| VJTAG at 2.5 V | 200 Ω to 1 kΩ |
| VJTAG at 1.8 V | 500 Ω to 1 kΩ |
| VJTAG at 1.5 V | 500 Ω to 1 kΩ |

*Note: Equivalent parallel resistance if more than one device is on the JTAG chain*

### TDI Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

### TDO Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

### TMS Test Mode Select

The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

### TRST Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from Table 3-2 and must satisfy the parallel resistance value requirement. The values in Table 3-2 correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

In critical applications, an upset in the JTAG circuit could allow entrance to an undesired JTAG state. In such cases, Microsemi recommends tying off TRST to GND through a resistor placed close to the FPGA pin.

Note that to operate at all VJTAG voltages, 500 Ω to 1 kΩ will satisfy the requirements.

# Special Function Pins

**NC** **No Connect**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

**DC** **Do Not Connect**

This pin should not be connected to any signals on the PCB. These pins should be left unconnected.

# Packaging

Semiconductor technology is constantly shrinking in size while growing in capability and functional integration. To enable next-generation silicon technologies, semiconductor packages have also evolved to provide improved performance and flexibility.

Microsemi consistently delivers packages that provide the necessary mechanical and environmental protection to ensure consistent reliability and performance. Microsemi IC packaging technology efficiently supports high-density FPGAs with large-pin-count Ball Grid Arrays (BGAs), but is also flexible enough to accommodate stringent form factor requirements for Chip Scale Packaging (CSP). In addition, Microsemi offers a variety of packages designed to meet your most demanding application and economic requirements for today's embedded and mobile systems.

# Related Documents

## User’s Guides

*IGLOO FPGA Fabric User’s Guide*

http://www.microsemi.com/soc/documents/IGLOO_UG.pdf

## Packaging Documents

The following documents provide packaging information and device selection for low power flash devices.

### *Product Catalog*

http://www.microsemi.com/soc/documents/ProdCat_PIB.pdf

Lists devices currently recommended for new designs and the packages available for each member of the family. Use this document or the datasheet tables to determine the best package for your design, and which package drawing to use.

### *Package Mechanical Drawings*

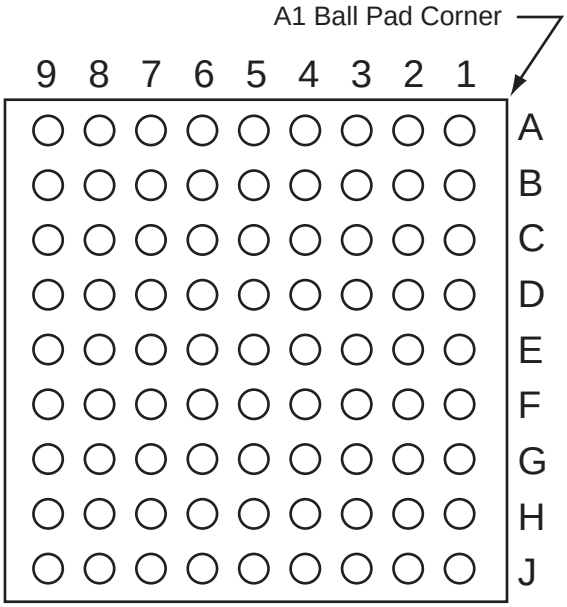
http://www.microsemi.com/soc/documents/PckgMechDrwngs.pdf

This document contains the package mechanical drawings for all packages currently or previously supplied by Microsemi. Use the bookmarks to navigate to the package mechanical drawings.

Additional packaging materials are available on the Microsemi SoC Products Group website at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

# 4 – Package Pin Assignments

## UC81




*Note: This is the bottom view of the package.*

### Note

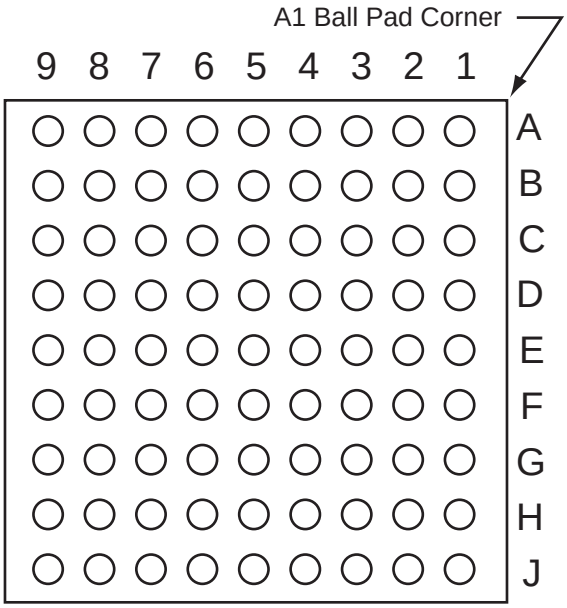
For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| UC81 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| A1 | IO00RSB0 |
| A2 | IO02RSB0 |
| A3 | IO06RSB0 |
| A4 | IO11RSB0 |
| A5 | IO16RSB0 |
| A6 | IO19RSB0 |
| A7 | IO22RSB0 |
| A8 | IO24RSB0 |
| A9 | IO26RSB0 |
| B1 | IO81RSB1 |
| B2 | IO04RSB0 |
| B3 | IO10RSB0 |
| B4 | IO13RSB0 |
| B5 | IO15RSB0 |
| B6 | IO20RSB0 |
| B7 | IO21RSB0 |
| B8 | IO28RSB0 |
| B9 | IO25RSB0 |
| C1 | IO79RSB1 |
| C2 | IO80RSB1 |
| C3 | IO08RSB0 |
| C4 | IO12RSB0 |
| C5 | IO17RSB0 |
| C6 | IO14RSB0 |
| C7 | IO18RSB0 |
| C8 | IO29RSB0 |
| C9 | IO27RSB0 |
| D1 | IO74RSB1 |
| D2 | IO76RSB1 |
| D3 | IO77RSB1 |
| D4 | VCC |
| D5 | VCCIB0 |
| D6 | GND |
| D7 | IO23RSB0 |
| D8 | IO31RSB0 |
| D9 | IO30RSB0 |

| UC81 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| E1 | GEB0/IO71RSB1 |
| E2 | GEA0/IO72RSB1 |
| E3 | GEC0/IO73RSB1 |
| E4 | VCCIB1 |
| E5 | VCC |
| E6 | VCCIB0 |
| E7 | GDC0/IO32RSB0 |
| E8 | GDA0/IO33RSB0 |
| E9 | GDB0/IO34RSB0 |
| F1 | IO68RSB1 |
| F2 | IO67RSB1 |
| F3 | IO64RSB1 |
| F4 | GND |
| F5 | VCCIB1 |
| F6 | IO47RSB1 |
| F7 | IO36RSB0 |
| F8 | IO38RSB0 |
| F9 | IO40RSB0 |
| G1 | IO65RSB1 |
| G2 | IO66RSB1 |
| G3 | IO57RSB1 |
| G4 | IO53RSB1 |
| G5 | IO49RSB1 |
| G6 | IO45RSB1 |
| G7 | IO46RSB1 |
| G8 | VJTAG |
| G9 | TRST |
| H1 | IO62RSB1 |
| H2 | FF/IO60RSB1 |
| H3 | IO58RSB1 |
| H4 | IO54RSB1 |
| H5 | IO48RSB1 |
| H6 | IO43RSB1 |
| H7 | IO42RSB1 |
| H8 | TDI |
| H9 | TDO |

| UC81 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| J1 | IO63RSB1 |
| J2 | IO61RSB1 |
| J3 | IO59RSB1 |
| J4 | IO56RSB1 |
| J5 | IO52RSB1 |
| J6 | IO44RSB1 |
| J7 | TCK |
| J8 | TMS |
| J9 | VPUMP |

# CS81




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| CS81 | |
|---|---|
| Pin Number | AGL030 Function |
| A1 | IO00RSB0 |
| A2 | IO02RSB0 |
| A3 | IO06RSB0 |
| A4 | IO11RSB0 |
| A5 | IO16RSB0 |
| A6 | IO19RSB0 |
| A7 | IO22RSB0 |
| A8 | IO24RSB0 |
| A9 | IO26RSB0 |
| B1 | IO81RSB1 |
| B2 | IO04RSB0 |
| B3 | IO10RSB0 |
| B4 | IO13RSB0 |
| B5 | IO15RSB0 |
| B6 | IO20RSB0 |
| B7 | IO21RSB0 |
| B8 | IO28RSB0 |
| B9 | IO25RSB0 |
| C1 | IO79RSB1 |
| C2 | IO80RSB1 |
| C3 | IO08RSB0 |
| C4 | IO12RSB0 |
| C5 | IO17RSB0 |
| C6 | IO14RSB0 |
| C7 | IO18RSB0 |
| C8 | IO29RSB0 |
| C9 | IO27RSB0 |
| D1 | IO74RSB1 |
| D2 | IO76RSB1 |
| D3 | IO77RSB1 |
| D4 | VCC |
| D5 | VCCIB0 |
| D6 | GND |
| D7 | IO23RSB0 |
| D8 | IO31RSB0 |
| D9 | IO30RSB0 |

| CS81 | |
|---|---|
| Pin Number | AGL030 Function |
| E1 | GEB0/IO71RSB1 |
| E2 | GEA0/IO72RSB1 |
| E3 | GEC0/IO73RSB1 |
| E4 | VCCIB1 |
| E5 | VCC |
| E6 | VCCIB0 |
| E7 | GDC0/IO32RSB0 |
| E8 | GDA0/IO33RSB0 |
| E9 | GDB0/IO34RSB0 |
| F1 | IO68RSB1 |
| F2 | IO67RSB1 |
| F3 | IO64RSB1 |
| F4 | GND |
| F5 | VCCIB1 |
| F6 | IO47RSB1 |
| F7 | IO36RSB0 |
| F8 | IO38RSB0 |
| F9 | IO40RSB0 |
| G1 | IO65RSB1 |
| G2 | IO66RSB1 |
| G3 | IO57RSB1 |
| G4 | IO53RSB1 |
| G5 | IO49RSB1 |
| G6 | IO44RSB1 |
| G7 | IO46RSB1 |
| G8 | VJTAG |
| G9 | TRST |
| H1 | IO62RSB1 |
| H2 | FF/IO60RSB1 |
| H3 | IO58RSB1 |
| H4 | IO54RSB1 |
| H5 | IO48RSB1 |
| H6 | IO43RSB1 |
| H7 | IO42RSB1 |
| H8 | TDI |
| H9 | TDO |

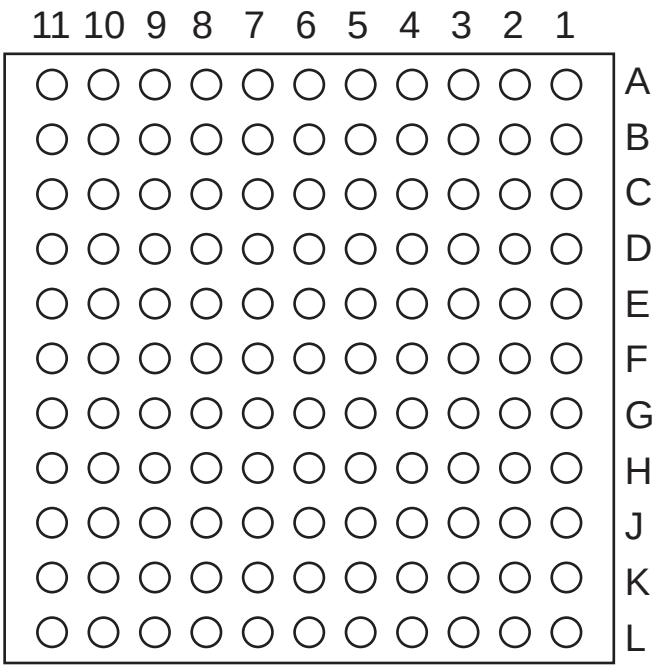
| CS81 | |
|---|---|
| Pin Number | AGL030 Function |
| J1 | IO63RSB1 |
| J2 | IO61RSB1 |
| J3 | IO59RSB1 |
| J4 | IO56RSB1 |
| J5 | IO52RSB1 |
| J6 | IO45RSB1 |
| J7 | TCK |
| J8 | TMS |
| J9 | VPUMP |

| CS81 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| A1 | GAA0/IO00RSB0 |
| A2 | GAA1/IO01RSB0 |
| A3 | GAC0/IO04RSB0 |
| A4 | IO13RSB0 |
| A5 | IO21RSB0 |
| A6 | IO27RSB0 |
| A7 | GBB0/IO37RSB0 |
| A8 | GBA1/IO40RSB0 |
| A9 | GBA2/IO41PPB1 |
| B1 | GAA2/IO118UPB3 |
| B2 | GAB0/IO02RSB0 |
| B3 | GAC1/IO05RSB0 |
| B4 | IO11RSB0 |
| B5 | IO23RSB0 |
| B6 | GBC0/IO35RSB0 |
| B7 | GBB1/IO38RSB0 |
| B8 | IO41NPB1 |
| B9 | GBB2/IO42PSB1 |
| C1 | GAB2/IO117UPB3 |
| C2 | IO118VPB3 |
| C3 | GND |
| C4 | IO15RSB0 |
| C5 | IO25RSB0 |
| C6 | GND |
| C7 | GBA0/IO39RSB0 |
| C8 | GBC2/IO43PDB1 |
| C9 | IO43NDB1 |
| D1 | GAC2/IO116USB3 |
| D2 | IO117VPB3 |
| D3 | GFA2/IO107PSB3 |
| D4 | VCC |
| D5 | VCCIB0 |
| D6 | GND |
| D7 | IO52NPB1 |
| D8 | GCC1/IO48PDB1 |
| D9 | GCC0/IO48NDB1 |

| CS81 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| E1 | GFB0/IO109NDB3 |
| E2 | GFB1/IO109PDB3 |
| E3 | GFA1/IO108PSB3 |
| E4 | VCCIB3 |
| E5 | VCC |
| E6 | VCCIB1 |
| E7 | GCA0/IO50NDB1 |
| E8 | GCA1/IO50PDB1 |
| E9 | GCB2/IO52PPB1 |
| F1 | VCCPLF |
| F2 | VCOMPLF |
| F3 | GND |
| F4 | GND |
| F5 | VCCIB2 |
| F6 | GND |
| F7 | GDA1/IO60USB1 |
| F8 | GDC1/IO58UDB1 |
| F9 | GDC0/IO58VDB1 |
| G1 | GEA0/IO98NDB3 |
| G2 | GEC1/IO100PDB3 |
| G3 | GEC0/IO100NDB3 |
| G4 | IO91RSB2 |
| G5 | IO86RSB2 |
| G6 | IO71RSB2 |
| G7 | GDB2/IO62RSB2 |
| G8 | VJTAG |
| G9 | TRST |
| H1 | GEA1/IO98PDB3 |
| H2 | FF/GEB2/IO96RSB2 |
| H3 | IO93RSB2 |
| H4 | IO90RSB2 |
| H5 | IO85RSB2 |
| H6 | IO77RSB2 |
| H7 | GDA2/IO61RSB2 |
| H8 | TDI |
| H9 | TDO |

| CS81 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| J1 | GEA2/IO97RSB2 |
| J2 | GEC2/IO95RSB2 |
| J3 | IO92RSB2 |
| J4 | IO88RSB2 |
| J5 | IO84RSB2 |
| J6 | IO74RSB2 |
| J7 | TCK |
| J8 | TMS |
| J9 | VPUMP |

# CS121




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

** Pin numbers F1 and G1 must be connected to ground because a PLL is not supported for AGL060-CS/G121.*

| CS121 | |
|---|---|
| Pin Number | AGL060 Function |
| A1 | GNDQ |
| A2 | IO01RSB0 |
| A3 | GAA1/IO03RSB0 |
| A4 | GAC1/IO07RSB0 |
| A5 | IO15RSB0 |
| A6 | IO13RSB0 |
| A7 | IO17RSB0 |
| A8 | GBB1/IO22RSB0 |
| A9 | GBA1/IO24RSB0 |
| A10 | GNDQ |
| A11 | VMV0 |
| B1 | GAA2/IO95RSB1 |
| B2 | IO00RSB0 |
| B3 | GAA0/IO02RSB0 |
| B4 | GAC0/IO06RSB0 |
| B5 | IO08RSB0 |
| B6 | IO12RSB0 |
| B7 | IO16RSB0 |
| B8 | GBC1/IO20RSB0 |
| B9 | GBB0/IO21RSB0 |
| B10 | GBB2/IO27RSB0 |
| B11 | GBA2/IO25RSB0 |
| C1 | IO89RSB1 |
| C2 | GAC2/IO91RSB1 |
| C3 | GAB1/IO05RSB0 |
| C4 | GAB0/IO04RSB0 |
| C5 | IO09RSB0 |
| C6 | IO14RSB0 |
| C7 | GBA0/IO23RSB0 |
| C8 | GBC0/IO19RSB0 |
| C9 | IO26RSB0 |
| C10 | IO28RSB0 |
| C11 | GBC2/IO29RSB0 |
| D1 | IO88RSB1 |
| D2 | IO90RSB1 |
| D3 | GAB2/IO93RSB1 |

| CS121 | |
|---|---|
| Pin Number | AGL060 Function |
| D4 | IO10RSB0 |
| D5 | IO11RSB0 |
| D6 | IO18RSB0 |
| D7 | IO32RSB0 |
| D8 | IO31RSB0 |
| D9 | GCA2/IO41RSB0 |
| D10 | IO30RSB0 |
| D11 | IO33RSB0 |
| E1 | IO87RSB1 |
| E2 | GFC0/IO85RSB1 |
| E3 | IO92RSB1 |
| E4 | IO94RSB1 |
| E5 | VCC |
| E6 | VCCIB0 |
| E7 | GND |
| E8 | GCC0/IO36RSB0 |
| E9 | IO34RSB0 |
| E10 | GCB1/IO37RSB0 |
| E11 | GCC1/IO35RSB0 |
| F1* | VCOMPLF |
| F2 | GFB0/IO83RSB1 |
| F3 | GFA0/IO82RSB1 |
| F4 | GFC1/IO86RSB1 |
| F5 | VCCIB1 |
| F6 | VCC |
| F7 | VCCIB0 |
| F8 | GCB2/IO42RSB0 |
| F9 | GCC2/IO43RSB0 |
| F10 | GCB0/IO38RSB0 |
| F11 | GCA1/IO39RSB0 |
| G1* | VCCPLF |
| G2 | GFB2/IO79RSB1 |
| G3 | GFA1/IO81RSB1 |
| G4 | GFB1/IO84RSB1 |
| G5 | GND |
| G6 | VCCIB1 |

| CS121 | |
|---|---|
| Pin Number | AGL060 Function |
| G7 | VCC |
| G8 | GDC0/IO46RSB0 |
| G9 | GDA1/IO49RSB0 |
| G10 | GDB0/IO48RSB0 |
| G11 | GCA0/IO40RSB0 |
| H1 | IO75RSB1 |
| H2 | IO76RSB1 |
| H3 | GFC2/IO78RSB1 |
| H4 | GFA2/IO80RSB1 |
| H5 | IO77RSB1 |
| H6 | GEC2/IO66RSB1 |
| H7 | IO54RSB1 |
| H8 | GDC2/IO53RSB1 |
| H9 | VJTAG |
| H10 | TRST |
| H11 | IO44RSB0 |
| J1 | GEC1/IO74RSB1 |
| J2 | GEC0/IO73RSB1 |
| J3 | GEB1/IO72RSB1 |
| J4 | GEA0/IO69RSB1 |
| J5 | FF/GEB2/IO67RSB1 |
| J6 | IO62RSB1 |
| J7 | GDA2/IO51RSB1 |
| J8 | GDB2/IO52RSB1 |
| J9 | TDI |
| J10 | TDO |
| J11 | GDC1/IO45RSB0 |
| K1 | GEB0/IO71RSB1 |
| K2 | GEA1/IO70RSB1 |
| K3 | GEA2/IO68RSB1 |
| K4 | IO64RSB1 |
| K5 | IO60RSB1 |
| K6 | IO59RSB1 |
| K7 | IO56RSB1 |
| K8 | TCK |
| K9 | TMS |

| CS121 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| K10 | VPUMP |
| K11 | GDB1/IO47RSB0 |
| L1 | VMV1 |
| L2 | GNDQ |
| L3 | IO65RSB1 |
| L4 | IO63RSB1 |
| L5 | IO61RSB1 |
| L6 | IO58RSB1 |
| L7 | IO57RSB1 |
| L8 | IO55RSB1 |
| L9 | GNDQ |
| L10 | GDA0/IO50RSB0 |
| L11 | VMV1 |

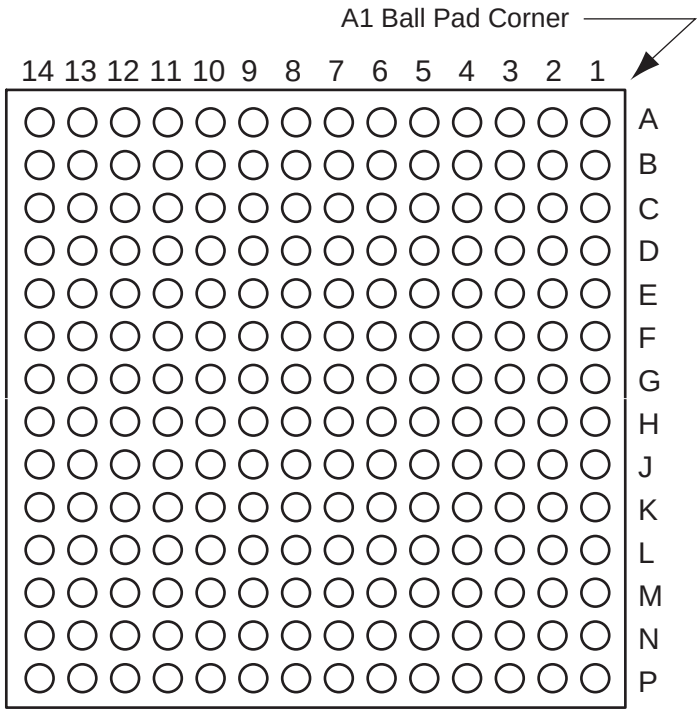
| CS121 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| A1 | GNDQ |
| A2 | IO09RSB0 |
| A3 | GAA1/IO01RSB0 |
| A4 | GAC1/IO05RSB0 |
| A5 | IO26RSB0 |
| A6 | IO22RSB0 |
| A7 | IO31RSB0 |
| A8 | GBB1/IO38RSB0 |
| A9 | GBA1/IO40RSB0 |
| A10 | GNDQ |
| A11 | VMV0 |
| B1 | GAA2/IO132RSB1 |
| B2 | IO07RSB0 |
| B3 | GAA0/IO00RSB0 |
| B4 | GAC0/IO04RSB0 |
| B5 | IO11RSB0 |
| B6 | IO20RSB0 |
| B7 | IO28RSB0 |
| B8 | GBC1/IO36RSB0 |
| B9 | GBB0/IO37RSB0 |
| B10 | GBB2/IO43RSB0 |
| B11 | GBA2/IO41RSB0 |
| C1 | IO126RSB1 |
| C2 | GAC2/IO128RSB1 |
| C3 | GAB1/IO03RSB0 |
| C4 | GAB0/IO02RSB0 |
| C5 | IO13RSB0 |
| C6 | IO24RSB0 |
| C7 | GBA0/IO39RSB0 |
| C8 | GBC0/IO35RSB0 |
| C9 | IO42RSB0 |
| C10 | IO44RSB0 |
| C11 | GBC2/IO45RSB0 |
| D1 | IO125RSB1 |
| D2 | IO127RSB1 |
| D3 | GAB2/IO130RSB1 |

| CS121 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| D4 | IO15RSB0 |
| D5 | IO18RSB0 |
| D6 | IO33RSB0 |
| D7 | IO48RSB0 |
| D8 | IO47RSB0 |
| D9 | GCA2/IO57RSB0 |
| D10 | IO46RSB0 |
| D11 | IO49RSB0 |
| E1 | IO124RSB1 |
| E2 | GFC0/IO122RSB1 |
| E3 | IO129RSB1 |
| E4 | IO131RSB1 |
| E5 | VCC |
| E6 | VCCIB0 |
| E7 | GND |
| E8 | GCC0/IO52RSB0 |
| E9 | IO50RSB0 |
| E10 | GCB1/IO53RSB0 |
| E11 | GCC1/IO51RSB0 |
| F1 | VCOMPLF |
| F2 | GFB0/IO120RSB1 |
| F3 | GFA0/IO119RSB1 |
| F4 | GFC1/IO123RSB1 |
| F5 | VCCIB1 |
| F6 | VCC |
| F7 | VCCIB0 |
| F8 | GCB2/IO58RSB0 |
| F9 | GCC2/IO59RSB0 |
| F10 | GCB0/IO54RSB0 |
| F11 | GCA1/IO55RSB0 |
| G1 | VCCPLF |
| G2 | GFB2/IO116RSB1 |
| G3 | GFA1/IO118RSB1 |
| G4 | GFB1/IO121RSB1 |
| G5 | GND |
| G6 | VCCIB1 |

| CS121 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| G7 | VCC |
| G8 | GDC0/IO62RSB0 |
| G9 | GDA1/IO65RSB0 |
| G10 | GDB0/IO64RSB0 |
| G11 | GCA0/IO56RSB0 |
| H1 | IO112RSB1 |
| H2 | IO113RSB1 |
| H3 | GFC2/IO115RSB1 |
| H4 | GFA2/IO117RSB1 |
| H5 | IO114RSB1 |
| H6 | GEC2/IO101RSB1 |
| H7 | IO71RSB1 |
| H8 | GDC2/IO69RSB1 |
| H9 | VJTAG |
| H10 | TRST |
| H11 | IO60RSB0 |
| J1 | GEC1/IO109RSB1 |
| J2 | GEC0/IO108RSB1 |
| J3 | GEB1/IO107RSB1 |
| J4 | GEA0/IO104RSB1 |
| J5 | FF/GEB2/IO102RSB1 |
| J6 | IO91RSB1 |
| J7 | GDA2/IO67RSB1 |
| J8 | GDB2/IO68RSB1 |
| J9 | TDI |
| J10 | TDO |
| J11 | GDC1/IO61RSB0 |
| K1 | GEB0/IO106RSB1 |
| K2 | GEA1/IO105RSB1 |
| K3 | GEA2/IO103RSB1 |
| K4 | IO95RSB1 |
| K5 | IO85RSB1 |
| K6 | IO83RSB1 |
| K7 | IO77RSB1 |
| K8 | TCK |
| K9 | TMS |

| CS121 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| K10 | VPUMP |
| K11 | GDB1/IO63RSB0 |
| L1 | VMV1 |
| L1 | VMV1 |
| L2 | GNDQ |
| L3 | IO99RSB1 |
| L4 | IO93RSB1 |
| L5 | IO87RSB1 |
| L6 | IO81RSB1 |
| L7 | IO79RSB1 |
| L8 | IO73RSB1 |
| L9 | GNDQ |
| L10 | GDA0/IO66RSB0 |
| L11 | VMV1 |

# CS196




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| CS196 | |
|---|---|
| Pin Number | AGL125 Function |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAC0/IO04RSB0 |
| A4 | GAC1/IO05RSB0 |
| A5 | IO09RSB0 |
| A6 | IO15RSB0 |
| A7 | IO18RSB0 |
| A8 | IO22RSB0 |
| A9 | IO27RSB0 |
| A10 | GBC0/IO35RSB0 |
| A11 | GBB0/IO37RSB0 |
| A12 | GBB1/IO38RSB0 |
| A13 | GBA1/IO40RSB0 |
| A14 | GND |
| B1 | VCCIB1 |
| B2 | VMV0 |
| B3 | GAA1/IO01RSB0 |
| B4 | GAB1/IO03RSB0 |
| B5 | GND |
| B6 | IO16RSB0 |
| B7 | IO20RSB0 |
| B8 | IO24RSB0 |
| B9 | IO28RSB0 |
| B10 | GND |
| B11 | GBC1/IO36RSB0 |
| B12 | GBA0/IO39RSB0 |
| B13 | GBA2/IO41RSB0 |
| B14 | GBB2/IO43RSB0 |
| C1 | GAC2/IO128RSB1 |
| C2 | GAB2/IO130RSB1 |
| C3 | GNDQ |
| C4 | VCCIB0 |
| C5 | GAB0/IO02RSB0 |
| C6 | IO14RSB0 |
| C7 | VCCIB0 |
| C8 | NC |

| CS196 | |
|---|---|
| Pin Number | AGL125 Function |
| C9 | IO23RSB0 |
| C10 | IO29RSB0 |
| C11 | VCCIB0 |
| C12 | IO42RSB0 |
| C13 | GNDQ |
| C14 | IO44RSB0 |
| D1 | IO127RSB1 |
| D2 | IO129RSB1 |
| D3 | GAA2/IO132RSB1 |
| D4 | IO126RSB1 |
| D5 | IO06RSB0 |
| D6 | IO13RSB0 |
| D7 | IO19RSB0 |
| D8 | IO21RSB0 |
| D9 | IO26RSB0 |
| D10 | IO31RSB0 |
| D11 | IO30RSB0 |
| D12 | VMV0 |
| D13 | IO46RSB0 |
| D14 | GBC2/IO45RSB0 |
| E1 | IO125RSB1 |
| E2 | GND |
| E3 | IO131RSB1 |
| E4 | VCCIB1 |
| E5 | NC |
| E6 | IO08RSB0 |
| E7 | IO17RSB0 |
| E8 | IO12RSB0 |
| E9 | IO11RSB0 |
| E10 | NC |
| E11 | VCCIB0 |
| E12 | IO32RSB0 |
| E13 | GND |
| E14 | IO34RSB0 |
| F1 | IO124RSB1 |
| F2 | IO114RSB1 |

| CS196 | |
|---|---|
| Pin Number | AGL125 Function |
| F3 | IO113RSB1 |
| F4 | IO112RSB1 |
| F5 | IO111RSB1 |
| F6 | NC |
| F7 | VCC |
| F8 | VCC |
| F9 | NC |
| F10 | IO07RSB0 |
| F11 | IO25RSB0 |
| F12 | IO10RSB0 |
| F13 | IO33RSB0 |
| F14 | IO47RSB0 |
| G1 | GFB1/IO121RSB1 |
| G2 | GFA0/IO119RSB1 |
| G3 | GFA2/IO117RSB1 |
| G4 | VCOMPLF |
| G5 | GFC0/IO122RSB1 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | VCC |
| G10 | GCC0/IO52RSB0 |
| G11 | GCB1/IO53RSB0 |
| G12 | GCA0/IO56RSB0 |
| G13 | IO48RSB0 |
| G14 | GCC2/IO59RSB0 |
| H1 | GFB0/IO120RSB1 |
| H2 | GFA1/IO118RSB1 |
| H3 | VCCPLF |
| H4 | GFB2/IO116RSB1 |
| H5 | GFC1/IO123RSB1 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | VCC |
| H10 | GCC1/IO51RSB0 |

| CS196 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| H11 | GCB0/IO54RSB0 |
| H12 | GCA1/IO55RSB0 |
| H13 | IO49RSB0 |
| H14 | GCA2/IO57RSB0 |
| J1 | GFC2/IO115RSB1 |
| J2 | IO110RSB1 |
| J3 | IO94RSB1 |
| J4 | IO93RSB1 |
| J5 | IO89RSB1 |
| J6 | NC |
| J7 | VCC |
| J8 | VCC |
| J9 | NC |
| J10 | IO60RSB0 |
| J11 | GCB2/IO58RSB0 |
| J12 | IO50RSB0 |
| J13 | GDC1/IO61RSB0 |
| J14 | GDC0/IO62RSB0 |
| K1 | IO99RSB1 |
| K2 | GND |
| K3 | IO95RSB1 |
| K4 | VCCIB1 |
| K5 | NC |
| K6 | IO86RSB1 |
| K7 | IO80RSB1 |
| K8 | IO74RSB1 |
| K9 | IO72RSB1 |
| K10 | NC |
| K11 | VCCIB0 |
| K12 | GDA1/IO65RSB0 |
| K13 | GND |
| K14 | GDB1/IO63RSB0 |
| L1 | GEB1/IO107RSB1 |
| L2 | GEC1/IO109RSB1 |
| L3 | GEC0/IO108RSB1 |
| L4 | IO96RSB1 |

| CS196 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| L5 | IO91RSB1 |
| L6 | IO90RSB1 |
| L7 | IO83RSB1 |
| L8 | IO81RSB1 |
| L9 | IO71RSB1 |
| L10 | IO70RSB1 |
| L11 | VPUMP |
| L12 | VJTAG |
| L13 | GDA0/IO66RSB0 |
| L14 | GDB0/IO64RSB0 |
| M1 | GEB0/IO106RSB1 |
| M2 | GEA1/IO105RSB1 |
| M3 | GNDQ |
| M4 | VCCIB1 |
| M5 | IO92RSB1 |
| M6 | IO88RSB1 |
| M7 | NC |
| M8 | VCCIB1 |
| M9 | IO76RSB1 |
| M10 | GDB2/IO68RSB1 |
| M11 | VCCIB1 |
| M12 | VMV1 |
| M13 | TRST |
| M14 | VCCIB0 |
| N1 | GEA0/IO104RSB1 |
| N2 | VMV1 |
| N3 | GEC2/IO101RSB1 |
| N4 | IO100RSB1 |
| N5 | GND |
| N6 | IO87RSB1 |
| N7 | IO82RSB1 |
| N8 | IO78RSB1 |
| N9 | IO73RSB1 |
| N10 | GND |
| N11 | TCK |
| N12 | TDI |

| CS196 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| N13 | GNDQ |
| N14 | TDO |
| P1 | GND |
| P2 | GEA2/IO103RSB1 |
| P3 | FF/GEB2/IO102RSB1 |
| P4 | IO98RSB1 |
| P5 | IO97RSB1 |
| P6 | IO85RSB1 |
| P7 | IO84RSB1 |
| P8 | IO79RSB1 |
| P9 | IO77RSB1 |
| P10 | IO75RSB1 |
| P11 | GDC2/IO69RSB1 |
| P12 | GDA2/IO67RSB1 |
| P13 | TMS |
| P14 | GND |

| CS196 | |
|---|---|
| Pin Number | AGL250 Function |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAC0/IO04RSB0 |
| A4 | GAC1/IO05RSB0 |
| A5 | IO10RSB0 |
| A6 | IO13RSB0 |
| A7 | IO17RSB0 |
| A8 | IO19RSB0 |
| A9 | IO23RSB0 |
| A10 | GBC0/IO35RSB0 |
| A11 | GBB0/IO37RSB0 |
| A12 | GBB1/IO38RSB0 |
| A13 | GBA1/IO40RSB0 |
| A14 | GND |
| B1 | VCCIB3 |
| B2 | VMV0 |
| B3 | GAA1/IO01RSB0 |
| B4 | GAB1/IO03RSB0 |
| B5 | GND |
| B6 | IO12RSB0 |
| B7 | IO16RSB0 |
| B8 | IO22RSB0 |
| B9 | IO24RSB0 |
| B10 | GND |
| B11 | GBC1/IO36RSB0 |
| B12 | GBA0/IO39RSB0 |
| B13 | GBA2/IO41PPB1 |
| B14 | GBB2/IO42PDB1 |
| C1 | GAC2/IO116UDB3 |
| C2 | GAB2/IO117UDB3 |
| C3 | GNDQ |
| C4 | VCCIB0 |
| C5 | GAB0/IO02RSB0 |
| C6 | IO11RSB0 |
| C7 | VCCIB0 |
| C8 | IO20RSB0 |

| CS196 | |
|---|---|
| Pin Number | AGL250 Function |
| C9 | IO30RSB0 |
| C10 | IO33RSB0 |
| C11 | VCCIB0 |
| C12 | IO41NPB1 |
| C13 | GNDQ |
| C14 | IO42NDB1 |
| D1 | IO116VDB3 |
| D2 | IO117VDB3 |
| D3 | GAA2/IO118UDB3 |
| D4 | IO113PPB3 |
| D5 | IO08RSB0 |
| D6 | IO14RSB0 |
| D7 | IO15RSB0 |
| D8 | IO18RSB0 |
| D9 | IO25RSB0 |
| D10 | IO32RSB0 |
| D11 | IO44PPB1 |
| D12 | VMV1 |
| D13 | IO43NDB1 |
| D14 | GBC2/IO43PDB1 |
| E1 | IO112PDB3 |
| E2 | GND |
| E3 | IO118VDB3 |
| E4 | VCCIB3 |
| E5 | IO114USB3 |
| E6 | IO07RSB0 |
| E7 | IO09RSB0 |
| E8 | IO21RSB0 |
| E9 | IO31RSB0 |
| E10 | IO34RSB0 |
| E11 | VCCIB1 |
| E12 | IO44NPB1 |
| E13 | GND |
| E14 | IO45PDB1 |
| F1 | IO112NDB3 |
| F2 | IO107NPB3 |

| CS196 | |
|---|---|
| Pin Number | AGL250 Function |
| F3 | IO111PDB3 |
| F4 | IO111NDB3 |
| F5 | IO113NPB3 |
| F6 | IO06RSB0 |
| F7 | VCC |
| F8 | VCC |
| F9 | IO28RSB0 |
| F10 | IO54PDB1 |
| F11 | IO54NDB1 |
| F12 | IO47NDB1 |
| F13 | IO47PDB1 |
| F14 | IO45NDB1 |
| G1 | GFB1/IO109PDB3 |
| G2 | GFA0/IO108NDB3 |
| G3 | GFA2/IO107PPB3 |
| G4 | VCOMPLF |
| G5 | GFC0/IO110NDB3 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | VCC |
| G10 | GCC0/IO48NDB1 |
| G11 | GCB1/IO49PDB1 |
| G12 | GCA0/IO50NDB1 |
| G13 | IO53NDB1 |
| G14 | GCC2/IO53PDB1 |
| H1 | GFB0/IO109NDB3 |
| H2 | GFA1/IO108PDB3 |
| H3 | VCCPLF |
| H4 | GFB2/IO106PPB3 |
| H5 | GFC1/IO110PDB3 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | VCC |
| H10 | GCC1/IO48PDB1 |

| CS196 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| H11 | GCB0/IO49NDB1 |
| H12 | GCA1/IO50PDB1 |
| H13 | IO51NDB1 |
| H14 | GCA2/IO51PDB1 |
| J1 | GFC2/IO105PDB3 |
| J2 | IO104PPB3 |
| J3 | IO106NPB3 |
| J4 | IO103PDB3 |
| J5 | IO103NDB3 |
| J6 | IO80RSB2 |
| J7 | VCC |
| J8 | VCC |
| J9 | IO64RSB2 |
| J10 | IO56PDB1 |
| J11 | GCB2/IO52PDB1 |
| J12 | IO52NDB1 |
| J13 | GDC1/IO58UDB1 |
| J14 | GDC0/IO58VDB1 |
| K1 | IO105NDB3 |
| K2 | GND |
| K3 | IO104NPB3 |
| K4 | VCCIB3 |
| K5 | IO101PPB3 |
| K6 | IO91RSB2 |
| K7 | IO81RSB2 |
| K8 | IO73RSB2 |
| K9 | IO77RSB2 |
| K10 | IO56NDB1 |
| K11 | VCCIB1 |
| K12 | GDA1/IO60UPB1 |
| K13 | GND |
| K14 | GDB1/IO59UDB1 |
| L1 | GEB1/IO99PDB3 |
| L2 | GEC1/IO100PDB3 |
| L3 | GEC0/IO100NDB3 |
| L4 | IO101NPB3 |

| CS196 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| L5 | IO89RSB2 |
| L6 | IO92RSB2 |
| L7 | IO75RSB2 |
| L8 | IO66RSB2 |
| L9 | IO65RSB2 |
| L10 | IO71RSB2 |
| L11 | VPUMP |
| L12 | VJTAG |
| L13 | GDA0/IO60VPB1 |
| L14 | GDB0/IO59VDB1 |
| M1 | GEB0/IO99NDB3 |
| M2 | GEA1/IO98PPB3 |
| M3 | GNDQ |
| M4 | VCCIB2 |
| M5 | IO88RSB2 |
| M6 | IO87RSB2 |
| M7 | IO82RSB2 |
| M8 | VCCIB2 |
| M9 | IO67RSB2 |
| M10 | GDB2/IO62RSB2 |
| M11 | VCCIB2 |
| M12 | VMV2 |
| M13 | TRST |
| M14 | VCCIB1 |
| N1 | GEA0/IO98NPB3 |
| N2 | VMV3 |
| N3 | GEC2/IO95RSB2 |
| N4 | IO94RSB2 |
| N5 | GND |
| N6 | IO86RSB2 |
| N7 | IO78RSB2 |
| N8 | IO74RSB2 |
| N9 | IO69RSB2 |
| N10 | GND |
| N11 | TCK |
| N12 | TDI |

| CS196 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| N13 | GNDQ |
| N14 | TDO |
| P1 | GND |
| P2 | GEA2/IO97RSB2 |
| P3 | FF/GEB2/IO96RSB2 |
| P4 | IO90RSB2 |
| P5 | IO85RSB2 |
| P6 | IO83RSB2 |
| P7 | IO79RSB2 |
| P8 | IO76RSB2 |
| P9 | IO72RSB2 |
| P10 | IO68RSB2 |
| P11 | GDC2/IO63RSB2 |
| P12 | GDA2/IO61RSB2 |
| P13 | TMS |
| P14 | GND |

| CS196 | |
|---|---|
| Pin Number | AGL400 Function |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAC0/IO04RSB0 |
| A4 | GAC1/IO05RSB0 |
| A5 | IO14RSB0 |
| A6 | IO18RSB0 |
| A7 | IO26RSB0 |
| A8 | IO29RSB0 |
| A9 | IO36RSB0 |
| A10 | GBC0/IO54RSB0 |
| A11 | GBB0/IO56RSB0 |
| A12 | GBB1/IO57RSB0 |
| A13 | GBA1/IO59RSB0 |
| A14 | GND |
| B1 | VCCIB3 |
| B2 | VMV0 |
| B2 | VMV0 |
| B3 | GAA1/IO01RSB0 |
| B4 | GAB1/IO03RSB0 |
| B5 | GND |
| B6 | IO17RSB0 |
| B7 | IO25RSB0 |
| B8 | IO34RSB0 |
| B9 | IO39RSB0 |
| B10 | GND |
| B11 | GBC1/IO55RSB0 |
| B12 | GBA0/IO58RSB0 |
| B13 | GBA2/IO60PPB1 |
| B14 | GBB2/IO61PDB1 |
| C1 | GAC2/IO153UDB3 |
| C2 | GAB2/IO154UDB3 |
| C3 | GNDQ |
| C4 | VCCIB0 |
| C5 | GAB0/IO02RSB0 |
| C6 | IO15RSB0 |
| C7 | VCCIB0 |

| CS196 | |
|---|---|
| Pin Number | AGL400 Function |
| C8 | IO31RSB0 |
| C9 | IO44RSB0 |
| C10 | IO49RSB0 |
| C11 | VCCIB0 |
| C12 | IO60NPB1 |
| C13 | GNDQ |
| C14 | IO61NDB1 |
| D1 | IO153VDB3 |
| D2 | IO154VDB3 |
| D3 | GAA2/IO155UDB3 |
| D4 | IO150PPB3 |
| D5 | IO11RSB0 |
| D6 | IO20RSB0 |
| D7 | IO23RSB0 |
| D8 | IO28RSB0 |
| D9 | IO41RSB0 |
| D10 | IO47RSB0 |
| D11 | IO63PPB1 |
| D12 | VMV1 |
| D13 | IO62NDB1 |
| D14 | GBC2/IO62PDB1 |
| E1 | IO149PDB3 |
| E2 | GND |
| E3 | IO155VDB3 |
| E4 | VCCIB3 |
| E5 | IO151USB3 |
| E6 | IO09RSB0 |
| E7 | IO12RSB0 |
| E8 | IO32RSB0 |
| E9 | IO46RSB0 |
| E10 | IO51RSB0 |
| E11 | VCCIB1 |
| E12 | IO63NPB1 |
| E13 | GND |
| E14 | IO64PDB1 |
| F1 | IO149NDB3 |

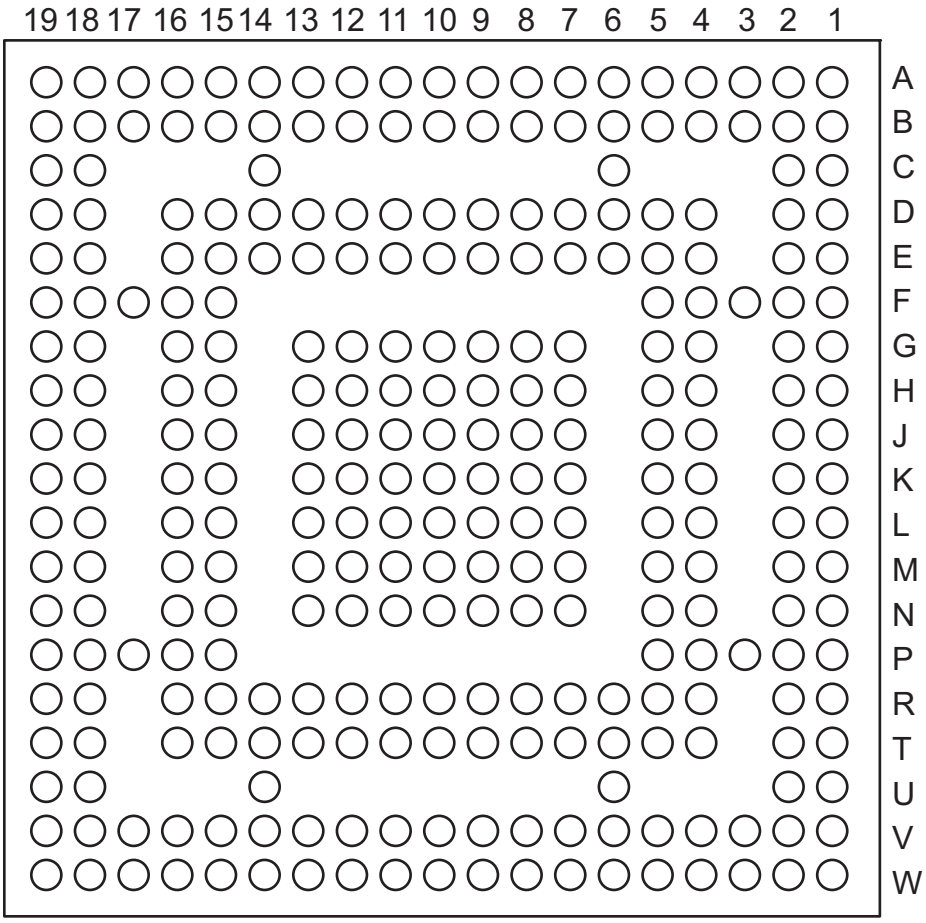
| CS196 | |
|---|---|
| Pin Number | AGL400 Function |
| F2 | IO144NPB3 |
| F3 | IO148PDB3 |
| F4 | IO148NDB3 |
| F5 | IO150NPB3 |
| F6 | IO07RSB0 |
| F7 | VCC |
| F8 | VCC |
| F9 | IO43RSB0 |
| F10 | IO73PDB1 |
| F11 | IO73NDB1 |
| F12 | IO66NDB1 |
| F13 | IO66PDB1 |
| F14 | IO64NDB1 |
| G1 | GFB1/IO146PDB3 |
| G2 | GFA0/IO145NDB3 |
| G3 | GFA2/IO144PPB3 |
| G4 | VCOMPLF |
| G5 | GFC0/IO147NDB3 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | VCC |
| G10 | GCC0/IO67NDB1 |
| G11 | GCB1/IO68PDB1 |
| G12 | GCA0/IO69NDB1 |
| G13 | IO72NDB1 |
| G14 | GCC2/IO72PDB1 |
| H1 | GFB0/IO146NDB3 |
| H2 | GFA1/IO145PDB3 |
| H3 | VCCPLF |
| H4 | GFB2/IO143PPB3 |
| H5 | GFC1/IO147PDB3 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | VCC |

| CS196 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| H10 | GCC1/IO67PDB1 |
| H11 | GCB0/IO68NDB1 |
| H12 | GCA1/IO69PDB1 |
| H13 | IO70NDB1 |
| H14 | GCA2/IO70PDB1 |
| J1 | GFC2/IO142PDB3 |
| J2 | IO141PPB3 |
| J3 | IO143NPB3 |
| J4 | IO140PDB3 |
| J5 | IO140NDB3 |
| J6 | IO109RSB2 |
| J7 | VCC |
| J8 | VCC |
| J9 | IO84RSB2 |
| J10 | IO75PDB1 |
| J11 | GCB2/IO71PDB1 |
| J12 | IO71NDB1 |
| J13 | GDC1/IO77UDB1 |
| J14 | GDC0/IO77VDB1 |
| K1 | IO142NDB3 |
| K2 | GND |
| K3 | IO141NPB3 |
| K4 | VCCIB3 |
| K5 | IO138PPB3 |
| K6 | IO125RSB2 |
| K7 | IO110RSB2 |
| K8 | IO98RSB2 |
| K9 | IO104RSB2 |
| K10 | IO75NDB1 |
| K11 | VCCIB1 |
| K12 | GDA1/IO79UPB1 |
| K13 | GND |
| K14 | GDB1/IO78UDB1 |
| L1 | GEB1/IO136PDB3 |
| L2 | GEC1/IO137PDB3 |
| L3 | GEC0/IO137NDB3 |

| CS196 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| L4 | IO138NPB3 |
| L5 | IO122RSB2 |
| L6 | IO128RSB2 |
| L7 | IO101RSB2 |
| L8 | IO88RSB2 |
| L9 | IO86RSB2 |
| L10 | IO94RSB2 |
| L11 | VPUMP |
| L12 | VJTAG |
| L13 | GDA0/IO79VPB1 |
| L14 | GDB0/IO78VDB1 |
| M1 | GEB0/IO136NDB3 |
| M2 | GEA1/IO135PPB3 |
| M3 | GNDQ |
| M4 | VCCIB2 |
| M5 | IO120RSB2 |
| M6 | IO119RSB2 |
| M7 | IO112RSB2 |
| M8 | VCCIB2 |
| M9 | IO89RSB2 |
| M10 | GDB2/IO81RSB2 |
| M11 | VCCIB2 |
| M12 | VMV2 |
| M12 | VMV2 |
| M13 | TRST |
| M14 | VCCIB1 |
| N1 | GEA0/IO135NPB3 |
| N2 | VMV3 |
| N3 | GEC2/IO132RSB2 |
| N4 | IO130RSB2 |
| N5 | GND |
| N6 | IO117RSB2 |
| N7 | IO106RSB2 |
| N8 | IO100RSB2 |
| N9 | IO92RSB2 |
| N10 | GND |

| CS196 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| N11 | TCK |
| N12 | TDI |
| N13 | GNDQ |
| N14 | TDO |
| P1 | GND |
| P2 | GEA2/IO134RSB2 |
| P3 | FF/GEB2/IO133RSB2 |
| P4 | IO123RSB2 |
| P5 | IO116RSB2 |
| P6 | IO114RSB2 |
| P7 | IO107RSB2 |
| P8 | IO103RSB2 |
| P9 | IO95RSB2 |
| P10 | IO91RSB2 |
| P11 | GDC2/IO82RSB2 |
| P12 | GDA2/IO80RSB2 |
| P13 | TMS |
| P14 | GND |

# CS281




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| A1 | GND |
| A2 | GAB0/IO02RSB0 |
| A3 | GAC1/IO05RSB0 |
| A4 | IO07RSB0 |
| A5 | IO10RSB0 |
| A6 | IO14RSB0 |
| A7 | IO18RSB0 |
| A8 | IO21RSB0 |
| A9 | IO22RSB0 |
| A10 | VCCIB0 |
| A11 | IO33RSB0 |
| A12 | IO40RSB0 |
| A13 | IO37RSB0 |
| A14 | IO48RSB0 |
| A15 | IO51RSB0 |
| A16 | IO53RSB0 |
| A17 | GBC1/IO55RSB0 |
| A18 | GBA0/IO58RSB0 |
| A19 | GND |
| B1 | GAA2/IO174PPB3 |
| B2 | VCCIB0 |
| B3 | GAB1/IO03RSB0 |
| B4 | GAC0/IO04RSB0 |
| B5 | IO06RSB0 |
| B6 | GND |
| B7 | IO15RSB0 |
| B8 | IO20RSB0 |
| B9 | IO23RSB0 |
| B10 | IO24RSB0 |
| B11 | IO36RSB0 |
| B12 | IO35RSB0 |
| B13 | IO44RSB0 |
| B14 | GND |
| B15 | IO52RSB0 |
| B16 | GBC0/IO54RSB0 |
| B17 | GBA1/IO59RSB0 |

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| B18 | VCCIB1 |
| B19 | IO61NDB1 |
| C1 | GAB2/IO173PPB3 |
| C2 | IO174NPB3 |
| C6 | IO12RSB0 |
| C14 | IO50RSB0 |
| C18 | IO60NPB1 |
| C19 | GBB2/IO61PDB1 |
| D1 | IO170PPB3 |
| D2 | IO172NPB3 |
| D4 | GAA0/IO00RSB0 |
| D5 | GAA1/IO01RSB0 |
| D6 | IO09RSB0 |
| D7 | IO16RSB0 |
| D8 | IO19RSB0 |
| D9 | IO26RSB0 |
| D10 | GND |
| D11 | IO34RSB0 |
| D12 | IO45RSB0 |
| D13 | IO49RSB0 |
| D14 | IO47RSB0 |
| D15 | GBB0/IO56RSB0 |
| D16 | GBA2/IO60PPB1 |
| D18 | GBC2/IO62PPB1 |
| D19 | IO66NPB1 |
| E1 | IO169NPB3 |
| E2 | IO171PPB3 |
| E4 | IO171NPB3 |
| E5 | IO08RSB0 |
| E6 | IO11RSB0 |
| E7 | IO13RSB0 |
| E8 | IO17RSB0 |
| E9 | IO25RSB0 |
| E10 | IO30RSB0 |
| E11 | IO41RSB0 |
| E12 | IO42RSB0 |

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| E13 | IO46RSB0 |
| E14 | GBB1/IO57RSB0 |
| E15 | IO62NPB1 |
| E16 | IO63PPB1 |
| E18 | IO64PPB1 |
| E19 | IO65NPB1 |
| F1 | IO168NPB3 |
| F2 | GND |
| F3 | IO169PPB3 |
| F4 | IO170NPB3 |
| F5 | IO173NPB3 |
| F15 | IO63NPB1 |
| F16 | IO65PPB1 |
| F17 | IO64NPB1 |
| F18 | GND |
| F19 | IO68PPB1 |
| G1 | IO167NPB3 |
| G2 | IO165NDB3 |
| G4 | IO168PPB3 |
| G5 | IO167PPB3 |
| G7 | GAC2/IO172PPB3 |
| G8 | VCCIB0 |
| G9 | IO28RSB0 |
| G10 | IO32RSB0 |
| G11 | IO43RSB0 |
| G12 | VCCIB0 |
| G13 | IO66PPB1 |
| G15 | IO67NDB1 |
| G16 | IO67PDB1 |
| G18 | GCC0/IO69NPB1 |
| G19 | GCB1/IO70PPB1 |
| H1 | GFB0/IO163NPB3 |
| H2 | IO165PDB3 |
| H4 | GFC1/IO164PPB3 |
| H5 | GFB1/IO163PPB3 |
| H7 | VCCIB3 |

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| H8 | VCC |
| H9 | VCCIB0 |
| H10 | VCC |
| H11 | VCCIB0 |
| H12 | VCC |
| H13 | VCCIB1 |
| H15 | IO68NPB1 |
| H16 | GCB0/IO70NPB1 |
| H18 | GCA1/IO71PPB1 |
| H19 | GCA2/IO72PPB1 |
| J1 | VCOMPLF |
| J2 | GFA0/IO162NDB3 |
| J4 | VCCPLF |
| J5 | GFC0/IO164NPB3 |
| J7 | GFA2/IO161PDB3 |
| J8 | VCCIB3 |
| J9 | GND |
| J10 | GND |
| J11 | GND |
| J12 | VCCIB1 |
| J13 | GCC1/IO69PPB1 |
| J15 | GCA0/IO71NPB1 |
| J16 | GCB2/IO73PPB1 |
| J18 | IO72NPB1 |
| J19 | IO75PSB1 |
| K1 | VCCIB3 |
| K2 | GFA1/IO162PDB3 |
| K4 | GND |
| K5 | IO159NPB3 |
| K7 | IO161NDB3 |
| K8 | VCC |
| K9 | GND |
| K10 | GND |
| K11 | GND |
| K12 | VCC |
| K13 | GCC2/IO74PPB1 |

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| K15 | IO73NPB1 |
| K16 | GND |
| K18 | IO74NPB1 |
| K19 | VCCIB1 |
| L1 | GFB2/IO160PDB3 |
| L2 | IO160NDB3 |
| L4 | GFC2/IO159PPB3 |
| L5 | IO153PPB3 |
| L7 | IO153NPB3 |
| L8 | VCCIB3 |
| L9 | GND |
| L10 | GND |
| L11 | GND |
| L12 | VCCIB1 |
| L13 | IO76PPB1 |
| L15 | IO76NPB1 |
| L16 | IO77PPB1 |
| L18 | IO78NPB1 |
| L19 | IO77NPB1 |
| M1 | IO158PDB3 |
| M2 | IO158NDB3 |
| M4 | IO154NPB3 |
| M5 | IO152PPB3 |
| M7 | VCCIB3 |
| M8 | VCC |
| M9 | VCCIB2 |
| M10 | VCC |
| M11 | VCCIB2 |
| M12 | VCC |
| M13 | VCCIB1 |
| M15 | IO79NPB1 |
| M16 | IO81NPB1 |
| M18 | IO79PPB1 |
| M19 | IO78PPB1 |
| N1 | IO154PPB3 |
| N2 | IO152NPB3 |

| CS281 | |
|---|---|
| Pin Number | AGL600 Function |
| N4 | IO150PPB3 |
| N5 | IO148NPB3 |
| N7 | GEA2/IO143RSB2 |
| N8 | VCCIB2 |
| N9 | IO117RSB2 |
| N10 | IO115RSB2 |
| N11 | IO114RSB2 |
| N12 | VCCIB2 |
| N13 | VPUMP |
| N15 | IO82PPB1 |
| N16 | IO85PPB1 |
| N18 | IO82NPB1 |
| N19 | IO81PPB1 |
| P1 | IO151PDB3 |
| P2 | GND |
| P3 | IO151NDB3 |
| P4 | IO149PPB3 |
| P5 | GEA0/IO144NPB3 |
| P15 | IO83NDB1 |
| P16 | IO83PDB1 |
| P17 | GDC1/IO86PPB1 |
| P18 | GND |
| P19 | IO85NPB1 |
| R1 | IO150NPB3 |
| R2 | IO149NPB3 |
| R4 | GEC1/IO146PPB3 |
| R5 | GEB1/IO145PPB3 |
| R6 | IO138RSB2 |
| R7 | IO127RSB2 |
| R8 | IO123RSB2 |
| R9 | IO118RSB2 |
| R10 | IO111RSB2 |
| R11 | IO106RSB2 |
| R12 | IO103RSB2 |
| R13 | IO97RSB2 |
| R14 | IO95RSB2 |

| CS281 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| R15 | IO94RSB2 |
| R16 | GDA1/IO88PPB1 |
| R18 | GDB0/IO87NPB1 |
| R19 | GDC0/IO86NPB1 |
| T1 | IO148PPB3 |
| T2 | GEC0/IO146NPB3 |
| T4 | GEB0/IO145NPB3 |
| T5 | IO132RSB2 |
| T6 | IO136RSB2 |
| T7 | IO130RSB2 |
| T8 | IO126RSB2 |
| T9 | IO120RSB2 |
| T10 | GND |
| T11 | IO113RSB2 |
| T12 | IO104RSB2 |
| T13 | IO101RSB2 |
| T14 | IO98RSB2 |
| T15 | GDC2/IO91RSB2 |
| T16 | TMS |
| T18 | VJTAG |
| T19 | GDB1/IO87PPB1 |
| U1 | IO147PDB3 |
| U2 | GEA1/IO144PPB3 |
| U6 | IO131RSB2 |
| U14 | IO99RSB2 |
| U18 | TRST |
| U19 | GDA0/IO88NPB1 |
| V1 | IO147NDB3 |
| V2 | VCCIB3 |
| V3 | GEC2/IO141RSB2 |
| V4 | IO140RSB2 |
| V5 | IO135RSB2 |
| V6 | GND |
| V7 | IO125RSB2 |
| V8 | IO122RSB2 |
| V9 | IO116RSB2 |

| CS281 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| V10 | IO112RSB2 |
| V11 | IO110RSB2 |
| V12 | IO108RSB2 |
| V13 | IO102RSB2 |
| V14 | GND |
| V15 | IO93RSB2 |
| V16 | GDA2/IO89RSB2 |
| V17 | TDI |
| V18 | VCCIB2 |
| V19 | TDO |
| W1 | GND |
| W2 | FF/GEB2/IO142RSB2 |
| W3 | IO139RSB2 |
| W4 | IO137RSB2 |
| W5 | IO134RSB2 |
| W6 | IO133RSB2 |
| W7 | IO128RSB2 |
| W8 | IO124RSB2 |
| W9 | IO119RSB2 |
| W10 | VCCIB2 |
| W11 | IO109RSB2 |
| W12 | IO107RSB2 |
| W13 | IO105RSB2 |
| W14 | IO100RSB2 |
| W15 | IO96RSB2 |
| W16 | IO92RSB2 |
| W17 | GDB2/IO90RSB2 |
| W18 | TCK |
| W19 | GND |

| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| A1 | GND |
| A2 | GAB0/IO02RSB0 |
| A3 | GAC1/IO05RSB0 |
| A4 | IO13RSB0 |
| A5 | IO11RSB0 |
| A6 | IO16RSB0 |
| A7 | IO20RSB0 |
| A8 | IO24RSB0 |
| A9 | IO29RSB0 |
| A10 | VCCIB0 |
| A11 | IO39RSB0 |
| A12 | IO45RSB0 |
| A13 | IO48RSB0 |
| A14 | IO58RSB0 |
| A15 | IO61RSB0 |
| A16 | IO62RSB0 |
| A17 | GBC1/IO73RSB0 |
| A18 | GBA0/IO76RSB0 |
| A19 | GND |
| B1 | GAA2/IO225PPB3 |
| B2 | VCCIB0 |
| B3 | GAB1/IO03RSB0 |
| B4 | GAC0/IO04RSB0 |
| B5 | IO12RSB0 |
| B6 | GND |
| B7 | IO21RSB0 |
| B8 | IO26RSB0 |
| B9 | IO34RSB0 |
| B10 | IO35RSB0 |
| B11 | IO36RSB0 |
| B12 | IO46RSB0 |
| B13 | IO52RSB0 |
| B14 | GND |
| B15 | IO59RSB0 |
| B16 | GBC0/IO72RSB0 |
| B17 | GBA1/IO77RSB0 |

| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| B18 | VCCIB1 |
| B19 | IO79NDB1 |
| C1 | GAB2/IO224PPB3 |
| C2 | IO225NPB3 |
| C6 | IO18RSB0 |
| C14 | IO63RSB0 |
| C18 | IO78NPB1 |
| C19 | GBB2/IO79PDB1 |
| D1 | IO219PPB3 |
| D2 | IO223NPB3 |
| D4 | GAA0/IO00RSB0 |
| D5 | GAA1/IO01RSB0 |
| D6 | IO15RSB0 |
| D7 | IO19RSB0 |
| D8 | IO27RSB0 |
| D9 | IO32RSB0 |
| D10 | GND |
| D11 | IO38RSB0 |
| D12 | IO44RSB0 |
| D13 | IO47RSB0 |
| D14 | IO60RSB0 |
| D15 | GBB0/IO74RSB0 |
| D16 | GBA2/IO78PPB1 |
| D18 | GBC2/IO80PPB1 |
| D19 | IO88NPB1 |
| E1 | IO217NPB3 |
| E2 | IO221PPB3 |
| E4 | IO221NPB3 |
| E5 | IO10RSB0 |
| E6 | IO14RSB0 |
| E7 | IO25RSB0 |
| E8 | IO28RSB0 |
| E9 | IO31RSB0 |
| E10 | IO33RSB0 |
| E11 | IO42RSB0 |
| E12 | IO49RSB0 |

| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| E13 | IO53RSB0 |
| E14 | GBB1/IO75RSB0 |
| E15 | IO80NPB1 |
| E16 | IO85PPB1 |
| E18 | IO83PPB1 |
| E19 | IO84NPB1 |
| F1 | IO214NPB3 |
| F2 | GND |
| F3 | IO217PPB3 |
| F4 | IO219NPB3 |
| F5 | IO224NPB3 |
| F15 | IO85NPB1 |
| F16 | IO84PPB1 |
| F17 | IO83NPB1 |
| F18 | GND |
| F19 | IO90PPB1 |
| G1 | IO212NPB3 |
| G2 | IO211NDB3 |
| G4 | IO214PPB3 |
| G5 | IO212PPB3 |
| G7 | GAC2/IO223PPB3 |
| G8 | VCCIB0 |
| G9 | IO30RSB0 |
| G10 | IO37RSB0 |
| G11 | IO43RSB0 |
| G12 | VCCIB0 |
| G13 | IO88PPB1 |
| G15 | IO89NDB1 |
| G16 | IO89PDB1 |
| G18 | GCC0/IO91NPB1 |
| G19 | GCB1/IO92PPB1 |
| H1 | GFB0/IO208NPB3 |
| H2 | IO211PDB3 |
| H4 | GFC1/IO209PPB3 |
| H5 | GFB1/IO208PPB3 |
| H7 | VCCIB3 |

| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| H8 | VCC |
| H9 | VCCIB0 |
| H10 | VCC |
| H11 | VCCIB0 |
| H12 | VCC |
| H13 | VCCIB1 |
| H15 | IO90NPB1 |
| H16 | GCB0/IO92NPB1 |
| H18 | GCA1/IO93PPB1 |
| H19 | GCA2/IO94PPB1 |
| J1 | VCOMPLF |
| J2 | GFA0/IO207NDB3 |
| J4 | VCCPLF |
| J5 | GFC0/IO209NPB3 |
| J7 | GFA2/IO206PDB3 |
| J8 | VCCIB3 |
| J9 | GND |
| J10 | GND |
| J11 | GND |
| J12 | VCCIB1 |
| J13 | GCC1/IO91PPB1 |
| J15 | GCA0/IO93NPB1 |
| J16 | GCB2/IO95PPB1 |
| J18 | IO94NPB1 |
| J19 | IO102PSB1 |
| K1 | VCCIB3 |
| K2 | GFA1/IO207PDB3 |
| K4 | GND |
| K5 | IO204NPB3 |
| K7 | IO206NDB3 |
| K8 | VCC |
| K9 | GND |
| K10 | GND |
| K11 | GND |
| K12 | VCC |
| K13 | GCC2/IO96PPB1 |

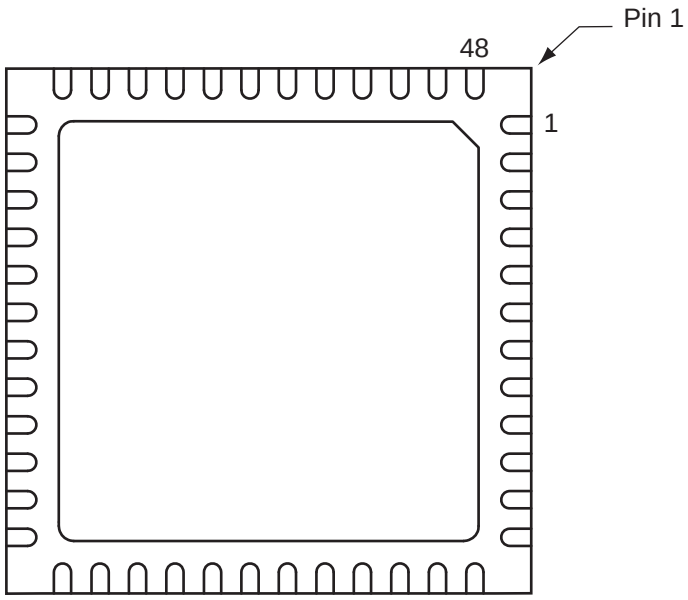
| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| K15 | IO95NPB1 |
| K16 | GND |
| K18 | IO96NPB1 |
| K19 | VCCIB1 |
| L1 | GFB2/IO205PDB3 |
| L2 | IO205NDB3 |
| L4 | GFC2/IO204PPB3 |
| L5 | IO203PPB3 |
| L7 | IO203NPB3 |
| L8 | VCCIB3 |
| L9 | GND |
| L10 | GND |
| L11 | GND |
| L12 | VCCIB1 |
| L13 | IO103PPB1 |
| L15 | IO103NPB1 |
| L16 | IO97PPB1 |
| L18 | IO98NPB1 |
| L19 | IO97NPB1 |
| M1 | IO202PDB3 |
| M2 | IO202NDB3 |
| M4 | IO201NPB3 |
| M5 | IO198PPB3 |
| M7 | VCCIB3 |
| M8 | VCC |
| M9 | VCCIB2 |
| M10 | VCC |
| M11 | VCCIB2 |
| M12 | VCC |
| M13 | VCCIB1 |
| M15 | IO104NPB1 |
| M16 | IO100NPB1 |
| M18 | IO104PPB1 |
| M19 | IO98PPB1 |
| N1 | IO201PPB3 |
| N2 | IO198NPB3 |

| CS281 | |
|---|---|
| Pin Number | AGL1000 Function |
| N4 | IO196PPB3 |
| N5 | IO197NPB3 |
| N7 | GEA2/IO187RSB2 |
| N8 | VCCIB2 |
| N9 | IO155RSB2 |
| N10 | IO154RSB2 |
| N11 | IO150RSB2 |
| N12 | VCCIB2 |
| N13 | VPUMP |
| N15 | IO107PPB1 |
| N16 | IO105PPB1 |
| N18 | IO107NPB1 |
| N19 | IO100PPB1 |
| P1 | IO195PDB3 |
| P2 | GND |
| P3 | IO195NDB3 |
| P4 | IO194PPB3 |
| P5 | GEA0/IO188NPB3 |
| P15 | IO108NDB1 |
| P16 | IO108PDB1 |
| P17 | GDC1/IO111PPB1 |
| P18 | GND |
| P19 | IO105NPB1 |
| R1 | IO196NPB3 |
| R2 | IO194NPB3 |
| R4 | GEC1/IO190PPB3 |
| R5 | GEB1/IO189PPB3 |
| R6 | IO184RSB2 |
| R7 | IO173RSB2 |
| R8 | IO168RSB2 |
| R9 | IO160RSB2 |
| R10 | IO151RSB2 |
| R11 | IO141RSB2 |
| R12 | IO136RSB2 |
| R13 | IO127RSB2 |
| R14 | IO124RSB2 |

| CS281 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| R15 | IO122RSB2 |
| R16 | GDA1/IO113PPB1 |
| R18 | GDB0/IO112NPB1 |
| R19 | GDC0/IO111NPB1 |
| T1 | IO197PPB3 |
| T2 | GEC0/IO190NPB3 |
| T4 | GEB0/IO189NPB3 |
| T5 | IO181RSB2 |
| T6 | IO172RSB2 |
| T7 | IO171RSB2 |
| T8 | IO156RSB2 |
| T9 | IO159RSB2 |
| T10 | GND |
| T11 | IO139RSB2 |
| T12 | IO138RSB2 |
| T13 | IO129RSB2 |
| T14 | IO123RSB2 |
| T15 | GDC2/IO116RSB2 |
| T16 | TMS |
| T18 | VJTAG |
| T19 | GDB1/IO112PPB1 |
| U1 | IO193PDB3 |
| U2 | GEA1/IO188PPB3 |
| U6 | IO167RSB2 |
| U14 | IO128RSB2 |
| U18 | TRST |
| U19 | GDA0/IO113NPB1 |
| V1 | IO193NDB3 |
| V2 | VCCIB3 |
| V3 | GEC2/IO185RSB2 |
| V4 | IO182RSB2 |
| V5 | IO175RSB2 |
| V6 | GND |
| V7 | IO161RSB2 |
| V8 | IO143RSB2 |
| V9 | IO146RSB2 |

| CS281 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| V10 | IO145RSB2 |
| V11 | IO144RSB2 |
| V12 | IO134RSB2 |
| V13 | IO133RSB2 |
| V14 | GND |
| V15 | IO119RSB2 |
| V16 | GDA2/IO114RSB2 |
| V17 | TDI |
| V18 | VCCIB2 |
| V19 | TDO |
| W1 | GND |
| W2 | FF/GEB2/IO186RSB2 |
| W3 | IO183RSB2 |
| W4 | IO176RSB2 |
| W5 | IO170RSB2 |
| W6 | IO162RSB2 |
| W7 | IO157RSB2 |
| W8 | IO152RSB2 |
| W9 | IO149RSB2 |
| W10 | VCCIB2 |
| W11 | IO140RSB2 |
| W12 | IO135RSB2 |
| W13 | IO130RSB2 |
| W14 | IO125RSB2 |
| W15 | IO120RSB2 |
| W16 | IO118RSB2 |
| W17 | GDB2/IO115RSB2 |
| W18 | TCK |
| W19 | GND |

# QN48




*Notes:*

1. *This is the bottom view of the package.*
2. *The die attach paddle center of the package is tied to ground (GND).*

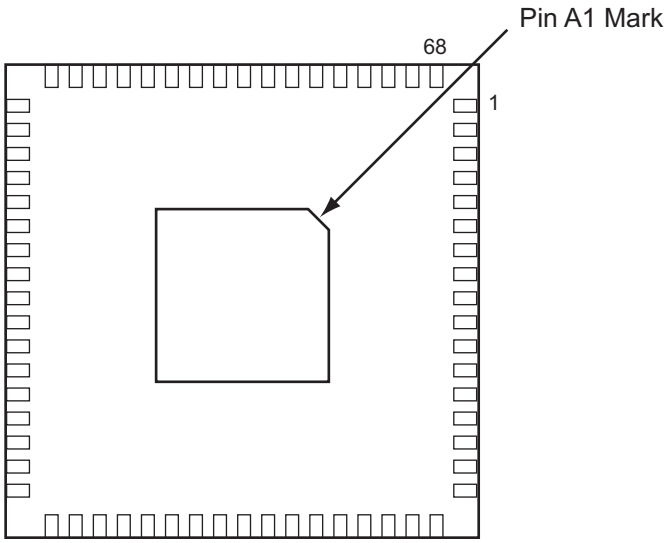
## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| QN48 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| 1 | IO82RSB1 |
| 2 | GEC0/IO73RSB1 |
| 3 | GEA0/IO72RSB1 |
| 4 | GEB0/IO71RSB1 |
| 5 | GND |
| 6 | VCCIB1 |
| 7 | IO68RSB1 |
| 8 | IO67RSB1 |
| 9 | IO66RSB1 |
| 10 | IO65RSB1 |
| 11 | IO64RSB1 |
| 12 | IO62RSB1 |
| 13 | IO61RSB1 |
| 14 | FF/IO60RSB1 |
| 15 | IO57RSB1 |
| 16 | IO55RSB1 |
| 17 | IO53RSB1 |
| 18 | VCC |
| 19 | VCCIB1 |
| 20 | IO46RSB1 |
| 21 | IO42RSB1 |
| 22 | TCK |
| 23 | TDI |
| 24 | TMS |
| 25 | VPUMP |
| 26 | TDO |
| 27 | TRST |
| 28 | VJTAG |
| 29 | IO38RSB0 |
| 30 | GDB0/IO34RSB0 |
| 31 | GDA0/IO33RSB0 |
| 32 | GDC0/IO32RSB0 |
| 33 | VCCIB0 |
| 34 | GND |
| 35 | VCC |
| 36 | IO25RSB0 |

| QN48 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| 37 | IO24RSB0 |
| 38 | IO22RSB0 |
| 39 | IO20RSB0 |
| 40 | IO18RSB0 |
| 41 | IO16RSB0 |
| 42 | IO14RSB0 |
| 43 | IO10RSB0 |
| 44 | IO08RSB0 |
| 45 | IO06RSB0 |
| 46 | IO04RSB0 |
| 47 | IO02RSB0 |
| 48 | IO00RSB0 |

# QN68




*Notes:*

1. *This is the bottom view of the package.*
2. *The die attach paddle center of the package is tied to ground (GND).*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

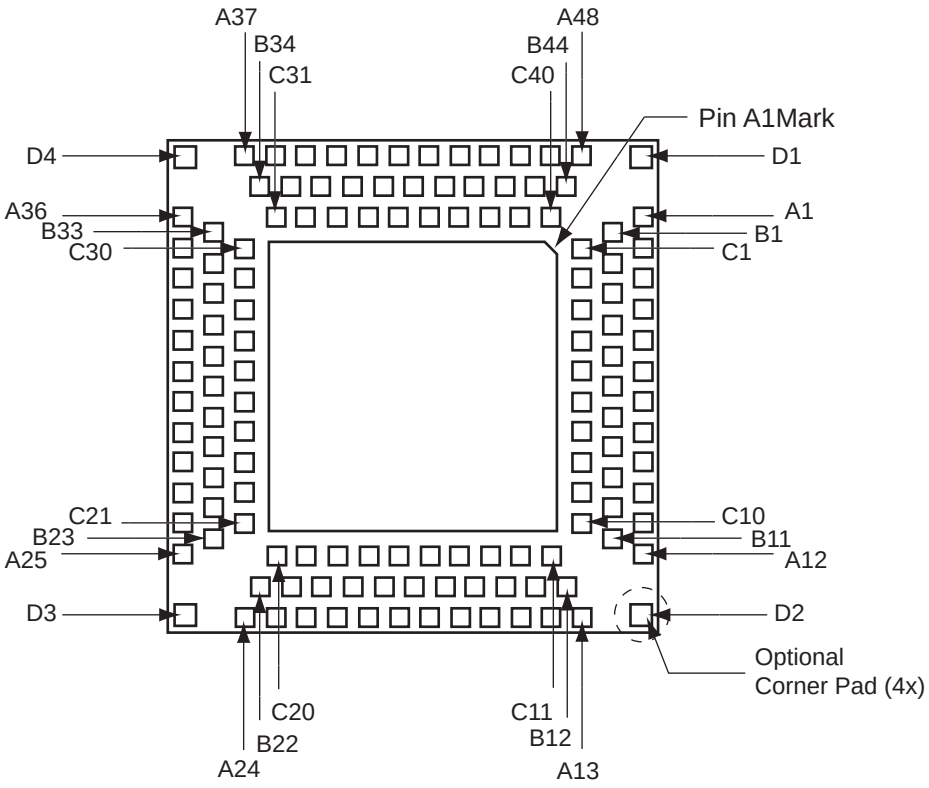
| QN68 | |
|---|---|
| **Pin Number** | **AGL015 Function** |
| 1 | IO82RSB1 |
| 2 | IO80RSB1 |
| 3 | IO78RSB1 |
| 4 | IO76RSB1 |
| 5 | GEC0/IO73RSB1 |
| 6 | GEA0/IO72RSB1 |
| 7 | GEB0/IO71RSB1 |
| 8 | VCC |
| 9 | GND |
| 10 | VCCIB1 |
| 11 | IO68RSB1 |
| 12 | IO67RSB1 |
| 13 | IO66RSB1 |
| 14 | IO65RSB1 |
| 15 | IO64RSB1 |
| 16 | IO63RSB1 |
| 17 | IO62RSB1 |
| 18 | FF/IO60RSB1 |
| 19 | IO58RSB1 |
| 20 | IO56RSB1 |
| 21 | IO54RSB1 |
| 22 | IO52RSB1 |
| 23 | IO51RSB1 |
| 24 | VCC |
| 25 | GND |
| 26 | VCCIB1 |
| 27 | IO50RSB1 |
| 28 | IO48RSB1 |
| 29 | IO46RSB1 |
| 30 | IO44RSB1 |
| 31 | IO42RSB1 |
| 32 | TCK |
| 33 | TDI |
| 34 | TMS |
| 35 | VPUMP |
| 36 | TDO |

| QN68 | |
|---|---|
| **Pin Number** | **AGL015 Function** |
| 37 | TRST |
| 38 | VJTAG |
| 39 | IO40RSB0 |
| 40 | IO37RSB0 |
| 41 | GDB0/IO34RSB0 |
| 42 | GDA0/IO33RSB0 |
| 43 | GDC0/IO32RSB0 |
| 44 | VCCIB0 |
| 45 | GND |
| 46 | VCC |
| 47 | IO31RSB0 |
| 48 | IO29RSB0 |
| 49 | IO28RSB0 |
| 50 | IO27RSB0 |
| 51 | IO25RSB0 |
| 52 | IO24RSB0 |
| 53 | IO22RSB0 |
| 54 | IO21RSB0 |
| 55 | IO19RSB0 |
| 56 | IO17RSB0 |
| 57 | IO15RSB0 |
| 58 | IO14RSB0 |
| 59 | VCCIB0 |
| 60 | GND |
| 61 | VCC |
| 62 | IO12RSB0 |
| 63 | IO10RSB0 |
| 64 | IO08RSB0 |
| 65 | IO06RSB0 |
| 66 | IO04RSB0 |
| 67 | IO02RSB0 |
| 68 | IO00RSB0 |

| QN68 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| 1 | IO82RSB1 |
| 2 | IO80RSB1 |
| 3 | IO78RSB1 |
| 4 | IO76RSB1 |
| 5 | GEC0/IO73RSB1 |
| 6 | GEA0/IO72RSB1 |
| 7 | GEB0/IO71RSB1 |
| 8 | VCC |
| 9 | GND |
| 10 | VCCIB1 |
| 11 | IO68RSB1 |
| 12 | IO67RSB1 |
| 13 | IO66RSB1 |
| 14 | IO65RSB1 |
| 15 | IO64RSB1 |
| 16 | IO63RSB1 |
| 17 | IO62RSB1 |
| 18 | FF/IO60RSB1 |
| 19 | IO58RSB1 |
| 20 | IO56RSB1 |
| 21 | IO54RSB1 |
| 22 | IO52RSB1 |
| 23 | IO51RSB1 |
| 24 | VCC |
| 25 | GND |
| 26 | VCCIB1 |
| 27 | IO50RSB1 |
| 28 | IO48RSB1 |
| 29 | IO46RSB1 |
| 30 | IO44RSB1 |
| 31 | IO42RSB1 |
| 32 | TCK |
| 33 | TDI |
| 34 | TMS |
| 35 | VPUMP |
| 36 | TDO |

| QN68 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| 37 | TRST |
| 38 | VJTAG |
| 39 | IO40RSB0 |
| 40 | IO37RSB0 |
| 41 | GDB0/IO34RSB0 |
| 42 | GDA0/IO33RSB0 |
| 43 | GDC0/IO32RSB0 |
| 44 | VCCIB0 |
| 45 | GND |
| 46 | VCC |
| 47 | IO31RSB0 |
| 48 | IO29RSB0 |
| 49 | IO28RSB0 |
| 50 | IO27RSB0 |
| 51 | IO25RSB0 |
| 52 | IO24RSB0 |
| 53 | IO22RSB0 |
| 54 | IO21RSB0 |
| 55 | IO19RSB0 |
| 56 | IO17RSB0 |
| 57 | IO15RSB0 |
| 58 | IO14RSB0 |
| 59 | VCCIB0 |
| 60 | GND |
| 61 | VCC |
| 62 | IO12RSB0 |
| 63 | IO10RSB0 |
| 64 | IO08RSB0 |
| 65 | IO06RSB0 |
| 66 | IO04RSB0 |
| 67 | IO02RSB0 |
| 68 | IO00RSB0 |

# QN132




*Notes:*

1. *This is the bottom view of the package.*
2. *The die attach paddle center of the package is tied to ground (GND).*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| QN132 | |
|---|---|
| Pin Number | AGL030 Function |
| A1 | IO80RSB1 |
| A2 | IO77RSB1 |
| A3 | NC |
| A4 | IO76RSB1 |
| A5 | GEC0/IO73RSB1 |
| A6 | NC |
| A7 | GEB0/IO71RSB1 |
| A8 | IO69RSB1 |
| A9 | NC |
| A10 | VCC |
| A11 | IO67RSB1 |
| A12 | IO64RSB1 |
| A13 | IO59RSB1 |
| A14 | IO56RSB1 |
| A15 | NC |
| A16 | IO55RSB1 |
| A17 | IO53RSB1 |
| A18 | VCC |
| A19 | IO50RSB1 |
| A20 | IO48RSB1 |
| A21 | IO45RSB1 |
| A22 | IO44RSB1 |
| A23 | IO43RSB1 |
| A24 | TDI |
| A25 | TRST |
| A26 | IO40RSB0 |
| A27 | NC |
| A28 | IO39RSB0 |
| A29 | IO38RSB0 |
| A30 | IO36RSB0 |
| A31 | IO35RSB0 |
| A32 | GDC0/IO32RSB0 |
| A33 | NC |
| A34 | VCC |
| A35 | IO30RSB0 |
| A36 | IO27RSB0 |

| QN132 | |
|---|---|
| Pin Number | AGL030 Function |
| A37 | IO22RSB0 |
| A38 | IO19RSB0 |
| A39 | NC |
| A40 | IO18RSB0 |
| A41 | IO16RSB0 |
| A42 | IO14RSB0 |
| A43 | VCC |
| A44 | IO11RSB0 |
| A45 | IO08RSB0 |
| A46 | IO06RSB0 |
| A47 | IO05RSB0 |
| A48 | IO02RSB0 |
| B1 | IO81RSB1 |
| B2 | IO78RSB1 |
| B3 | GND |
| B4 | IO75RSB1 |
| B5 | NC |
| B6 | GND |
| B7 | IO70RSB1 |
| B8 | NC |
| B9 | GND |
| B10 | IO66RSB1 |
| B11 | IO63RSB1 |
| B12 | FF/IO60RSB1 |
| B13 | IO57RSB1 |
| B14 | GND |
| B15 | IO54RSB1 |
| B16 | IO52RSB1 |
| B17 | GND |
| B18 | IO49RSB1 |
| B19 | IO46RSB1 |
| B20 | GND |
| B21 | IO42RSB1 |
| B22 | TMS |
| B23 | TDO |
| B24 | IO41RSB0 |

| QN132 | |
|---|---|
| Pin Number | AGL030 Function |
| B25 | GND |
| B26 | NC |
| B27 | IO37RSB0 |
| B28 | GND |
| B29 | GDA0/IO33RSB0 |
| B30 | NC |
| B31 | GND |
| B32 | IO29RSB0 |
| B33 | IO26RSB0 |
| B34 | IO23RSB0 |
| B35 | IO20RSB0 |
| B36 | GND |
| B37 | IO17RSB0 |
| B38 | IO15RSB0 |
| B39 | GND |
| B40 | IO12RSB0 |
| B41 | IO09RSB0 |
| B42 | GND |
| B43 | IO04RSB0 |
| B44 | IO01RSB0 |
| C1 | IO82RSB1 |
| C2 | IO79RSB1 |
| C3 | NC |
| C4 | IO74RSB1 |
| C5 | GEA0/IO72RSB1 |
| C6 | NC |
| C7 | NC |
| C8 | VCCIB1 |
| C9 | IO65RSB1 |
| C10 | IO62RSB1 |
| C11 | IO61RSB1 |
| C12 | IO58RSB1 |
| C13 | NC |
| C14 | NC |
| C15 | IO51RSB1 |
| C16 | VCCIB1 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL030 Function** |
| C17 | IO47RSB1 |
| C18 | NC |
| C19 | TCK |
| C20 | NC |
| C21 | VPUMP |
| C22 | VJTAG |
| C23 | NC |
| C24 | NC |
| C25 | NC |
| C26 | GDB0/IO34RSB0 |
| C27 | NC |
| C28 | VCCIB0 |
| C29 | IO28RSB0 |
| C30 | IO25RSB0 |
| C31 | IO24RSB0 |
| C32 | IO21RSB0 |
| C33 | NC |
| C34 | NC |
| C35 | VCCIB0 |
| C36 | IO13RSB0 |
| C37 | IO10RSB0 |
| C38 | IO07RSB0 |
| C39 | IO03RSB0 |
| C40 | IO00RSB0 |
| D1 | GND |
| D2 | GND |
| D3 | GND |
| D4 | GND |

| QN132 | |
|---|---|
| Pin Number | AGL060 Function |
| A1 | GAB2/IO00RSB1 |
| A2 | IO93RSB1 |
| A3 | VCCIB1 |
| A4 | GFC1/IO89RSB1 |
| A5 | GFB0/IO86RSB1 |
| A6 | VCCPLF |
| A7 | GFA1/IO84RSB1 |
| A8 | GFC2/IO81RSB1 |
| A9 | IO78RSB1 |
| A10 | VCC |
| A11 | GEB1/IO75RSB1 |
| A12 | GEA0/IO72RSB1 |
| A13 | GEC2/IO69RSB1 |
| A14 | IO65RSB1 |
| A15 | VCC |
| A16 | IO64RSB1 |
| A17 | IO63RSB1 |
| A18 | IO62RSB1 |
| A19 | IO61RSB1 |
| A20 | IO58RSB1 |
| A21 | GDB2/IO55RSB1 |
| A22 | NC |
| A23 | GDA2/IO54RSB1 |
| A24 | TDI |
| A25 | TRST |
| A26 | GDC1/IO48RSB0 |
| A27 | VCC |
| A28 | IO47RSB0 |
| A29 | GCC2/IO46RSB0 |
| A30 | GCA2/IO44RSB0 |
| A31 | GCA0/IO43RSB0 |
| A32 | GCB1/IO40RSB0 |
| A33 | IO36RSB0 |
| A34 | VCC |
| A35 | IO31RSB0 |
| A36 | GBA2/IO28RSB0 |

| QN132 | |
|---|---|
| Pin Number | AGL060 Function |
| A37 | GBB1/IO25RSB0 |
| A38 | GBC0/IO22RSB0 |
| A39 | VCCIB0 |
| A40 | IO21RSB0 |
| A41 | IO18RSB0 |
| A42 | IO15RSB0 |
| A43 | IO14RSB0 |
| A44 | IO11RSB0 |
| A45 | GAB1/IO08RSB0 |
| A46 | NC |
| A47 | GAB0/IO07RSB0 |
| A48 | IO04RSB0 |
| B1 | IO01RSB1 |
| B2 | GAC2/IO94RSB1 |
| B3 | GND |
| B4 | GFC0/IO88RSB1 |
| B5 | VCOMPLF |
| B6 | GND |
| B7 | GFB2/IO82RSB1 |
| B8 | IO79RSB1 |
| B9 | GND |
| B10 | GEB0/IO74RSB1 |
| B11 | VMV1 |
| B12 | FF/GEB2/IO70RSB1 |
| B13 | IO67RSB1 |
| B14 | GND |
| B15 | NC |
| B16 | NC |
| B17 | GND |
| B18 | IO59RSB1 |
| B19 | GDC2/IO56RSB1 |
| B20 | GND |
| B21 | GNDQ |
| B22 | TMS |
| B23 | TDO |

| QN132 | |
|---|---|
| Pin Number | AGL060 Function |
| B24 | GDC0/IO49RSB0 |
| B25 | GND |
| B26 | NC |
| B27 | GCB2/IO45RSB0 |
| B28 | GND |
| B29 | GCB0/IO41RSB0 |
| B30 | GCC1/IO38RSB0 |
| B31 | GND |
| B32 | GBB2/IO30RSB0 |
| B33 | VMV0 |
| B34 | GBA0/IO26RSB0 |
| B35 | GBC1/IO23RSB0 |
| B36 | GND |
| B37 | IO20RSB0 |
| B38 | IO17RSB0 |
| B39 | GND |
| B40 | IO12RSB0 |
| B41 | GAC0/IO09RSB0 |
| B42 | GND |
| B43 | GAA1/IO06RSB0 |
| B44 | GNDQ |
| C1 | GAA2/IO02RSB1 |
| C2 | IO95RSB1 |
| C3 | VCC |
| C4 | GFB1/IO87RSB1 |
| C5 | GFA0/IO85RSB1 |
| C6 | GFA2/IO83RSB1 |
| C7 | IO80RSB1 |
| C8 | VCCIB1 |
| C9 | GEA1/IO73RSB1 |
| C10 | GNDQ |
| C11 | GEA2/IO71RSB1 |
| C12 | IO68RSB1 |
| C13 | VCCIB1 |
| C14 | NC |
| C15 | NC |

| QN132 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| C16 | IO60RSB1 |
| C17 | IO57RSB1 |
| C18 | NC |
| C19 | TCK |
| C20 | VMV1 |
| C21 | VPUMP |
| C22 | VJTAG |
| C23 | VCCIB0 |
| C24 | NC |
| C25 | NC |
| C26 | GCA1/IO42RSB0 |
| C27 | GCC0/IO39RSB0 |
| C28 | VCCIB0 |
| C29 | IO29RSB0 |
| C30 | GNDQ |
| C31 | GBA1/IO27RSB0 |
| C32 | GBB0/IO24RSB0 |
| C33 | VCC |
| C34 | IO19RSB0 |
| C35 | IO16RSB0 |
| C36 | IO13RSB0 |
| C37 | GAC1/IO10RSB0 |
| C38 | NC |
| C39 | GAA0/IO05RSB0 |
| C40 | VMV0 |
| D1 | GND |
| D2 | GND |
| D3 | GND |
| D4 | GND |

| QN132 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| A1 | GAB2/IO69RSB1 |
| A2 | IO130RSB1 |
| A3 | VCCIB1 |
| A4 | GFC1/IO126RSB1 |
| A5 | GFB0/IO123RSB1 |
| A6 | VCCPLF |
| A7 | GFA1/IO121RSB1 |
| A8 | GFC2/IO118RSB1 |
| A9 | IO115RSB1 |
| A10 | VCC |
| A11 | GEB1/IO110RSB1 |
| A12 | GEA0/IO107RSB1 |
| A13 | GEC2/IO104RSB1 |
| A14 | IO100RSB1 |
| A15 | VCC |
| A16 | IO99RSB1 |
| A17 | IO96RSB1 |
| A18 | IO94RSB1 |
| A19 | IO91RSB1 |
| A20 | IO85RSB1 |
| A21 | IO79RSB1 |
| A22 | VCC |
| A23 | GDB2/IO71RSB1 |
| A24 | TDI |
| A25 | TRST |
| A26 | GDC1/IO61RSB0 |
| A27 | VCC |
| A28 | IO60RSB0 |
| A29 | GCC2/IO59RSB0 |
| A30 | GCA2/IO57RSB0 |
| A31 | GCA0/IO56RSB0 |
| A32 | GCB1/IO53RSB0 |
| A33 | IO49RSB0 |
| A34 | VCC |
| A35 | IO44RSB0 |
| A36 | GBA2/IO41RSB0 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| A37 | GBB1/IO38RSB0 |
| A38 | GBC0/IO35RSB0 |
| A39 | VCCIB0 |
| A40 | IO28RSB0 |
| A41 | IO22RSB0 |
| A42 | IO18RSB0 |
| A43 | IO14RSB0 |
| A44 | IO11RSB0 |
| A45 | IO07RSB0 |
| A46 | VCC |
| A47 | GAC1/IO05RSB0 |
| A48 | GAB0/IO02RSB0 |
| B1 | IO68RSB1 |
| B2 | GAC2/IO131RSB1 |
| B3 | GND |
| B4 | GFC0/IO125RSB1 |
| B5 | VCOMPLF |
| B6 | GND |
| B7 | GFB2/IO119RSB1 |
| B8 | IO116RSB1 |
| B9 | GND |
| B10 | GEB0/IO109RSB1 |
| B11 | VMV1 |
| B12 | FF/GEB2/IO105RSB1 |
| B13 | IO101RSB1 |
| B14 | GND |
| B15 | IO98RSB1 |
| B16 | IO95RSB1 |
| B17 | GND |
| B18 | IO87RSB1 |
| B19 | IO81RSB1 |
| B20 | GND |
| B21 | GNDQ |
| B22 | TMS |
| B23 | TDO |
| B24 | GDC0/IO62RSB0 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| B25 | GND |
| B26 | NC |
| B27 | GCB2/IO58RSB0 |
| B28 | GND |
| B29 | GCB0/IO54RSB0 |
| B30 | GCC1/IO51RSB0 |
| B31 | GND |
| B32 | GBB2/IO43RSB0 |
| B33 | VMV0 |
| B34 | GBA0/IO39RSB0 |
| B35 | GBC1/IO36RSB0 |
| B36 | GND |
| B37 | IO26RSB0 |
| B38 | IO21RSB0 |
| B39 | GND |
| B40 | IO13RSB0 |
| B41 | IO08RSB0 |
| B42 | GND |
| B43 | GAC0/IO04RSB0 |
| B44 | GNDQ |
| C1 | GAA2/IO67RSB1 |
| C2 | IO132RSB1 |
| C3 | VCC |
| C4 | GFB1/IO124RSB1 |
| C5 | GFA0/IO122RSB1 |
| C6 | GFA2/IO120RSB1 |
| C7 | IO117RSB1 |
| C8 | VCCIB1 |
| C9 | GEA1/IO108RSB1 |
| C10 | GNDQ |
| C11 | GEA2/IO106RSB1 |
| C12 | IO103RSB1 |
| C13 | VCCIB1 |
| C14 | IO97RSB1 |
| C15 | IO93RSB1 |
| C16 | IO89RSB1 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| C17 | IO83RSB1 |
| C18 | VCCIB1 |
| C19 | TCK |
| C20 | VMV1 |
| C21 | VPUMP |
| C22 | VJTAG |
| C23 | VCCIB0 |
| C24 | NC |
| C25 | NC |
| C26 | GCA1/IO55RSB0 |
| C27 | GCC0/IO52RSB0 |
| C28 | VCCIB0 |
| C29 | IO42RSB0 |
| C30 | GNDQ |
| C31 | GBA1/IO40RSB0 |
| C32 | GBB0/IO37RSB0 |
| C33 | VCC |
| C34 | IO24RSB0 |
| C35 | IO19RSB0 |
| C36 | IO16RSB0 |
| C37 | IO10RSB0 |
| C38 | VCCIB0 |
| C39 | GAB1/IO03RSB0 |
| C40 | VMV0 |
| D1 | GND |
| D2 | GND |
| D3 | GND |
| D4 | GND |

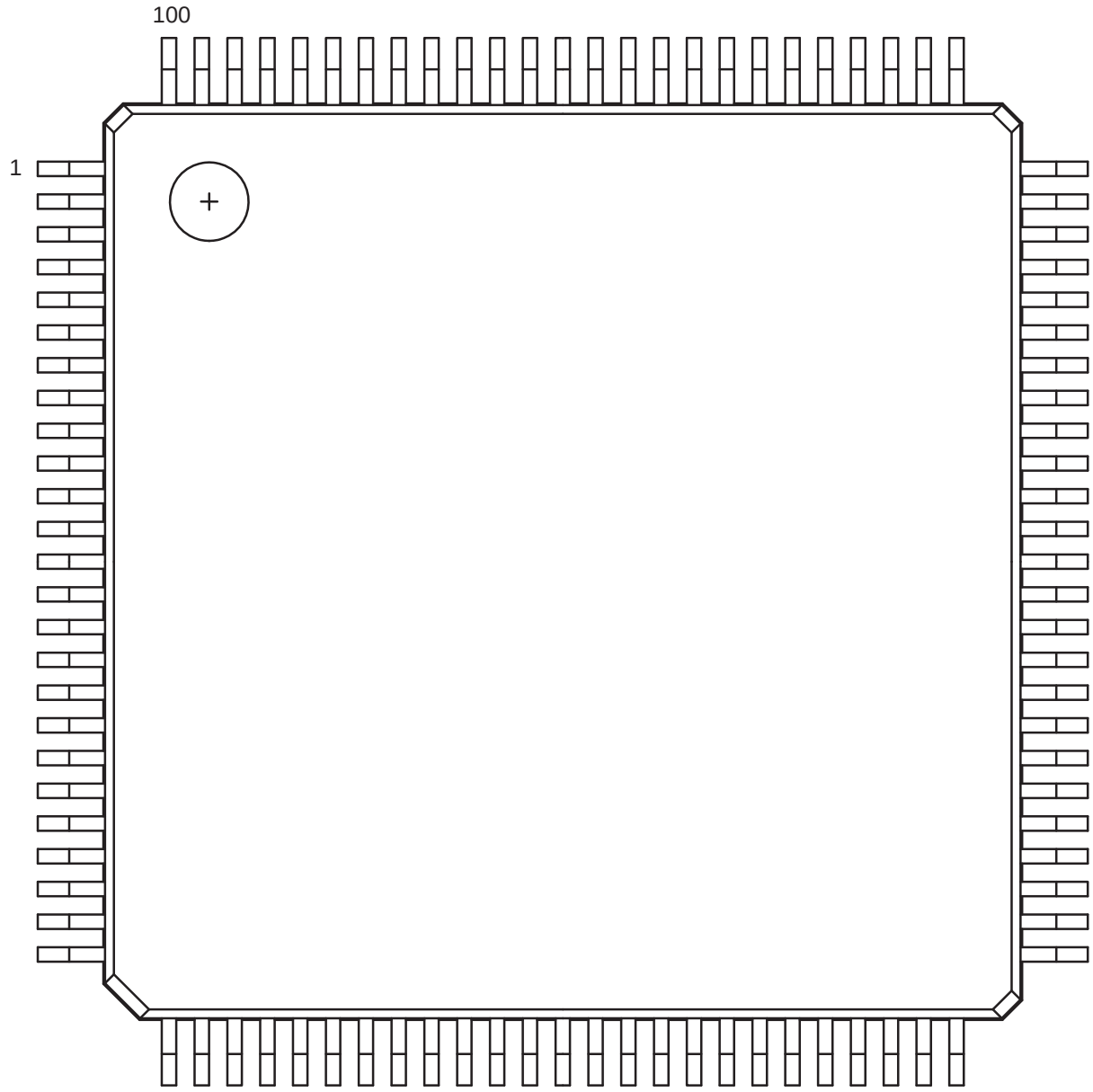
| QN132 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| A1 | GAB2/IO117UPB3 |
| A2 | IO117VPB3 |
| A3 | VCCIB3 |
| A4 | GFC1/IO110PDB3 |
| A5 | GFB0/IO109NPB3 |
| A6 | VCCPLF |
| A7 | GFA1/IO108PPB3 |
| A8 | GFC2/IO105PPB3 |
| A9 | IO103NDB3 |
| A10 | VCC |
| A11 | GEA1/IO98PPB3 |
| A12 | GEA0/IO98NPB3 |
| A13 | GEC2/IO95RSB2 |
| A14 | IO91RSB2 |
| A15 | VCC |
| A16 | IO90RSB2 |
| A17 | IO87RSB2 |
| A18 | IO85RSB2 |
| A19 | IO82RSB2 |
| A20 | IO76RSB2 |
| A21 | IO70RSB2 |
| A22 | VCC |
| A23 | GDB2/IO62RSB2 |
| A24 | TDI |
| A25 | TRST |
| A26 | GDC1/IO58UDB1 |
| A27 | VCC |
| A28 | IO54NDB1 |
| A29 | IO52NDB1 |
| A30 | GCA2/IO51PPB1 |
| A31 | GCA0/IO50NPB1 |
| A32 | GCB1/IO49PDB1 |
| A33 | IO47NSB1 |
| A34 | VCC |
| A35 | IO41NPB1 |
| A36 | GBA2/IO41PPB1 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| A37 | GBB1/IO38RSB0 |
| A38 | GBC0/IO35RSB0 |
| A39 | VCCIB0 |
| A40 | IO28RSB0 |
| A41 | IO22RSB0 |
| A42 | IO18RSB0 |
| A43 | IO14RSB0 |
| A44 | IO11RSB0 |
| A45 | IO07RSB0 |
| A46 | VCC |
| A47 | GAC1/IO05RSB0 |
| A48 | GAB0/IO02RSB0 |
| B1 | IO118VDB3 |
| B2 | GAC2/IO116UDB3 |
| B3 | GND |
| B4 | GFC0/IO110NDB3 |
| B5 | VCOMPLF |
| B6 | GND |
| B7 | GFB2/IO106PSB3 |
| B8 | IO103PDB3 |
| B9 | GND |
| B10 | GEB0/IO99NDB3 |
| B11 | VMV3 |
| B12 | FF/GEB2/IO96RSB2 |
| B13 | IO92RSB2 |
| B14 | GND |
| B15 | IO89RSB2 |
| B16 | IO86RSB2 |
| B17 | GND |
| B18 | IO78RSB2 |
| B19 | IO72RSB2 |
| B20 | GND |
| B21 | GNDQ |
| B22 | TMS |
| B23 | TDO |
| B24 | GDC0/IO58VDB1 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| B25 | GND |
| B26 | IO54PDB1 |
| B27 | GCB2/IO52PDB1 |
| B28 | GND |
| B29 | GCB0/IO49NDB1 |
| B30 | GCC1/IO48PDB1 |
| B31 | GND |
| B32 | GBB2/IO42PDB1 |
| B33 | VMV1 |
| B34 | GBA0/IO39RSB0 |
| B35 | GBC1/IO36RSB0 |
| B36 | GND |
| B37 | IO26RSB0 |
| B38 | IO21RSB0 |
| B39 | GND |
| B40 | IO13RSB0 |
| B41 | IO08RSB0 |
| B42 | GND |
| B43 | GAC0/IO04RSB0 |
| B44 | GNDQ |
| C1 | GAA2/IO118UDB3 |
| C2 | IO116VDB3 |
| C3 | VCC |
| C4 | GFB1/IO109PPB3 |
| C5 | GFA0/IO108NPB3 |
| C6 | GFA2/IO107PSB3 |
| C7 | IO105NPB3 |
| C8 | VCCIB3 |
| C9 | GEB1/IO99PDB3 |
| C10 | GNDQ |
| C11 | GEA2/IO97RSB2 |
| C12 | IO94RSB2 |
| C13 | VCCIB2 |
| C14 | IO88RSB2 |
| C15 | IO84RSB2 |
| C16 | IO80RSB2 |

| QN132 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| C17 | IO74RSB2 |
| C18 | VCCIB2 |
| C19 | TCK |
| C20 | VMV2 |
| C21 | VPUMP |
| C22 | VJTAG |
| C23 | VCCIB1 |
| C24 | IO53NSB1 |
| C25 | IO51NPB1 |
| C26 | GCA1/IO50PPB1 |
| C27 | GCC0/IO48NDB1 |
| C28 | VCCIB1 |
| C29 | IO42NDB1 |
| C30 | GNDQ |
| C31 | GBA1/IO40RSB0 |
| C32 | GBB0/IO37RSB0 |
| C33 | VCC |
| C34 | IO24RSB0 |
| C35 | IO19RSB0 |
| C36 | IO16RSB0 |
| C37 | IO10RSB0 |
| C38 | VCCIB0 |
| C39 | GAB1/IO03RSB0 |
| C40 | VMV0 |
| D1 | GND |
| D2 | GND |
| D3 | GND |
| D4 | GND |

# VQ100




*Note: This is the top view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| VQ100 | |
|---|---|
| Pin Number | AGL030 Function |
| 1 | GND |
| 2 | IO82RSB1 |
| 3 | IO81RSB1 |
| 4 | IO80RSB1 |
| 5 | IO79RSB1 |
| 6 | IO78RSB1 |
| 7 | IO77RSB1 |
| 8 | IO76RSB1 |
| 9 | GND |
| 10 | IO75RSB1 |
| 11 | IO74RSB1 |
| 12 | GEC0/IO73RSB1 |
| 13 | GEA0/IO72RSB1 |
| 14 | GEB0/IO71RSB1 |
| 15 | IO70RSB1 |
| 16 | IO69RSB1 |
| 17 | VCC |
| 18 | VCCIB1 |
| 19 | IO68RSB1 |
| 20 | IO67RSB1 |
| 21 | IO66RSB1 |
| 22 | IO65RSB1 |
| 23 | IO64RSB1 |
| 24 | IO63RSB1 |
| 25 | IO62RSB1 |
| 26 | IO61RSB1 |
| 27 | FF/IO60RSB1 |
| 28 | IO59RSB1 |
| 29 | IO58RSB1 |
| 30 | IO57RSB1 |
| 31 | IO56RSB1 |
| 32 | IO55RSB1 |
| 33 | IO54RSB1 |
| 34 | IO53RSB1 |
| 35 | IO52RSB1 |
| 36 | IO51RSB1 |

| VQ100 | |
|---|---|
| Pin Number | AGL030 Function |
| 37 | VCC |
| 38 | GND |
| 39 | VCCIB1 |
| 40 | IO49RSB1 |
| 41 | IO47RSB1 |
| 42 | IO46RSB1 |
| 43 | IO45RSB1 |
| 44 | IO44RSB1 |
| 45 | IO43RSB1 |
| 46 | IO42RSB1 |
| 47 | TCK |
| 48 | TDI |
| 49 | TMS |
| 50 | NC |
| 51 | GND |
| 52 | VPUMP |
| 53 | NC |
| 54 | TDO |
| 55 | TRST |
| 56 | VJTAG |
| 57 | IO41RSB0 |
| 58 | IO40RSB0 |
| 59 | IO39RSB0 |
| 60 | IO38RSB0 |
| 61 | IO37RSB0 |
| 62 | IO36RSB0 |
| 63 | GDB0/IO34RSB0 |
| 64 | GDA0/IO33RSB0 |
| 65 | GDC0/IO32RSB0 |
| 66 | VCCIB0 |
| 67 | GND |
| 68 | VCC |
| 69 | IO31RSB0 |
| 70 | IO30RSB0 |
| 71 | IO29RSB0 |
| 72 | IO28RSB0 |

| VQ100 | |
|---|---|
| Pin Number | AGL030 Function |
| 73 | IO27RSB0 |
| 74 | IO26RSB0 |
| 75 | IO25RSB0 |
| 76 | IO24RSB0 |
| 77 | IO23RSB0 |
| 78 | IO22RSB0 |
| 79 | IO21RSB0 |
| 80 | IO20RSB0 |
| 81 | IO19RSB0 |
| 82 | IO18RSB0 |
| 83 | IO17RSB0 |
| 84 | IO16RSB0 |
| 85 | IO15RSB0 |
| 86 | IO14RSB0 |
| 87 | VCCIB0 |
| 88 | GND |
| 89 | VCC |
| 90 | IO12RSB0 |
| 91 | IO10RSB0 |
| 92 | IO08RSB0 |
| 93 | IO07RSB0 |
| 94 | IO06RSB0 |
| 95 | IO05RSB0 |
| 96 | IO04RSB0 |
| 97 | IO03RSB0 |
| 98 | IO02RSB0 |
| 99 | IO01RSB0 |
| 100 | IO00RSB0 |

| VQ100 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| 1 | GND |
| 2 | GAA2/IO51RSB1 |
| 3 | IO52RSB1 |
| 4 | GAB2/IO53RSB1 |
| 5 | IO95RSB1 |
| 6 | GAC2/IO94RSB1 |
| 7 | IO93RSB1 |
| 8 | IO92RSB1 |
| 9 | GND |
| 10 | GFB1/IO87RSB1 |
| 11 | GFB0/IO86RSB1 |
| 12 | VCOMPLF |
| 13 | GFA0/IO85RSB1 |
| 14 | VCCPLF |
| 15 | GFA1/IO84RSB1 |
| 16 | GFA2/IO83RSB1 |
| 17 | VCC |
| 18 | VCCIB1 |
| 19 | GEC1/IO77RSB1 |
| 20 | GEB1/IO75RSB1 |
| 21 | GEB0/IO74RSB1 |
| 22 | GEA1/IO73RSB1 |
| 23 | GEA0/IO72RSB1 |
| 24 | VMV1 |
| 25 | GNDQ |
| 26 | GEA2/IO71RSB1 |
| 27 | FF/GEB2/IO70RSB1 |
| 28 | GEC2/IO69RSB1 |
| 29 | IO68RSB1 |
| 30 | IO67RSB1 |
| 31 | IO66RSB1 |
| 32 | IO65RSB1 |
| 33 | IO64RSB1 |
| 34 | IO63RSB1 |
| 35 | IO62RSB1 |
| 36 | IO61RSB1 |

| VQ100 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| 37 | VCC |
| 38 | GND |
| 39 | VCCIB1 |
| 40 | IO60RSB1 |
| 41 | IO59RSB1 |
| 42 | IO58RSB1 |
| 43 | IO57RSB1 |
| 44 | GDC2/IO56RSB1 |
| 45 | GDB2/IO55RSB1 |
| 46 | GDA2/IO54RSB1 |
| 47 | TCK |
| 48 | TDI |
| 49 | TMS |
| 50 | VMV1 |
| 51 | GND |
| 52 | VPUMP |
| 53 | NC |
| 54 | TDO |
| 55 | TRST |
| 56 | VJTAG |
| 57 | GDA1/IO49RSB0 |
| 58 | GDC0/IO46RSB0 |
| 59 | GDC1/IO45RSB0 |
| 60 | GCC2/IO43RSB0 |
| 61 | GCB2/IO42RSB0 |
| 62 | GCA0/IO40RSB0 |
| 63 | GCA1/IO39RSB0 |
| 64 | GCC0/IO36RSB0 |
| 65 | GCC1/IO35RSB0 |
| 66 | VCCIB0 |
| 67 | GND |
| 68 | VCC |
| 69 | IO31RSB0 |
| 70 | GBC2/IO29RSB0 |
| 71 | GBB2/IO27RSB0 |
| 72 | IO26RSB0 |

| VQ100 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| 73 | GBA2/IO25RSB0 |
| 74 | VMV0 |
| 75 | GNDQ |
| 76 | GBA1/IO24RSB0 |
| 77 | GBA0/IO23RSB0 |
| 78 | GBB1/IO22RSB0 |
| 79 | GBB0/IO21RSB0 |
| 80 | GBC1/IO20RSB0 |
| 81 | GBC0/IO19RSB0 |
| 82 | IO18RSB0 |
| 83 | IO17RSB0 |
| 84 | IO15RSB0 |
| 85 | IO13RSB0 |
| 86 | IO11RSB0 |
| 87 | VCCIB0 |
| 88 | GND |
| 89 | VCC |
| 90 | IO10RSB0 |
| 91 | IO09RSB0 |
| 92 | IO08RSB0 |
| 93 | GAC1/IO07RSB0 |
| 94 | GAC0/IO06RSB0 |
| 95 | GAB1/IO05RSB0 |
| 96 | GAB0/IO04RSB0 |
| 97 | GAA1/IO03RSB0 |
| 98 | GAA0/IO02RSB0 |
| 99 | IO01RSB0 |
| 100 | IO00RSB0 |

| VQ100 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| 1 | GND |
| 2 | GAA2/IO67RSB1 |
| 3 | IO68RSB1 |
| 4 | GAB2/IO69RSB1 |
| 5 | IO132RSB1 |
| 6 | GAC2/IO131RSB1 |
| 7 | IO130RSB1 |
| 8 | IO129RSB1 |
| 9 | GND |
| 10 | GFB1/IO124RSB1 |
| 11 | GFB0/IO123RSB1 |
| 12 | VCOMPLF |
| 13 | GFA0/IO122RSB1 |
| 14 | VCCPLF |
| 15 | GFA1/IO121RSB1 |
| 16 | GFA2/IO120RSB1 |
| 17 | VCC |
| 18 | VCCIB1 |
| 19 | GEC0/IO111RSB1 |
| 20 | GEB1/IO110RSB1 |
| 21 | GEB0/IO109RSB1 |
| 22 | GEA1/IO108RSB1 |
| 23 | GEA0/IO107RSB1 |
| 24 | VMV1 |
| 25 | GNDQ |
| 26 | GEA2/IO106RSB1 |
| 27 | FF/GEB2/IO105RSB1 |
| 28 | GEC2/IO104RSB1 |
| 29 | IO102RSB1 |
| 30 | IO100RSB1 |
| 31 | IO99RSB1 |
| 32 | IO97RSB1 |
| 33 | IO96RSB1 |
| 34 | IO95RSB1 |
| 35 | IO94RSB1 |

| VQ100 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| 36 | IO93RSB1 |
| 37 | VCC |
| 38 | GND |
| 39 | VCCIB1 |
| 40 | IO87RSB1 |
| 41 | IO84RSB1 |
| 42 | IO81RSB1 |
| 43 | IO75RSB1 |
| 44 | GDC2/IO72RSB1 |
| 45 | GDB2/IO71RSB1 |
| 46 | GDA2/IO70RSB1 |
| 47 | TCK |
| 48 | TDI |
| 49 | TMS |
| 50 | VMV1 |
| 51 | GND |
| 52 | VPUMP |
| 53 | NC |
| 54 | TDO |
| 55 | TRST |
| 56 | VJTAG |
| 57 | GDA1/IO65RSB0 |
| 58 | GDC0/IO62RSB0 |
| 59 | GDC1/IO61RSB0 |
| 60 | GCC2/IO59RSB0 |
| 61 | GCB2/IO58RSB0 |
| 62 | GCA0/IO56RSB0 |
| 63 | GCA1/IO55RSB0 |
| 64 | GCC0/IO52RSB0 |
| 65 | GCC1/IO51RSB0 |
| 66 | VCCIB0 |
| 67 | GND |
| 68 | VCC |
| 69 | IO47RSB0 |
| 70 | GBC2/IO45RSB0 |
| 71 | GBB2/IO43RSB0 |

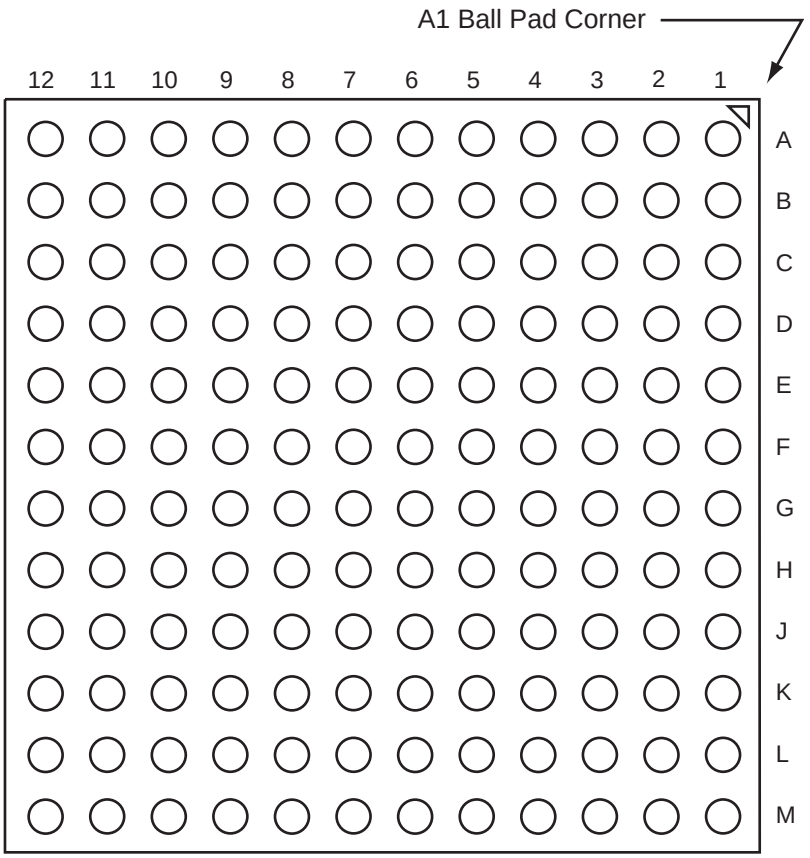
| VQ100 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| 72 | IO42RSB0 |
| 73 | GBA2/IO41RSB0 |
| 74 | VMV0 |
| 75 | GNDQ |
| 76 | GBA1/IO40RSB0 |
| 77 | GBA0/IO39RSB0 |
| 78 | GBB1/IO38RSB0 |
| 79 | GBB0/IO37RSB0 |
| 80 | GBC1/IO36RSB0 |
| 81 | GBC0/IO35RSB0 |
| 82 | IO32RSB0 |
| 83 | IO28RSB0 |
| 84 | IO25RSB0 |
| 85 | IO22RSB0 |
| 86 | IO19RSB0 |
| 87 | VCCIB0 |
| 88 | GND |
| 89 | VCC |
| 90 | IO15RSB0 |
| 91 | IO13RSB0 |
| 92 | IO11RSB0 |
| 93 | IO09RSB0 |
| 94 | IO07RSB0 |
| 95 | GAC1/IO05RSB0 |
| 96 | GAC0/IO04RSB0 |
| 97 | GAB1/IO03RSB0 |
| 98 | GAB0/IO02RSB0 |
| 99 | GAA1/IO01RSB0 |
| 100 | GAA0/IO00RSB0 |

| VQ100 | |
|---|---|
| Pin Number | AGL250 Function |
| 1 | GND |
| 2 | GAA2/IO118UDB3 |
| 3 | IO118VDB3 |
| 4 | GAB2/IO117UDB3 |
| 5 | IO117VDB3 |
| 6 | GAC2/IO116UDB3 |
| 7 | IO116VDB3 |
| 8 | IO112PSB3 |
| 9 | GND |
| 10 | GFB1/IO109PDB3 |
| 11 | GFB0/IO109NDB3 |
| 12 | VCOMPLF |
| 13 | GFA0/IO108NPB3 |
| 14 | VCCPLF |
| 15 | GFA1/IO108PPB3 |
| 16 | GFA2/IO107PSB3 |
| 17 | VCC |
| 18 | VCCIB3 |
| 19 | GFC2/IO105PSB3 |
| 20 | GEC1/IO100PDB3 |
| 21 | GEC0/IO100NDB3 |
| 22 | GEA1/IO98PDB3 |
| 23 | GEA0/IO98NDB3 |
| 24 | VMV3 |
| 25 | GNDQ |
| 26 | GEA2/IO97RSB2 |
| 27 | FF/GEB2/IO96RSB2 |
| 28 | GEC2/IO95RSB2 |
| 29 | IO93RSB2 |
| 30 | IO92RSB2 |
| 31 | IO91RSB2 |
| 32 | IO90RSB2 |
| 33 | IO88RSB2 |
| 34 | IO86RSB2 |
| 35 | IO85RSB2 |
| 36 | IO84RSB2 |

| VQ100 | |
|---|---|
| Pin Number | AGL250 Function |
| 37 | VCC |
| 38 | GND |
| 39 | VCCIB2 |
| 40 | IO77RSB2 |
| 41 | IO74RSB2 |
| 42 | IO71RSB2 |
| 43 | GDC2/IO63RSB2 |
| 44 | GDB2/IO62RSB2 |
| 45 | GDA2/IO61RSB2 |
| 46 | GNDQ |
| 47 | TCK |
| 48 | TDI |
| 49 | TMS |
| 50 | VMV2 |
| 51 | GND |
| 52 | VPUMP |
| 53 | NC |
| 54 | TDO |
| 55 | TRST |
| 56 | VJTAG |
| 57 | GDA1/IO60USB1 |
| 58 | GDC0/IO58VDB1 |
| 59 | GDC1/IO58UDB1 |
| 60 | IO52NDB1 |
| 61 | GCB2/IO52PDB1 |
| 62 | GCA1/IO50PDB1 |
| 63 | GCA0/IO50NDB1 |
| 64 | GCC0/IO48NDB1 |
| 65 | GCC1/IO48PDB1 |
| 66 | VCCIB1 |
| 67 | GND |
| 68 | VCC |
| 69 | IO43NDB1 |
| 70 | GBC2/IO43PDB1 |
| 71 | GBB2/IO42PSB1 |
| 72 | IO41NDB1 |

| VQ100 | |
|---|---|
| Pin Number | AGL250 Function |
| 73 | GBA2/IO41PDB1 |
| 74 | VMV1 |
| 75 | GNDQ |
| 76 | GBA1/IO40RSB0 |
| 77 | GBA0/IO39RSB0 |
| 78 | GBB1/IO38RSB0 |
| 79 | GBB0/IO37RSB0 |
| 80 | GBC1/IO36RSB0 |
| 81 | GBC0/IO35RSB0 |
| 82 | IO29RSB0 |
| 83 | IO27RSB0 |
| 84 | IO25RSB0 |
| 85 | IO23RSB0 |
| 86 | IO21RSB0 |
| 87 | VCCIB0 |
| 88 | GND |
| 89 | VCC |
| 90 | IO15RSB0 |
| 91 | IO13RSB0 |
| 92 | IO11RSB0 |
| 93 | GAC1/IO05RSB0 |
| 94 | GAC0/IO04RSB0 |
| 95 | GAB1/IO03RSB0 |
| 96 | GAB0/IO02RSB0 |
| 97 | GAA1/IO01RSB0 |
| 98 | GAA0/IO00RSB0 |
| 99 | GNDQ |
| 100 | VMV0 |

# FG144




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| FG144 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO04RSB0 |
| A4 | GAB1/IO05RSB0 |
| A5 | IO08RSB0 |
| A6 | GND |
| A7 | IO11RSB0 |
| A8 | VCC |
| A9 | IO16RSB0 |
| A10 | GBA0/IO23RSB0 |
| A11 | GBA1/IO24RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO53RSB1 |
| B2 | GND |
| B3 | GAA0/IO02RSB0 |
| B4 | GAA1/IO03RSB0 |
| B5 | IO00RSB0 |
| B6 | IO10RSB0 |
| B7 | IO12RSB0 |
| B8 | IO14RSB0 |
| B9 | GBB0/IO21RSB0 |
| B10 | GBB1/IO22RSB0 |
| B11 | GND |
| B12 | VMV0 |
| C1 | IO95RSB1 |
| C2 | GFA2/IO83RSB1 |
| C3 | GAC2/IO94RSB1 |
| C4 | VCC |
| C5 | IO01RSB0 |
| C6 | IO09RSB0 |
| C7 | IO13RSB0 |
| C8 | IO15RSB0 |
| C9 | IO17RSB0 |
| C10 | GBA2/IO25RSB0 |
| C11 | IO26RSB0 |
| C12 | GBC2/IO29RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| D1 | IO91RSB1 |
| D2 | IO92RSB1 |
| D3 | IO93RSB1 |
| D4 | GAA2/IO51RSB1 |
| D5 | GAC0/IO06RSB0 |
| D6 | GAC1/IO07RSB0 |
| D7 | GBC0/IO19RSB0 |
| D8 | GBC1/IO20RSB0 |
| D9 | GBB2/IO27RSB0 |
| D10 | IO18RSB0 |
| D11 | IO28RSB0 |
| D12 | GCB1/IO37RSB0 |
| E1 | VCC |
| E2 | GFC0/IO88RSB1 |
| E3 | GFC1/IO89RSB1 |
| E4 | VCCIB1 |
| E5 | IO52RSB1 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO35RSB0 |
| E9 | VCCIB0 |
| E10 | VCC |
| E11 | GCA0/IO40RSB0 |
| E12 | IO30RSB0 |
| F1 | GFB0/IO86RSB1 |
| F2 | VCOMPLF |
| F3 | GFB1/IO87RSB1 |
| F4 | IO90RSB1 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO36RSB0 |
| F9 | GCB0/IO38RSB0 |
| F10 | GND |
| F11 | GCA1/IO39RSB0 |
| F12 | GCA2/IO41RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| G1 | GFA1/IO84RSB1 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO85RSB1 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO45RSB0 |
| G9 | IO32RSB0 |
| G10 | GCC2/IO43RSB0 |
| G11 | IO31RSB0 |
| G12 | GCB2/IO42RSB0 |
| H1 | VCC |
| H2 | GFB2/IO82RSB1 |
| H3 | GFC2/IO81RSB1 |
| H4 | GEC1/IO77RSB1 |
| H5 | VCC |
| H6 | IO34RSB0 |
| H7 | IO44RSB0 |
| H8 | GDB2/IO55RSB1 |
| H9 | GDC0/IO46RSB0 |
| H10 | VCCIB0 |
| H11 | IO33RSB0 |
| H12 | VCC |
| J1 | GEB1/IO75RSB1 |
| J2 | IO78RSB1 |
| J3 | VCCIB1 |
| J4 | GEC0/IO76RSB1 |
| J5 | IO79RSB1 |
| J6 | IO80RSB1 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO54RSB1 |
| J10 | TDO |
| J11 | GDA1/IO49RSB0 |
| J12 | GDB1/IO47RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL060 Function** |
| K1 | GEB0/IO74RSB1 |
| K2 | GEA1/IO73RSB1 |
| K3 | GEA0/IO72RSB1 |
| K4 | GEA2/IO71RSB1 |
| K5 | IO65RSB1 |
| K6 | IO64RSB1 |
| K7 | GND |
| K8 | IO57RSB1 |
| K9 | GDC2/IO56RSB1 |
| K10 | GND |
| K11 | GDA0/IO50RSB0 |
| K12 | GDB0/IO48RSB0 |
| L1 | GND |
| L2 | VMV1 |
| L3 | FF/GEB2/IO70RSB1 |
| L4 | IO67RSB1 |
| L5 | VCCIB1 |
| L6 | IO62RSB1 |
| L7 | IO59RSB1 |
| L8 | IO58RSB1 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV1 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO69RSB1 |
| M3 | IO68RSB1 |
| M4 | IO66RSB1 |
| M5 | IO63RSB1 |
| M6 | IO61RSB1 |
| M7 | IO60RSB1 |
| M8 | NC |
| M9 | TDI |
| M10 | VCCIB1 |
| M11 | VPUMP |
| M12 | GNDQ |

| FG144 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO02RSB0 |
| A4 | GAB1/IO03RSB0 |
| A5 | IO11RSB0 |
| A6 | GND |
| A7 | IO18RSB0 |
| A8 | VCC |
| A9 | IO25RSB0 |
| A10 | GBA0/IO39RSB0 |
| A11 | GBA1/IO40RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO69RSB1 |
| B2 | GND |
| B3 | GAA0/IO00RSB0 |
| B4 | GAA1/IO01RSB0 |
| B5 | IO08RSB0 |
| B6 | IO14RSB0 |
| B7 | IO19RSB0 |
| B8 | IO22RSB0 |
| B9 | GBB0/IO37RSB0 |
| B10 | GBB1/IO38RSB0 |
| B11 | GND |
| B12 | VMV0 |
| C1 | IO132RSB1 |
| C2 | GFA2/IO120RSB1 |
| C3 | GAC2/IO131RSB1 |
| C4 | VCC |
| C5 | IO10RSB0 |
| C6 | IO12RSB0 |
| C7 | IO21RSB0 |
| C8 | IO24RSB0 |
| C9 | IO27RSB0 |
| C10 | GBA2/IO41RSB0 |
| C11 | IO42RSB0 |
| C12 | GBC2/IO45RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| D1 | IO128RSB1 |
| D2 | IO129RSB1 |
| D3 | IO130RSB1 |
| D4 | GAA2/IO67RSB1 |
| D5 | GAC0/IO04RSB0 |
| D6 | GAC1/IO05RSB0 |
| D7 | GBC0/IO35RSB0 |
| D8 | GBC1/IO36RSB0 |
| D9 | GBB2/IO43RSB0 |
| D10 | IO28RSB0 |
| D11 | IO44RSB0 |
| D12 | GCB1/IO53RSB0 |
| E1 | VCC |
| E2 | GFC0/IO125RSB1 |
| E3 | GFC1/IO126RSB1 |
| E4 | VCCIB1 |
| E5 | IO68RSB1 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO51RSB0 |
| E9 | VCCIB0 |
| E10 | VCC |
| E11 | GCA0/IO56RSB0 |
| E12 | IO46RSB0 |
| F1 | GFB0/IO123RSB1 |
| F2 | VCOMPLF |
| F3 | GFB1/IO124RSB1 |
| F4 | IO127RSB1 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO52RSB0 |
| F9 | GCB0/IO54RSB0 |
| F10 | GND |
| F11 | GCA1/IO55RSB0 |
| F12 | GCA2/IO57RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| G1 | GFA1/IO121RSB1 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO122RSB1 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO61RSB0 |
| G9 | IO48RSB0 |
| G10 | GCC2/IO59RSB0 |
| G11 | IO47RSB0 |
| G12 | GCB2/IO58RSB0 |
| H1 | VCC |
| H2 | GFB2/IO119RSB1 |
| H3 | GFC2/IO118RSB1 |
| H4 | GEC1/IO112RSB1 |
| H5 | VCC |
| H6 | IO50RSB0 |
| H7 | IO60RSB0 |
| H8 | GDB2/IO71RSB1 |
| H9 | GDC0/IO62RSB0 |
| H10 | VCCIB0 |
| H11 | IO49RSB0 |
| H12 | VCC |
| J1 | GEB1/IO110RSB1 |
| J2 | IO115RSB1 |
| J3 | VCCIB1 |
| J4 | GEC0/IO111RSB1 |
| J5 | IO116RSB1 |
| J6 | IO117RSB1 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO70RSB1 |
| J10 | TDO |
| J11 | GDA1/IO65RSB0 |
| J12 | GDB1/IO63RSB0 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL125 Function** |
| K1 | GEB0/IO109RSB1 |
| K2 | GEA1/IO108RSB1 |
| K3 | GEA0/IO107RSB1 |
| K4 | GEA2/IO106RSB1 |
| K5 | IO100RSB1 |
| K6 | IO98RSB1 |
| K7 | GND |
| K8 | IO73RSB1 |
| K9 | GDC2/IO72RSB1 |
| K10 | GND |
| K11 | GDA0/IO66RSB0 |
| K12 | GDB0/IO64RSB0 |
| L1 | GND |
| L2 | VMV1 |
| L3 | FF/GEB2/IO105RSB1 |
| L4 | IO102RSB1 |
| L5 | VCCIB1 |
| L6 | IO95RSB1 |
| L7 | IO85RSB1 |
| L8 | IO74RSB1 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV1 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO104RSB1 |
| M3 | IO103RSB1 |
| M4 | IO101RSB1 |
| M5 | IO97RSB1 |
| M6 | IO94RSB1 |
| M7 | IO86RSB1 |
| M8 | IO75RSB1 |
| M9 | TDI |
| M10 | VCCIB1 |
| M11 | VPUMP |
| M12 | GNDQ |

| FG144 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO02RSB0 |
| A4 | GAB1/IO03RSB0 |
| A5 | IO16RSB0 |
| A6 | GND |
| A7 | IO29RSB0 |
| A8 | VCC |
| A9 | IO33RSB0 |
| A10 | GBA0/IO39RSB0 |
| A11 | GBA1/IO40RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO117UDB3 |
| B2 | GND |
| B3 | GAA0/IO00RSB0 |
| B4 | GAA1/IO01RSB0 |
| B5 | IO14RSB0 |
| B6 | IO19RSB0 |
| B7 | IO22RSB0 |
| B8 | IO30RSB0 |
| B9 | GBB0/IO37RSB0 |
| B10 | GBB1/IO38RSB0 |
| B11 | GND |
| B12 | VMV1 |
| C1 | IO117VDB3 |
| C2 | GFA2/IO107PPB3 |
| C3 | GAC2/IO116UDB3 |
| C4 | VCC |
| C5 | IO12RSB0 |
| C6 | IO17RSB0 |
| C7 | IO24RSB0 |
| C8 | IO31RSB0 |
| C9 | IO34RSB0 |
| C10 | GBA2/IO41PDB1 |
| C11 | IO41NDB1 |
| C12 | GBC2/IO43PPB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| D1 | IO112NDB3 |
| D2 | IO112PDB3 |
| D3 | IO116VDB3 |
| D4 | GAA2/IO118UPB3 |
| D5 | GAC0/IO04RSB0 |
| D6 | GAC1/IO05RSB0 |
| D7 | GBC0/IO35RSB0 |
| D8 | GBC1/IO36RSB0 |
| D9 | GBB2/IO42PDB1 |
| D10 | IO42NDB1 |
| D11 | IO43NPB1 |
| D12 | GCB1/IO49PPB1 |
| E1 | VCC |
| E2 | GFC0/IO110NDB3 |
| E3 | GFC1/IO110PDB3 |
| E4 | VCCIB3 |
| E5 | IO118VPB3 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO48PDB1 |
| E9 | VCCIB1 |
| E10 | VCC |
| E11 | GCA0/IO50NDB1 |
| E12 | IO51NDB1 |
| F1 | GFB0/IO109NPB3 |
| F2 | VCOMPLF |
| F3 | GFB1/IO109PPB3 |
| F4 | IO107NPB3 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO48NDB1 |
| F9 | GCB0/IO49NPB1 |
| F10 | GND |
| F11 | GCA1/IO50PDB1 |
| F12 | GCA2/IO51PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| G1 | GFA1/IO108PPB3 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO108NPB3 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO58UPB1 |
| G9 | IO53NDB1 |
| G10 | GCC2/IO53PDB1 |
| G11 | IO52NDB1 |
| G12 | GCB2/IO52PDB1 |
| H1 | VCC |
| H2 | GFB2/IO106PDB3 |
| H3 | GFC2/IO105PSB3 |
| H4 | GEC1/IO100PDB3 |
| H5 | VCC |
| H6 | IO79RSB2 |
| H7 | IO65RSB2 |
| H8 | GDB2/IO62RSB2 |
| H9 | GDC0/IO58VPB1 |
| H10 | VCCIB1 |
| H11 | IO54PSB1 |
| H12 | VCC |
| J1 | GEB1/IO99PDB3 |
| J2 | IO106NDB3 |
| J3 | VCCIB3 |
| J4 | GEC0/IO100NDB3 |
| J5 | IO88RSB2 |
| J6 | IO81RSB2 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO61RSB2 |
| J10 | TDO |
| J11 | GDA1/IO60UDB1 |
| J12 | GDB1/IO59UDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL250 Function** |
| K1 | GEB0/IO99NDB3 |
| K2 | GEA1/IO98PDB3 |
| K3 | GEA0/IO98NDB3 |
| K4 | GEA2/IO97RSB2 |
| K5 | IO90RSB2 |
| K6 | IO84RSB2 |
| K7 | GND |
| K8 | IO66RSB2 |
| K9 | GDC2/IO63RSB2 |
| K10 | GND |
| K11 | GDA0/IO60VDB1 |
| K12 | GDB0/IO59VDB1 |
| L1 | GND |
| L2 | VMV3 |
| L3 | FF/GEB2/IO96RSB2 |
| L4 | IO91RSB2 |
| L5 | VCCIB2 |
| L6 | IO82RSB2 |
| L7 | IO80RSB2 |
| L8 | IO72RSB2 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV2 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO95RSB2 |
| M3 | IO92RSB2 |
| M4 | IO89RSB2 |
| M5 | IO87RSB2 |
| M6 | IO85RSB2 |
| M7 | IO78RSB2 |
| M8 | IO76RSB2 |
| M9 | TDI |
| M10 | VCCIB2 |
| M11 | VPUMP |
| M12 | GNDQ |

| FG144 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO02RSB0 |
| A4 | GAB1/IO03RSB0 |
| A5 | IO16RSB0 |
| A6 | GND |
| A7 | IO30RSB0 |
| A8 | VCC |
| A9 | IO34RSB0 |
| A10 | GBA0/IO58RSB0 |
| A11 | GBA1/IO59RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO154UDB3 |
| B2 | GND |
| B3 | GAA0/IO00RSB0 |
| B4 | GAA1/IO01RSB0 |
| B5 | IO14RSB0 |
| B6 | IO19RSB0 |
| B7 | IO23RSB0 |
| B8 | IO31RSB0 |
| B9 | GBB0/IO56RSB0 |
| B10 | GBB1/IO57RSB0 |
| B11 | GND |
| B12 | VMV1 |
| C1 | IO154VDB3 |
| C2 | GFA2/IO144PPB3 |
| C3 | GAC2/IO153UDB3 |
| C4 | VCC |
| C5 | IO12RSB0 |
| C6 | IO17RSB0 |
| C7 | IO25RSB0 |
| C8 | IO32RSB0 |
| C9 | IO53RSB0 |
| C10 | GBA2/IO60PDB1 |
| C11 | IO60NDB1 |
| C12 | GBC2/IO62PPB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| D1 | IO149NDB3 |
| D2 | IO149PDB3 |
| D3 | IO153VDB3 |
| D4 | GAA2/IO155UPB3 |
| D5 | GAC0/IO04RSB0 |
| D6 | GAC1/IO05RSB0 |
| D7 | GBC0/IO54RSB0 |
| D8 | GBC1/IO55RSB0 |
| D9 | GBB2/IO61PDB1 |
| D10 | IO61NDB1 |
| D11 | IO62NPB1 |
| D12 | GCB1/IO68PPB1 |
| E1 | VCC |
| E2 | GFC0/IO147NDB3 |
| E3 | GFC1/IO147PDB3 |
| E4 | VCCIB3 |
| E5 | IO155VPB3 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO67PDB1 |
| E9 | VCCIB1 |
| E10 | VCC |
| E11 | GCA0/IO69NDB1 |
| E12 | IO70NDB1 |
| F1 | GFB0/IO146NPB3 |
| F2 | VCOMPLF |
| F3 | GFB1/IO146PPB3 |
| F4 | IO144NPB3 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO67NDB1 |
| F9 | GCB0/IO68NPB1 |
| F10 | GND |
| F11 | GCA1/IO69PDB1 |
| F12 | GCA2/IO70PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| G1 | GFA1/IO145PPB3 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO145NPB3 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO77UPB1 |
| G9 | IO72NDB1 |
| G10 | GCC2/IO72PDB1 |
| G11 | IO71NDB1 |
| G12 | GCB2/IO71PDB1 |
| H1 | VCC |
| H2 | GFB2/IO143PDB3 |
| H3 | GFC2/IO142PSB3 |
| H4 | GEC1/IO137PDB3 |
| H5 | VCC |
| H6 | IO75PDB1 |
| H7 | IO75NDB1 |
| H8 | GDB2/IO81RSB2 |
| H9 | GDC0/IO77VPB1 |
| H10 | VCCIB1 |
| H11 | IO73PSB1 |
| H12 | VCC |
| J1 | GEB1/IO136PDB3 |
| J2 | IO143NDB3 |
| J3 | VCCIB3 |
| J4 | GEC0/IO137NDB3 |
| J5 | IO125RSB2 |
| J6 | IO116RSB2 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO80RSB2 |
| J10 | TDO |
| J11 | GDA1/IO79UDB1 |
| J12 | GDB1/IO78UDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| K1 | GEB0/IO136NDB3 |
| K2 | GEA1/IO135PDB3 |
| K3 | GEA0/IO135NDB3 |
| K4 | GEA2/IO134RSB2 |
| K5 | IO127RSB2 |
| K6 | IO121RSB2 |
| K7 | GND |
| K8 | IO104RSB2 |
| K9 | GDC2/IO82RSB2 |
| K10 | GND |
| K11 | GDA0/IO79VDB1 |
| K12 | GDB0/IO78VDB1 |
| L1 | GND |
| L2 | VMV3 |
| L3 | FF/GEB2/IO133RSB2 |
| L4 | IO128RSB2 |
| L5 | VCCIB2 |
| L6 | IO119RSB2 |
| L7 | IO114RSB2 |
| L8 | IO110RSB2 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV2 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO132RSB2 |
| M3 | IO129RSB2 |
| M4 | IO126RSB2 |
| M5 | IO124RSB2 |
| M6 | IO122RSB2 |
| M7 | IO117RSB2 |
| M8 | IO115RSB2 |
| M9 | TDI |
| M10 | VCCIB2 |
| M11 | VPUMP |
| M12 | GNDQ |

| FG144 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO02RSB0 |
| A4 | GAB1/IO03RSB0 |
| A5 | IO10RSB0 |
| A6 | GND |
| A7 | IO34RSB0 |
| A8 | VCC |
| A9 | IO50RSB0 |
| A10 | GBA0/IO58RSB0 |
| A11 | GBA1/IO59RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO173PDB3 |
| B2 | GND |
| B3 | GAA0/IO00RSB0 |
| B4 | GAA1/IO01RSB0 |
| B5 | IO13RSB0 |
| B6 | IO19RSB0 |
| B7 | IO31RSB0 |
| B8 | IO39RSB0 |
| B9 | GBB0/IO56RSB0 |
| B10 | GBB1/IO57RSB0 |
| B11 | GND |
| B12 | VMV1 |
| C1 | IO173NDB3 |
| C2 | GFA2/IO161PPB3 |
| C3 | GAC2/IO172PDB3 |
| C4 | VCC |
| C5 | IO16RSB0 |
| C6 | IO25RSB0 |
| C7 | IO28RSB0 |
| C8 | IO42RSB0 |
| C9 | IO45RSB0 |
| C10 | GBA2/IO60PDB1 |
| C11 | IO60NDB1 |
| C12 | GBC2/IO62PPB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| D1 | IO169PDB3 |
| D2 | IO169NDB3 |
| D3 | IO172NDB3 |
| D4 | GAA2/IO174PPB3 |
| D5 | GAC0/IO04RSB0 |
| D6 | GAC1/IO05RSB0 |
| D7 | GBC0/IO54RSB0 |
| D8 | GBC1/IO55RSB0 |
| D9 | GBB2/IO61PDB1 |
| D10 | IO61NDB1 |
| D11 | IO62NPB1 |
| D12 | GCB1/IO70PPB1 |
| E1 | VCC |
| E2 | GFC0/IO164NDB3 |
| E3 | GFC1/IO164PDB3 |
| E4 | VCCIB3 |
| E5 | IO174NPB3 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO69PDB1 |
| E9 | VCCIB1 |
| E10 | VCC |
| E11 | GCA0/IO71NDB1 |
| E12 | IO72NDB1 |
| F1 | GFB0/IO163NPB3 |
| F2 | VCOMPLF |
| F3 | GFB1/IO163PPB3 |
| F4 | IO161NPB3 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO69NDB1 |
| F9 | GCB0/IO70NPB1 |
| F10 | GND |
| F11 | GCA1/IO71PDB1 |
| F12 | GCA2/IO72PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| G1 | GFA1/IO162PPB3 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO162NPB3 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO86PPB1 |
| G9 | IO74NDB1 |
| G10 | GCC2/IO74PDB1 |
| G11 | IO73NDB1 |
| G12 | GCB2/IO73PDB1 |
| H1 | VCC |
| H2 | GFB2/IO160PDB3 |
| H3 | GFC2/IO159PSB3 |
| H4 | GEC1/IO146PDB3 |
| H5 | VCC |
| H6 | IO80PDB1 |
| H7 | IO80NDB1 |
| H8 | GDB2/IO90RSB2 |
| H9 | GDC0/IO86NPB1 |
| H10 | VCCIB1 |
| H11 | IO84PSB1 |
| H12 | VCC |
| J1 | GEB1/IO145PDB3 |
| J2 | IO160NDB3 |
| J3 | VCCIB3 |
| J4 | GEC0/IO146NDB3 |
| J5 | IO129RSB2 |
| J6 | IO131RSB2 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO89RSB2 |
| J10 | TDO |
| J11 | GDA1/IO88PDB1 |
| J12 | GDB1/IO87PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| K1 | GEB0/IO145NDB3 |
| K2 | GEA1/IO144PDB3 |
| K3 | GEA0/IO144NDB3 |
| K4 | GEA2/IO143RSB2 |
| K5 | IO119RSB2 |
| K6 | IO111RSB2 |
| K7 | GND |
| K8 | IO94RSB2 |
| K9 | GDC2/IO91RSB2 |
| K10 | GND |
| K11 | GDA0/IO88NDB1 |
| K12 | GDB0/IO87NDB1 |
| L1 | GND |
| L2 | VMV3 |
| L3 | FF/GEB2/IO142RSB2 |
| L4 | IO136RSB2 |
| L5 | VCCIB2 |
| L6 | IO115RSB2 |
| L7 | IO103RSB2 |
| L8 | IO97RSB2 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV2 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO141RSB2 |
| M3 | IO138RSB2 |
| M4 | IO123RSB2 |
| M5 | IO126RSB2 |
| M6 | IO134RSB2 |
| M7 | IO108RSB2 |
| M8 | IO99RSB2 |
| M9 | TDI |
| M10 | VCCIB2 |
| M11 | VPUMP |
| M12 | GNDQ |

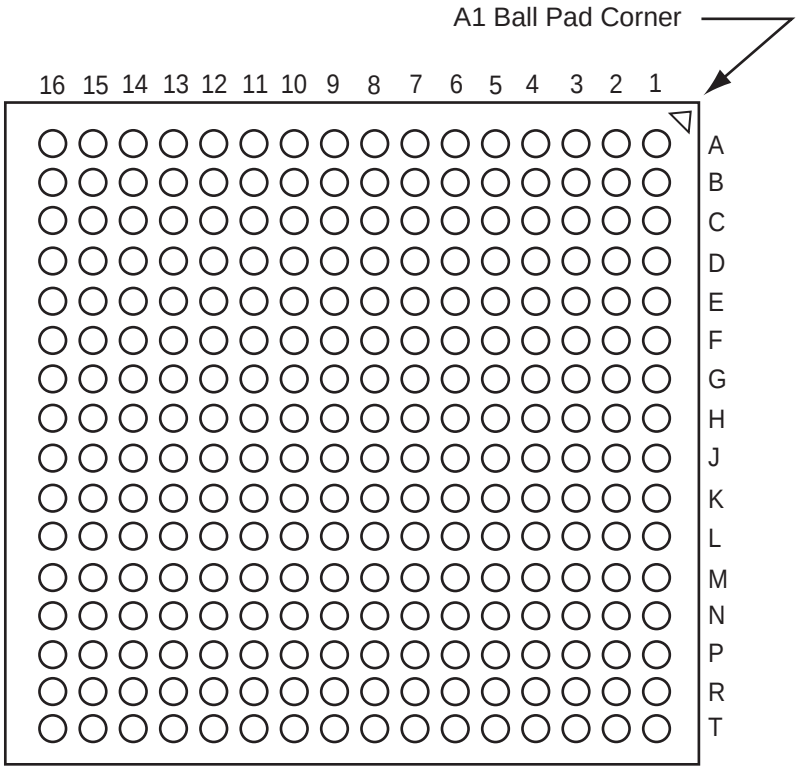
| FG144 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| A1 | GNDQ |
| A2 | VMV0 |
| A3 | GAB0/IO02RSB0 |
| A4 | GAB1/IO03RSB0 |
| A5 | IO10RSB0 |
| A6 | GND |
| A7 | IO44RSB0 |
| A8 | VCC |
| A9 | IO69RSB0 |
| A10 | GBA0/IO76RSB0 |
| A11 | GBA1/IO77RSB0 |
| A12 | GNDQ |
| B1 | GAB2/IO224PDB3 |
| B2 | GND |
| B3 | GAA0/IO00RSB0 |
| B4 | GAA1/IO01RSB0 |
| B5 | IO13RSB0 |
| B6 | IO26RSB0 |
| B7 | IO35RSB0 |
| B8 | IO60RSB0 |
| B9 | GBB0/IO74RSB0 |
| B10 | GBB1/IO75RSB0 |
| B11 | GND |
| B12 | VMV1 |
| C1 | IO224NDB3 |
| C2 | GFA2/IO206PPB3 |
| C3 | GAC2/IO223PDB3 |
| C4 | VCC |
| C5 | IO16RSB0 |
| C6 | IO29RSB0 |
| C7 | IO32RSB0 |
| C8 | IO63RSB0 |
| C9 | IO66RSB0 |
| C10 | GBA2/IO78PDB1 |
| C11 | IO78NDB1 |
| C12 | GBC2/IO80PPB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| D1 | IO213PDB3 |
| D2 | IO213NDB3 |
| D3 | IO223NDB3 |
| D4 | GAA2/IO225PPB3 |
| D5 | GAC0/IO04RSB0 |
| D6 | GAC1/IO05RSB0 |
| D7 | GBC0/IO72RSB0 |
| D8 | GBC1/IO73RSB0 |
| D9 | GBB2/IO79PDB1 |
| D10 | IO79NDB1 |
| D11 | IO80NPB1 |
| D12 | GCB1/IO92PPB1 |
| E1 | VCC |
| E2 | GFC0/IO209NDB3 |
| E3 | GFC1/IO209PDB3 |
| E4 | VCCIB3 |
| E5 | IO225NPB3 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | GCC1/IO91PDB1 |
| E9 | VCCIB1 |
| E10 | VCC |
| E11 | GCA0/IO93NDB1 |
| E12 | IO94NDB1 |
| F1 | GFB0/IO208NPB3 |
| F2 | VCOMPLF |
| F3 | GFB1/IO208PPB3 |
| F4 | IO206NPB3 |
| F5 | GND |
| F6 | GND |
| F7 | GND |
| F8 | GCC0/IO91NDB1 |
| F9 | GCB0/IO92NPB1 |
| F10 | GND |
| F11 | GCA1/IO93PDB1 |
| F12 | GCA2/IO94PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| G1 | GFA1/IO207PPB3 |
| G2 | GND |
| G3 | VCCPLF |
| G4 | GFA0/IO207NPB3 |
| G5 | GND |
| G6 | GND |
| G7 | GND |
| G8 | GDC1/IO111PPB1 |
| G9 | IO96NDB1 |
| G10 | GCC2/IO96PDB1 |
| G11 | IO95NDB1 |
| G12 | GCB2/IO95PDB1 |
| H1 | VCC |
| H2 | GFB2/IO205PDB3 |
| H3 | GFC2/IO204PSB3 |
| H4 | GEC1/IO190PDB3 |
| H5 | VCC |
| H6 | IO105PDB1 |
| H7 | IO105NDB1 |
| H8 | GDB2/IO115RSB2 |
| H9 | GDC0/IO111NPB1 |
| H10 | VCCIB1 |
| H11 | IO101PSB1 |
| H12 | VCC |
| J1 | GEB1/IO189PDB3 |
| J2 | IO205NDB3 |
| J3 | VCCIB3 |
| J4 | GEC0/IO190NDB3 |
| J5 | IO160RSB2 |
| J6 | IO157RSB2 |
| J7 | VCC |
| J8 | TCK |
| J9 | GDA2/IO114RSB2 |
| J10 | TDO |
| J11 | GDA1/IO113PDB1 |
| J12 | GDB1/IO112PDB1 |

| FG144 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| K1 | GEB0/IO189NDB3 |
| K2 | GEA1/IO188PDB3 |
| K3 | GEA0/IO188NDB3 |
| K4 | GEA2/IO187RSB2 |
| K5 | IO169RSB2 |
| K6 | IO152RSB2 |
| K7 | GND |
| K8 | IO117RSB2 |
| K9 | GDC2/IO116RSB2 |
| K10 | GND |
| K11 | GDA0/IO113NDB1 |
| K12 | GDB0/IO112NDB1 |
| L1 | GND |
| L2 | VMV3 |
| L3 | FF/GEB2/IO186RSB2 |
| L4 | IO172RSB2 |
| L5 | VCCIB2 |
| L6 | IO153RSB2 |
| L7 | IO144RSB2 |
| L8 | IO140RSB2 |
| L9 | TMS |
| L10 | VJTAG |
| L11 | VMV2 |
| L12 | TRST |
| M1 | GNDQ |
| M2 | GEC2/IO185RSB2 |
| M3 | IO173RSB2 |
| M4 | IO168RSB2 |
| M5 | IO161RSB2 |
| M6 | IO156RSB2 |
| M7 | IO145RSB2 |
| M8 | IO141RSB2 |
| M9 | TDI |
| M10 | VCCIB2 |
| M11 | VPUMP |
| M12 | GNDQ |

# FG256




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAA1/IO01RSB0 |
| A4 | GAB0/IO02RSB0 |
| A5 | IO16RSB0 |
| A6 | IO17RSB0 |
| A7 | IO22RSB0 |
| A8 | IO28RSB0 |
| A9 | IO34RSB0 |
| A10 | IO37RSB0 |
| A11 | IO41RSB0 |
| A12 | IO43RSB0 |
| A13 | GBB1/IO57RSB0 |
| A14 | GBA0/IO58RSB0 |
| A15 | GBA1/IO59RSB0 |
| A16 | GND |
| B1 | GAB2/IO154UDB3 |
| B2 | GAA2/IO155UDB3 |
| B3 | IO12RSB0 |
| B4 | GAB1/IO03RSB0 |
| B5 | IO13RSB0 |
| B6 | IO14RSB0 |
| B7 | IO21RSB0 |
| B8 | IO27RSB0 |
| B9 | IO32RSB0 |
| B10 | IO38RSB0 |
| B11 | IO42RSB0 |
| B12 | GBC1/IO55RSB0 |
| B13 | GBB0/IO56RSB0 |
| B14 | IO44RSB0 |
| B15 | GBA2/IO60PDB1 |
| B16 | IO60NDB1 |
| C1 | IO154VDB3 |
| C2 | IO155VDB3 |
| C3 | IO11RSB0 |
| C4 | IO07RSB0 |
| C5 | GAC0/IO04RSB0 |
| C6 | GAC1/IO05RSB0 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| C7 | IO20RSB0 |
| C8 | IO24RSB0 |
| C9 | IO33RSB0 |
| C10 | IO39RSB0 |
| C11 | IO45RSB0 |
| C12 | GBC0/IO54RSB0 |
| C13 | IO48RSB0 |
| C14 | VMV0 |
| C15 | IO61NPB1 |
| C16 | IO63PDB1 |
| D1 | IO151VDB3 |
| D2 | IO151UDB3 |
| D3 | GAC2/IO153UDB3 |
| D4 | IO06RSB0 |
| D5 | GNDQ |
| D6 | IO10RSB0 |
| D7 | IO19RSB0 |
| D8 | IO26RSB0 |
| D9 | IO30RSB0 |
| D10 | IO40RSB0 |
| D11 | IO46RSB0 |
| D12 | GNDQ |
| D13 | IO47RSB0 |
| D14 | GBB2/IO61PPB1 |
| D15 | IO53RSB0 |
| D16 | IO63NDB1 |
| E1 | IO150PDB3 |
| E2 | IO08RSB0 |
| E3 | IO153VDB3 |
| E4 | IO152VDB3 |
| E5 | VMV0 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | IO25RSB0 |
| E9 | IO31RSB0 |
| E10 | VCCIB0 |
| E11 | VCCIB0 |
| E12 | VMV1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| E13 | GBC2/IO62PDB1 |
| E14 | IO65RSB1 |
| E15 | IO52RSB0 |
| E16 | IO66PDB1 |
| F1 | IO150NDB3 |
| F2 | IO149NPB3 |
| F3 | IO09RSB0 |
| F4 | IO152UDB3 |
| F5 | VCCIB3 |
| F6 | GND |
| F7 | VCC |
| F8 | VCC |
| F9 | VCC |
| F10 | VCC |
| F11 | GND |
| F12 | VCCIB1 |
| F13 | IO62NDB1 |
| F14 | IO49RSB0 |
| F15 | IO64PPB1 |
| F16 | IO66NDB1 |
| G1 | IO148NDB3 |
| G2 | IO148PDB3 |
| G3 | IO149PPB3 |
| G4 | GFC1/IO147PPB3 |
| G5 | VCCIB3 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | GND |
| G10 | GND |
| G11 | VCC |
| G12 | VCCIB1 |
| G13 | GCC1/IO67PPB1 |
| G14 | IO64NPB1 |
| G15 | IO73PDB1 |
| G16 | IO73NDB1 |
| H1 | GFB0/IO146NPB3 |
| H2 | GFA0/IO145NDB3 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| H3 | GFB1/IO146PPB3 |
| H4 | VCOMPLF |
| H5 | GFC0/IO147NPB3 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | GND |
| H10 | GND |
| H11 | VCC |
| H12 | GCC0/IO67NPB1 |
| H13 | GCB1/IO68PPB1 |
| H14 | GCA0/IO69NPB1 |
| H15 | NC |
| H16 | GCB0/IO68NPB1 |
| J1 | GFA2/IO144PPB3 |
| J2 | GFA1/IO145PDB3 |
| J3 | VCCPLF |
| J4 | IO143NDB3 |
| J5 | GFB2/IO143PDB3 |
| J6 | VCC |
| J7 | GND |
| J8 | GND |
| J9 | GND |
| J10 | GND |
| J11 | VCC |
| J12 | GCB2/IO71PPB1 |
| J13 | GCA1/IO69PPB1 |
| J14 | GCC2/IO72PPB1 |
| J15 | NC |
| J16 | GCA2/IO70PDB1 |
| K1 | GFC2/IO142PDB3 |
| K2 | IO144NPB3 |
| K3 | IO141PPB3 |
| K4 | IO120RSB2 |
| K5 | VCCIB3 |
| K6 | VCC |
| K7 | GND |
| K8 | GND |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| K9 | GND |
| K10 | GND |
| K11 | VCC |
| K12 | VCCIB1 |
| K13 | IO71NPB1 |
| K14 | IO74RSB1 |
| K15 | IO72NPB1 |
| K16 | IO70NDB1 |
| L1 | IO142NDB3 |
| L2 | IO141NPB3 |
| L3 | IO125RSB2 |
| L4 | IO139RSB3 |
| L5 | VCCIB3 |
| L6 | GND |
| L7 | VCC |
| L8 | VCC |
| L9 | VCC |
| L10 | VCC |
| L11 | GND |
| L12 | VCCIB1 |
| L13 | GDB0/IO78VPB1 |
| L14 | IO76VDB1 |
| L15 | IO76UDB1 |
| L16 | IO75PDB1 |
| M1 | IO140PDB3 |
| M2 | IO130RSB2 |
| M3 | IO138NPB3 |
| M4 | GEC0/IO137NPB3 |
| M5 | VMV3 |
| M6 | VCCIB2 |
| M7 | VCCIB2 |
| M8 | IO108RSB2 |
| M9 | IO101RSB2 |
| M10 | VCCIB2 |
| M11 | VCCIB2 |
| M12 | VMV2 |
| M13 | IO83RSB2 |
| M14 | GDB1/IO78UPB1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| M15 | GDC1/IO77UDB1 |
| M16 | IO75NDB1 |
| N1 | IO140NDB3 |
| N2 | IO138PPB3 |
| N3 | GEC1/IO137PPB3 |
| N4 | IO131RSB2 |
| N5 | GNDQ |
| N6 | GEA2/IO134RSB2 |
| N7 | IO117RSB2 |
| N8 | IO111RSB2 |
| N9 | IO99RSB2 |
| N10 | IO94RSB2 |
| N11 | IO87RSB2 |
| N12 | GNDQ |
| N13 | IO93RSB2 |
| N14 | VJTAG |
| N15 | GDC0/IO77VDB1 |
| N16 | GDA1/IO79UDB1 |
| P1 | GEB1/IO136PDB3 |
| P2 | GEB0/IO136NDB3 |
| P3 | VMV2 |
| P4 | IO129RSB2 |
| P5 | IO128RSB2 |
| P6 | IO122RSB2 |
| P7 | IO115RSB2 |
| P8 | IO110RSB2 |
| P9 | IO98RSB2 |
| P10 | IO95RSB2 |
| P11 | IO88RSB2 |
| P12 | IO84RSB2 |
| P13 | TCK |
| P14 | VPUMP |
| P15 | TRST |
| P16 | GDA0/IO79VDB1 |
| R1 | GEA1/IO135PDB3 |
| R2 | GEA0/IO135NDB3 |
| R3 | IO127RSB2 |
| R4 | GEC2/IO132RSB2 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| R5 | IO123RSB2 |
| R6 | IO118RSB2 |
| R7 | IO112RSB2 |
| R8 | IO106RSB2 |
| R9 | IO100RSB2 |
| R10 | IO96RSB2 |
| R11 | IO89RSB2 |
| R12 | IO85RSB2 |
| R13 | GDB2/IO81RSB2 |
| R14 | TDI |
| R15 | NC |
| R16 | TDO |
| T1 | GND |
| T2 | IO126RSB2 |
| T3 | FF/GEB2/IO133RSB2 |
| T4 | IO124RSB2 |
| T5 | IO116RSB2 |
| T6 | IO113RSB2 |
| T7 | IO107RSB2 |
| T8 | IO105RSB2 |
| T9 | IO102RSB2 |
| T10 | IO97RSB2 |
| T11 | IO92RSB2 |
| T12 | GDC2/IO82RSB2 |
| T13 | IO86RSB2 |
| T14 | GDA2/IO80RSB2 |
| T15 | TMS |
| T16 | GND |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAA1/IO01RSB0 |
| A4 | GAB0/IO02RSB0 |
| A5 | IO11RSB0 |
| A6 | IO16RSB0 |
| A7 | IO18RSB0 |
| A8 | IO28RSB0 |
| A9 | IO34RSB0 |
| A10 | IO37RSB0 |
| A11 | IO41RSB0 |
| A12 | IO43RSB0 |
| A13 | GBB1/IO57RSB0 |
| A14 | GBA0/IO58RSB0 |
| A15 | GBA1/IO59RSB0 |
| A16 | GND |
| B1 | GAB2/IO173PDB3 |
| B2 | GAA2/IO174PDB3 |
| B3 | GNDQ |
| B4 | GAB1/IO03RSB0 |
| B5 | IO13RSB0 |
| B6 | IO14RSB0 |
| B7 | IO21RSB0 |
| B8 | IO27RSB0 |
| B9 | IO32RSB0 |
| B10 | IO38RSB0 |
| B11 | IO42RSB0 |
| B12 | GBC1/IO55RSB0 |
| B13 | GBB0/IO56RSB0 |
| B14 | IO52RSB0 |
| B15 | GBA2/IO60PDB1 |
| B16 | IO60NDB1 |
| C1 | IO173NDB3 |
| C2 | IO174NDB3 |
| C3 | VMV3 |
| C4 | IO07RSB0 |
| C5 | GAC0/IO04RSB0 |
| C6 | GAC1/IO05RSB0 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| C7 | IO20RSB0 |
| C8 | IO24RSB0 |
| C9 | IO33RSB0 |
| C10 | IO39RSB0 |
| C11 | IO44RSB0 |
| C12 | GBC0/IO54RSB0 |
| C13 | IO51RSB0 |
| C14 | VMV0 |
| C15 | IO61NPB1 |
| C16 | IO63PDB1 |
| D1 | IO171NDB3 |
| D2 | IO171PDB3 |
| D3 | GAC2/IO172PDB3 |
| D4 | IO06RSB0 |
| D5 | GNDQ |
| D6 | IO10RSB0 |
| D7 | IO19RSB0 |
| D8 | IO26RSB0 |
| D9 | IO30RSB0 |
| D10 | IO40RSB0 |
| D11 | IO45RSB0 |
| D12 | GNDQ |
| D13 | IO50RSB0 |
| D14 | GBB2/IO61PPB1 |
| D15 | IO53RSB0 |
| D16 | IO63NDB1 |
| E1 | IO166PDB3 |
| E2 | IO167NPB3 |
| E3 | IO172NDB3 |
| E4 | IO169NDB3 |
| E5 | VMV0 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | IO25RSB0 |
| E9 | IO31RSB0 |
| E10 | VCCIB0 |
| E11 | VCCIB0 |
| E12 | VMV1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| E13 | GBC2/IO62PDB1 |
| E14 | IO67PPB1 |
| E15 | IO64PPB1 |
| E16 | IO66PDB1 |
| F1 | IO166NDB3 |
| F2 | IO168NPB3 |
| F3 | IO167PPB3 |
| F4 | IO169PDB3 |
| F5 | VCCIB3 |
| F6 | GND |
| F7 | VCC |
| F8 | VCC |
| F9 | VCC |
| F10 | VCC |
| F11 | GND |
| F12 | VCCIB1 |
| F13 | IO62NDB1 |
| F14 | IO64NPB1 |
| F15 | IO65PPB1 |
| F16 | IO66NDB1 |
| G1 | IO165NDB3 |
| G2 | IO165PDB3 |
| G3 | IO168PPB3 |
| G4 | GFC1/IO164PPB3 |
| G5 | VCCIB3 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | GND |
| G10 | GND |
| G11 | VCC |
| G12 | VCCIB1 |
| G13 | GCC1/IO69PPB1 |
| G14 | IO65NPB1 |
| G15 | IO75PDB1 |
| G16 | IO75NDB1 |
| H1 | GFB0/IO163NPB3 |
| H2 | GFA0/IO162NDB3 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| H3 | GFB1/IO163PPB3 |
| H4 | VCOMPLF |
| H5 | GFC0/IO164NPB3 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | GND |
| H10 | GND |
| H11 | VCC |
| H12 | GCC0/IO69NPB1 |
| H13 | GCB1/IO70PPB1 |
| H14 | GCA0/IO71NPB1 |
| H15 | IO67NPB1 |
| H16 | GCB0/IO70NPB1 |
| J1 | GFA2/IO161PPB3 |
| J2 | GFA1/IO162PDB3 |
| J3 | VCCPLF |
| J4 | IO160NDB3 |
| J5 | GFB2/IO160PDB3 |
| J6 | VCC |
| J7 | GND |
| J8 | GND |
| J9 | GND |
| J10 | GND |
| J11 | VCC |
| J12 | GCB2/IO73PPB1 |
| J13 | GCA1/IO71PPB1 |
| J14 | GCC2/IO74PPB1 |
| J15 | IO80PPB1 |
| J16 | GCA2/IO72PDB1 |
| K1 | GFC2/IO159PDB3 |
| K2 | IO161NPB3 |
| K3 | IO156PPB3 |
| K4 | IO129RSB2 |
| K5 | VCCIB3 |
| K6 | VCC |
| K7 | GND |
| K8 | GND |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| K9 | GND |
| K10 | GND |
| K11 | VCC |
| K12 | VCCIB1 |
| K13 | IO73NPB1 |
| K14 | IO80NPB1 |
| K15 | IO74NPB1 |
| K16 | IO72NDB1 |
| L1 | IO159NDB3 |
| L2 | IO156NPB3 |
| L3 | IO151PPB3 |
| L4 | IO158PSB3 |
| L5 | VCCIB3 |
| L6 | GND |
| L7 | VCC |
| L8 | VCC |
| L9 | VCC |
| L10 | VCC |
| L11 | GND |
| L12 | VCCIB1 |
| L13 | GDB0/IO87NPB1 |
| L14 | IO85NDB1 |
| L15 | IO85PDB1 |
| L16 | IO84PDB1 |
| M1 | IO150PDB3 |
| M2 | IO151NPB3 |
| M3 | IO147NPB3 |
| M4 | GEC0/IO146NPB3 |
| M5 | VMV3 |
| M6 | VCCIB2 |
| M7 | VCCIB2 |
| M8 | IO117RSB2 |
| M9 | IO110RSB2 |
| M10 | VCCIB2 |
| M11 | VCCIB2 |
| M12 | VMV2 |
| M13 | IO94RSB2 |
| M14 | GDB1/IO87PPB1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| M15 | GDC1/IO86PDB1 |
| M16 | IO84NDB1 |
| N1 | IO150NDB3 |
| N2 | IO147PPB3 |
| N3 | GEC1/IO146PPB3 |
| N4 | IO140RSB2 |
| N5 | GNDQ |
| N6 | GEA2/IO143RSB2 |
| N7 | IO126RSB2 |
| N8 | IO120RSB2 |
| N9 | IO108RSB2 |
| N10 | IO103RSB2 |
| N11 | IO99RSB2 |
| N12 | GNDQ |
| N13 | IO92RSB2 |
| N14 | VJTAG |
| N15 | GDC0/IO86NDB1 |
| N16 | GDA1/IO88PDB1 |
| P1 | GEB1/IO145PDB3 |
| P2 | GEB0/IO145NDB3 |
| P3 | VMV2 |
| P4 | IO138RSB2 |
| P5 | IO136RSB2 |
| P6 | IO131RSB2 |
| P7 | IO124RSB2 |
| P8 | IO119RSB2 |
| P9 | IO107RSB2 |
| P10 | IO104RSB2 |
| P11 | IO97RSB2 |
| P12 | VMV1 |
| P13 | TCK |
| P14 | VPUMP |
| P15 | TRST |
| P16 | GDA0/IO88NDB1 |
| R1 | GEA1/IO144PDB3 |
| R2 | GEA0/IO144NDB3 |
| R3 | IO139RSB2 |
| R4 | GEC2/IO141RSB2 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL600 Function** |
| R5 | IO132RSB2 |
| R6 | IO127RSB2 |
| R7 | IO121RSB2 |
| R8 | IO114RSB2 |
| R9 | IO109RSB2 |
| R10 | IO105RSB2 |
| R11 | IO98RSB2 |
| R12 | IO96RSB2 |
| R13 | GDB2/IO90RSB2 |
| R14 | TDI |
| R15 | GNDQ |
| R16 | TDO |
| T1 | GND |
| T2 | IO137RSB2 |
| T3 | FF/GEB2/IO142RSB2 |
| T4 | IO134RSB2 |
| T5 | IO125RSB2 |
| T6 | IO123RSB2 |
| T7 | IO118RSB2 |
| T8 | IO115RSB2 |
| T9 | IO111RSB2 |
| T10 | IO106RSB2 |
| T11 | IO102RSB2 |
| T12 | GDC2/IO91RSB2 |
| T13 | IO93RSB2 |
| T14 | GDA2/IO89RSB2 |
| T15 | TMS |
| T16 | GND |

| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| A1 | GND |
| A2 | GAA0/IO00RSB0 |
| A3 | GAA1/IO01RSB0 |
| A4 | GAB0/IO02RSB0 |
| A5 | IO16RSB0 |
| A6 | IO22RSB0 |
| A7 | IO28RSB0 |
| A8 | IO35RSB0 |
| A9 | IO45RSB0 |
| A10 | IO50RSB0 |
| A11 | IO55RSB0 |
| A12 | IO61RSB0 |
| A13 | GBB1/IO75RSB0 |
| A14 | GBA0/IO76RSB0 |
| A15 | GBA1/IO77RSB0 |
| A16 | GND |
| B1 | GAB2/IO224PDB3 |
| B2 | GAA2/IO225PDB3 |
| B3 | GNDQ |
| B4 | GAB1/IO03RSB0 |
| B5 | IO17RSB0 |
| B6 | IO21RSB0 |
| B7 | IO27RSB0 |
| B8 | IO34RSB0 |
| B9 | IO44RSB0 |
| B10 | IO51RSB0 |
| B11 | IO57RSB0 |
| B12 | GBC1/IO73RSB0 |
| B13 | GBB0/IO74RSB0 |
| B14 | IO71RSB0 |
| B15 | GBA2/IO78PDB1 |
| B16 | IO81PDB1 |
| C1 | IO224NDB3 |
| C2 | IO225NDB3 |
| C3 | VMV3 |
| C4 | IO11RSB0 |
| C5 | GAC0/IO04RSB0 |
| C6 | GAC1/IO05RSB0 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| C7 | IO25RSB0 |
| C8 | IO36RSB0 |
| C9 | IO42RSB0 |
| C10 | IO49RSB0 |
| C11 | IO56RSB0 |
| C12 | GBC0/IO72RSB0 |
| C13 | IO62RSB0 |
| C14 | VMV0 |
| C15 | IO78NDB1 |
| C16 | IO81NDB1 |
| D1 | IO222NDB3 |
| D2 | IO222PDB3 |
| D3 | GAC2/IO223PDB3 |
| D4 | IO223NDB3 |
| D5 | GNDQ |
| D6 | IO23RSB0 |
| D7 | IO29RSB0 |
| D8 | IO33RSB0 |
| D9 | IO46RSB0 |
| D10 | IO52RSB0 |
| D11 | IO60RSB0 |
| D12 | GNDQ |
| D13 | IO80NDB1 |
| D14 | GBB2/IO79PDB1 |
| D15 | IO79NDB1 |
| D16 | IO82NSB1 |
| E1 | IO217PDB3 |
| E2 | IO218PDB3 |
| E3 | IO221NDB3 |
| E4 | IO221PDB3 |
| E5 | VMV0 |
| E6 | VCCIB0 |
| E7 | VCCIB0 |
| E8 | IO38RSB0 |
| E9 | IO47RSB0 |
| E10 | VCCIB0 |
| E11 | VCCIB0 |
| E12 | VMV1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| E13 | GBC2/IO80PDB1 |
| E14 | IO83PPB1 |
| E15 | IO86PPB1 |
| E16 | IO87PDB1 |
| F1 | IO217NDB3 |
| F2 | IO218NDB3 |
| F3 | IO216PDB3 |
| F4 | IO216NDB3 |
| F5 | VCCIB3 |
| F6 | GND |
| F7 | VCC |
| F8 | VCC |
| F9 | VCC |
| F10 | VCC |
| F11 | GND |
| F12 | VCCIB1 |
| F13 | IO83NPB1 |
| F14 | IO86NPB1 |
| F15 | IO90PPB1 |
| F16 | IO87NDB1 |
| G1 | IO210PSB3 |
| G2 | IO213NDB3 |
| G3 | IO213PDB3 |
| G4 | GFC1/IO209PPB3 |
| G5 | VCCIB3 |
| G6 | VCC |
| G7 | GND |
| G8 | GND |
| G9 | GND |
| G10 | GND |
| G11 | VCC |
| G12 | VCCIB1 |
| G13 | GCC1/IO91PPB1 |
| G14 | IO90NPB1 |
| G15 | IO88PDB1 |
| G16 | IO88NDB1 |
| H1 | GFB0/IO208NPB3 |
| H2 | GFA0/IO207NDB3 |

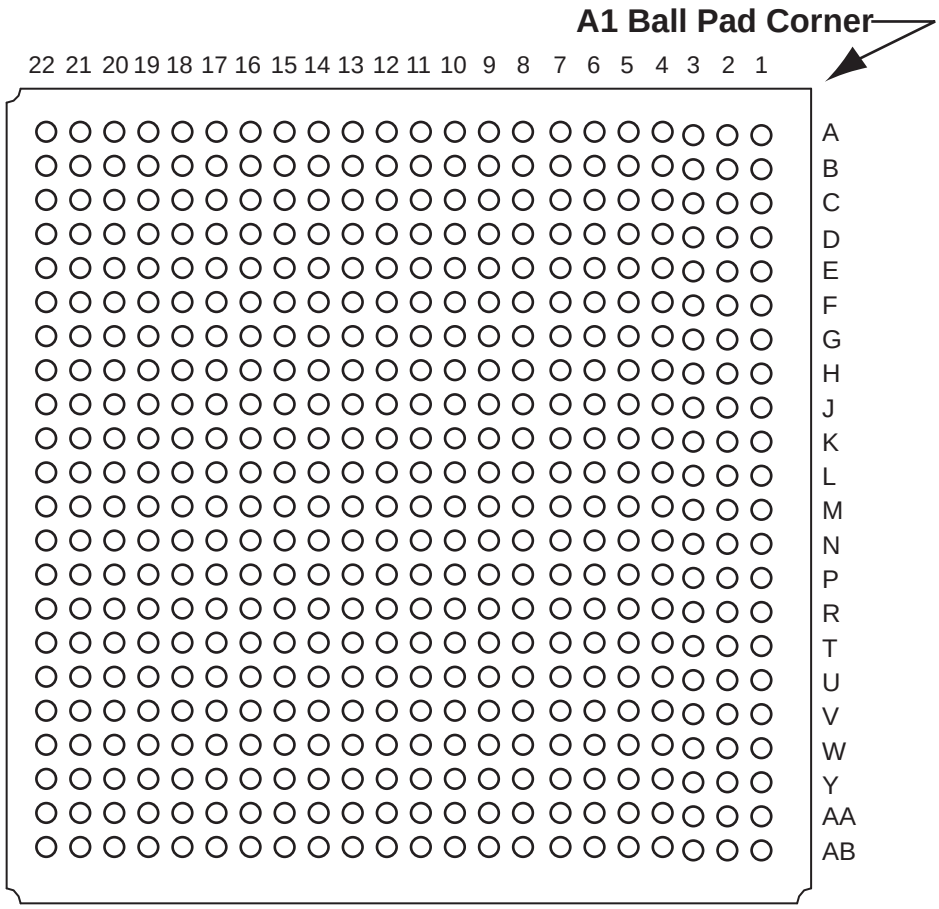
| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| H3 | GFB1/IO208PPB3 |
| H4 | VCOMPLF |
| H5 | GFC0/IO209NPB3 |
| H6 | VCC |
| H7 | GND |
| H8 | GND |
| H9 | GND |
| H10 | GND |
| H11 | VCC |
| H12 | GCC0/IO91NPB1 |
| H13 | GCB1/IO92PPB1 |
| H14 | GCA0/IO93NPB1 |
| H15 | IO96NPB1 |
| H16 | GCB0/IO92NPB1 |
| J1 | GFA2/IO206PSB3 |
| J2 | GFA1/IO207PDB3 |
| J3 | VCCPLF |
| J4 | IO205NDB3 |
| J5 | GFB2/IO205PDB3 |
| J6 | VCC |
| J7 | GND |
| J8 | GND |
| J9 | GND |
| J10 | GND |
| J11 | VCC |
| J12 | GCB2/IO95PPB1 |
| J13 | GCA1/IO93PPB1 |
| J14 | GCC2/IO96PPB1 |
| J15 | IO100PPB1 |
| J16 | GCA2/IO94PSB1 |
| K1 | GFC2/IO204PDB3 |
| K2 | IO204NDB3 |
| K3 | IO203NDB3 |
| K4 | IO203PDB3 |
| K5 | VCCIB3 |
| K6 | VCC |
| K7 | GND |
| K8 | GND |

| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| K9 | GND |
| K10 | GND |
| K11 | VCC |
| K12 | VCCIB1 |
| K13 | IO95NPB1 |
| K14 | IO100NPB1 |
| K15 | IO102NDB1 |
| K16 | IO102PDB1 |
| L1 | IO202NDB3 |
| L2 | IO202PDB3 |
| L3 | IO196PPB3 |
| L4 | IO193PPB3 |
| L5 | VCCIB3 |
| L6 | GND |
| L7 | VCC |
| L8 | VCC |
| L9 | VCC |
| L10 | VCC |
| L11 | GND |
| L12 | VCCIB1 |
| L13 | GDB0/IO112NPB1 |
| L14 | IO106NDB1 |
| L15 | IO106PDB1 |
| L16 | IO107PDB1 |
| M1 | IO197NSB3 |
| M2 | IO196NPB3 |
| M3 | IO193NPB3 |
| M4 | GEC0/IO190NPB3 |
| M5 | VMV3 |
| M6 | VCCIB2 |
| M7 | VCCIB2 |
| M8 | IO147RSB2 |
| M9 | IO136RSB2 |
| M10 | VCCIB2 |
| M11 | VCCIB2 |
| M12 | VMV2 |
| M13 | IO110NDB1 |
| M14 | GDB1/IO112PPB1 |

| FG256 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| M15 | GDC1/IO111PDB1 |
| M16 | IO107NDB1 |
| N1 | IO194PSB3 |
| N2 | IO192PPB3 |
| N3 | GEC1/IO190PPB3 |
| N4 | IO192NPB3 |
| N5 | GNDQ |
| N6 | GEA2/IO187RSB2 |
| N7 | IO161RSB2 |
| N8 | IO155RSB2 |
| N9 | IO141RSB2 |
| N10 | IO129RSB2 |
| N11 | IO124RSB2 |
| N12 | GNDQ |
| N13 | IO110PDB1 |
| N14 | VJTAG |
| N15 | GDC0/IO111NDB1 |
| N16 | GDA1/IO113PDB1 |
| P1 | GEB1/IO189PDB3 |
| P2 | GEB0/IO189NDB3 |
| P3 | VMV2 |
| P4 | IO179RSB2 |
| P5 | IO171RSB2 |
| P6 | IO165RSB2 |
| P7 | IO159RSB2 |
| P8 | IO151RSB2 |
| P9 | IO137RSB2 |
| P10 | IO134RSB2 |
| P11 | IO128RSB2 |
| P12 | VMV1 |
| P13 | TCK |
| P14 | VPUMP |
| P15 | TRST |
| P16 | GDA0/IO113NDB1 |
| R1 | GEA1/IO188PDB3 |
| R2 | GEA0/IO188NDB3 |
| R3 | IO184RSB2 |
| R4 | GEC2/IO185RSB2 |

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|---|---|
| **Pin Number** | **AGL1000 Function** |
| R5 | IO168RSB2 |
| R6 | IO163RSB2 |
| R7 | IO157RSB2 |
| R8 | IO149RSB2 |
| R9 | IO143RSB2 |
| R10 | IO138RSB2 |
| R11 | IO131RSB2 |
| R12 | IO125RSB2 |
| R13 | GDB2/IO115RSB2 |
| R14 | TDI |
| R15 | GNDQ |
| R16 | TDO |
| T1 | GND |
| T2 | IO183RSB2 |
| T3 | FF/GEB2/IO186RSB2 |
| T4 | IO172RSB2 |
| T5 | IO170RSB2 |
| T6 | IO164RSB2 |
| T7 | IO158RSB2 |
| T8 | IO153RSB2 |
| T9 | IO142RSB2 |
| T10 | IO135RSB2 |
| T11 | IO130RSB2 |
| T12 | GDC2/IO116RSB2 |
| T13 | IO120RSB2 |
| T14 | GDA2/IO114RSB2 |
| T15 | TMS |
| T16 | GND |

# FG484




*Note: This is the bottom view of the package.*

## Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

| FG484 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| A1 | GND |
| A2 | GND |
| A3 | VCCIB0 |
| A4 | NC |
| A5 | NC |
| A6 | IO15RSB0 |
| A7 | IO18RSB0 |
| A8 | NC |
| A9 | NC |
| A10 | IO23RSB0 |
| A11 | IO29RSB0 |
| A12 | IO35RSB0 |
| A13 | IO36RSB0 |
| A14 | NC |
| A15 | NC |
| A16 | IO50RSB0 |
| A17 | IO51RSB0 |
| A18 | NC |
| A19 | NC |
| A20 | VCCIB0 |
| A21 | GND |
| A22 | GND |
| AA1 | GND |
| AA2 | VCCIB3 |
| AA3 | NC |
| AA4 | NC |
| AA5 | NC |
| AA6 | NC |
| AA7 | NC |
| AA8 | NC |
| AA9 | NC |
| AA10 | NC |
| AA11 | NC |
| AA12 | NC |
| AA13 | NC |
| AA14 | NC |

| FG484 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| AA15 | NC |
| AA16 | NC |
| AA17 | NC |
| AA18 | NC |
| AA19 | NC |
| AA20 | NC |
| AA21 | VCCIB1 |
| AA22 | GND |
| AB1 | GND |
| AB2 | GND |
| AB3 | VCCIB2 |
| AB4 | NC |
| AB5 | NC |
| AB6 | IO121RSB2 |
| AB7 | IO119RSB2 |
| AB8 | IO114RSB2 |
| AB9 | IO109RSB2 |
| AB10 | NC |
| AB11 | NC |
| AB12 | IO104RSB2 |
| AB13 | IO103RSB2 |
| AB14 | NC |
| AB15 | NC |
| AB16 | IO91RSB2 |
| AB17 | IO90RSB2 |
| AB18 | NC |
| AB19 | NC |
| AB20 | VCCIB2 |
| AB21 | GND |
| AB22 | GND |
| B1 | GND |
| B2 | VCCIB3 |
| B3 | NC |
| B4 | NC |
| B5 | NC |
| B6 | NC |

| FG484 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| B7 | NC |
| B8 | NC |
| B9 | NC |
| B10 | NC |
| B11 | NC |
| B12 | NC |
| B13 | NC |
| B14 | NC |
| B15 | NC |
| B16 | NC |
| B17 | NC |
| B18 | NC |
| B19 | NC |
| B20 | NC |
| B21 | VCCIB1 |
| B22 | GND |
| C1 | VCCIB3 |
| C2 | NC |
| C3 | NC |
| C4 | NC |
| C5 | GND |
| C6 | NC |
| C7 | NC |
| C8 | VCC |
| C9 | VCC |
| C10 | NC |
| C11 | NC |
| C12 | NC |
| C13 | NC |
| C14 | VCC |
| C15 | VCC |
| C16 | NC |
| C17 | NC |
| C18 | GND |
| C19 | NC |
| C20 | NC |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| C21 | NC |
| C22 | VCCIB1 |
| D1 | NC |
| D2 | NC |
| D3 | NC |
| D4 | GND |
| D5 | GAA0/IO00RSB0 |
| D6 | GAA1/IO01RSB0 |
| D7 | GAB0/IO02RSB0 |
| D8 | IO16RSB0 |
| D9 | IO17RSB0 |
| D10 | IO22RSB0 |
| D11 | IO28RSB0 |
| D12 | IO34RSB0 |
| D13 | IO37RSB0 |
| D14 | IO41RSB0 |
| D15 | IO43RSB0 |
| D16 | GBB1/IO57RSB0 |
| D17 | GBA0/IO58RSB0 |
| D18 | GBA1/IO59RSB0 |
| D19 | GND |
| D20 | NC |
| D21 | NC |
| D22 | NC |
| E1 | NC |
| E2 | NC |
| E3 | GND |
| E4 | GAB2/IO154UDB3 |
| E5 | GAA2/IO155UDB3 |
| E6 | IO12RSB0 |
| E7 | GAB1/IO03RSB0 |
| E8 | IO13RSB0 |
| E9 | IO14RSB0 |
| E10 | IO21RSB0 |
| E11 | IO27RSB0 |
| E12 | IO32RSB0 |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| E13 | IO38RSB0 |
| E14 | IO42RSB0 |
| E15 | GBC1/IO55RSB0 |
| E16 | GBB0/IO56RSB0 |
| E17 | IO44RSB0 |
| E18 | GBA2/IO60PDB1 |
| E19 | IO60NDB1 |
| E20 | GND |
| E21 | NC |
| E22 | NC |
| F1 | NC |
| F2 | NC |
| F3 | NC |
| F4 | IO154VDB3 |
| F5 | IO155VDB3 |
| F6 | IO11RSB0 |
| F7 | IO07RSB0 |
| F8 | GAC0/IO04RSB0 |
| F9 | GAC1/IO05RSB0 |
| F10 | IO20RSB0 |
| F11 | IO24RSB0 |
| F12 | IO33RSB0 |
| F13 | IO39RSB0 |
| F14 | IO45RSB0 |
| F15 | GBC0/IO54RSB0 |
| F16 | IO48RSB0 |
| F17 | VMV0 |
| F18 | IO61NPB1 |
| F19 | IO63PDB1 |
| F20 | NC |
| F21 | NC |
| F22 | NC |
| G1 | NC |
| G2 | NC |
| G3 | NC |
| G4 | IO151VDB3 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL400 Function** |
| G5 | IO151UDB3 |
| G6 | GAC2/IO153UDB3 |
| G7 | IO06RSB0 |
| G8 | GNDQ |
| G9 | IO10RSB0 |
| G10 | IO19RSB0 |
| G11 | IO26RSB0 |
| G12 | IO30RSB0 |
| G13 | IO40RSB0 |
| G14 | IO46RSB0 |
| G15 | GNDQ |
| G16 | IO47RSB0 |
| G17 | GBB2/IO61PPB1 |
| G18 | IO53RSB0 |
| G19 | IO63NDB1 |
| G20 | NC |
| G21 | NC |
| G22 | NC |
| H1 | NC |
| H2 | NC |
| H3 | VCC |
| H4 | IO150PDB3 |
| H5 | IO08RSB0 |
| H6 | IO153VDB3 |
| H7 | IO152VDB3 |
| H8 | VMV0 |
| H9 | VCCIB0 |
| H10 | VCCIB0 |
| H11 | IO25RSB0 |
| H12 | IO31RSB0 |
| H13 | VCCIB0 |
| H14 | VCCIB0 |
| H15 | VMV1 |
| H16 | GBC2/IO62PDB1 |
| H17 | IO65RSB1 |
| H18 | IO52RSB0 |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| H19 | IO66PDB1 |
| H20 | VCC |
| H21 | NC |
| H22 | NC |
| J1 | NC |
| J2 | NC |
| J3 | NC |
| J4 | IO150NDB3 |
| J5 | IO149NPB3 |
| J6 | IO09RSB0 |
| J7 | IO152UDB3 |
| J8 | VCCIB3 |
| J9 | GND |
| J10 | VCC |
| J11 | VCC |
| J12 | VCC |
| J13 | VCC |
| J14 | GND |
| J15 | VCCIB1 |
| J16 | IO62NDB1 |
| J17 | IO49RSB0 |
| J18 | IO64PPB1 |
| J19 | IO66NDB1 |
| J20 | NC |
| J21 | NC |
| J22 | NC |
| K1 | NC |
| K2 | NC |
| K3 | NC |
| K4 | IO148NDB3 |
| K5 | IO148PDB3 |
| K6 | IO149PPB3 |
| K7 | GFC1/IO147PPB3 |
| K8 | VCCIB3 |
| K9 | VCC |
| K10 | GND |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| K11 | GND |
| K12 | GND |
| K13 | GND |
| K14 | VCC |
| K15 | VCCIB1 |
| K16 | GCC1/IO67PPB1 |
| K17 | IO64NPB1 |
| K18 | IO73PDB1 |
| K19 | IO73NDB1 |
| K20 | NC |
| K21 | NC |
| K22 | NC |
| L1 | NC |
| L2 | NC |
| L3 | NC |
| L4 | GFB0/IO146NPB3 |
| L5 | GFA0/IO145NDB3 |
| L6 | GFB1/IO146PPB3 |
| L7 | VCOMPLF |
| L8 | GFC0/IO147NPB3 |
| L9 | VCC |
| L10 | GND |
| L11 | GND |
| L12 | GND |
| L13 | GND |
| L14 | VCC |
| L15 | GCC0/IO67NPB1 |
| L16 | GCB1/IO68PPB1 |
| L17 | GCA0/IO69NPB1 |
| L18 | NC |
| L19 | GCB0/IO68NPB1 |
| L20 | NC |
| L21 | NC |
| L22 | NC |
| M1 | NC |
| M2 | NC |

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| **Pin Number** | **AGL400 Function** |
| M3 | NC |
| M4 | GFA2/IO144PPB3 |
| M5 | GFA1/IO145PDB3 |
| M6 | VCCPLF |
| M7 | IO143NDB3 |
| M8 | GFB2/IO143PDB3 |
| M9 | VCC |
| M10 | GND |
| M11 | GND |
| M12 | GND |
| M13 | GND |
| M14 | VCC |
| M15 | GCB2/IO71PPB1 |
| M16 | GCA1/IO69PPB1 |
| M17 | GCC2/IO72PPB1 |
| M18 | NC |
| M19 | GCA2/IO70PDB1 |
| M20 | NC |
| M21 | NC |
| M22 | NC |
| N1 | NC |
| N2 | NC |
| N3 | NC |
| N4 | GFC2/IO142PDB3 |
| N5 | IO144NPB3 |
| N6 | IO141PPB3 |
| N7 | IO120RSB2 |
| N8 | VCCIB3 |
| N9 | VCC |
| N10 | GND |
| N11 | GND |
| N12 | GND |
| N13 | GND |
| N14 | VCC |
| N15 | VCCIB1 |
| N16 | IO71NPB1 |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| N17 | IO74RSB1 |
| N18 | IO72NPB1 |
| N19 | IO70NDB1 |
| N20 | NC |
| N21 | NC |
| N22 | NC |
| P1 | NC |
| P2 | NC |
| P3 | NC |
| P4 | IO142NDB3 |
| P5 | IO141NPB3 |
| P6 | IO125RSB2 |
| P7 | IO139RSB3 |
| P8 | VCCIB3 |
| P9 | GND |
| P10 | VCC |
| P11 | VCC |
| P12 | VCC |
| P13 | VCC |
| P14 | GND |
| P15 | VCCIB1 |
| P16 | GDB0/IO78VPB1 |
| P17 | IO76VDB1 |
| P18 | IO76UDB1 |
| P19 | IO75PDB1 |
| P20 | NC |
| P21 | NC |
| P22 | NC |
| R1 | NC |
| R2 | NC |
| R3 | VCC |
| R4 | IO140PDB3 |
| R5 | IO130RSB2 |
| R6 | IO138NPB3 |
| R7 | GEC0/IO137NPB3 |
| R8 | VMV3 |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| R9 | VCCIB2 |
| R10 | VCCIB2 |
| R11 | IO108RSB2 |
| R12 | IO101RSB2 |
| R13 | VCCIB2 |
| R14 | VCCIB2 |
| R15 | VMV2 |
| R16 | IO83RSB2 |
| R17 | GDB1/IO78UPB1 |
| R18 | GDC1/IO77UDB1 |
| R19 | IO75NDB1 |
| R20 | VCC |
| R21 | NC |
| R22 | NC |
| T1 | NC |
| T2 | NC |
| T3 | NC |
| T4 | IO140NDB3 |
| T5 | IO138PPB3 |
| T6 | GEC1/IO137PPB3 |
| T7 | IO131RSB2 |
| T8 | GNDQ |
| T9 | GEA2/IO134RSB2 |
| T10 | IO117RSB2 |
| T11 | IO111RSB2 |
| T12 | IO99RSB2 |
| T13 | IO94RSB2 |
| T14 | IO87RSB2 |
| T15 | GNDQ |
| T16 | IO93RSB2 |
| T17 | VJTAG |
| T18 | GDC0/IO77VDB1 |
| T19 | GDA1/IO79UDB1 |
| T20 | NC |
| T21 | NC |
| T22 | NC |

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| **Pin Number** | **AGL400 Function** |
| U1 | NC |
| U2 | NC |
| U3 | NC |
| U4 | GEB1/IO136PDB3 |
| U5 | GEB0/IO136NDB3 |
| U6 | VMV2 |
| U7 | IO129RSB2 |
| U8 | IO128RSB2 |
| U9 | IO122RSB2 |
| U10 | IO115RSB2 |
| U11 | IO110RSB2 |
| U12 | IO98RSB2 |
| U13 | IO95RSB2 |
| U14 | IO88RSB2 |
| U15 | IO84RSB2 |
| U16 | TCK |
| U17 | VPUMP |
| U18 | TRST |
| U19 | GDA0/IO79VDB1 |
| U20 | NC |
| U21 | NC |
| U22 | NC |
| V1 | NC |
| V2 | NC |
| V3 | GND |
| V4 | GEA1/IO135PDB3 |
| V5 | GEA0/IO135NDB3 |
| V6 | IO127RSB2 |
| V7 | GEC2/IO132RSB2 |
| V8 | IO123RSB2 |
| V9 | IO118RSB2 |
| V10 | IO112RSB2 |
| V11 | IO106RSB2 |
| V12 | IO100RSB2 |
| V13 | IO96RSB2 |
| V14 | IO89RSB2 |

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| **Pin Number** | **AGL400 Function** |
| V15 | IO85RSB2 |
| V16 | GDB2/IO81RSB2 |
| V17 | TDI |
| V18 | NC |
| V19 | TDO |
| V20 | GND |
| V21 | NC |
| V22 | NC |
| W1 | NC |
| W2 | NC |
| W3 | NC |
| W4 | GND |
| W5 | IO126RSB2 |
| W6 | FF/GEB2/IO133RSB2 |
| W7 | IO124RSB2 |
| W8 | IO116RSB2 |
| W9 | IO113RSB2 |
| W10 | IO107RSB2 |
| W11 | IO105RSB2 |
| W12 | IO102RSB2 |
| W13 | IO97RSB2 |
| W14 | IO92RSB2 |
| W15 | GDC2/IO82RSB2 |
| W16 | IO86RSB2 |
| W17 | GDA2/IO80RSB2 |
| W18 | TMS |
| W19 | GND |
| W20 | NC |
| W21 | NC |
| W22 | NC |
| Y1 | VCCIB3 |
| Y2 | NC |
| Y3 | NC |
| Y4 | NC |
| Y5 | GND |
| Y6 | NC |

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|---|---|
| **Pin Number** | **AGL400 Function** |
| Y7 | NC |
| Y8 | VCC |
| Y9 | VCC |
| Y10 | NC |
| Y11 | NC |
| Y12 | NC |
| Y13 | NC |
| Y14 | VCC |
| Y15 | VCC |
| Y16 | NC |
| Y17 | NC |
| Y18 | GND |
| Y19 | NC |
| Y20 | NC |
| Y21 | NC |
| Y22 | VCCIB1 |

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| **Pin Number** | **AGL600 Function** |
| A1 | GND |
| A2 | GND |
| A3 | VCCIB0 |
| A4 | NC |
| A5 | NC |
| A6 | IO09RSB0 |
| A7 | IO15RSB0 |
| A8 | NC |
| A9 | NC |
| A10 | IO22RSB0 |
| A11 | IO23RSB0 |
| A12 | IO29RSB0 |
| A13 | IO35RSB0 |
| A14 | NC |
| A15 | NC |
| A16 | IO46RSB0 |
| A17 | IO48RSB0 |
| A18 | NC |
| A19 | NC |
| A20 | VCCIB0 |
| A21 | GND |
| A22 | GND |
| AA1 | GND |
| AA2 | VCCIB3 |
| AA3 | NC |
| AA4 | NC |
| AA5 | NC |
| AA6 | IO135RSB2 |
| AA7 | IO133RSB2 |
| AA8 | NC |
| AA9 | NC |
| AA10 | NC |
| AA11 | NC |
| AA12 | NC |
| AA13 | NC |
| AA14 | NC |

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| **Pin Number** | **AGL600 Function** |
| AA15 | NC |
| AA16 | IO101RSB2 |
| AA17 | NC |
| AA18 | NC |
| AA19 | NC |
| AA20 | NC |
| AA21 | VCCIB1 |
| AA22 | GND |
| AB1 | GND |
| AB2 | GND |
| AB3 | VCCIB2 |
| AB4 | NC |
| AB5 | NC |
| AB6 | IO130RSB2 |
| AB7 | IO128RSB2 |
| AB8 | IO122RSB2 |
| AB9 | IO116RSB2 |
| AB10 | NC |
| AB11 | NC |
| AB12 | IO113RSB2 |
| AB13 | IO112RSB2 |
| AB14 | NC |
| AB15 | NC |
| AB16 | IO100RSB2 |
| AB17 | IO95RSB2 |
| AB18 | NC |
| AB19 | NC |
| AB20 | VCCIB2 |
| AB21 | GND |
| AB22 | GND |
| B1 | GND |
| B2 | VCCIB3 |
| B3 | NC |
| B4 | NC |
| B5 | NC |
| B6 | IO08RSB0 |

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|---|---|
| **Pin Number** | **AGL600 Function** |
| B7 | IO12RSB0 |
| B8 | NC |
| B9 | NC |
| B10 | IO17RSB0 |
| B11 | NC |
| B12 | NC |
| B13 | IO36RSB0 |
| B14 | NC |
| B15 | NC |
| B16 | IO47RSB0 |
| B17 | IO49RSB0 |
| B18 | NC |
| B19 | NC |
| B20 | NC |
| B21 | VCCIB1 |
| B22 | GND |
| C1 | VCCIB3 |
| C2 | NC |
| C3 | NC |
| C4 | NC |
| C5 | GND |
| C6 | NC |
| C7 | NC |
| C8 | VCC |
| C9 | VCC |
| C10 | NC |
| C11 | NC |
| C12 | NC |
| C13 | NC |
| C14 | VCC |
| C15 | VCC |
| C16 | NC |
| C17 | NC |
| C18 | GND |
| C19 | NC |
| C20 | NC |

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| **Pin Number** | **AGL600 Function** |
| C21 | NC |
| C22 | VCCIB1 |
| D1 | NC |
| D2 | NC |
| D3 | NC |
| D4 | GND |
| D5 | GAA0/IO00RSB0 |
| D6 | GAA1/IO01RSB0 |
| D7 | GAB0/IO02RSB0 |
| D8 | IO11RSB0 |
| D9 | IO16RSB0 |
| D10 | IO18RSB0 |
| D11 | IO28RSB0 |
| D12 | IO34RSB0 |
| D13 | IO37RSB0 |
| D14 | IO41RSB0 |
| D15 | IO43RSB0 |
| D16 | GBB1/IO57RSB0 |
| D17 | GBA0/IO58RSB0 |
| D18 | GBA1/IO59RSB0 |
| D19 | GND |
| D20 | NC |
| D21 | NC |
| D22 | NC |
| E1 | NC |
| E2 | NC |
| E3 | GND |
| E4 | GAB2/IO173PDB3 |
| E5 | GAA2/IO174PDB3 |
| E6 | GNDQ |
| E7 | GAB1/IO03RSB0 |
| E8 | IO13RSB0 |
| E9 | IO14RSB0 |
| E10 | IO21RSB0 |
| E11 | IO27RSB0 |
| E12 | IO32RSB0 |

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| **Pin Number** | **AGL600 Function** |
| E13 | IO38RSB0 |
| E14 | IO42RSB0 |
| E15 | GBC1/IO55RSB0 |
| E16 | GBB0/IO56RSB0 |
| E17 | IO52RSB0 |
| E18 | GBA2/IO60PDB1 |
| E19 | IO60NDB1 |
| E20 | GND |
| E21 | NC |
| E22 | NC |
| F1 | NC |
| F2 | NC |
| F3 | NC |
| F4 | IO173NDB3 |
| F5 | IO174NDB3 |
| F6 | VMV3 |
| F7 | IO07RSB0 |
| F8 | GAC0/IO04RSB0 |
| F9 | GAC1/IO05RSB0 |
| F10 | IO20RSB0 |
| F11 | IO24RSB0 |
| F12 | IO33RSB0 |
| F13 | IO39RSB0 |
| F14 | IO44RSB0 |
| F15 | GBC0/IO54RSB0 |
| F16 | IO51RSB0 |
| F17 | VMV0 |
| F18 | IO61NPB1 |
| F19 | IO63PDB1 |
| F20 | NC |
| F21 | NC |
| F22 | NC |
| G1 | IO170NDB3 |
| G2 | IO170PDB3 |
| G3 | NC |
| G4 | IO171NDB3 |

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| **Pin Number** | **AGL600 Function** |
| G5 | IO171PDB3 |
| G6 | GAC2/IO172PDB3 |
| G7 | IO06RSB0 |
| G8 | GNDQ |
| G9 | IO10RSB0 |
| G10 | IO19RSB0 |
| G11 | IO26RSB0 |
| G12 | IO30RSB0 |
| G13 | IO40RSB0 |
| G14 | IO45RSB0 |
| G15 | GNDQ |
| G16 | IO50RSB0 |
| G17 | GBB2/IO61PPB1 |
| G18 | IO53RSB0 |
| G19 | IO63NDB1 |
| G20 | NC |
| G21 | NC |
| G22 | NC |
| H1 | NC |
| H2 | NC |
| H3 | VCC |
| H4 | IO166PDB3 |
| H5 | IO167NPB3 |
| H6 | IO172NDB3 |
| H7 | IO169NDB3 |
| H8 | VMV0 |
| H9 | VCCIB0 |
| H10 | VCCIB0 |
| H11 | IO25RSB0 |
| H12 | IO31RSB0 |
| H13 | VCCIB0 |
| H14 | VCCIB0 |
| H15 | VMV1 |
| H16 | GBC2/IO62PDB1 |
| H17 | IO67PPB1 |
| H18 | IO64PPB1 |

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| **Pin Number** | **AGL600 Function** |
| H19 | IO66PDB1 |
| H20 | VCC |
| H21 | NC |
| H22 | NC |
| J1 | NC |
| J2 | NC |
| J3 | NC |
| J4 | IO166NDB3 |
| J5 | IO168NPB3 |
| J6 | IO167PPB3 |
| J7 | IO169PDB3 |
| J8 | VCCIB3 |
| J9 | GND |
| J10 | VCC |
| J11 | VCC |
| J12 | VCC |
| J13 | VCC |
| J14 | GND |
| J15 | VCCIB1 |
| J16 | IO62NDB1 |
| J17 | IO64NPB1 |
| J18 | IO65PPB1 |
| J19 | IO66NDB1 |
| J20 | NC |
| J21 | IO68PDB1 |
| J22 | IO68NDB1 |
| K1 | IO157PDB3 |
| K2 | IO157NDB3 |
| K3 | NC |
| K4 | IO165NDB3 |
| K5 | IO165PDB3 |
| K6 | IO168PPB3 |
| K7 | GFC1/IO164PPB3 |
| K8 | VCCIB3 |
| K9 | VCC |
| K10 | GND |

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| **Pin Number** | **AGL600 Function** |
| K11 | GND |
| K12 | GND |
| K13 | GND |
| K14 | VCC |
| K15 | VCCIB1 |
| K16 | GCC1/IO69PPB1 |
| K17 | IO65NPB1 |
| K18 | IO75PDB1 |
| K19 | IO75NDB1 |
| K20 | NC |
| K21 | IO76NDB1 |
| K22 | IO76PDB1 |
| L1 | NC |
| L2 | IO155PDB3 |
| L3 | NC |
| L4 | GFB0/IO163NPB3 |
| L5 | GFA0/IO162NDB3 |
| L6 | GFB1/IO163PPB3 |
| L7 | VCOMPLF |
| L8 | GFC0/IO164NPB3 |
| L9 | VCC |
| L10 | GND |
| L11 | GND |
| L12 | GND |
| L13 | GND |
| L14 | VCC |
| L15 | GCC0/IO69NPB1 |
| L16 | GCB1/IO70PPB1 |
| L17 | GCA0/IO71NPB1 |
| L18 | IO67NPB1 |
| L19 | GCB0/IO70NPB1 |
| L20 | IO77PDB1 |
| L21 | IO77NDB1 |
| L22 | IO78NPB1 |
| M1 | NC |
| M2 | IO155NDB3 |

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|---|---|
| **Pin Number** | **AGL600 Function** |
| M3 | IO158NPB3 |
| M4 | GFA2/IO161PPB3 |
| M5 | GFA1/IO162PDB3 |
| M6 | VCCPLF |
| M7 | IO160NDB3 |
| M8 | GFB2/IO160PDB3 |
| M9 | VCC |
| M10 | GND |
| M11 | GND |
| M12 | GND |
| M13 | GND |
| M14 | VCC |
| M15 | GCB2/IO73PPB1 |
| M16 | GCA1/IO71PPB1 |
| M17 | GCC2/IO74PPB1 |
| M18 | IO80PPB1 |
| M19 | GCA2/IO72PDB1 |
| M20 | IO79PPB1 |
| M21 | IO78PPB1 |
| M22 | NC |
| N1 | IO154NDB3 |
| N2 | IO154PDB3 |
| N3 | NC |
| N4 | GFC2/IO159PDB3 |
| N5 | IO161NPB3 |
| N6 | IO156PPB3 |
| N7 | IO129RSB2 |
| N8 | VCCIB3 |
| N9 | VCC |
| N10 | GND |
| N11 | GND |
| N12 | GND |
| N13 | GND |
| N14 | VCC |
| N15 | VCCIB1 |
| N16 | IO73NPB1 |

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| **Pin Number** | **AGL600 Function** |
| N17 | IO80NPB1 |
| N18 | IO74NPB1 |
| N19 | IO72NDB1 |
| N20 | NC |
| N21 | IO79NPB1 |
| N22 | NC |
| P1 | NC |
| P2 | IO153PDB3 |
| P3 | IO153NDB3 |
| P4 | IO159NDB3 |
| P5 | IO156NPB3 |
| P6 | IO151PPB3 |
| P7 | IO158PPB3 |
| P8 | VCCIB3 |
| P9 | GND |
| P10 | VCC |
| P11 | VCC |
| P12 | VCC |
| P13 | VCC |
| P14 | GND |
| P15 | VCCIB1 |
| P16 | GDB0/IO87NPB1 |
| P17 | IO85NDB1 |
| P18 | IO85PDB1 |
| P19 | IO84PDB1 |
| P20 | NC |
| P21 | IO81PDB1 |
| P22 | NC |
| R1 | NC |
| R2 | NC |
| R3 | VCC |
| R4 | IO150PDB3 |
| R5 | IO151NPB3 |
| R6 | IO147NPB3 |
| R7 | GEC0/IO146NPB3 |
| R8 | VMV3 |

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|---|---|
| **Pin Number** | **AGL600 Function** |
| R9 | VCCIB2 |
| R10 | VCCIB2 |
| R11 | IO117RSB2 |
| R12 | IO110RSB2 |
| R13 | VCCIB2 |
| R14 | VCCIB2 |
| R15 | VMV2 |
| R16 | IO94RSB2 |
| R17 | GDB1/IO87PPB1 |
| R18 | GDC1/IO86PDB1 |
| R19 | IO84NDB1 |
| R20 | VCC |
| R21 | IO81NDB1 |
| R22 | IO82PDB1 |
| T1 | IO152PDB3 |
| T2 | IO152NDB3 |
| T3 | NC |
| T4 | IO150NDB3 |
| T5 | IO147PPB3 |
| T6 | GEC1/IO146PPB3 |
| T7 | IO140RSB2 |
| T8 | GNDQ |
| T9 | GEA2/IO143RSB2 |
| T10 | IO126RSB2 |
| T11 | IO120RSB2 |
| T12 | IO108RSB2 |
| T13 | IO103RSB2 |
| T14 | IO99RSB2 |
| T15 | GNDQ |
| T16 | IO92RSB2 |
| T17 | VJTAG |
| T18 | GDC0/IO86NDB1 |
| T19 | GDA1/IO88PDB1 |
| T20 | NC |
| T21 | IO83PDB1 |
| T22 | IO82NDB1 |

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| **Pin Number** | **AGL600 Function** |
| U1 | IO149PDB3 |
| U2 | IO149NDB3 |
| U3 | NC |
| U4 | GEB1/IO145PDB3 |
| U5 | GEB0/IO145NDB3 |
| U6 | VMV2 |
| U7 | IO138RSB2 |
| U8 | IO136RSB2 |
| U9 | IO131RSB2 |
| U10 | IO124RSB2 |
| U11 | IO119RSB2 |
| U12 | IO107RSB2 |
| U13 | IO104RSB2 |
| U14 | IO97RSB2 |
| U15 | VMV1 |
| U16 | TCK |
| U17 | VPUMP |
| U18 | TRST |
| U19 | GDA0/IO88NDB1 |
| U20 | NC |
| U21 | IO83NDB1 |
| U22 | NC |
| V1 | NC |
| V2 | NC |
| V3 | GND |
| V4 | GEA1/IO144PDB3 |
| V5 | GEA0/IO144NDB3 |
| V6 | IO139RSB2 |
| V7 | GEC2/IO141RSB2 |
| V8 | IO132RSB2 |
| V9 | IO127RSB2 |
| V10 | IO121RSB2 |
| V11 | IO114RSB2 |
| V12 | IO109RSB2 |
| V13 | IO105RSB2 |
| V14 | IO98RSB2 |

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|---|---|
| **Pin Number** | **AGL600 Function** |
| V15 | IO96RSB2 |
| V16 | GDB2/IO90RSB2 |
| V17 | TDI |
| V18 | GNDQ |
| V19 | TDO |
| V20 | GND |
| V21 | NC |
| V22 | NC |
| W1 | NC |
| W2 | IO148PDB3 |
| W3 | NC |
| W4 | GND |
| W5 | IO137RSB2 |
| W6 | FF/GEB2/IO142RSB2 |
| W7 | IO134RSB2 |
| W8 | IO125RSB2 |
| W9 | IO123RSB2 |
| W10 | IO118RSB2 |
| W11 | IO115RSB2 |
| W12 | IO111RSB2 |
| W13 | IO106RSB2 |
| W14 | IO102RSB2 |
| W15 | GDC2/IO91RSB2 |
| W16 | IO93RSB2 |
| W17 | GDA2/IO89RSB2 |
| W18 | TMS |
| W19 | GND |
| W20 | NC |
| W21 | NC |
| W22 | NC |
| Y1 | VCCIB3 |
| Y2 | IO148NDB3 |
| Y3 | NC |
| Y4 | NC |
| Y5 | GND |
| Y6 | NC |

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|---|---|
| **Pin Number** | **AGL600 Function** |
| Y7 | NC |
| Y8 | VCC |
| Y9 | VCC |
| Y10 | NC |
| Y11 | NC |
| Y12 | NC |
| Y13 | NC |
| Y14 | VCC |
| Y15 | VCC |
| Y16 | NC |
| Y17 | NC |
| Y18 | GND |
| Y19 | NC |
| Y20 | NC |
| Y21 | NC |
| Y22 | VCCIB1 |

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|---|---|
| **Pin Number** | **AGL1000 Function** |
| A1 | GND |
| A2 | GND |
| A3 | VCCIB0 |
| A4 | IO07RSB0 |
| A5 | IO09RSB0 |
| A6 | IO13RSB0 |
| A7 | IO18RSB0 |
| A8 | IO20RSB0 |
| A9 | IO26RSB0 |
| A10 | IO32RSB0 |
| A11 | IO40RSB0 |
| A12 | IO41RSB0 |
| A13 | IO53RSB0 |
| A14 | IO59RSB0 |
| A15 | IO64RSB0 |
| A16 | IO65RSB0 |
| A17 | IO67RSB0 |
| A18 | IO69RSB0 |
| A19 | NC |
| A20 | VCCIB0 |
| A21 | GND |
| A22 | GND |
| AA1 | GND |
| AA2 | VCCIB3 |
| AA3 | NC |
| AA4 | IO181RSB2 |
| AA5 | IO178RSB2 |
| AA6 | IO175RSB2 |
| AA7 | IO169RSB2 |
| AA8 | IO166RSB2 |
| AA9 | IO160RSB2 |
| AA10 | IO152RSB2 |
| AA11 | IO146RSB2 |
| AA12 | IO139RSB2 |
| AA13 | IO133RSB2 |
| AA14 | NC |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| AA15 | NC |
| AA16 | IO122RSB2 |
| AA17 | IO119RSB2 |
| AA18 | IO117RSB2 |
| AA19 | NC |
| AA20 | NC |
| AA21 | VCCIB1 |
| AA22 | GND |
| AB1 | GND |
| AB2 | GND |
| AB3 | VCCIB2 |
| AB4 | IO180RSB2 |
| AB5 | IO176RSB2 |
| AB6 | IO173RSB2 |
| AB7 | IO167RSB2 |
| AB8 | IO162RSB2 |
| AB9 | IO156RSB2 |
| AB10 | IO150RSB2 |
| AB11 | IO145RSB2 |
| AB12 | IO144RSB2 |
| AB13 | IO132RSB2 |
| AB14 | IO127RSB2 |
| AB15 | IO126RSB2 |
| AB16 | IO123RSB2 |
| AB17 | IO121RSB2 |
| AB18 | IO118RSB2 |
| AB19 | NC |
| AB20 | VCCIB2 |
| AB21 | GND |
| AB22 | GND |
| B1 | GND |
| B2 | VCCIB3 |
| B3 | NC |
| B4 | IO06RSB0 |
| B5 | IO08RSB0 |
| B6 | IO12RSB0 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| B7 | IO15RSB0 |
| B8 | IO19RSB0 |
| B9 | IO24RSB0 |
| B10 | IO31RSB0 |
| B11 | IO39RSB0 |
| B12 | IO48RSB0 |
| B13 | IO54RSB0 |
| B14 | IO58RSB0 |
| B15 | IO63RSB0 |
| B16 | IO66RSB0 |
| B17 | IO68RSB0 |
| B18 | IO70RSB0 |
| B19 | NC |
| B20 | NC |
| B21 | VCCIB1 |
| B22 | GND |
| C1 | VCCIB3 |
| C2 | IO220PDB3 |
| C3 | NC |
| C4 | NC |
| C5 | GND |
| C6 | IO10RSB0 |
| C7 | IO14RSB0 |
| C8 | VCC |
| C9 | VCC |
| C10 | IO30RSB0 |
| C11 | IO37RSB0 |
| C12 | IO43RSB0 |
| C13 | NC |
| C14 | VCC |
| C15 | VCC |
| C16 | NC |
| C17 | NC |
| C18 | GND |
| C19 | NC |
| C20 | NC |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| C21 | NC |
| C22 | VCCIB1 |
| D1 | IO219PDB3 |
| D2 | IO220NDB3 |
| D3 | NC |
| D4 | GND |
| D5 | GAA0/IO00RSB0 |
| D6 | GAA1/IO01RSB0 |
| D7 | GAB0/IO02RSB0 |
| D8 | IO16RSB0 |
| D9 | IO22RSB0 |
| D10 | IO28RSB0 |
| D11 | IO35RSB0 |
| D12 | IO45RSB0 |
| D13 | IO50RSB0 |
| D14 | IO55RSB0 |
| D15 | IO61RSB0 |
| D16 | GBB1/IO75RSB0 |
| D17 | GBA0/IO76RSB0 |
| D18 | GBA1/IO77RSB0 |
| D19 | GND |
| D20 | NC |
| D21 | NC |
| D22 | NC |
| E1 | IO219NDB3 |
| E2 | NC |
| E3 | GND |
| E4 | GAB2/IO224PDB3 |
| E5 | GAA2/IO225PDB3 |
| E6 | GNDQ |
| E7 | GAB1/IO03RSB0 |
| E8 | IO17RSB0 |
| E9 | IO21RSB0 |
| E10 | IO27RSB0 |
| E11 | IO34RSB0 |
| E12 | IO44RSB0 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| E13 | IO51RSB0 |
| E14 | IO57RSB0 |
| E15 | GBC1/IO73RSB0 |
| E16 | GBB0/IO74RSB0 |
| E17 | IO71RSB0 |
| E18 | GBA2/IO78PDB1 |
| E19 | IO81PDB1 |
| E20 | GND |
| E21 | NC |
| E22 | IO84PDB1 |
| F1 | NC |
| F2 | IO215PDB3 |
| F3 | IO215NDB3 |
| F4 | IO224NDB3 |
| F5 | IO225NDB3 |
| F6 | VMV3 |
| F7 | IO11RSB0 |
| F8 | GAC0/IO04RSB0 |
| F9 | GAC1/IO05RSB0 |
| F10 | IO25RSB0 |
| F11 | IO36RSB0 |
| F12 | IO42RSB0 |
| F13 | IO49RSB0 |
| F14 | IO56RSB0 |
| F15 | GBC0/IO72RSB0 |
| F16 | IO62RSB0 |
| F17 | VMV0 |
| F18 | IO78NDB1 |
| F19 | IO81NDB1 |
| F20 | IO82PPB1 |
| F21 | NC |
| F22 | IO84NDB1 |
| G1 | IO214NDB3 |
| G2 | IO214PDB3 |
| G3 | NC |
| G4 | IO222NDB3 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| G5 | IO222PDB3 |
| G6 | GAC2/IO223PDB3 |
| G7 | IO223NDB3 |
| G8 | GNDQ |
| G9 | IO23RSB0 |
| G10 | IO29RSB0 |
| G11 | IO33RSB0 |
| G12 | IO46RSB0 |
| G13 | IO52RSB0 |
| G14 | IO60RSB0 |
| G15 | GNDQ |
| G16 | IO80NDB1 |
| G17 | GBB2/IO79PDB1 |
| G18 | IO79NDB1 |
| G19 | IO82NPB1 |
| G20 | IO85PDB1 |
| G21 | IO85NDB1 |
| G22 | NC |
| H1 | NC |
| H2 | NC |
| H3 | VCC |
| H4 | IO217PDB3 |
| H5 | IO218PDB3 |
| H6 | IO221NDB3 |
| H7 | IO221PDB3 |
| H8 | VMV0 |
| H9 | VCCIB0 |
| H10 | VCCIB0 |
| H11 | IO38RSB0 |
| H12 | IO47RSB0 |
| H13 | VCCIB0 |
| H14 | VCCIB0 |
| H15 | VMV1 |
| H16 | GBC2/IO80PDB1 |
| H17 | IO83PPB1 |
| H18 | IO86PPB1 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| H19 | IO87PDB1 |
| H20 | VCC |
| H21 | NC |
| H22 | NC |
| J1 | IO212NDB3 |
| J2 | IO212PDB3 |
| J3 | NC |
| J4 | IO217NDB3 |
| J5 | IO218NDB3 |
| J6 | IO216PDB3 |
| J7 | IO216NDB3 |
| J8 | VCCIB3 |
| J9 | GND |
| J10 | VCC |
| J11 | VCC |
| J12 | VCC |
| J13 | VCC |
| J14 | GND |
| J15 | VCCIB1 |
| J16 | IO83NPB1 |
| J17 | IO86NPB1 |
| J18 | IO90PPB1 |
| J19 | IO87NDB1 |
| J20 | NC |
| J21 | IO89PDB1 |
| J22 | IO89NDB1 |
| K1 | IO211PDB3 |
| K2 | IO211NDB3 |
| K3 | NC |
| K4 | IO210PPB3 |
| K5 | IO213NDB3 |
| K6 | IO213PDB3 |
| K7 | GFC1/IO209PPB3 |
| K8 | VCCIB3 |
| K9 | VCC |
| K10 | GND |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| K11 | GND |
| K12 | GND |
| K13 | GND |
| K14 | VCC |
| K15 | VCCIB1 |
| K16 | GCC1/IO91PPB1 |
| K17 | IO90NPB1 |
| K18 | IO88PDB1 |
| K19 | IO88NDB1 |
| K20 | IO94NPB1 |
| K21 | IO98NDB1 |
| K22 | IO98PDB1 |
| L1 | NC |
| L2 | IO200PDB3 |
| L3 | IO210NPB3 |
| L4 | GFB0/IO208NPB3 |
| L5 | GFA0/IO207NDB3 |
| L6 | GFB1/IO208PPB3 |
| L7 | VCOMPLF |
| L8 | GFC0/IO209NPB3 |
| L9 | VCC |
| L10 | GND |
| L11 | GND |
| L12 | GND |
| L13 | GND |
| L14 | VCC |
| L15 | GCC0/IO91NPB1 |
| L16 | GCB1/IO92PPB1 |
| L17 | GCA0/IO93NPB1 |
| L18 | IO96NPB1 |
| L19 | GCB0/IO92NPB1 |
| L20 | IO97PDB1 |
| L21 | IO97NDB1 |
| L22 | IO99NPB1 |
| M1 | NC |
| M2 | IO200NDB3 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| M3 | IO206NDB3 |
| M4 | GFA2/IO206PDB3 |
| M5 | GFA1/IO207PDB3 |
| M6 | VCCPLF |
| M7 | IO205NDB3 |
| M8 | GFB2/IO205PDB3 |
| M9 | VCC |
| M10 | GND |
| M11 | GND |
| M12 | GND |
| M13 | GND |
| M14 | VCC |
| M15 | GCB2/IO95PPB1 |
| M16 | GCA1/IO93PPB1 |
| M17 | GCC2/IO96PPB1 |
| M18 | IO100PPB1 |
| M19 | GCA2/IO94PPB1 |
| M20 | IO101PPB1 |
| M21 | IO99PPB1 |
| M22 | NC |
| N1 | IO201NDB3 |
| N2 | IO201PDB3 |
| N3 | NC |
| N4 | GFC2/IO204PDB3 |
| N5 | IO204NDB3 |
| N6 | IO203NDB3 |
| N7 | IO203PDB3 |
| N8 | VCCIB3 |
| N9 | VCC |
| N10 | GND |
| N11 | GND |
| N12 | GND |
| N13 | GND |
| N14 | VCC |
| N15 | VCCIB1 |
| N16 | IO95NPB1 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| N17 | IO100NPB1 |
| N18 | IO102NDB1 |
| N19 | IO102PDB1 |
| N20 | NC |
| N21 | IO101NPB1 |
| N22 | IO103PDB1 |
| P1 | NC |
| P2 | IO199PDB3 |
| P3 | IO199NDB3 |
| P4 | IO202NDB3 |
| P5 | IO202PDB3 |
| P6 | IO196PPB3 |
| P7 | IO193PPB3 |
| P8 | VCCIB3 |
| P9 | GND |
| P10 | VCC |
| P11 | VCC |
| P12 | VCC |
| P13 | VCC |
| P14 | GND |
| P15 | VCCIB1 |
| P16 | GDB0/IO112NPB1 |
| P17 | IO106NDB1 |
| P18 | IO106PDB1 |
| P19 | IO107PDB1 |
| P20 | NC |
| P21 | IO104PDB1 |
| P22 | IO103NDB1 |
| R1 | NC |
| R2 | IO197PPB3 |
| R3 | VCC |
| R4 | IO197NPB3 |
| R5 | IO196NPB3 |
| R6 | IO193NPB3 |
| R7 | GEC0/IO190NPB3 |
| R8 | VMV3 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| R9 | VCCIB2 |
| R10 | VCCIB2 |
| R11 | IO147RSB2 |
| R12 | IO136RSB2 |
| R13 | VCCIB2 |
| R14 | VCCIB2 |
| R15 | VMV2 |
| R16 | IO110NDB1 |
| R17 | GDB1/IO112PPB1 |
| R18 | GDC1/IO111PDB1 |
| R19 | IO107NDB1 |
| R20 | VCC |
| R21 | IO104NDB1 |
| R22 | IO105PDB1 |
| T1 | IO198PDB3 |
| T2 | IO198NDB3 |
| T3 | NC |
| T4 | IO194PPB3 |
| T5 | IO192PPB3 |
| T6 | GEC1/IO190PPB3 |
| T7 | IO192NPB3 |
| T8 | GNDQ |
| T9 | GEA2/IO187RSB2 |
| T10 | IO161RSB2 |
| T11 | IO155RSB2 |
| T12 | IO141RSB2 |
| T13 | IO129RSB2 |
| T14 | IO124RSB2 |
| T15 | GNDQ |
| T16 | IO110PDB1 |
| T17 | VJTAG |
| T18 | GDC0/IO111NDB1 |
| T19 | GDA1/IO113PDB1 |
| T20 | NC |
| T21 | IO108PDB1 |
| T22 | IO105NDB1 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| U1 | IO195PDB3 |
| U2 | IO195NDB3 |
| U3 | IO194NPB3 |
| U4 | GEB1/IO189PDB3 |
| U5 | GEB0/IO189NDB3 |
| U6 | VMV2 |
| U7 | IO179RSB2 |
| U8 | IO171RSB2 |
| U9 | IO165RSB2 |
| U10 | IO159RSB2 |
| U11 | IO151RSB2 |
| U12 | IO137RSB2 |
| U13 | IO134RSB2 |
| U14 | IO128RSB2 |
| U15 | VMV1 |
| U16 | TCK |
| U17 | VPUMP |
| U18 | TRST |
| U19 | GDA0/IO113NDB1 |
| U20 | NC |
| U21 | IO108NDB1 |
| U22 | IO109PDB1 |
| V1 | NC |
| V2 | NC |
| V3 | GND |
| V4 | GEA1/IO188PDB3 |
| V5 | GEA0/IO188NDB3 |
| V6 | IO184RSB2 |
| V7 | GEC2/IO185RSB2 |
| V8 | IO168RSB2 |
| V9 | IO163RSB2 |
| V10 | IO157RSB2 |
| V11 | IO149RSB2 |
| V12 | IO143RSB2 |
| V13 | IO138RSB2 |
| V14 | IO131RSB2 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| V15 | IO125RSB2 |
| V16 | GDB2/IO115RSB2 |
| V17 | TDI |
| V18 | GNDQ |
| V19 | TDO |
| V20 | GND |
| V21 | NC |
| V22 | IO109NDB1 |
| W1 | NC |
| W2 | IO191PDB3 |
| W3 | NC |
| W4 | GND |
| W5 | IO183RSB2 |
| W6 | FF/GEB2/IO186RSB2 |
| W7 | IO172RSB2 |
| W8 | IO170RSB2 |
| W9 | IO164RSB2 |
| W10 | IO158RSB2 |
| W11 | IO153RSB2 |
| W12 | IO142RSB2 |
| W13 | IO135RSB2 |
| W14 | IO130RSB2 |
| W15 | GDC2/IO116RSB2 |
| W16 | IO120RSB2 |
| W17 | GDA2/IO114RSB2 |
| W18 | TMS |
| W19 | GND |
| W20 | NC |
| W21 | NC |
| W22 | NC |
| Y1 | VCCIB3 |
| Y2 | IO191NDB3 |
| Y3 | NC |
| Y4 | IO182RSB2 |
| Y5 | GND |
| Y6 | IO177RSB2 |

| FG484 | |
|---|---|
| **Pin Number** | **AGL1000 Function** |
| Y7 | IO174RSB2 |
| Y8 | VCC |
| Y9 | VCC |
| Y10 | IO154RSB2 |
| Y11 | IO148RSB2 |
| Y12 | IO140RSB2 |
| Y13 | NC |
| Y14 | VCC |
| Y15 | VCC |
| Y16 | NC |
| Y17 | NC |
| Y18 | GND |
| Y19 | NC |
| Y20 | NC |
| Y21 | NC |
| Y22 | VCCIB1 |

# 5 – Datasheet Information

## List of Changes

The following tables list critical changes that were made in each revision of the IGLOO datasheet.

| Revision | Changes | Page |
|---|---|---|
| Revision 19 (September 2011) | CS121 was added to the product tables in the "IGLOO Low Power Flash FPGAs" section section for AGL125 (SAR 22737). CS81 was added for AGL250 (SAR 22737). | I |
| | Notes indicating that device/package support is TBD for AGL250-QN132 and AGL060-FG144 have been removed (SAR 33689). | I to IV |
| | M1AGL400 was removed from the "I/Os Per Package1" table. This device was discontinued in April 2009 (SAR 32450). | II |
| | Dimensions for the QN48 package were added to Table 1 • IGLOO FPGAs Package Sizes Dimensions (SAR 30537). | II |
| | The Y security option and Licensed DPA Logo were added to the "IGLOO Ordering Information" section. The trademarked Licensed DPA Logo identifies that a product is covered by a DPA counter-measures license from Cryptography Research (SAR 32151). | III |
| | The "In-System Programming (ISP) and Security" section and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 32865). | I, 1-2 |
| | The following sentence was removed from the "Advanced Architecture" section:<br>"In addition, extensive on-chip programming circuitry allows for rapid, single-voltage (3.3 V) programming of IGLOO devices via an IEEE 1532 JTAG interface" (SAR 28756). | 1-3 |
| | The "Specifying I/O States During Programming" section is new (SAR 21281). | 1-8 |
| | Values for VCCPLL at 1.2 V –1.5 V DC core supply voltage were revised in Table 2-2 • Recommended Operating Conditions [1] (SAR 22356).<br>The value for VPUMP operation was changed from "0 to 3.45 V" to "0 to 3.6 V" (SAR 25220).<br>The value for VCCPLL 1.5 V DC core supply voltage was changed from" 1.4 to 1.6 V" to "1.425 to 1.575 V" (SAR 26551).<br>The notes in the table were renumbered in order of their appearance in the table (SAR 21869). | 2-2 |
| | The temperature used in EQ 2 was revised from 110°C to 100°C for consistency with the limits given in Table 2-2 • Recommended Operating Conditions [1]. The resulting maximum power allowed is thus 1.28 W. Formerly it was 1.71 W (SAR 26259). | 2-6 |
| | Values for CS196, CS281, and QN132 packages were added to Table 2-5 • Package Thermal Resistivities (SARs 26228, 32301). | 2-6 |
| | Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.425 V) and Table 2-7 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.14 V) were updated to remove the column for –20°C and shift the data over to correct columns (SAR 23041). | 2-7 |
| | The tables in the "Quiescent Supply Current" section were updated with revised notes on IDD (SAR 24112). Table 2-8 • Power Supply State per Mode is new. | 2-7 |

| Revision | Changes | Page |
|---|---|---|
| Revision 19 (continued) | The formulas in the table notes for Table 2-41 • I/O Weak Pull-Up/Pull-Down Resistances were corrected (SAR 21348). | 2-37 |
| | The row for 110°C was removed from Table 2-45 • Duration of Short Circuit Event before Failure. The example in the associated paragraph was changed from 110°C to 100°C. Table 2-46 • I/O Input Rise Time, Fall Time, and Related I/O Reliability was revised to change 110° to 100°C. (SAR 26259). | 2-40 |
| | The notes regarding drive strength in the "Summary of I/O Timing Characteristics – Default I/O Software Settings" section, "3.3 V LVCMOS Wide Range" section and "1.2 V LVCMOS Wide Range" section tables were revised for clarification. They now state that the minimum drive strength for the default software configuration when run in wide range is ±100 µA. The drive strength displayed in software is supported in normal range only. For a detailed I/V curve, refer to the IBIS models (SAR 25700). | 2-28, 2-47, 2-77 |
| | The following sentence was deleted from the "2.5 V LVCMOS" section (SAR 24916): "It uses a 5 V–tolerant input buffer and push-pull output buffer." | 2-56 |
| | The values for $F_{DDRIMAX}$ and $F_{DDOMAX}$ were updated in the tables in the "Input DDR Module" section and "Output DDR Module" section (SAR 23919). | 2-94, 2-97 |
| | The following notes were removed from Table 2-147 • Minimum and Maximum DC Input and Output Levels (SAR 29428):<br>±5%<br>Differential input voltage = ±350 mV | 2-82 |
| | Table 2-189 • IGLOO CCC/PLL Specification and Table 2-190 • IGLOO CCC/PLL Specification were updated. A note was added to both tables indicating that when the CCC/PLL core is generated by Mircosemi core generator software, not all delay values of the specified delay increments are available (SAR 25705). | 2-115 |
| | The following figures were deleted (SAR 29991). Reference was made to a new application note, *Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs*, which covers these cases in detail (SAR 21770).<br>Figure 2-36 • Write Access after Write onto Same Address<br>Figure 2-37 • Read Access after Write onto Same Address<br>Figure 2-38 • Write Access after Read onto Same Address<br>The port names in the SRAM "Timing Waveforms", SRAM "Timing Characteristics" tables, Figure 2-38 • FIFO Reset, and the FIFO "Timing Characteristics" tables were revised to ensure consistency with the software names (SARs 29991, 30510). | N/A<br>2-118 to 2-128 |
| | The "Pin Descriptions" chapter has been added (SAR 21642). | 3-1 |
| | Package names used in the "Package Pin Assignments" section were revised to match standards given in *Package Mechanical Drawings* (SAR 27395). | 4-1 |
| | The "CS81" pin table for AGL250 is new (SAR 22737). | 4-5 |
| | The "CS121" pin table for AGL125 is new (SAR 22737). | 4-9 |
| | The P3 function was revised in the "CS196" pin table for AGL250 (SAR 24800). | 4-14 |
| | The "QN132" pin table for AGL250 was added.<br>The "FG144" pin table for AGL060 was added (SAR 33689) | 4-37, 4-45 |
| July 2010 | The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "IGLOO Device Status" table indicates the status for each device in the device family. | N/A |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| **Revision 18 (Nov 2009)** | The version changed to v2.0 for IGLOO datasheet chapters, indicating the datasheet contains information based on final characterization. Please review the datasheet carefully as most tables were updated with new data. | N/A |
| **Revision 17 (Sep 2009)**<br>Product Brief v1.6 | The "Reprogrammable Flash Technology" section was modified to add "250 MHz (1.5 V systems) and 160 MHz (1.2 V systems) System Performance." | I |
| | "IGLOO Ordering Information" was revised to note that halogen-free packages are available with RoHS-compliant packaging. | III |
| | Table 1-1 • I/O Standards Supported is new. | 1-7 |
| | The definitions of hot-swap and cold-sparing were added to the "I/Os with Advanced I/O Standards" section. | 1-7 |
| **Revision 16 (Apr 2009)**<br>Product Brief v1.5 | M1AGL400 is no longer offered and was removed from the "IGLOO Devices" product table, "IGLOO Ordering Information", and "Temperature Grade Offerings". | I, III, IV |
| | The –F speed grade is no longer offered for IGLOO devices. The speed grade column and note regarding –F speed grade were removed from "IGLOO Ordering Information". The "Speed Grade and Temperature Grade Matrix" section was removed. | III, IV |
| | This datasheet now has fully characterized data and has moved from being Advance to a Production version. The version number changed from Advance v0.5 to v2.0.<br>Please review the datasheet carefully as most tables were updated with new data. | N/A |
| DC and Switching Characteristics Advance v0.6 | 3.3 V LVCMOS and 1.2 V LVCMOS Wide Range support was added to the datasheet. This affects all tables that contained 3.3 V LVCMOS and 1.2 V LVCMOS data. | |
| | $I_{IL}$ and $I_{IH}$ input leakage current information was added to all "Minimum and Maximum DC Input and Output Levels" tables. | N/A |
| | –F was removed from the datasheet. The speed grade is no longer supported. | N/A |
| | The notes in Table 2-2 • Recommended Operating Conditions [1] were updated. | 2-2 |
| | Table 2-4 • Overshoot and Undershoot Limits 1 was updated. | 2-3 |
| | Table 2-5 • Package Thermal Resistivities was updated. | 2-6 |
| | Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.425 V) and Table 2-7 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.14 V) were updated. | 2-7 |
| | In Table 2-191 • RAM4K9 and Table 2-193 • RAM4K9, the following specifications were removed:<br>$t_{WRO}$<br>$t_{CCKH}$ | 2-121 and 2-123 |
| | In Table 2-192 • RAM512X18 and Table 2-194 • RAM512X18, the following specifications were removed:<br>$t_{WRO}$<br>$t_{CCKH}$ | 2-122 and 2-124 |
| **Revision 15 (Feb 2009)**<br>Packaging v1.9 | The "QN132" pin table for the AGL060 device is new. | 4-33 |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| **Revision 14 (Feb 2009)**<br>Product Brief v1.4 | The "Advanced I/O" section was revised to include two bullets regarding wide range power supply voltage support. | I |
| | 3.0 V wide range was added to the list of supported voltages in the "I/Os with Advanced I/O Standards" section. The "Wide Range I/O Support" section is new. | 1-8 |
| **Revision 13 (Jan 2009)**<br>Packaging v1.8 | The "CS121" pin table was revised to add a note regarding pins F1 and G1. | 4-7 |
| **Revision 12 (Dec 2008)**<br>Product Brief v1.3 | QN48 and QN68 were added to the AGL030 for the following tables:<br>"IGLOO Devices" Product Family Table<br>"IGLOO Ordering Information"<br>"Temperature Grade Offerings" | N/A |
| | QN132 is fully supported by AGL125 so footnote 3 was removed. | |
| Packaging v1.7 | The "QN48" pin diagram and pin table are new. | 4-26 |
| | The "QN68" pin table for AGL030 is new. | 4-28 |
| **Revision 12 (Dec 2008)** | The AGL600 Function for pin K15 in the "FG484" table was changed to VCCIB1. | 4-73 |
| **Revision 11 (Oct 2008)**<br>Product Brief v1.2 | This document was updated to include AGL400 device information. The following sections were updated:<br>"IGLOO Devices" Product Family Table<br>"IGLOO Ordering Information"<br>"Temperature Grade Offerings"<br>Figure 1-2 • IGLOO Device Architecture Overview with Four I/O Banks (AGL250, AGL600, AGL400, and AGL1000) | N/A |
| DC and Switching Characteristics Advance v0.5 | The tables in the "Quiescent Supply Current" section were updated with values for AGL400. In addition, the title was updated to include: (VCC = VJTAG = VPP = 0 V). | 2-7 |
| | The tables in the "Power Consumption of Various Internal Resources" section were updated with values for AGL400. | 2-13 |
| | Table 2-178 • AGL400 Global Resource is new. | 2-109 |
| Packaging v1.6 | The "CS196" table for the AGL400 device is new. | 4-16 |
| | The "FG144" table for the AGL400 device is new. | 4-51 |
| | The "FG256" table for the AGL400 device is new. | 4-58 |
| | The "FG484" table for the AGL400 device is new. | 4-68 |
| **Revision 10 (Aug 2008)** | 3.0 V LVCMOS wide range support data was added to Table 2-2 • Recommended Operating Conditions [1]. | 2-2 |
| DC and Switching Characteristics Advance v0.4 | 3.3 V LVCMOS wide range support data was added to Table 2-25 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings to Table 2-27 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings. | 2-24 to 2-26 |
| | 3.3 V LVCMOS wide range support data was added to Table 2-28 • Summary of Maximum and Minimum DC Input Levels. | 2-27 |
| | 3.3 V LVCMOS wide range support text was added to Table 2-49 · Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range. | 2-39 |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| DC & Switching, cont'd. | Table 2-49 · Minimum and Maximum DC Input and Output Levels for LVCMOS 3.3 V Wide Range is new. | 2-39 |
| **Revision 9 (Jul 2008)**<br>Product Brief v1.1<br>DC and Switching Characteristics Advance v0.3 | As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change 1.2 V / 1.5 V to 1.2 V to 1.5 V. | N/A |
| **Revision 8 (Jun 2008)** | As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change 1.2 V / 1.5 V to 1.2 V to 1.5 V. | N/A |
| DC and Switching Characteristics Advance v0.2 | Tables have been updated to reflect default values in the software. The default I/O capacitance is 5 pF. Tables have been updated to include the LVCMOS 1.2 V I/O set.<br>DDR Tables have two additional data points added to reflect both edges for Input DDR setup and hold time.<br>The power data table has been updated to match SmartPower data rather then simulation values.<br>AGL015 global clock delays have been added. | N/A |
| | Table 2-1 • Absolute Maximum Ratings was updated to combine the VCCI and VMV parameters in one row. The word "output" from the parameter description for VCCI and VMV, and table note 3 was added. | 2-1 |
| | Table 2-2 • Recommended Operating Conditions [1] was updated to add references to tables notes 4, 6, 7, and 8. VMV was added to the VCCI parameter row, and table note 9 was added. | 2-2 |
| | In Table 2-3 • Flash Programming Limits – Retention, Storage, and Operating Temperature1, the maximum operating junction temperature was changed from 110° to 100°. | 2-2 |
| | VMV was removed from Table 2-4 • Overshoot and Undershoot Limits 1. The table title was modified to remove "as measured on quiet I/Os." Table note 2 was revised to remove "estimated SSO density over cycles." Table note 3 was revised to remove "refers only to overshoot/undershoot limits for simultaneous switching I/Os." | 2-3 |
| | The "PLL Behavior at Brownout Condition" section is new. | 2-4 |
| | Figure 2-2 • V2 Devices – I/O State as a Function of VCCI and VCC Voltage Levels is new. | 2-5 |
| | EQ 2 was updated. The temperature was changed to 100°C, and therefore the end result changed. | 2-6 |
| | The table notes for Table 2-9 • Quiescent Supply Current (IDD) Characteristics, IGLOO Flash*Freeze Mode*, Table 2-10 • Quiescent Supply Current (IDD) Characteristics, IGLOO Sleep Mode*, and Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO Shutdown Mode were updated to remove VMV and include PDC6 and PDC7. VCCI and VJTAG were removed from the statement about IDD in the table note for Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO Shutdown Mode. | 2-7 |
| | Note 2 of Table 2-12 • Quiescent Supply Current (IDD), No IGLOO Flash*Freeze Mode1 was updated to include VCCPLL. Note 4 was updated to include PDC6 and PDC7. | 2-9 |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| **Revision 8 (cont'd)** | Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings, Table 2-14 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings, Table 2-15 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings, and Table 2-16 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings[1] were updated to change PDC2 to PDC6 and PDC3 to PDC7. The table notes were updated to reflect that power was measured on VCCI. | 2-10 through 2-11 |
| | In Table 2-19 • Different Components Contributing to Dynamic Power Consumption in IGLOO Devices, the description for PAC13 was changed from Static to Dynamic. | 2-13 |
| | Table 2-20 • Different Components Contributing to the Static Power Consumption in IGLOO Devices and Table 2-22 • Different Components Contributing to the Static Power Consumption in IGLOO Device were updated to add PDC6 and PDC7, and to change the definition for PDC5 to bank quiescent power. Subtitles were added to indicate type of devices and core supply voltage. | 2-14, 2-16 |
| | The "Total Static Power Consumption—$P_{STAT}$" section was updated to revise the calculation of $P_{STAT}$, including PDC6 and PDC7. | 2-17 |
| | Footnote † was updated to include information about PAC13. The PLL Contribution equation was changed from: $P_{PLL} = P_{AC13} + P_{AC14} * F_{CLKOUT}$ to $P_{PLL} = P_{DC4} + P_{AC13} * F_{CLKOUT}$. | 2-18 |
| **Revision 7 (Jun 2008)**<br>Packaging v1.5 | The "QN132" package diagram was updated to include D1 to D4. In addition, note 1 was changed from top view to bottom view, and note 2 is new. | 4-30 |
| **Revision 6 (Jun 2008)**<br>Packaging v1.4 | This document was divided into two sections and given a version number, starting at v1.0. The first section of the document includes features, benefits, ordering information, and temperature and speed grade offerings. The second section is a device family overview. | N/A |
| | Pin numbers were added to the "QN68" package diagram. Note 2 was added below the diagram. | 4-27 |
| **Revision 5 (Mar 2008)**<br>Packaging v1.3 | The "CS196" package and pin table was added for AGL250. | 4-14 |
| **Revision 4 (Mar 2008)**<br>Product Brief v1.0 | The "Low Power" section was updated to change "1.2 V and 1.5 V Core Voltage" to "1.2 V and 1.5 V Core and I/O Voltage." The text "(from 12 µW)" was removed from "Low Power Active FPGA Operation."<br>1.2_V was added to the list of core and I/O voltages in the "Advanced I/O" and "I/Os with Advanced I/O Standards" section sections. | I<br>I, 1-7 |
| | The "Embedded Memory" section was updated to remove the footnote reference from the section heading and place it instead after "4,608-Bit" and "True Dual-Port SRAM (except ×18)." | I |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| **Revision 3 (Feb 2008)**<br>Product Brief rev. 2 | This document was updated to include AGL015 device information. QN68 is a new package offered in the AGL015. The following sections were updated:<br>"Features and Benefits"<br>"IGLOO Ordering Information"<br>"Temperature Grade Offerings"<br>"IGLOO Devices" Product Family Table<br>Table 1 • IGLOO FPGAs Package Sizes Dimensions<br>"AGL015 and AGL030" note | N/A |
| | The "Temperature Grade Offerings" table was updated to include M1AGL600. | IV |
| | In the "IGLOO Ordering Information" table, the QN package measurements were updated to include both 0.4 mm and 0.5 mm. | III |
| | In the "General Description" section, the number of I/Os was updated from 288 to 300. | 1-1 |
| Packaging v1.2 | The "QN68" section is new. | 4-27 |
| **Revision 2 (Jan 2008)**<br>Packaging v1.1 | The "CS196" package and pin table was added for AGL125. | 4-12 |
| **Revision 1 (Jan 2008)**<br>Product Brief rev. 1 | The "Low Power" section was updated to change the description of low power active FPGA operation to "from 12 µW" from "from 25 µW." The same update was made in the "General Description" section and the "Flash*Freeze Technology" section. | I, 1-1 |
| **Revision 0 (Jan 2008)** | This document was previously in datasheet Advance v0.7. As a result of moving to the handbook format, Actel has restarted the numbering. | N/A |
| Advance v0.7 (December 2007) | Table 1 • IGLOO Product Family, the "I/Os Per Package1" table, and the Temperature Grade Offerings table were updated to reflect the following: CS196 is now supported for AGL250; device/package support for QN132 is to be determined for AGL250; the CS281 package was added for AGL600 and AGL1000. | i, ii, iv |
| | Table 2 • IGLOO FPGAs Package Sizes Dimensions is new, and package sizes were removed from the "I/Os Per Package1" table. | ii |
| | The "I/Os Per Package1"table was updated to reflect 77 instead of 79 single-ended I/Os for the VG100 package for AGL030. | ii |
| | The "Timing Model" was updated to be consistent with the revised timing numbers. | 2-20 |
| | In Table 2-27 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings, $T_J$ was changed to $T_A$ in notes 1 and 2. | 2-26 |
| | All AC Loading figures for single-ended I/O standards were changed from Datapaths at 35 pF to 5 pF. | N/A |
| | The "1.2 V LVCMOS (JESD8-12A)" section is new. | 2-74 |
| | This document was previously in datasheet Advance v0.7. As a result of moving to the handbook format, Actel has restarted the version numbers. The new version number is Advance v0.1. | N/A |
| | Table 2-4 • IGLOO CCC/PLL Specification and Table 2-5 • IGLOO CCC/PLL Specification were updated. | 2-19, 2-20 |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| Advance v0.7 (continued) | The former Table 2-16 • Maximum I/O Frequency for Single-Ended and Differential I/Os in All Banks in IGLOO Devices (maximum drive strength and high slew selected) was removed. | N/A |
| | The "During Flash*Freeze Mode" section was updated to include information about the output of the I/O to the FPGA core. | 2-57 |
| | Table 2-31 • Flash*Freeze Pin Location in IGLOO Family Packages (device-independent) was updated to add UC81 and CS281. Flash*Freeze pins were assigned for CS81, CS121, and CS196. | 2-61 |
| | Figure 2-40 • Flash*Freeze Mode Type 2 – Timing Diagram was updated to modify the LSICC Signal. | 2-55 |
| | Information regarding calculation of the quiescent supply current was added to the "Quiescent Supply Current" section. | 3-6 |
| | Table 3-8 • Quiescent Supply Current ($I_{DD}$) Characteristics, IGLOO Flash*Freeze Mode† was updated. | 3-6 |
| | Table 3-9 • Quiescent Supply Current ($I_{DD}$) Characteristics, IGLOO Sleep Mode (VCC = 0 V)† was updated. | 3-6 |
| | Table 3-11 • Quiescent Supply Current ($I_{DD}$), No IGLOO Flash*Freeze Mode1 was updated. | 3-7 |
| | Table 3-115 • Minimum and Maximum DC Input and Output Levels was updated. | 3-58 |
| | Table 3-156 • JTAG 1532 was updated and Table 3-155 • JTAG 1532 is new. | 3-104 |
| | The "121-Pin CSP" and "281-Pin CSP" packages are new. | 4-5, 4-7 |
| | The "81-Pin CSP" table for the AGL030 device was updated to change the G6 pin function to IO44RSB1 and the JG pin function to IO45RSB1. | 4-4 |
| | The "121-Pin CSP" table for the AGL060 device is new. | 4-6 |
| | The "256-Pin FBGA" table for the AGL1000 device is new. | 4-34 |
| | The "281-Pin CSP" table for the AGL 600 device is new. | 4-8 |
| | The "100-Pin VQFP" table for the AGL060 device is new. | 4-18 |
| | The "144-Pin FBGA" table for the AGL250 device is new. | 4-24 |
| | The "144-Pin FBGA" table for the AGL1000 device is new. | 4-28 |
| | The "484-Pin FBGA" table for the AGL600 device is new. | 4-38 |
| | The "484-Pin FBGA" table for the AGL1000 device is new. | 4-43 |
| Advance v0.6 (November 2007) | Table 1 • IGLOO Product Family, the "I/Os Per Package1" table, and the "IGLOO Ordering Information", and the Temperature Grade Offerings table were updated to add the UC81 package. | i, ii, iii, iv |
| | The "81-Pin µCSP" table for the AGL030 device is new. | 4-3 |
| | The "81-Pin CSP" table for the AGL030 device is new. | 4-1 |
| Advance v0.5 (September 2007) | Table 1 • IGLOO Product Family was updated for AGL030 in the Package Pins section to change CS181 to CS81. | i |

| Revision / Version | Changes (prior versioning system) | Page |
|---|---|---|
| Advance v0.4 (September 2007) | Cortex-M1 device information was added to Table 1 • IGLOO Product Family, the "I/Os Per Package1" table, "IGLOO Ordering Information", and Temperature Grade Offerings. | i, ii, iii, iv |
| | The number of single-ended I/Os for the CS81 package for AGL030 was updated to 66 in the "I/Os Per Package1" table. | ii |
| | The "Power Conservation Techniques" section was updated to recommend that unused I/O signals be left floating. | 2-51 |
| Advance v0.3 (August 2007) | In Table 1 • IGLOO Product Family, the CS81 package was added for AGL030. The CS196 was replaced by the CS121 for AGL060. Table note 3 was moved to the specific packages to which it applies for AGL060: QN132 and FG144. | i |
| | The CS81 and CS121 packages were added to the "I/Os Per Package1" table. The number of single-ended I/Os was removed for the CS196 package in AGL060. Table note 6 was moved to the specific packages to which it applies for AGL060: QN132 and FG144. | ii |
| | The CS81 and CS121 packages were added to the Temperature Grade Offerings table. The temperature grade offerings were removed for the CS196 package in AGL060. Table note 3 was moved to the specific packages to which it applies for AGL060: QN132 and FG144. | iv |
| | The CS81 and CS121 packages were added to Table 2-31 • Flash*Freeze Pin Location in IGLOO Family Packages (device-independent). | 2-61 |
| Advance v0.2 | The words "ambient temperature" were added to the temperature range in the "IGLOO Ordering Information", Temperature Grade Offerings, and "Speed Grade and Temperature Grade Matrix" sections. | iii, iv |
| | The $T_J$ parameter in Table 3-2 • Recommended Operating Conditions was changed to $T_A$, ambient temperature, and table notes 4–6 were added. | 3-2 |

# Datasheet Categories

### Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "IGLOO Device Status" table, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

### Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

### Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

### Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

### Unmarked (production)

This version contains information that is considered to be final.

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